

CBT (5-V) and CBTLV (3.3-V) Bus Switches

Data Book

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CBT (5-V) and CBTLV (3.3-V) Bus Switches Data Book



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INTRODUCTION

The CBT (5-V) and CBTLV (3.3-V) Bus Switches Data Book includes a comprehensive listing of the industry's standard for bus-switch technology, product offerings, and availability. These devices provide isolation when the switch is open and near-zero propagation delay when the switch is closed. Texas Instruments (TI™) bus switches provide ideal solutions for bus isolation, bus exchanging, memory interleaving, voltage translation, and docking support.

The CBTLV family is TI's new growing line of 3.3-V bus switches. Low-voltage bus switches allow for design ease in a low-voltage environment. Low voltage also means low power consumption – a key careabout for any battery-powered system.

TI's line of 5-V bus switches, the CBT family, is larger than ever. With single-gate devices, devices with integrated diodes, and Widebus™ devices available, the CBT bus-switch family offers a complete 5-V bus-switch portfolio.

TI's bus switches include 1-, 2-, 4-, 8-, 10-, 16-, 18-, 20-, and 24-bit solutions. CBT and CBTLV bus switches are designed to match the input/output combinations of traditional logic devices.

For more information on these products, including availability and pricing, please contact your local TI representative, authorized distributor, the TI technical support hotline at 972-644-5580, or visit the TI home page at <http://www.ti.com/sc/logic>.

For a listing of TI logic products, please order the *Logic CD-ROM* (literature number SCBC001) or *Logic Selection Guide* (literature number SDYU001) by calling the literature response center at 1-800-477-8924.

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If not all products specified in a data sheet are at the PRODUCTION DATA stage, then the first statement below is placed in the lower left corner of the first page of the data sheet. Subsequent pages of the data sheet containing PRODUCT PREVIEW information or ADVANCE INFORMATION are then marked in the lower left-hand corner with the appropriate statement given below:

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PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

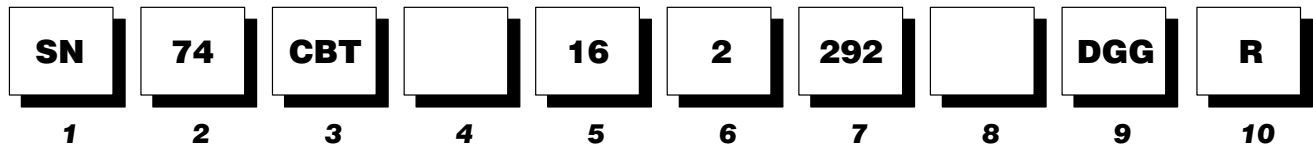
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Example:



1 Standard Prefix

Example: SN – Standard Prefix

2 Temperature Range

Examples: 54 – Military
74 – Commercial

3 Family

Examples: Blank – Transistor-Transistor Logic
ABT – Advanced BiCMOS Technology
ABTE – Advanced BiCMOS Technology/
Enhanced Transceiver Logic
AC/ACT – Advanced CMOS Logic
AHC/AHCT – Advanced High-Speed CMOS Logic
ALB – Advanced Low-Voltage BiCMOS
ALS – Advanced Low-Power Schottky Logic
ALVC – Advanced Low-Voltage CMOS Technology
AS – Advanced Schottky Logic
BCT – BiCMOS Bus-Interface Technology
CBT – Crossbar Technology
CBTLV – Low-Voltage Crossbar Technology
F – F Logic
FB – Backplane Transceiver Logic/Futurebus+
GTL – Gunning Transceiver Logic
HC/HCT – High-Speed CMOS Logic
HSTL – High-Speed Transceiver Logic
LS – Low-Power Schottky Logic
LV – Low-Voltage CMOS Technology
LVC – Low-Voltage CMOS Technology
LVT – Low-Voltage BiCMOS Technology
S – Schottky Logic
SSTL – Stub Series-Terminated Logic

4 Special Features

Examples: Blank = No Special Features
D – Level-Shifting Diode (CBTD)
H – Bus Hold (ALVCH)
R – Damping Resistor on Inputs/Outputs (LVCR)
S – Schottky Clamping Diode (CBTS)

5 Bit Width

Examples: Blank = Gates, MSI, and Octals
1G – Single Gate
8 – Octal IEEE Std 1149.1 (JTAG)
16 – Widebus™ (16, 18, and 20 bit)
18 – Widebus IEEE Std 1149.1 (JTAG)
32 – Widebus+™ (32 and 36 bit)

6 Options

Examples: Blank = No Options
2 – Series-Damping Resistor on Outputs
4 – Level Shifter
25 – 25-Ω Line Driver

7 Function

Examples: 244 – Noninverting Buffer/Driver
374 – D-Type Flip-Flop
573 – D-Type Transparent Latch
640 – Inverting Transceiver

8 Device Revision

Examples: Blank = No Revision
Letter Designator A–Z

9 Packages

Examples: D, DW – Small-Outline Integrated Circuit (SOIC)
DB, DBQ, DL – Shrink Small-Outline Package (SSOP)
DBB, DGV – Thin Very Small-Outline Package (TVSOP)
DBV, DCK – Small-Outline Transistor Package (SOT)
DGG, PW – Thin Shrink Small-Outline Package (TSSOP)
FK – Leadless Ceramic Chip Carrier (LCCC)
FN – Plastic Leaded Chip Carrier (PLCC)
GB – Ceramic Pin Grid Array (CPGA)
HFP, HS, HT, HV – Ceramic Quad Flat Package (CQFP)
J, JT – Ceramic Dual-In-Line Package (CDIP)
N, NP, NT – Plastic Dual-In-Line Package (PDIP)
PAG, PAH, PCA, PCB, PM, PN, PZ –
Thin Quad Flat Package (TQFP)
PH, PQ, RC – Quad Flat Package (QFP)
W, WA, WD – Ceramic Flat Package (CFP)

10 Tape and Reel

All new or changed devices in the DB and PW package types include the R designation for reeled product. Existing products designated as LE presently maintain that designation, but will be converted to R in the future.

Nomenclature Examples:

For an Existing Device – SN74LVTxxxDBLE

For a New or Changed Device – SN74LVTxxxADBR

LE – Left Embossed (valid for DB and PW packages only)

R – Standard (valid for all surface-mount packages except existing DB and PW devices)

There is no functional difference between LE and R designated products, with respect to the carrier tape, cover tape, or reels used.

NOTIFICATION OF PACKAGE NOMENCLATURE ALIAS (for Standard Linear and Logic device names of greater than 18 characters)

TI is converting from its current order-entry system to a more advanced system. This conversion requires modifications, both internal and external, to TI's current business processes. This new system will ultimately provide significant improvements to all facets of TI's business – from production, to order entry, to logistics. One change required is a limitation of TI part numbers to no more than 18 characters in length. Based on customer inputs, Standard Linear and Logic determined the least disruptive implementations as outlined below:

1. Package alias

TI will use a package alias to denote specific package types for devices currently exceeding 18 characters in length. Table 1 shows a mapping of package codes to an alias single-character representation.

Table 1

CURRENT PACKAGE CODE	ALIAS
DL	L
DGG/DBB	G
DGV	V
DLR	LR – tape/reel packing
DGGR/DBBR	GR – tape/reel packing
DGVR	VR – tape/reel packing

Current: SN74 ALVCH 162269A DGGR

New: SN74 ALVCH 162269A GR

2. Resistor-option nomenclature

For devices greater than 18 characters with input and output resistors, TI will adopt a simplified nomenclature to designate the resistor option. This will eliminate the redundant "2" (designating output resistors) when the part number also contains an "R" (designating input/output resistors).

Input/Output Resistor
Output Resistor

Current: SN74 ALVCH R 16 2 245 A
New: SN74 ALVCH R 16 245 A

There is no change to the device or data-sheet electrical parameters. The packages involved and the changes in nomenclature are noted in Table 1.

These nomenclature changes are being gradually implemented. The first customer-visible conversions for TI logic devices will be made to data sheets. Over the next few months, TI logic data sheets will be updated. These changes in device nomenclature do not reflect a change in device performance or process characteristics.

INTRODUCTION

These symbols, terms, and definitions are in accordance with those currently agreed upon by the JEDEC Council of the Electronic Industries Association (EIA) for use in the USA and by the International Electrotechnical Commission (IEC) for international use.

operating conditions and characteristics (in sequence by letter symbols)

C_i	Input capacitance The internal capacitance at an input of the device
C_{io}	Input/output capacitance Input-to-output internal capacitance; transcapacitance
C_o	Output capacitance The internal capacitance at an output of the device
C_{pd}	Power dissipation capacitance Used to determine the no-load dynamic power dissipation per logic function (see individual circuit pages): $P_D = C_{pd} V_{CC}^2 f + I_{CC} V_{CC}$
f_{max}	Maximum clock frequency The highest rate at which the clock input of a bistable circuit can be driven through its required sequence while maintaining stable transitions of logic level at the output with input conditions established that should cause changes of output logic level in accordance with the specification
I_{BHH}	Bus-hold high sustaining current The sourcing current of the bus-hold circuit to maintain the input at or above the minimum V_{IH} , if the last valid logic state at the input was a high
I_{BHHO}	Bus-hold high overdrive current The current required to overcome the sourcing current of the bus-hold circuit and switch the input to a low state
I_{BHL}	Bus-hold low sustaining current The sinking current of the bus-hold circuit to maintain the input at or below the maximum V_{IL} , if the last valid logic state at the input was a low
I_{BHLO}	Bus-hold low overdrive current The current required to overcome the sinking current of the bus-hold circuit and switch the input to a high state
I_{CC}	Supply current The current into* the V_{CC} supply terminal of an integrated circuit
ΔI_{CC}	Supply current change The increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}
I_{CEX}	Output high leakage current The maximum leakage current into the collector of the pulldown output transistor when the output is high and the output forcing condition $V_O = 5.5$ V

*Current out of a terminal is given as a negative value.

GLOSSARY

SYMBOLS, TERMS, AND DEFINITIONS

$I_{I(\text{hold})}$	Input hold current Input current that holds the input at the previous state when the driving device goes to a high-impedance state
I_{IH}	High-level input current The current into* an input when a high-level voltage is applied to that input
I_{IL}	Low-level input current The current into* an input when a low-level voltage is applied to that input
I_{off}	Input/output power-off leakage current The maximum leakage current into/out of the input/output transistors when forcing the input/output to 4.5 V and $V_{CC} = 0$ V
I_{OH}	High-level output current The current into* an output with input conditions applied that, according to the product specification, establishes a high level at the output
I_{OL}	Low-level output current The current into* an output with input conditions applied that, according to the product specification, establishes a low level at the output
I_{OZ}	Off-state (high-impedance-state) output current (of a 3-state output) The current that flows through the output gates when the device is in the high-impedance state
I_{OZPD}	Power-down (high-impedance-state) output current (of a 3-state output) The current that flows into or out of the output stage when the device is being powered down from the high-impedance state
I_{OZPU}	Power-up (high-impedance-state) output current (of a 3-state output) The current that flows into or out of the output stage when the device is being powered up from the high-impedance state
t_a	Access time The time interval between the application of a specified input pulse and the availability of valid signals at an output
t_c	Clock cycle time Clock cycle time is $1/f_{\text{max}}$.
t_{dis}	Disable time (of a 3-state or open-collector output) The propagation time between the specified reference points on the input and output voltage waveforms with the output changing from either of the defined active levels (high or low) to a high-impedance (off) state NOTE: For 3-state outputs, $t_{\text{dis}} = t_{\text{PHZ}}$ or t_{PLZ} . Open-collector outputs change only if they are low at the time of disabling, so $t_{\text{dis}} = t_{\text{PLH}}$.
t_{en}	Enable time (of a 3-state or open-collector output) The propagation time between the specified reference points on the input and output voltage waveforms with the output changing from a high-impedance (off) state to either of the defined active levels (high or low) NOTE: In the case of memories, this is the access time from an enable input (e.g., $\overline{\text{OE}}$). For 3-state outputs, $t_{\text{en}} = t_{\text{PZH}}$ or t_{PZL} . Open-collector outputs change only if they are responding to data that would cause the output to go low, so $t_{\text{en}} = t_{\text{PHL}}$.

*Current out of a terminal is given as a negative value.



t_h	Hold time The time interval during which a signal is retained at a specified input terminal after an active transition occurs at another specified input terminal NOTES: 1. The hold time is the actual time interval between two signal events and is determined by the system in which the digital circuit operates. A minimum value is specified that is the shortest interval for which correct operation of the digital circuit is to be expected. 2. The hold time may have a negative value in which case the minimum limit defines the longest interval (between the release of the signal and the active transition) for which correct operation of the digital circuit is to be expected.
t_{pd}	Propagation delay time The time between the specified reference points on the input and output voltage waveforms with the output changing from one defined level (high or low) to the other defined level (t _{pd} = t _{PHL} or t _{PLH})
t_{PHL}	Propagation delay time, high-to-low level output The time between the specified reference points on the input and output voltage waveforms with the output changing from the defined high level to the defined low level
t_{PHZ}	Disable time (of a 3-state output) from high level The time interval between the specified reference points on the input and the output voltage waveforms with the 3-state output changing from the defined high level to the high-impedance (off) state
t_{PLH}	Propagation delay time, low-to-high level output The time between the specified reference points on the input and output voltage waveforms with the output changing from the defined low level to the defined high level
t_{PLZ}	Disable time (of a 3-state output) from low level The time interval between the specified reference points on the input and the output voltage waveforms with the 3-state output changing from the defined low level to the high-impedance (off) state
t_{PZH}	Enable time (of a 3-state output) to high level The time interval between the specified reference points on the input and output voltage waveforms with the 3-state output changing from the high-impedance (off) state to the defined high level
t_{PZL}	Enable time (of a 3-state output) to low level The time interval between the specified reference points on the input and output voltage waveforms with the 3-state output changing from the high-impedance (off) state to the defined low level
t_{sk(o)}	Output skew The difference between any two propagation delay times when a single switching input or multiple inputs switching simultaneously cause multiple outputs to switch, as observed across all switching output. This parameter is used to describe the fanout capability of a clock driver and is of concern when making decisions on clock buffering and distribution networks.

GLOSSARY

SYMBOLS, TERMS, AND DEFINITIONS

t_{su}	Setup time The time interval between the application of a signal at a specified input terminal and a subsequent active transition at another specified input terminal NOTES: 1. The setup time is the actual time interval between two signal events and is determined by the system in which the digital circuit operates. A minimum value is specified that is the shortest interval for which correct operation of the digital circuit is to be expected. 2. The setup time may have a negative value, in which case the minimum limit defines the longest interval (between the active transition and the application of the other signal) for which correct operation of the digital circuit is to be expected.
t_w	Pulse duration (width) The time interval between specified reference points on the leading and trailing edges of the pulse waveform
$\Delta t/\Delta v$	Input voltage transition rate The input transition rise or fall rate corresponding to the change in signal amplitude with time
$\Delta t/\Delta V_{CC}$	Power supply power-up rate The power-up ramp rate corresponds to the transition rate of the supply voltage when the device is being powered up.
V_{IH}	High-level input voltage An input voltage within the more positive (less negative) of the two ranges of values used to represent the binary variables NOTE: A minimum is specified that is the least positive value of high-level input voltage for which operation of the logic element within specification limits is to be expected.
V_{IL}	Low-level input voltage An input voltage within the less positive (more negative) of the two ranges of values used to represent the binary variables NOTE: A maximum is specified that is the most positive value of low-level input voltage for which operation of the logic element within specification limits is to be expected.
V_{OH}	High-level output voltage The voltage at an output terminal with input conditions applied that, according to product specification, establishes a high level at the output
V_{OL}	Low-level output voltage The voltage at an output terminal with input conditions applied that, according to product specification, establishes a low level at the output
V_{IT+}	Positive-going input threshold level The voltage level at a transition-operated input that causes operation of the logic element according to specification as the input voltage rises from a level below the negative-going threshold voltage, V_{IT-}
V_{IT-}	Negative-going input threshold level The voltage level at a transition-operated input that causes operation of the logic element according to specification as the input voltage falls from a level above the positive-going threshold voltage, V_{IT+}

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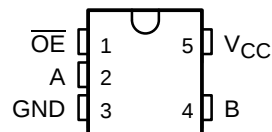
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SN74CBT1G125 SINGLE FET BUS SWITCH

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- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Packaged in Plastic Small-Outline Transistor (DBV, DCK) Packages

DBV OR DCK PACKAGE
(TOP VIEW)



description

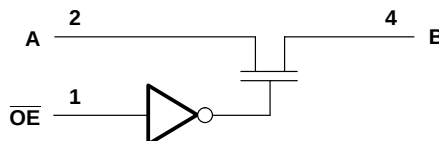
The SN74CBT1G125 features a single high-speed line switch. The switch is disabled when the output-enable ($\overline{OE}$) input is high.

The SN74CBT1G125 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBT1G125

SINGLE FET BUS SWITCH

SCDS046C – FEBRUARY 1998 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	347°C/W
DCK package	389°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±1	µA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			1	µA
C_i Control input	$V_I = 3$ V or 0			3	pF
$C_{io(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$			4	pF
r_{on}^S	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V, $V_I = 2.4$ V, $I_I = 15$ mA			14	20
	$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA	5	7
			$I_I = 30$ mA	5	7
		$V_I = 2.4$ V, $I_I = 15$ mA		10	15

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^S Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

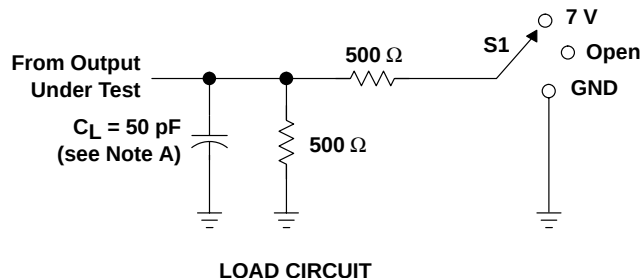
switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger\dagger}$	A or B	B or A		0.35		0.25	ns
t_{en}	$\overline{OE}$	A or B		5.5	1.6	4.9	ns
t_{dis}	$\overline{OE}$	A or B		4.5	1	4.2	ns

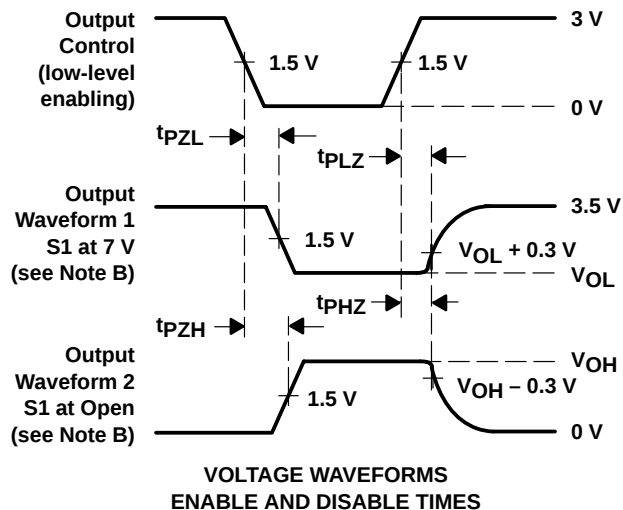
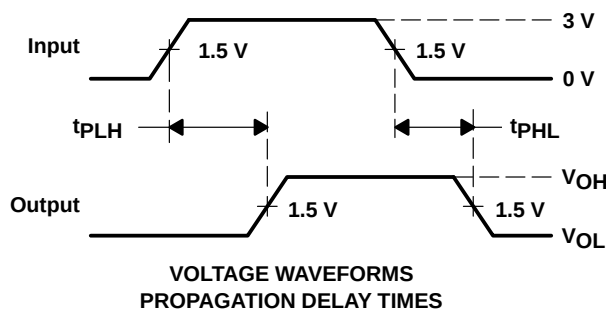
^{††} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The output is measured with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTD1G125 SINGLE FET BUS SWITCH WITH LEVEL SHIFTING

SCDS063B – JULY 1998 – REVISED OCTOBER 1998

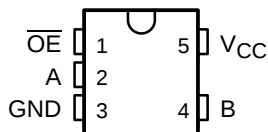
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Packaged in Plastic Small-Outline Transistor (DBV, DCK) Packages

description

The SN74CBTD1G125 features a single high-speed line switch. The switch is disabled when the output-enable ($\overline{OE}$) input is high. A diode to V_{CC} is integrated on the chip to allow for level shifting between 5-V inputs and 3.3-V outputs.

The SN74CBTD1G125 is characterized for operation from -40°C to 85°C .

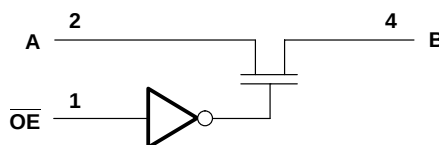
DBV OR DCK PACKAGE
(TOP VIEW)



FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



PRODUCT PREVIEW

SN74CBTD1G125

SINGLE FET BUS SWITCH

WITH LEVEL SHIFTING

SCDS063B – JULY 1998 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	347°C/W
DCK package	389°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
V_{OH}	See Figure 2				
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±1	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			1	μA
C_i Control input	$V_I = 3$ V or 0				pF
$C_{io(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$				pF
$r_{on}^{\S}$	$V_{CC} = 4.5$ V	$V_I = 0$		$I_I = 64$ mA	Ω
				$I_I = 30$ mA	
		$V_I = 2.4$ V,		$I_I = 15$ mA	

[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

[§] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

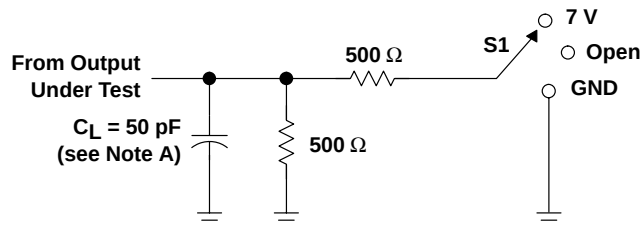
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PRODUCT PREVIEW

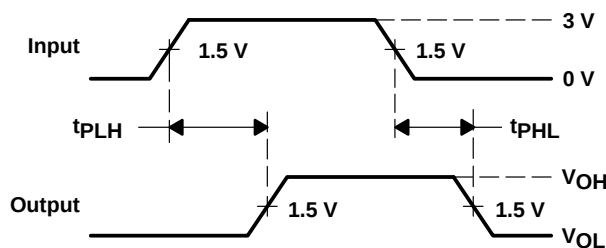


PARAMETER MEASUREMENT INFORMATION

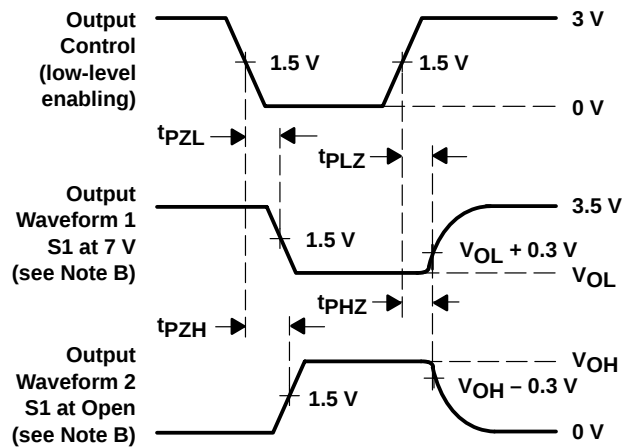


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The output is measured with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

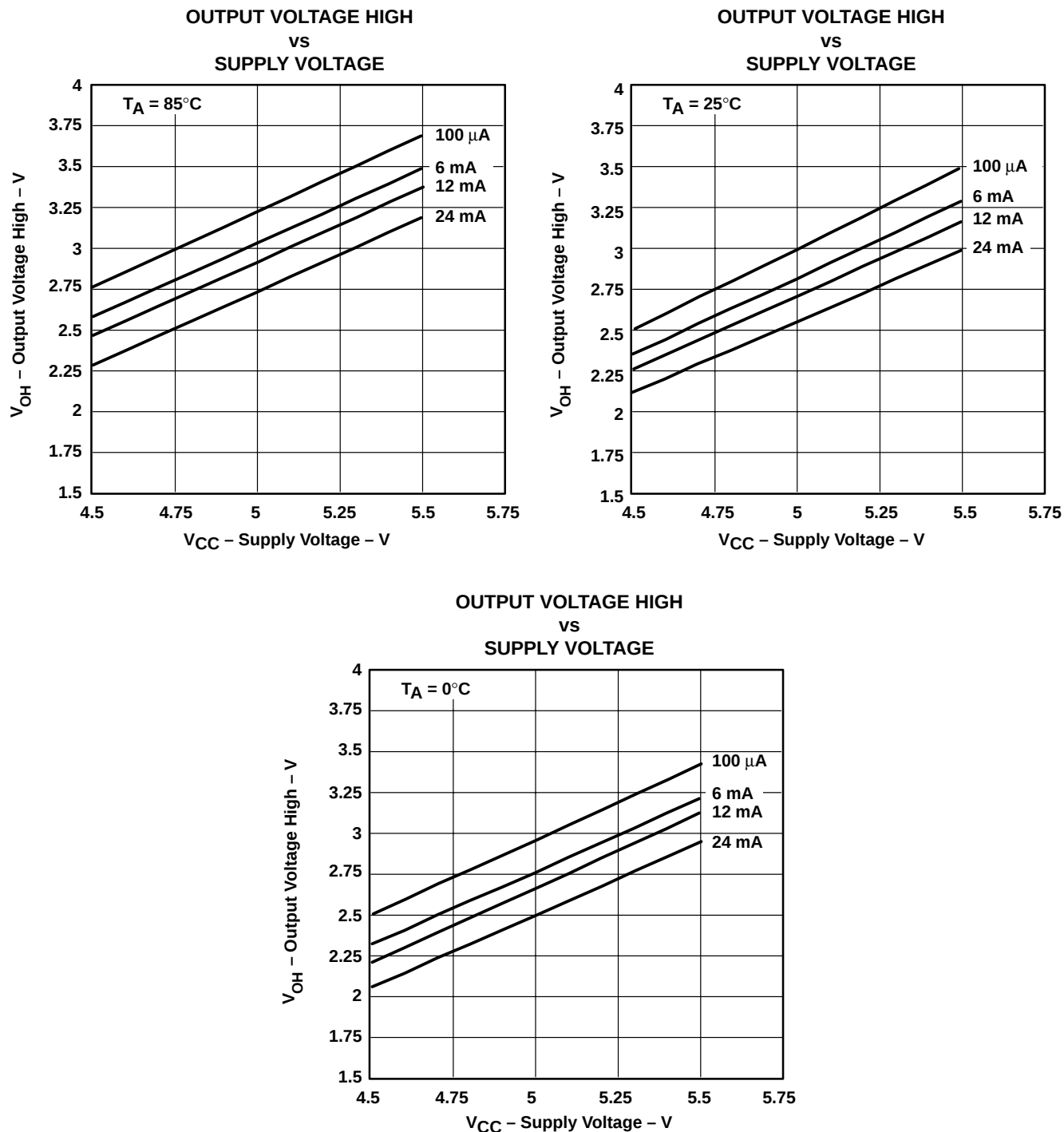


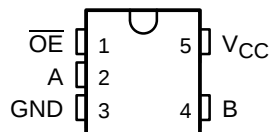
Figure 2. V_{OH} Values

SN74CBTS1G125 SINGLE FET BUS SWITCH

SCDS064A – JULY 1998 – REVISED OCTOBER 1998

- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Packaged in Plastic Small-Outline Transistor (DBV, DCK) Packages

DBV OR DCK PACKAGE
(TOP VIEW)



description

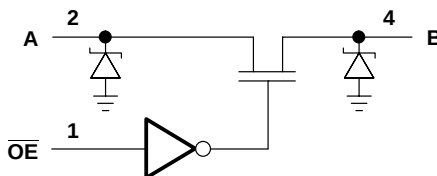
The SN74CBTS1G125 features a single high-speed line switch with Schottky diodes on the I/O to clamp undershoot. The switch is disabled when the output-enable ($\overline{OE}$) input is high.

The SN74CBTS1G125 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



PRODUCT PREVIEW

SN74CBTS1G125

SINGLE FET BUS SWITCH

SCDS064A – JULY 1998 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	347°C/W
DCK package	389°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–0.7	V
I_I	$V_{CC} = 5.5$ V, $V_I = \text{GND}$			–1	μA
	$V_{CC} = 5.5$ V, $V_I = 5.5$ V			50	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
C_i Control input	$V_I = 3$ V or 0				pF
$C_{io(\text{OFF})}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$				pF
$r_{on}^{\S}$	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V, $V_I = 2.4$ V, $I_I = 15$ mA				Ω
	$V_{CC} = 4.5$ V, $V_I = 0$, $I_I = 64$ mA				
	$V_{CC} = 4.5$ V, $V_I = 0$, $I_I = 30$ mA				
	$V_{CC} = 4.5$ V, $V_I = 2.4$ V, $I_I = 15$ mA				

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PRODUCT PREVIEW

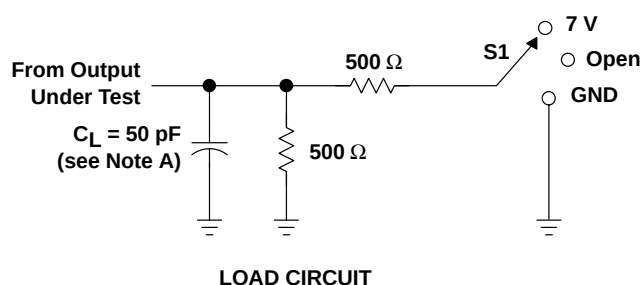


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

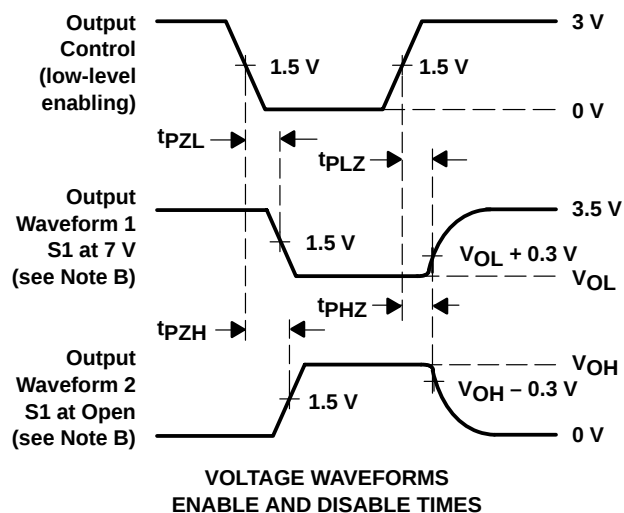
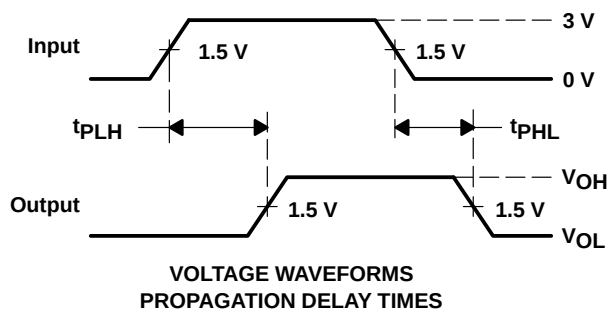
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PHL}	Open

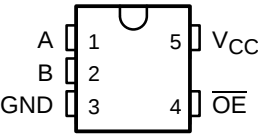


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The output is measured with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Packaged in Plastic Small-Outline Transistor (DBV, DCK) Packages

DBV OR DCK PACKAGE
(TOP VIEW)



description

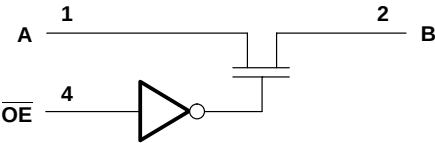
The SN74CBT1G384 features a single high-speed line switch. The switch is disabled when the output-enable ($\overline{\text{OE}}$) input is high.

The SN74CBT1G384 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT $\overline{\text{OE}}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBT1G384

SINGLE FET BUS SWITCH

SCDS065A – JULY 1998 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	347°C/W
DCK package	389°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±1	µA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			1	µA
C_i Control input	$V_I = 3$ V or 0				pF
$C_{io(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$				pF
r_{on}^S	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V, $V_I = 2.4$ V, $I_I = 15$ mA				Ω
	$V_{CC} = 4.5$ V, $V_I = 0$, $I_I = 64$ mA				
	$V_{CC} = 4.5$ V, $V_I = 0$, $I_I = 30$ mA				
	$V_{CC} = 4.5$ V, $V_I = 2.4$ V, $I_I = 15$ mA				

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^S Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

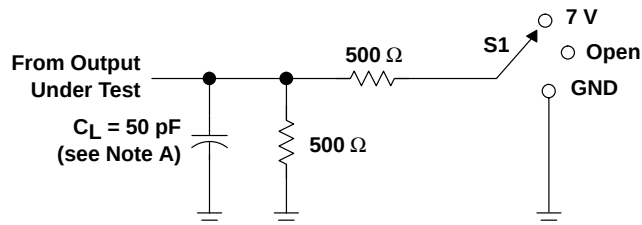
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger\dagger}$	A or B	B or A					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

^{††} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PRODUCT PREVIEW

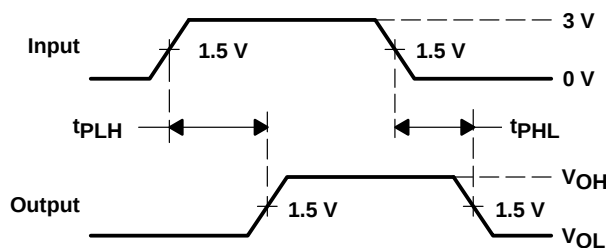


PARAMETER MEASUREMENT INFORMATION

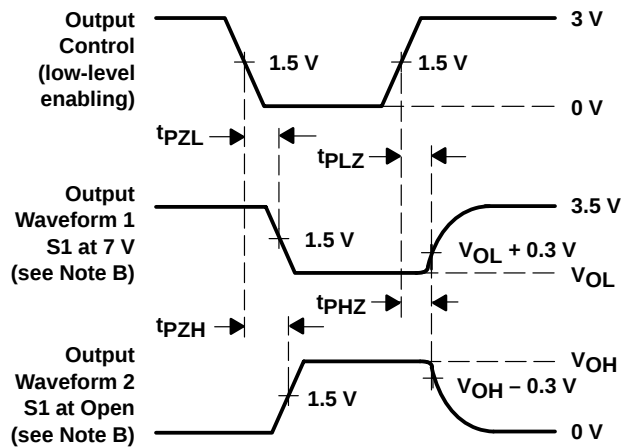


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The output is measured with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

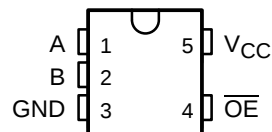
Figure 1. Load Circuit and Voltage Waveforms

SN74CBTD1G384 SINGLE FET BUS SWITCH WITH LEVEL SHIFTING

SCDS066B – JULY 1998 – REVISED OCTOBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Packaged in Plastic Small-Outline Transistor (DBV, DCK) Packages

DBV OR DCK PACKAGE
(TOP VIEW)



description

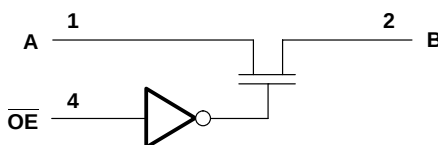
The SN74CBTD1G384 features a single high-speed line switch. The switch is disabled when the output-enable ($\overline{OE}$) input is high. A diode to V_{CC} is integrated on the chip to allow for level shifting between 5-V inputs and 3.3-V outputs.

The SN74CBTD1G384 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



PRODUCT PREVIEW

SCDS066B – JULY 1998 – REVISED OCTOBER 1998

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	347°C/W
DCK package	389°C/W
Storage temperature range, T_{Stg}	−65°C to 150°C

NOTES:

1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51.

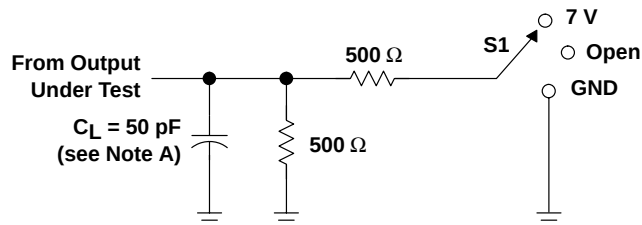
		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	V
V _{IH}	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
T _A	Operating free-air temperature	−40	85	°C

PARAMETER		TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = −18 mA			−1.2	V
V _{OH}		See Figure 2					
I _I		V _{CC} = 5.5 V,	V _I = 5.5 V or GND			±1	μA
I _{CC}		V _{CC} = 5.5 V,	I _O = 0, V _I = V _{CC} or GND			1	μA
C _i	Control input	V _I = 3 V or 0					pF
C _{IO} (OFF)		V _O = 3 V or 0, $\overline{\text{OE}}$ = V _{CC}					pF
r _{on} [§]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA			Ω
				I _I = 30 mA			
			V _I = 2.4 V, I _I = 15 mA				

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t _{pd} [¶]	A or B	B or A			ns
t _{en}	$\overline{\text{OE}}$	A or B			ns
t _{dis}	$\overline{\text{OE}}$	A or B			ns

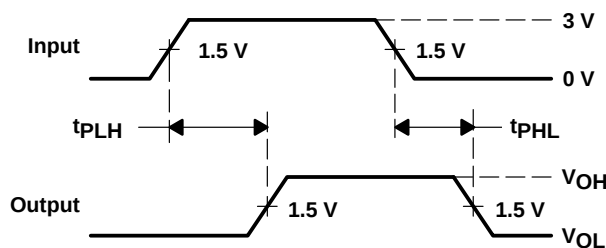


PARAMETER MEASUREMENT INFORMATION

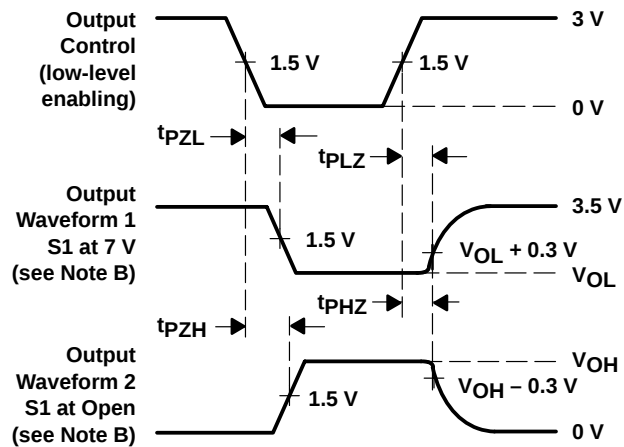


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The output is measured with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

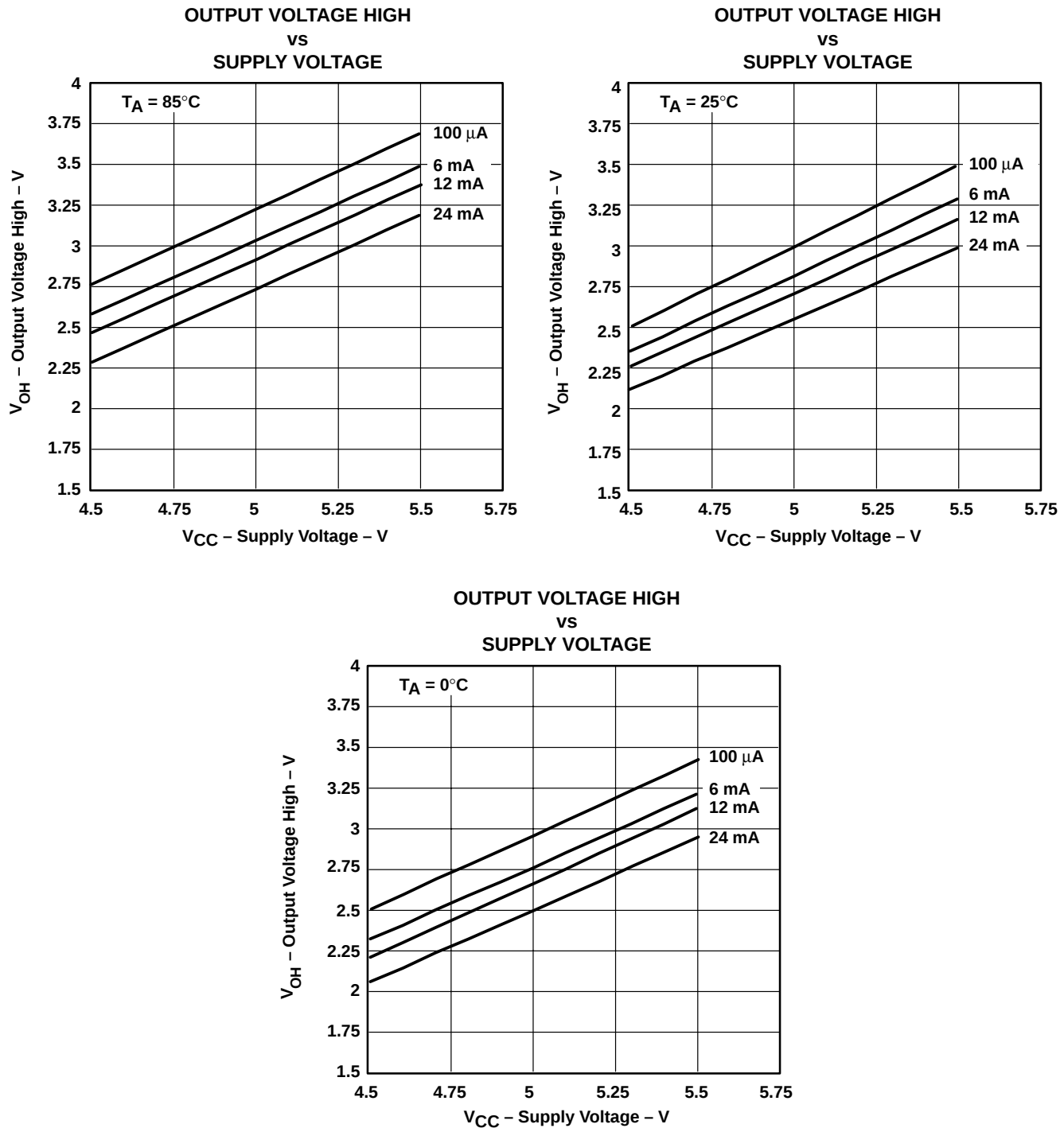
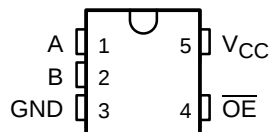


Figure 2. V_{OH} Values

- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Packaged in Plastic Small-Outline Transistor (DBV, DCK) Packages

DBV OR DCK PACKAGE
(TOP VIEW)



description

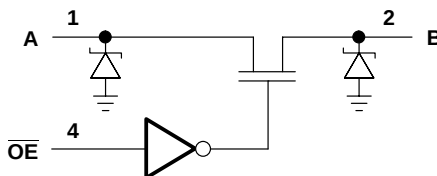
The SN74CBTS1G384 features a single high-speed line switch with Schottky diodes on the I/O to clamp undershoot. The switch is disabled when the output-enable ($\overline{OE}$) input is high.

The SN74CBTS1G384 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBTS1G384

SINGLE FET BUS SWITCH

SCDS067A – JULY 1998 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	347°C/W
DCK package	389°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–0.7	V
I_I	$V_{CC} = 5.5$ V, $V_I = \text{GND}$			–1	μA
	$V_{CC} = 5.5$ V, $V_I = 5.5$ V			50	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
C_i Control input	$V_I = 3$ V or 0				pF
$C_{io(\text{OFF})}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$				pF
$r_{on}^{\S}$	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V, $V_I = 2.4$ V, $I_I = 15$ mA				Ω
	$V_{CC} = 4.5$ V, $V_I = 0$, $I_I = 64$ mA				
	$V_{CC} = 4.5$ V, $V_I = 0$, $I_I = 30$ mA				
	$V_{CC} = 4.5$ V, $V_I = 2.4$ V, $I_I = 15$ mA				

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PRODUCT PREVIEW

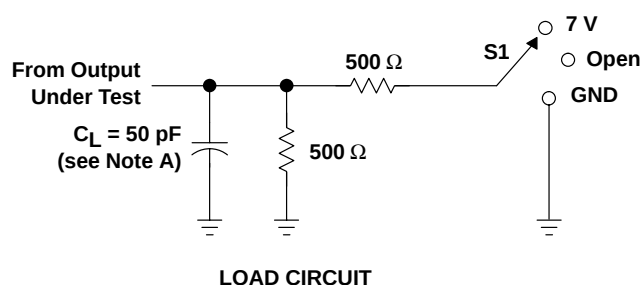


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

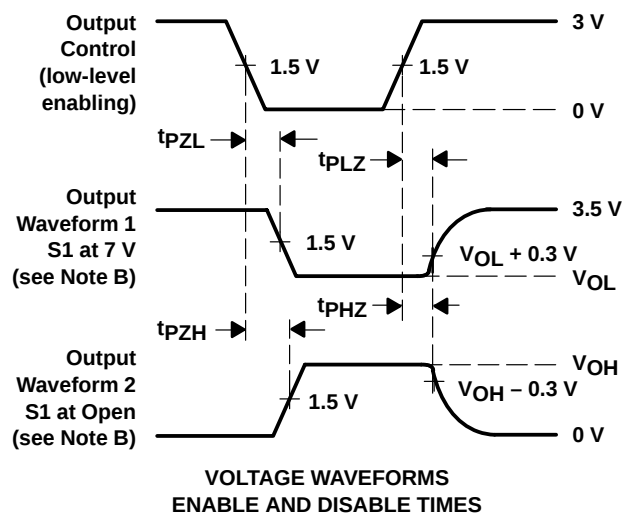
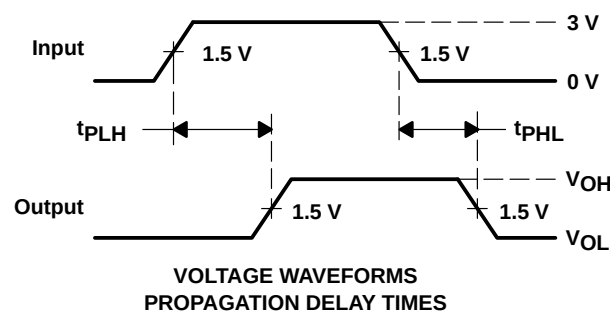
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The output is measured with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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SN74CBT3125 QUADRUPLE FET BUS SWITCH

SCDS021E – MAY 1995 – REVISED MAY 1998

- Standard '125-Type Pinout
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

description

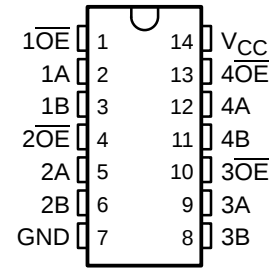
The SN74CBT3125 quadruple FET bus switch features independent line switches. Each switch is disabled when the associated output-enable ($\overline{OE}$) input is high.

The SN74CBT3125 is characterized for operation from -40°C to 85°C .

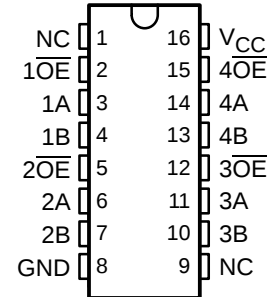
FUNCTION TABLE
(each bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

D, DB, DGV, OR PW PACKAGE
(TOP VIEW)

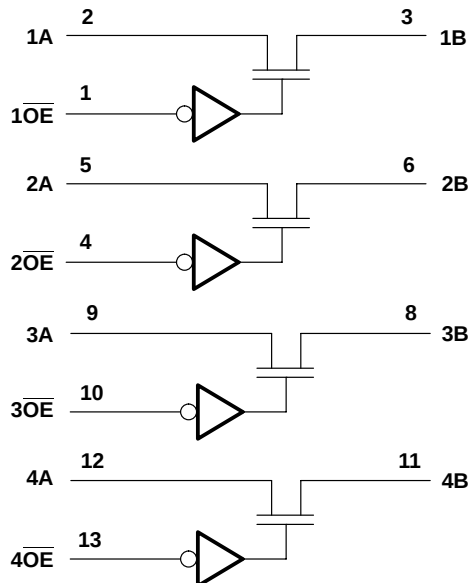


DBQ PACKAGE
(TOP VIEW)



NC – No internal connection

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, and PW packages.

SN74CBT3125

QUADRUPLE FET BUS SWITCH

SCDS021E – MAY 1995 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	127°C/W
DB package	158°C/W
DBQ package	139°C/W
DGV package	182°C/W
PW package	170°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4$ V,	$I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V,	$V_I = 5.5$ V or GND			±1	μA
I_{CC}	$V_{CC} = 5.5$ V,	$I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
$\Delta I_{CC}^{\S}$	Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i	Control inputs	$V_I = 3$ V or 0			3	pF
$C_{io(OFF)}$	$V_O = 3$ V or 0,	$\overline{OE} = V_{CC}$			4	pF
$r_{on}^{\parallel}$	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V, $I_I = 15$ mA		16	22	Ω
	$V_{CC} = 4.5$ V	$V_I = 0$, $I_I = 64$ mA		5	7	
		$I_I = 30$ mA		5	7	
		$V_I = 2.4$ V, $I_I = 15$ mA		10	15	

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

^{\parallel} Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.

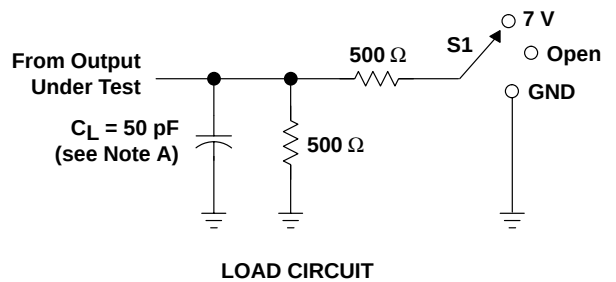


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

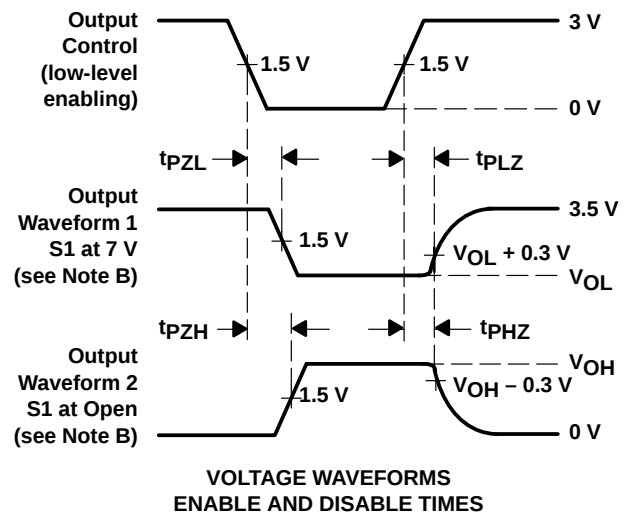
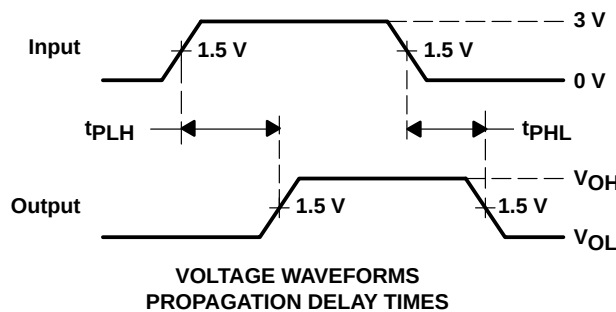
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.35		0.25		ns
t_{en}	$\overline{OE}$	A or B	6		1.6	5.4	ns
t_{dis}	$\overline{OE}$	A or B	5.1		1	4.7	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PHL}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PHL} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT3126 QUADRUPLE FET BUS SWITCH

SCDS020E – MAY 1995 – REVISED MAY 1998

- Standard '126-Type Pinout (D, DGV, and PW Packages)
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

description

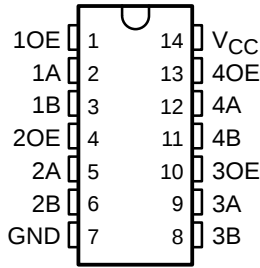
The SN74CBT3126 quadruple FET bus switch features independent line switches. Each switch is disabled when the associated output-enable (OE) input is low.

The SN74CBT3126 is characterized for operation from –40°C to 85°C.

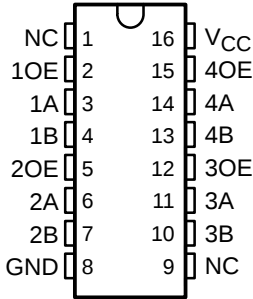
FUNCTION TABLE
(each bus switch)

INPUT OE	FUNCTION
L	Disconnect
H	A = B

D, DGV, OR PW PACKAGE
(TOP VIEW)

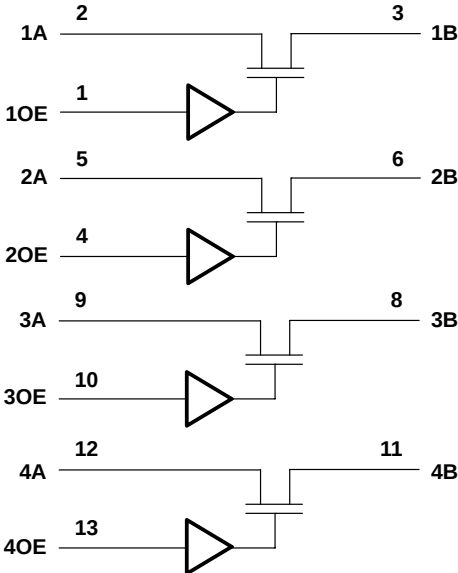


DBQ PACKAGE
(TOP VIEW)



NC – No internal connection

logic diagram (positive logic)



Pin numbers shown are for the D, DGV, and PW packages.

SN74CBT3126

QUADRUPLE FET BUS SWITCH

SCDS020E – MAY 1995 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	127°C/W
DBQ package	139°C/W
DGV package	182°C/W
PW package	170°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4$ V, $I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±1	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
$\Delta I_{CC}^{\S}$ Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i Control inputs	$V_I = 3$ V or 0			3	pF
$C_{io(OFF)}$	$V_O = 3$ V or 0, OE = GND			4	pF
$r_{on}^{\parallel}$	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V, $V_I = 2.4$ V, $I_I = 15$ mA			16	22
	$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA	5	7
			$I_I = 30$ mA	5	7
		$V_I = 2.4$ V, $I_I = 15$ mA		10	15

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

^{\parallel} Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

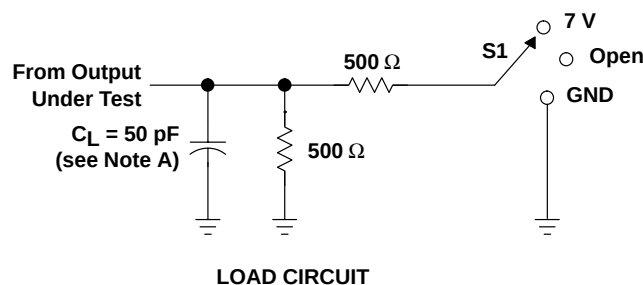


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

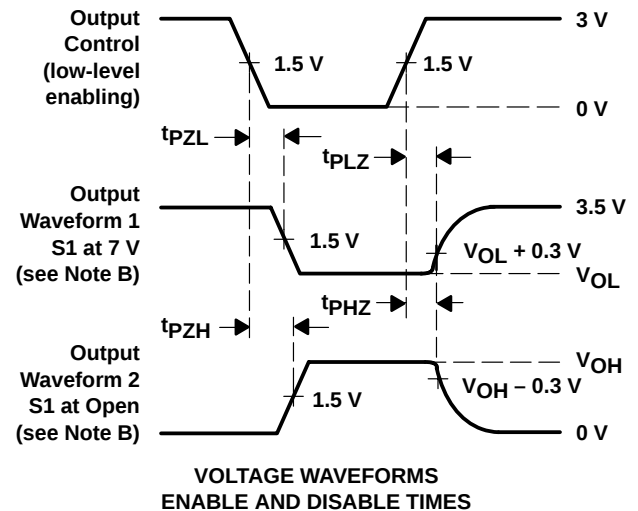
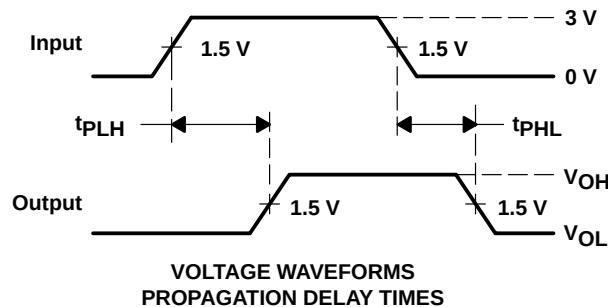
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.35		0.25		ns
t_{en}	OE	A or B	5.4		1.6	5.1	ns
t_{dis}	OE	A or B	5		1	4.5	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

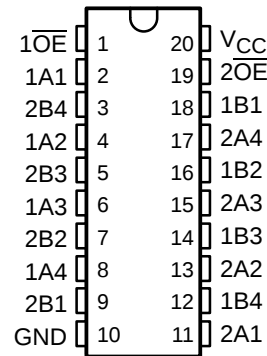


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Functionally Equivalent to QS3244
- Standard '244-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



description

The SN74CBT3244 provides eight bits of high-speed TTL-compatible bus switching in a standard '244 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

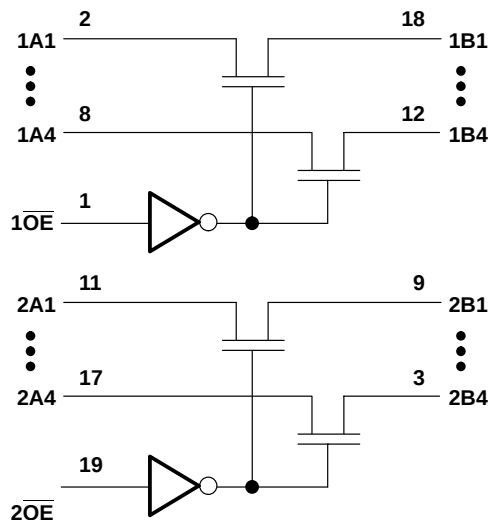
The device is organized as two 4-bit low-impedance switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and data can flow from port A to port B, or vice versa. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The SN74CBT3244 is characterized for operation from 0°C to 70 °C.

FUNCTION TABLE
(each 4-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBT3244

OCTAL FET BUS SWITCH

SCDS001H – NOVEMBER 1992 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	115°C/W
DBQ package	118°C/W
DGV package	146°C/W
DW package	97°C/W
PW package	128°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	0	70	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V,	$I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V,	$V_I = 5.5$ V or GND			±5	μA
I_{CC}	$V_{CC} = 5.5$ V,	$I_O = 0$, $V_I = V_{CC}$ or GND			50	μA
ΔI_{CC} [§] Control inputs	$V_{CC} = 5.5$ V,	One input at 3.4 V, Other inputs at V_{CC} or GND			3.5	mA
C_i Control inputs	$V_I = 3$ V or 0			3		pF
$C_{io(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$			6		pF
r_{on} [¶]	$V_{CC} = 4.5$ V	$V_I = 0$, $I_I = 64$ mA		5	7	Ω
		$I_I = 30$ mA		5	7	
		$V_I = 2.4$ V, $I_I = 15$ mA		10	15	

[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

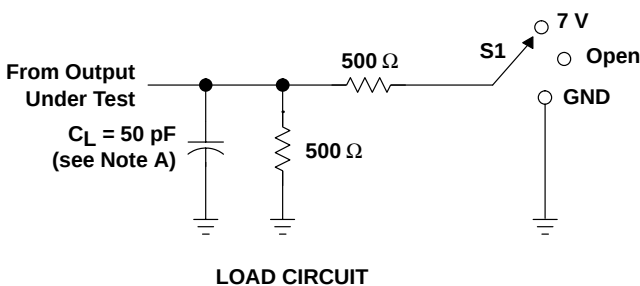


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

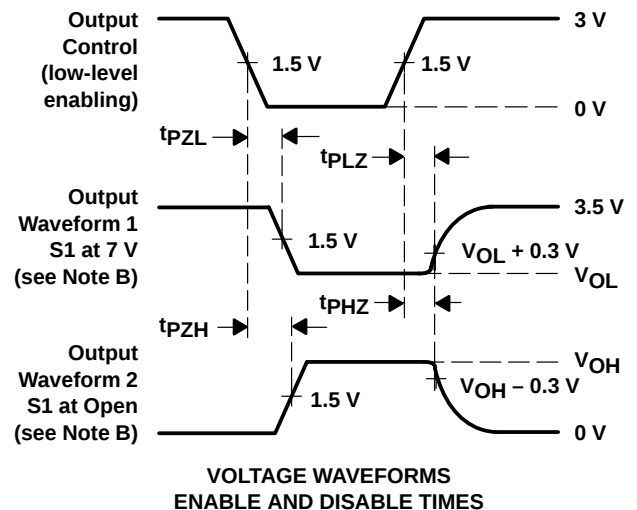
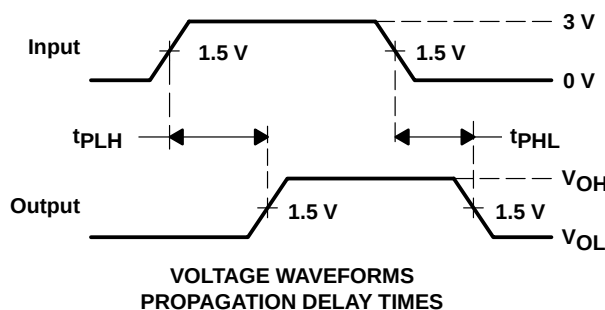
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^\dagger$	A or B	B or A		0.25	ns
t_{en}	$\overline{OE}$	A or B	1	8.9	ns
t_{dis}	$\overline{OE}$	A or B	1	7.4	ns

[†] This propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Functionally Equivalent to QS3244
- Standard '244-Type Pinout
- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

description

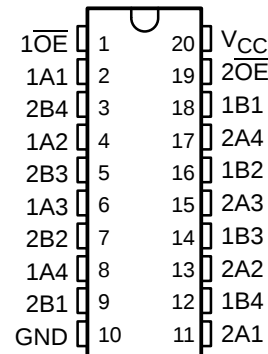
The SN74CBTR3244 provides eight bits of high-speed TTL-compatible bus switching in a standard '244 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 4-bit low-impedance switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and data can flow from port A to port B, or vice versa. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR3244 is characterized for operation from 0°C to 70 °C.

DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



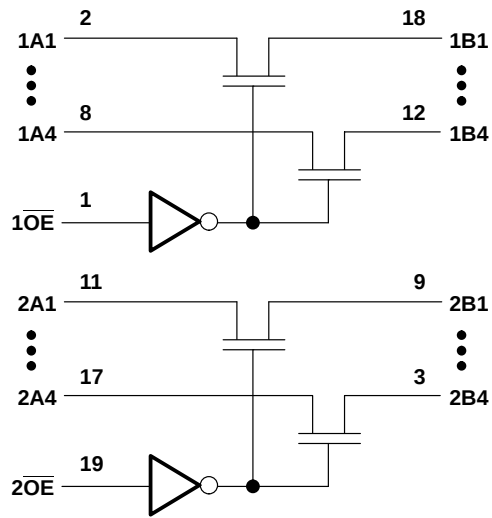
FUNCTION TABLE
(each 4-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

SN74CBTR3244
OCTAL FET BUS SWITCH

SCDS079 – JULY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	115°C/W
DBQ package	118°C/W
DGV package	146°C/W
DW package	97°C/W
PW package	128°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	0	70	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

PRODUCT PREVIEW



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2	V
I_I		$V_{CC} = 5.5\text{ V}$, $V_I = 5.5\text{ V}$ or GND			± 5	μA
I_{CC}		$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND			50	μA
$\Delta I_{CC}^{\ddagger}$	Control inputs	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND			3.5	mA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0				pF
$C_{io(OFF)}$		$V_O = 3\text{ V}$ or 0, $\overline{OE} = V_{CC}$				pF
$r_{on}^{\S}$		$V_{CC} = 4.5\text{ V}$, $V_I = 0$, $I_I = 64\text{ mA}$				Ω
		$V_I = 0$, $I_I = 30\text{ mA}$				
		$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$				

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

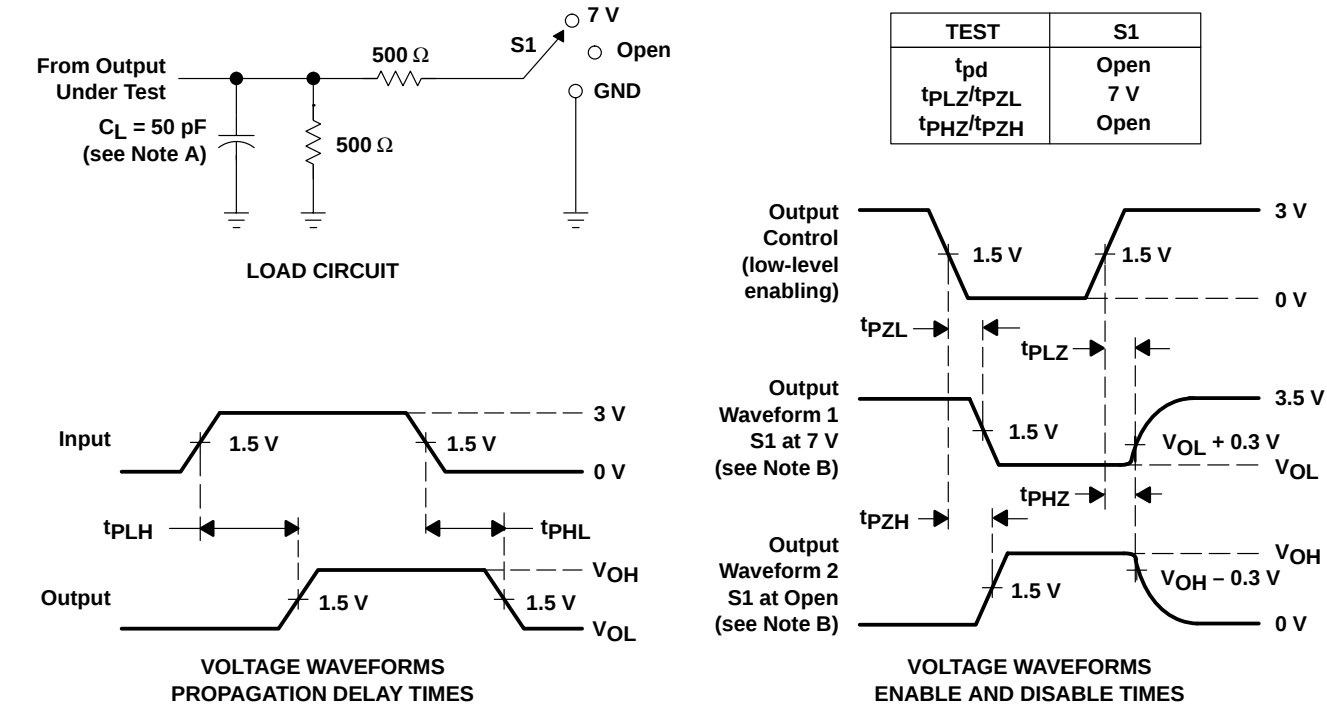
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

^{||} This propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBTR3244
OCTAL FET BUS SWITCH

SCDS079 – JULY 1998

PARAMETER MEASUREMENT INFORMATION

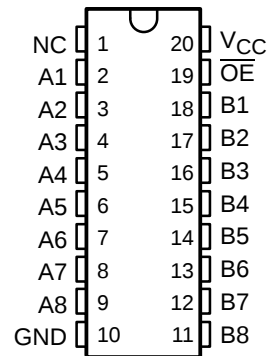


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Functionally Equivalent to QS3245
- Standard '245-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



NC – No internal connection

description

The SN74CBT3245A provides eight bits of high-speed TTL-compatible bus switching in a standard '245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

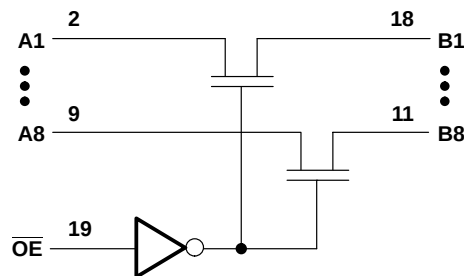
The device is organized as one 8-bit switch. When output enable ($\overline{OE}$) is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The SN74CBT3245A is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBT3245A

OCTAL FET BUS SWITCH

SCDS002J – NOVEMBER 1992 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	115°C/W
DBQ package	118°C/W
DGV package	146°C/W
DW package	97°C/W
PW package	128°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±5	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			50	μA
ΔI_{CC} [§] Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			3.5	mA
C_i Control inputs	$V_I = 3$ V or 0		4		pF
$C_{iO(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$		4		pF
r_{on} [¶]	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V, $I_I = 15$ mA			Ω
	$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA	5	
			$I_I = 30$ mA	5	
		$V_I = 2.4$ V, $I_I = 15$ mA		10	

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

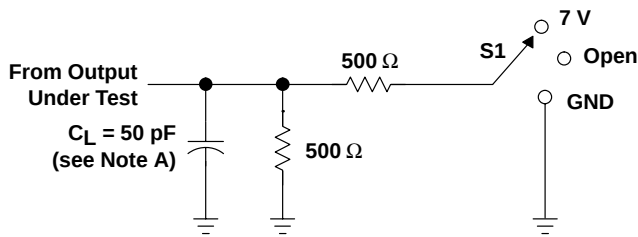


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.35		0.25		ns
t_{en}	$\overline{OE}$	A or B	6.4		1.9	5.9	ns
t_{dis}	$\overline{OE}$	A or B	5.7		2.1	6	ns

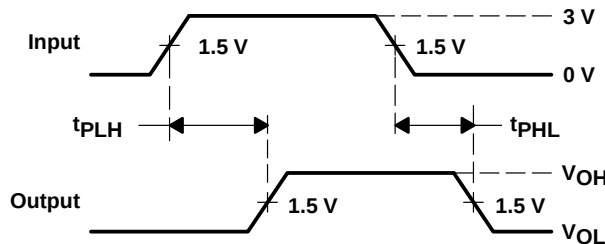
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

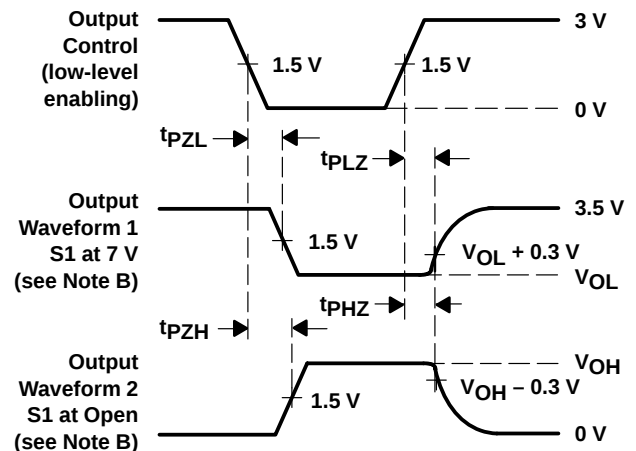


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Functionally Equivalent to QS3245
- Standard '245-Type Pinout
- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

description

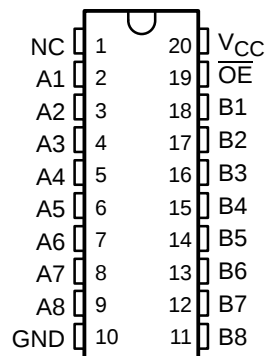
The SN74CBTR3245 provides eight bits of high-speed TTL-compatible bus switching in a standard '245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 8-bit switch. When output enable ($\overline{OE}$) is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR3245 is characterized for operation from -40°C to 85°C.

DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)

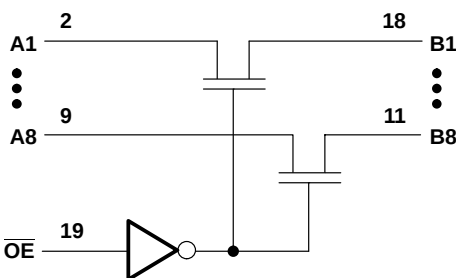


NC – No internal connection

FUNCTION TABLE

INPUT OE	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBTR3245

OCTAL FET BUS SWITCH

SCDS080 – JULY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	115°C/W
DBQ package	118°C/W
DGV package	146°C/W
DW package	97°C/W
PW package	128°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V,	$I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V,	$V_I = 5.5$ V or GND			±5	μA
I_{CC}	$V_{CC} = 5.5$ V,	$I_O = 0$, $V_I = V_{CC}$ or GND			50	μA
ΔI_{CC} [§] Control inputs	$V_{CC} = 5.5$ V,	One input at 3.4 V, Other inputs at V_{CC} or GND			3.5	mA
C_i Control inputs	$V_I = 3$ V or 0					pF
$C_{iO(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$					pF
r_{on} [¶]	$V_{CC} = 4.5$ V	$V_I = 0$, $I_I = 64$ mA				Ω
		$I_I = 30$ mA				
		$V_I = 2.4$ V, $I_I = 15$ mA				

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

PRODUCT PREVIEW

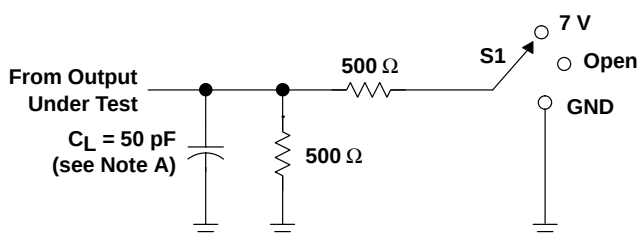


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^\dagger$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

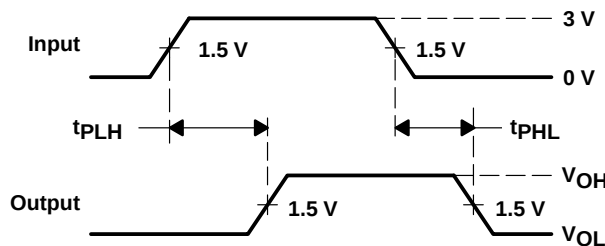
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

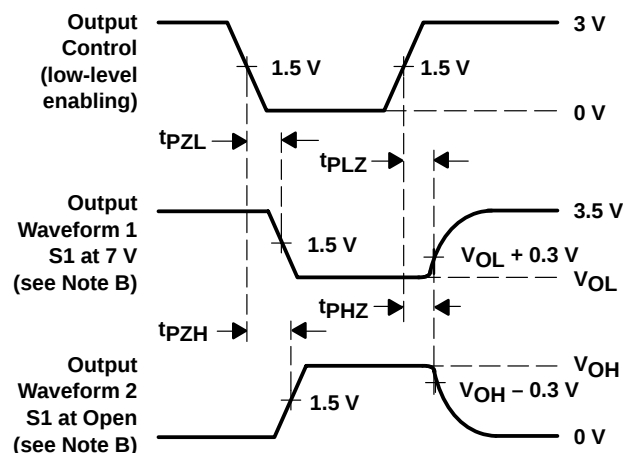


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT3251

1-OF-8 FET MULTIPLEXER/DEMULTIPLEXER

SCDS019G – MAY 1995 – REVISED MAY 1998

- Functionally Equivalent to QS3251
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

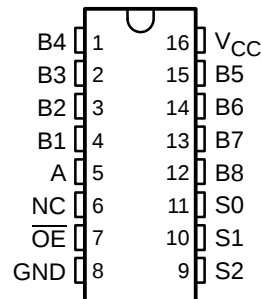
description

The SN74CBT3251 is a 1-of-8 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

When output enable ($\overline{OE}$) is low, the SN74CBT3251 is enabled. S0, S1, and S2 select one of the B outputs for the A-input data.

The SN74CBT3251 is characterized for operation from -40°C to 85°C .

D, DB, DBQ, DGV, OR PW PACKAGE
(TOP VIEW)



NC – No internal connection

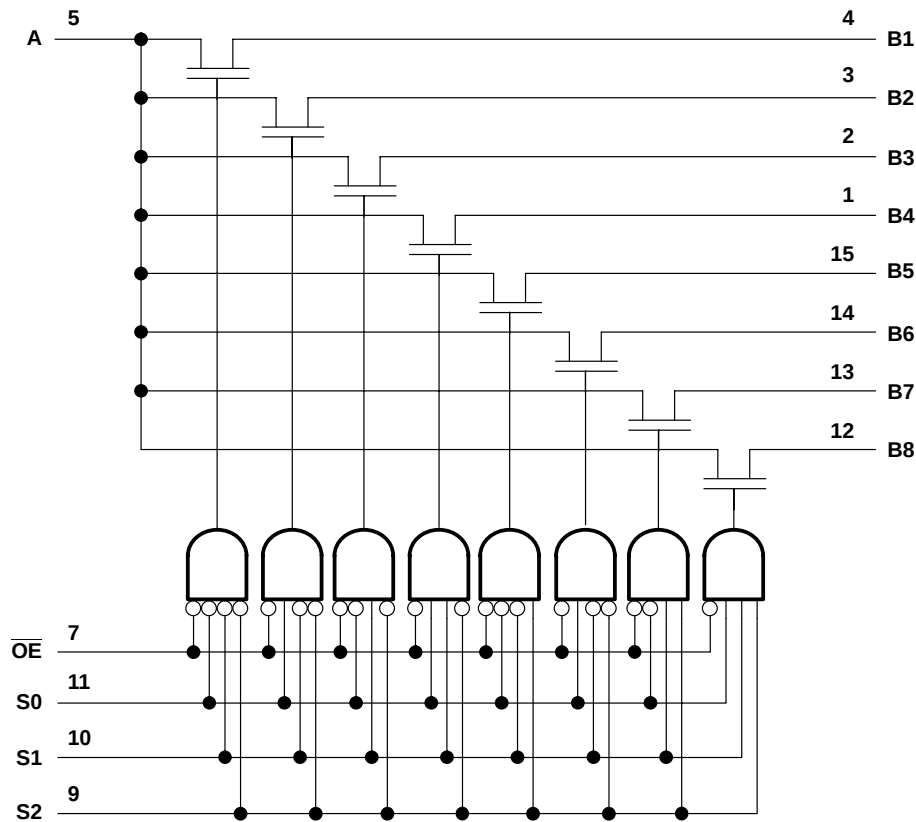
FUNCTION TABLE
(each multiplexer/demultiplexer)

INPUTS				FUNCTION
$\overline{OE}$	S2	S1	S0	
L	L	L	L	A port = B1 port
L	L	L	H	A port = B2 port
L	L	H	L	A port = B3 port
L	L	H	H	A port = B4 port
L	H	L	L	A port = B5 port
L	H	L	H	A port = B6 port
L	H	H	L	A port = B7 port
L	H	H	H	A port = B8 port
H	X	X	X	Disconnect

SN74CBT3251
1-OF-8 FET MULTIPLEXER/DEMULTIPLEXER

SCDS019G – MAY 1995 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	113°C/W
DB package	131°C/W
DBQ package	139°C/W
DGV package	180°C/W
PW package	149°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT	
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA					−1.2	V	
I _I		V _{CC} = 5.5 V, V _I = 5.5 V or GND					±1	μA	
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND					3	μA	
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND					2.5	mA	
C _i	Control inputs	V _I = 3 V or 0					3.5	pF	
C _{io} (OFF)	A port	V _O = 3 V or 0, $\overline{OE}$ = V _{CC}					17.5	pF	
	B port						4		
r _{on} [§]	V _{CC} = 4 V, TYP at V _{CC} = 4 V		V _I = 2.4 V, I _I = 15 mA				14	20	Ω
			V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				
	I _I = 30 mA						5	7	
	V _I = 2.4 V, I _I = 15 mA					10	15		

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

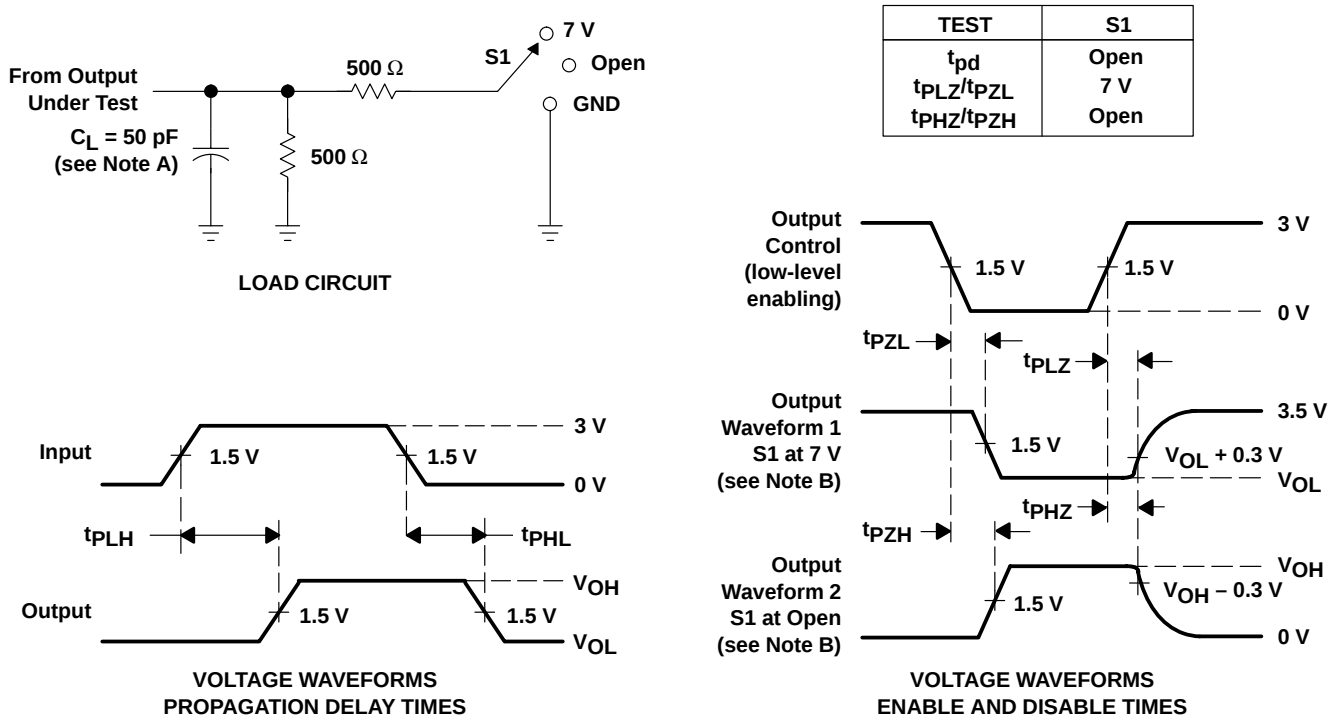
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A	0.35		0.25		ns
t _{pd}	S	A	6		2	5.5	ns
t _{en}	S	B	6.4		1.5	5.6	ns
	$\overline{OE}$	A or B	6.4		1.6	5.8	
t _{dis}	S	B	6.8		1.9	6.4	ns
	$\overline{OE}$	A or B	6		2.3	6.2	

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBT3251 1-OF-8 FET MULTIPLEXER/DEMULTIPLEXER

SCDS019G – MAY 1995 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT3253

DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS018I – MAY 1995 – REVISED MAY 1998

- Functionally Equivalent to QS3253
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

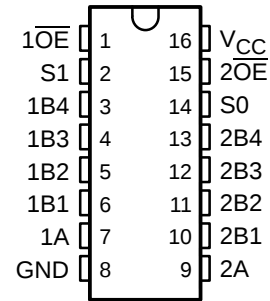
description

The SN74CBT3253 is a dual 1-of-4 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

$\overline{1OE}$, $\overline{2OE}$, S0, and S1 select the appropriate B output for the A-input data.

The SN74CBT3253 is characterized for operation from -40°C to 85°C .

D, DB, DBQ, DGV, OR PW PACKAGE
(TOP VIEW)



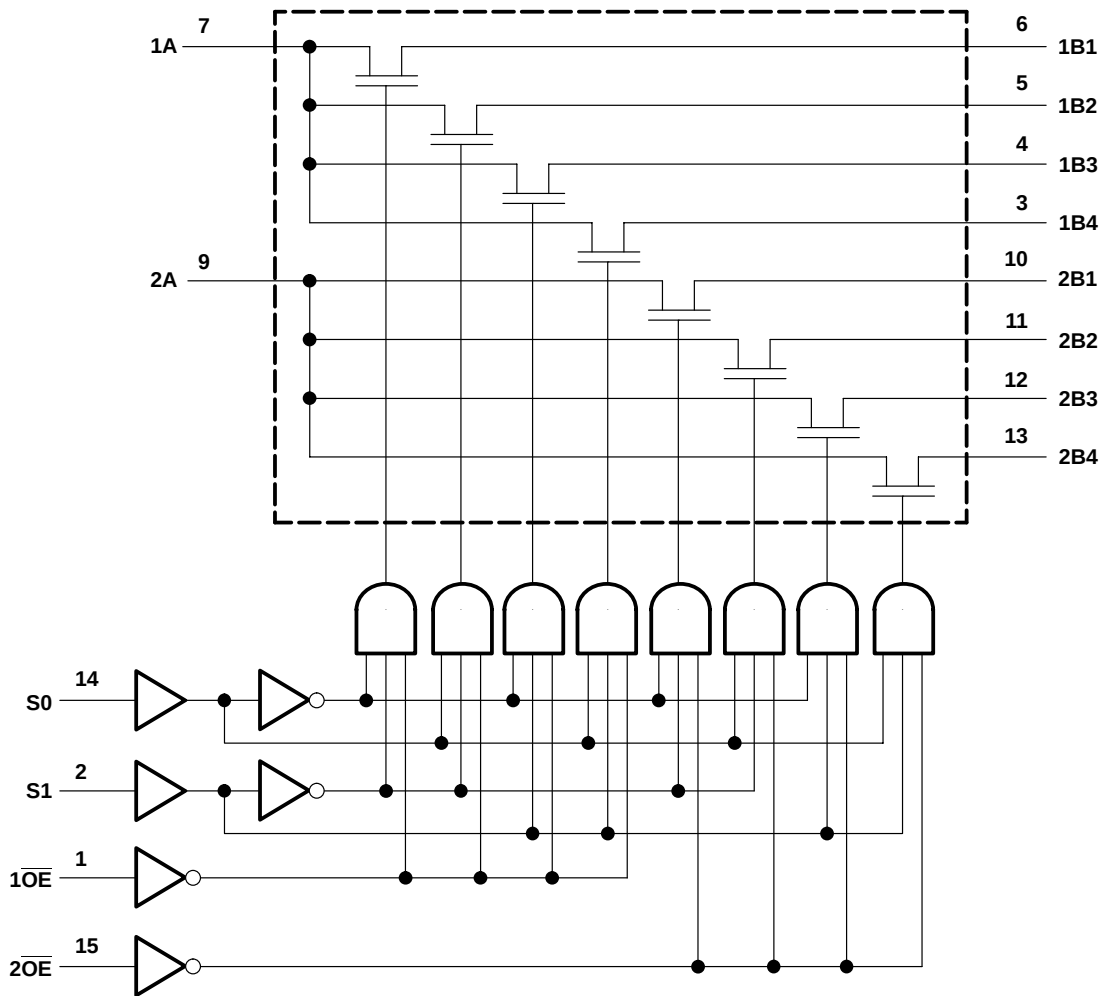
FUNCTION TABLE
(each multiplexer/demultiplexer)

INPUTS			FUNCTION
$\overline{OE}$	S1	S0	
L	L	L	A port = B1 port
L	L	H	A port = B2 port
L	H	L	A port = B3 port
L	H	H	A port = B4 port
H	X	X	Disconnect

SN74CBT3253
DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS018I – MAY 1995 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	113°C/W
DB package	131°C/W
DBQ package	139°C/W
DGV package	180°C/W
PW package	149°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = –18 mA				–1.2	V
I _I		V _{CC} = 5 V, V _I = 5.5 V or GND				±1	μA
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND				3	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				2.5	mA
C _i	Control inputs	V _I = 3 V or 0				3.5	pF
C _{io} (OFF)	A port	V _O = 3 V or 0, $\overline{OE}$ = V _{CC}				10	pF
	B port					4	
r _{on} [§]	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA					Ω
		V _I = 0, I _I = 64 mA				5 7	
	V _{CC} = 4.5 V	I _I = 30 mA				5 7	
		V _I = 2.4 V, I _I = 15 mA				10 15	

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

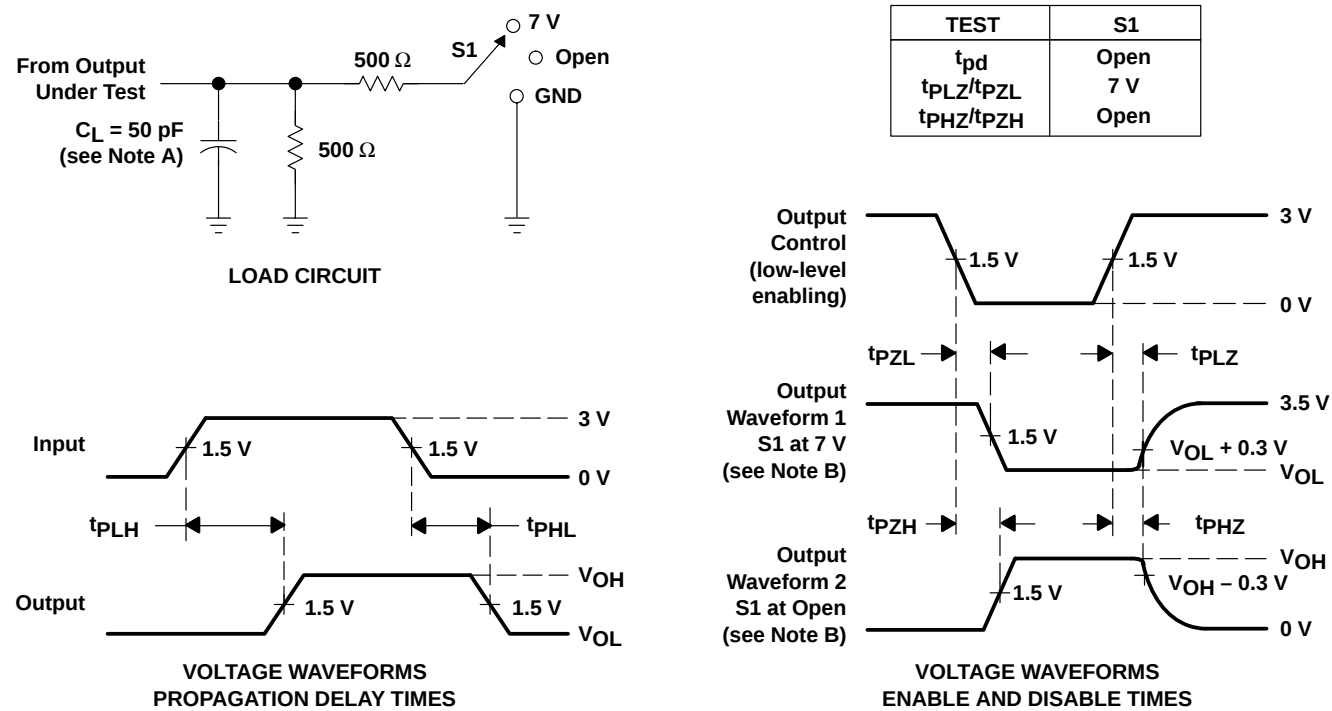
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A		0.35		0.25	ns
t _{pd}	S	A or B		6.6	1.6	6.2	ns
t _{en}	S	A or B		7.1	1.3	6.3	ns
	$\overline{OE}$			7.3	1.4	6.4	
t _{dis}	S	A or B		7.9	1.1	7.4	ns
	$\overline{OE}$			7.3	2.3	7	

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBT3253 DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS018I – MAY 1995 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION

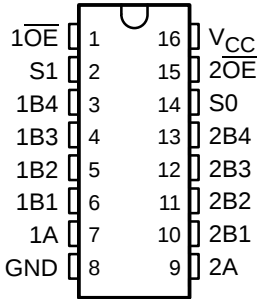


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Functionally Equivalent to QS3253
- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

D, DB, DBQ, DGV, OR PW PACKAGE
(TOP VIEW)



description

The SN74CBTR3253 is a dual 1-of-4 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

1OE, 2OE, S0, and S1 select the appropriate B output for the A-input data.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR3253 is characterized for operation from –40°C to 85°C.

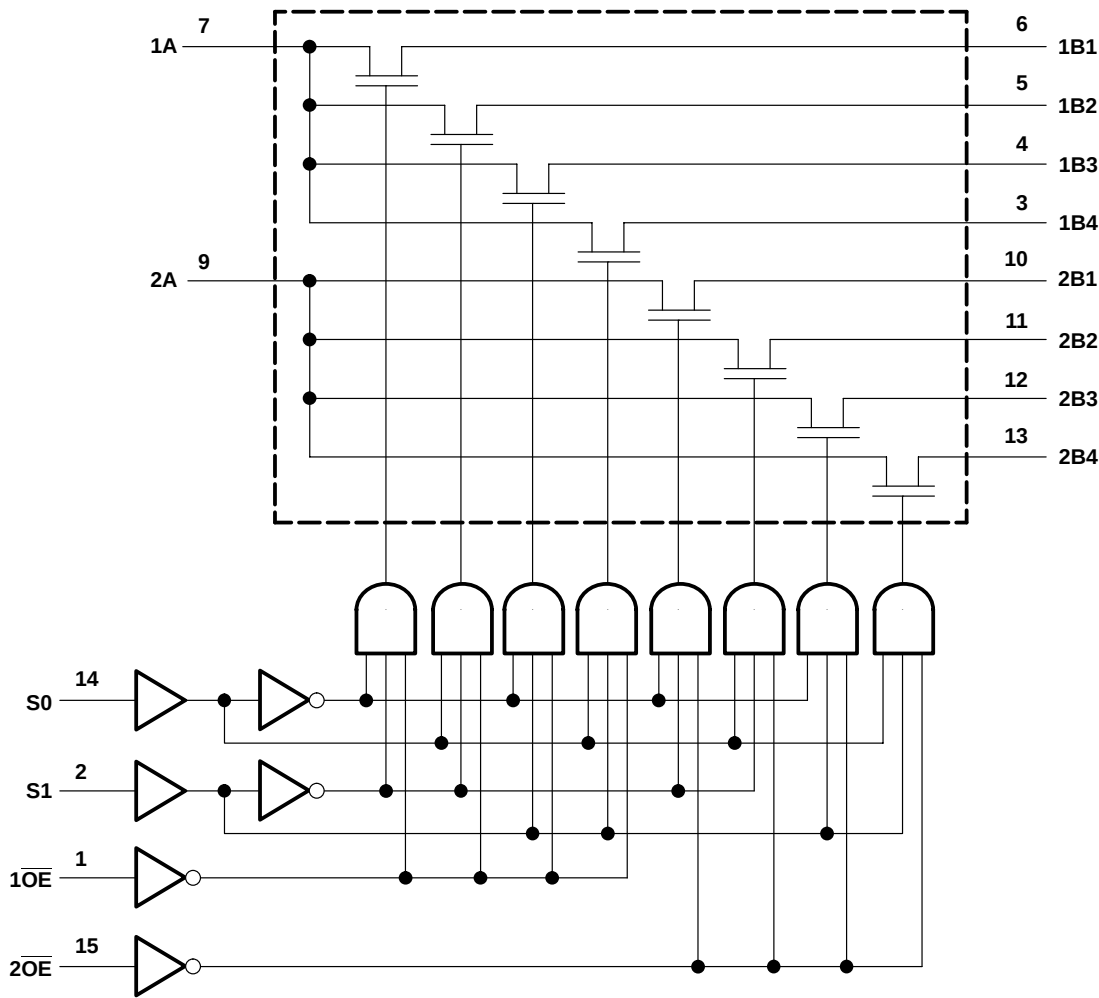
FUNCTION TABLE
(each multiplexer/demultiplexer)

INPUTS			FUNCTION
OE	S1	S0	
L	L	L	A port = B1 port
L	L	H	A port = B2 port
L	H	L	A port = B3 port
L	H	H	A port = B4 port
H	X	X	Disconnect

SN74CBTR3253
DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS081 – JULY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	113°C/W
DB package	131°C/W
DBQ package	139°C/W
DGV package	180°C/W
PW package	149°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4.5	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = –18 mA				–1.2	V
I _I		V _{CC} = 5 V, V _I = 5.5 V or GND				±1	μA
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND				3	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				2.5	mA
C _i	Control inputs	V _I = 3 V or 0					pF
C _{io} (OFF)	A port	V _O = 3 V or 0, $\overline{OE}$ = V _{CC}					pF
	B port						pF
r _{on} [§]		V _{CC} = 4.5 V, V _I = 0, I _I = 64 mA					Ω
		V _{CC} = 4.5 V, V _I = 0, I _I = 30 mA					
		V _{CC} = 4.5 V, V _I = 2.4 V, I _I = 15 mA					

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t _{pd} [¶]	A or B	B or A			ns
t _{pd}	S	A or B			ns
t _{en}	S	A or B			ns
	$\overline{OE}$				
t _{dis}	S	A or B			ns
	$\overline{OE}$				

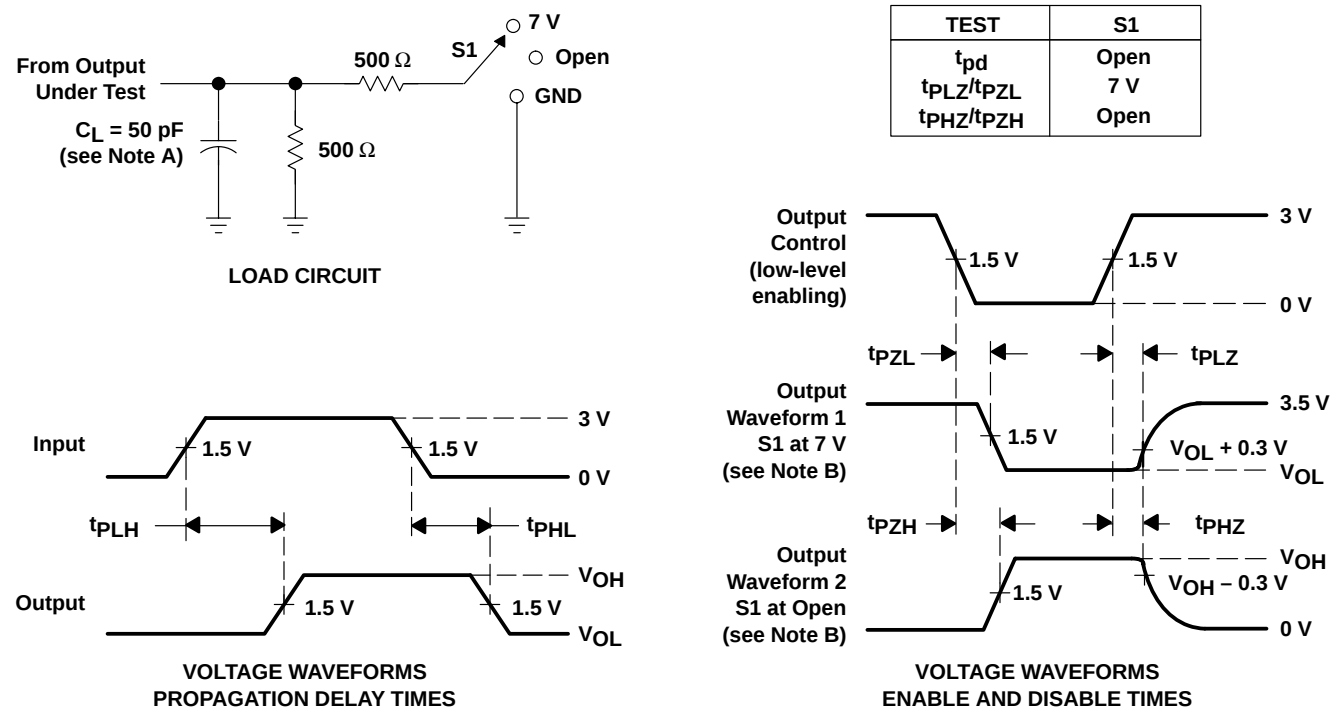
[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PRODUCT PREVIEW

SN74CBTR3253
DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS081 – JULY 1998

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT3257

4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS017I – MAY 1995 – REVISED MAY 1998

- Functionally Equivalent to QS3257
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB, DBQ), and Thin Shrink Small-Outline (PW) Packages

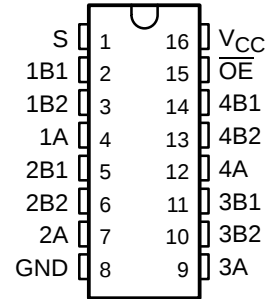
description

The SN74CBT3257 is a 4-bit 1-of-2 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

Output-enable ($\overline{OE}$) and select-control (S) inputs select the appropriate B1 and B2 outputs for the A-input data.

The SN74CBT3257 is characterized for operation from -40°C to 85°C .

D, DB, DBQ, OR PW PACKAGE
(TOP VIEW)



FUNCTION TABLE

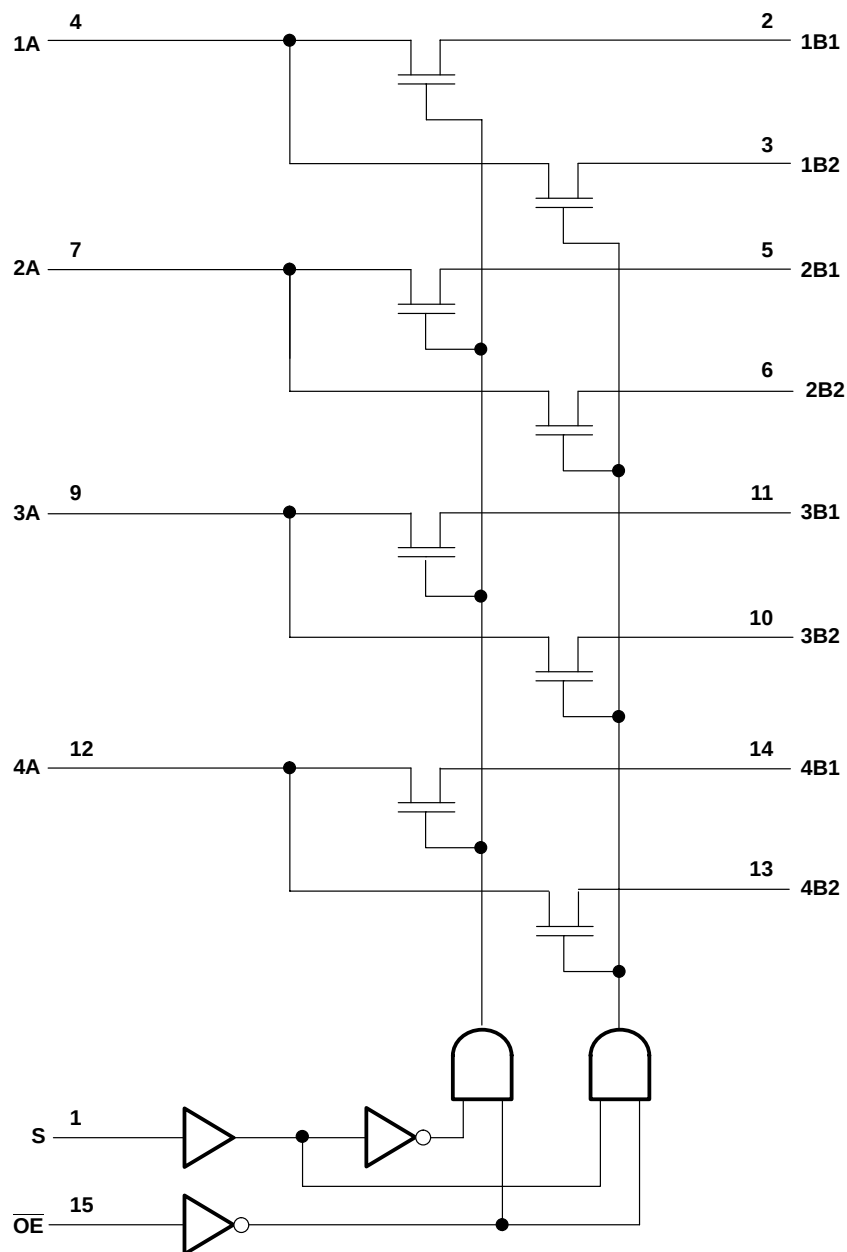
INPUTS		FUNCTION
$\overline{OE}$	S	
L	L	A port = B1 port
L	H	A port = B2 port
H	X	Disconnect

SN74CBT3257

4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS017I – MAY 1995 – REVISED MAY 1998

logic diagram (positive logic)



SN74CBT3257

4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS017I – MAY 1995 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	113°C/W
DB package	131°C/W
DBQ package	139°C/W
PW package	149°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±1	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
ΔI_{CC} [§]	Control inputs $V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i	Control inputs $V_I = 3$ V or 0			3.5	pF
$C_{io(OFF)}$	A port			6.5	pF
	B port			4	
r_{on} [¶]	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V,	$I_I = 15$ mA	14	Ω
	$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA	5	
			$I_I = 30$ mA	5	
		$V_I = 2.4$ V,	$I_I = 15$ mA	10	

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

SN74CBT3257 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

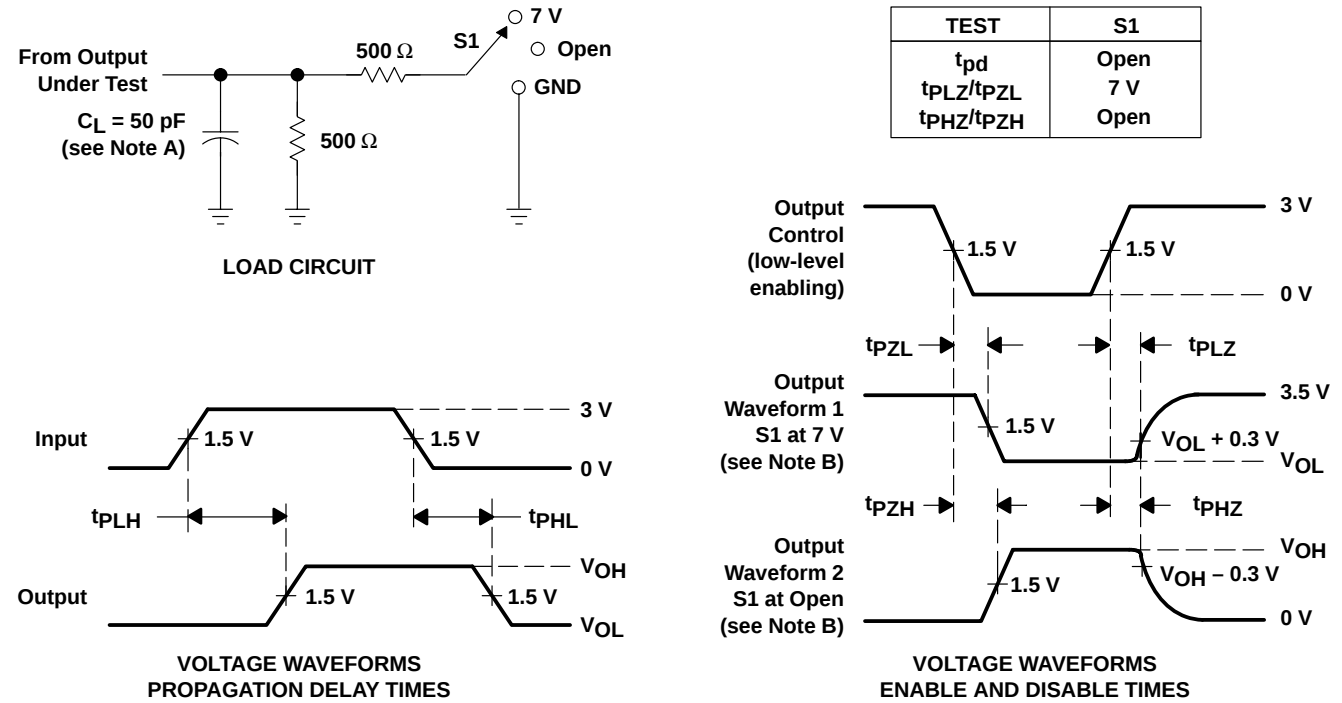
SCDS017I – MAY 1995 – REVISED MAY 1998

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [†]	A or B	B or A	0.35		0.25		ns
t _{pd}	S	A	5.5		1.6	5	ns
t _{en}	S	B	5.7		1.6	5.2	ns
	$\overline{\text{OE}}$	A or B	5.6		1.8	5.1	
t _{dis}	S	B	5.2		1	5	ns
	$\overline{\text{OE}}$	A or B	5.5		2.2	5.5	

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.

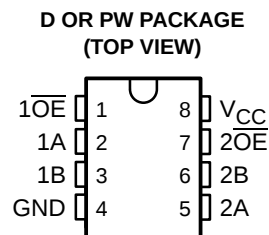
Figure 1. Load Circuit and Voltage Waveforms

- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (D) and Thin Shrink Small-Outline (PW) Packages

description

The SN74CBT3306 dual FET bus switch features independent line switches. Each switch is disabled when the associated output-enable (OE) input is high.

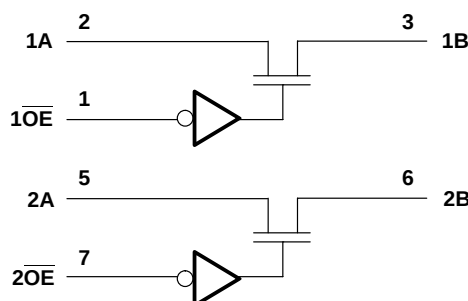
The SN74CBT3306 is characterized for operation from -40°C to 85°C .



FUNCTION TABLE
(each bus switch)

INPUT OE	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBT3306

DUAL FET BUS SWITCH

SCDS016E – MAY 1995 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	197°C/W
PW package	243°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±1	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
$\Delta I_{CC}^{\S}$ Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i Control inputs	$V_I = 3$ V or 0		3		pF
$C_{io(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$		4		pF
$r_{on}^{\parallel}$	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V, $V_I = 2.4$ V, $I_I = 15$ mA		14	20	Ω
	$V_{CC} = 4.5$ V, $V_I = 0$, $I_I = 64$ mA		5	7	
	$V_{CC} = 4.5$ V, $V_I = 0$, $I_I = 30$ mA		5	7	
	$V_{CC} = 4.5$ V, $V_I = 2.4$ V, $I_I = 15$ mA		10	15	

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

^{\parallel} Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

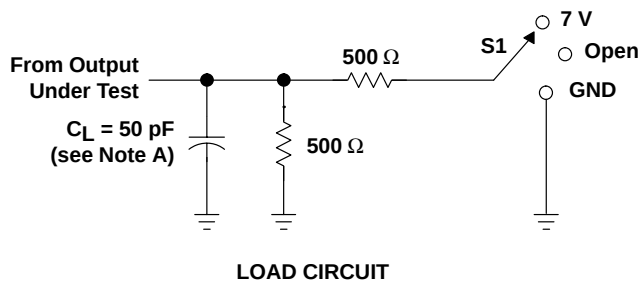


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

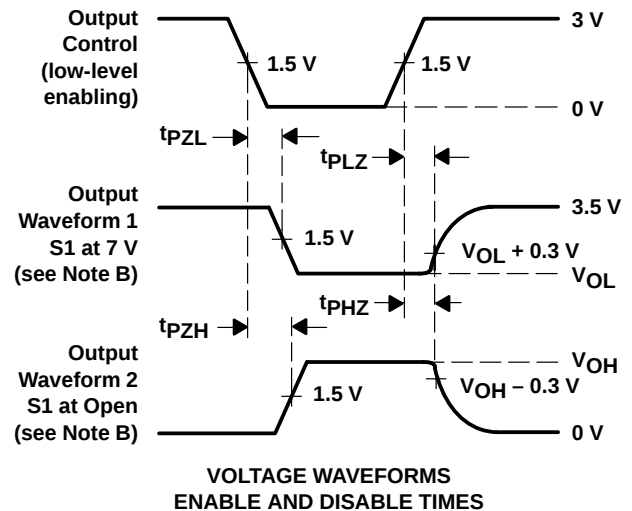
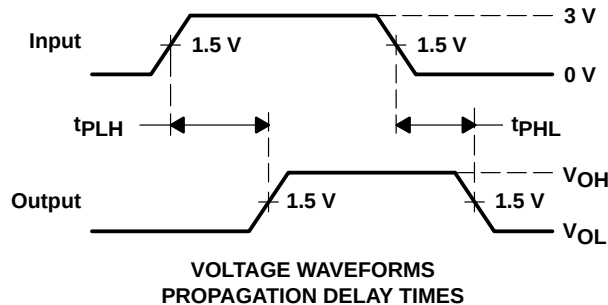
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.35		0.25		ns
t_{en}	$\overline{OE}$	A or B	5.6		1.8	5	ns
t_{dis}	$\overline{OE}$	A or B	4.6		1	4.3	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Standard '245-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Shrink Small-Outline (DB), Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

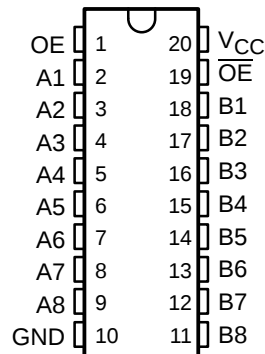
description

The SN74CBT3345 provides eight bits of high-speed TTL-compatible bus switching in a standard '245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 8-bit switch bank with dual output-enable ($\overline{OE}$ and $\overline{OE}$) inputs. When $\overline{OE}$ is low or $\overline{OE}$ is high, the switch is on and port A is connected to port B. When $\overline{OE}$ is high and $\overline{OE}$ is low, the switch is open and a high-impedance state exists between the two ports.

The SN74CBT3345 is characterized for operation from 0°C to 70°C.

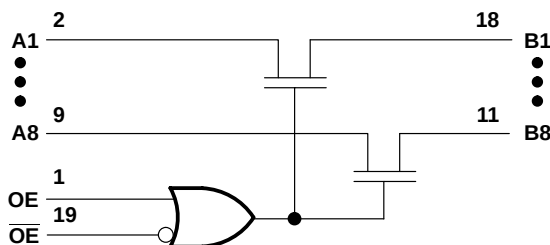
DB, DGV, DW, OR PW PACKAGE
(TOP VIEW)



FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBT3345

8-BIT FET BUS SWITCH

SCDS027D – MAY 1995 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	115°C
DGV package	146°C
DW package	97°C
PW package	128°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	0	70	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±1	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			50	μA
$\Delta I_{CC}^{\S}$ Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			3.5	mA
C_i Control inputs	$V_I = 3$ V or 0			3	pF
$C_{io(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$ or $OE = GND$			6	pF
$r_{on}^{\parallel}$	$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA	5	Ω
			$I_I = 30$ mA	5	
		$V_I = 2.4$ V, $I_I = 15$ mA		10	

[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

^{\parallel} Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

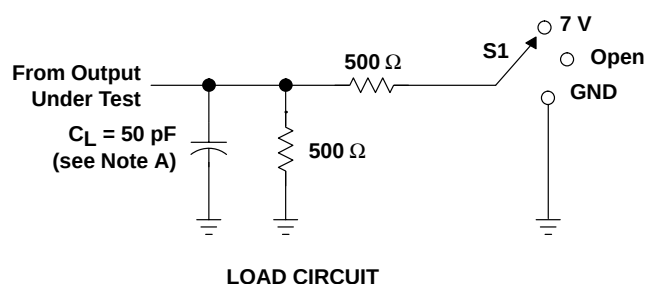


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

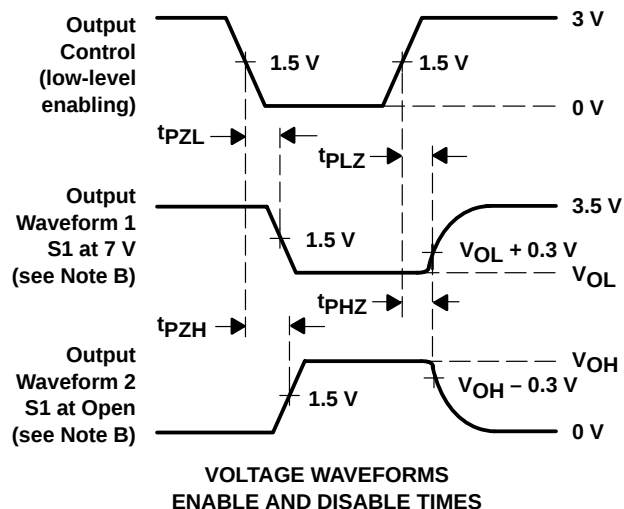
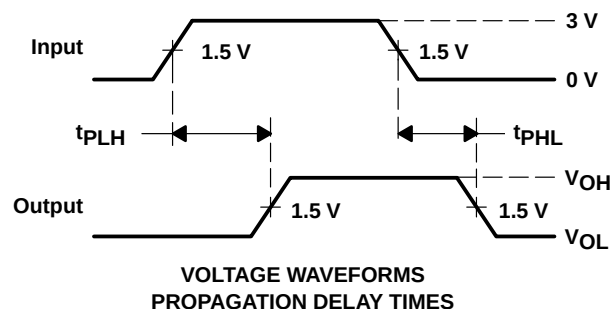
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.25		ns
t_{en}	$\overline{OE}$ or OE	A or B	1	9.1	ns
t_{dis}	$\overline{OE}$ or OE	A or B	1	8.7	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50\ \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

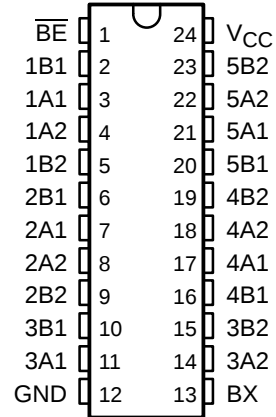
Figure 1. Load Circuit and Voltage Waveforms

SN54CBT3383, SN74CBT3383 10-BIT FET BUS-EXCHANGE SWITCHES

SCDS003I – NOVEMBER 1992 – REVISED MAY 1998

- Functionally Equivalent to QS3383 and QS3L383
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), and Thin Shrink Small-Outline (PW) Packages, Ceramic DIPs (JT), and Ceramic Flat (W) Package

SN54CBT3383 . . . JT OR W PACKAGE
SN74CBT3383 . . . DB, DBQ, DW, OR PW PACKAGE
(TOP VIEW)



description

The 'CBT3383 devices provide ten bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The devices operate as a 10-bit bus switch or a 5-bit bus exchanger, which provides swapping of the A and B pairs of signals. The bus-exchange function is selected when BX is high. The switches are connected when $\overline{BE}$ is low.

The SN54CBT3383 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74CBT3383 is characterized for operation from 0°C to 70°C .

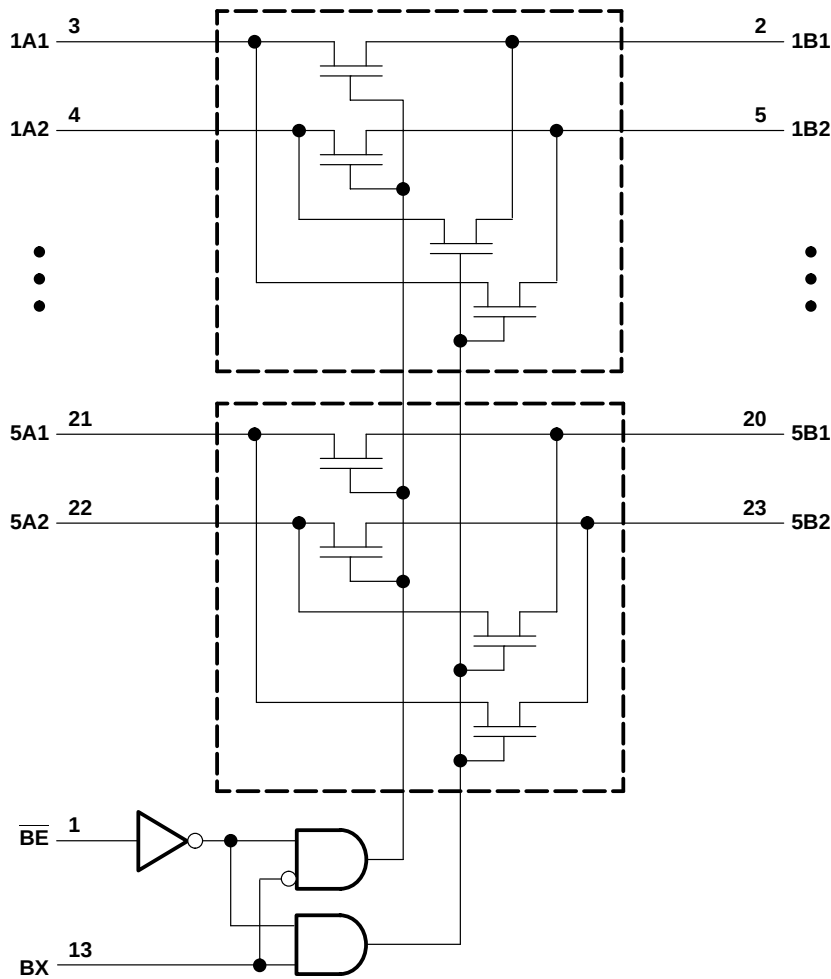
FUNCTION TABLE

INPUTS		INPUTS/OUTPUTS	
$\overline{BE}$	BX	1A1–5A1	1A2–5A2
L	L	1B1–5B1	1B2–5B2
L	H	1B2–5B2	1B1–5B1
H	X	Z	Z

SN54CBT3383, SN74CBT3383
10-BIT FET BUS-EXCHANGE SWITCHES

SCDS003I – NOVEMBER 1992 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	-50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	104°C/W
DBQ package	113°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

SN54CBT3383, SN74CBT3383 10-BIT FET BUS-EXCHANGE SWITCHES

SCDS003I – NOVEMBER 1992 – REVISED MAY 1998

recommended operating conditions (see Note 3)

		SN54CBT3383		SN74CBT3383		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level control input voltage	2		2		V
V_{IL}	Low-level control input voltage		0.8		0.8	V
T_A	Operating free-air temperature	-55	125	0	70	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	SN54CBT3383			SN74CBT3383			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2			-1.2	V
I_I		$V_{CC} = 5.5\text{ V}$, $V_I = 5.5\text{ V}$ or GND			±5			±1	μA
I_{CC}		$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND			50			50	μA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5			2.5	mA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0					3		pF
		$V_I = 2.5\text{ V}$			5				
$C_{io}(\text{OFF})$		$V_O = 3\text{ V}$ or 0, $\overline{BE} = V_{CC}$					6		pF
		$V_O = 2.5\text{ V}$, $\overline{BE} = V_{CC}$			6				
$r_{on}^\S$		$V_{CC} = 4.5\text{ V}$, $V_I = 0$, $I_I = 64\text{ mA}$		5	9.2		5	7	Ω
		$V_I = 0$, $I_I = 30\text{ mA}$					5	7	
		$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$		10	17		10	15	

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

§ Measured by the voltage drop between the input terminal and the output terminal at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

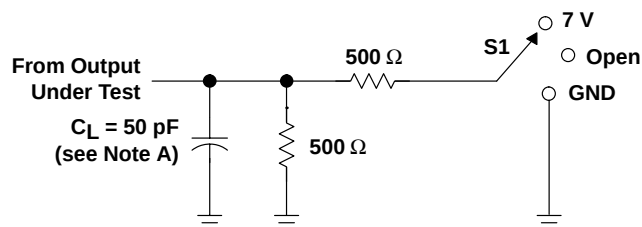
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54CBT3383		SN74CBT3383		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A		1.5		0.25	ns
t_{pd}	BX	A or B	1	10.2	1	9.2	ns
t_{en}	$\overline{BE}$	A or B	1	10.8	1	8.6	ns
t_{dis}	$\overline{BE}$	A or B	1	8.2	1	7.5	ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

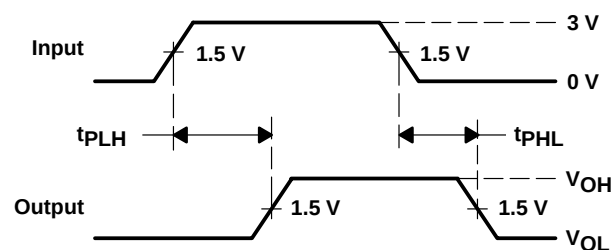
SN54CBT3383, SN74CBT3383 10-BIT FET BUS-EXCHANGE SWITCHES

SCDS0031 – NOVEMBER 1992 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION

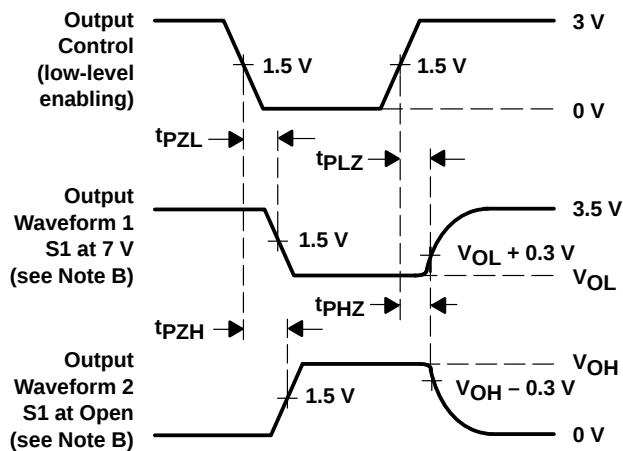


LOAD CIRCUIT



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTH3383

10-BIT FET BUS-EXCHANGE SWITCH WITH BUS HOLD

SCDS023G – MAY 1995 – REVISED OCTOBER 1998

- Functionally Equivalent to QS3388
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Bus Hold on Data Inputs/Outputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages

description

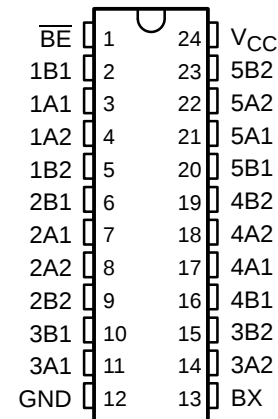
The SN74CBTH3383 provides ten bits of high-speed TTL-compatible bus switching or exchanging with bus hold on all I/Os. The low on-state resistance of the switch allows connection to be made with minimal propagation delay.

The device operates as a 10-bit bus switch or a 5-bit bus exchanger, which provides swapping of the A and B pairs of signals. The bus-exchange function is selected when $\overline{BE}$ is low. The switches are open when $\overline{BE}$ is high. Active bus-hold circuitry is provided to hold unused or floating data inputs/outputs at a valid logic level.

When the switch is turned off, the bus-hold circuit pulls all I/Os to V_{CC} or to GND, depending on the last-known state of the pin. The bus-hold feature is active only when the SN74CBTH3383 I/Os are in the high-impedance state.

The SN74CBTH3383 is characterized for operation from -40°C to 85°C .

DB, DW, OR PW PACKAGE
(TOP VIEW)



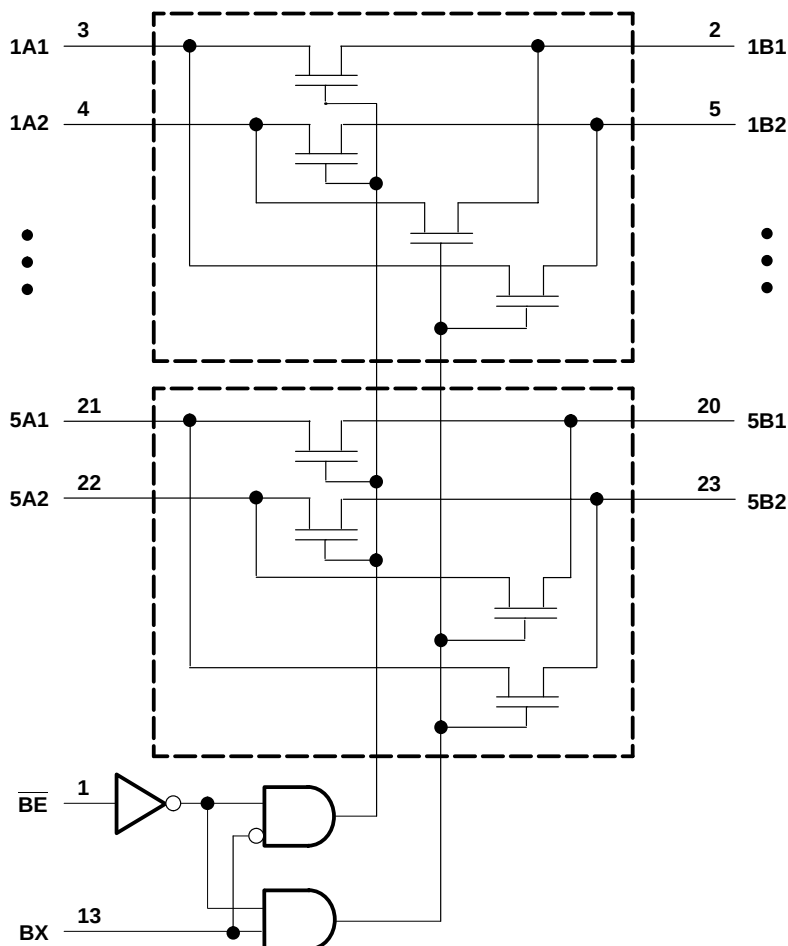
FUNCTION TABLE

INPUTS		INPUTS/OUTPUTS		FUNCTION
$\overline{BE}$	BX	A1 PORT	A2 PORT	
L	L	B1 port	B2 port	A1 port = B1 port A2 port = B2 port
L	H	B2 port	B1 port	A2 port = B2 port A2 port = B1 port
H	X	Z	Z	Disconnect All ports = bus hold

SN74CBTH3383 10-BIT FET BUS-EXCHANGE SWITCH WITH BUS HOLD

SCDS023G – MAY 1995 – REVISED OCTOBER 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} to V_{DD}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	104°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

SN74CBTH3383
10-BIT FET BUS-EXCHANGE SWITCH
WITH BUS HOLD

SCDS023G – MAY 1995 – REVISED OCTOBER 1998

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA			–1.2	V
I _I	V _{CC} = 5.5 V, V _I = 5.5 V or GND			±1	μA
I _{BHL} ‡	V _{CC} = 4.5 V, V _I = 0.8 V	100			μA
I _{BHH} §	V _{CC} = 4.5 V, V _I = 2 V	–100			μA
I _{BHLO} ¶	V _{CC} = 5.5 V, V _I = 0 to 5.5 V	500			μA
I _{BHHO} #	V _{CC} = 5.5 V, V _I = 0 to 5.5 V	–500			μA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			3	μA
ΔI _{CC}	Control inputs V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA
C _i	Control inputs V _I = 3 V or 0		3		pF
C _{io} (OFF)	V _O = 3 V or 0, $\overline{BE} = V_{CC}$		6		pF
r _{on} ★	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4, I _I = 15 mA	16	22	Ω
	V _{CC} = 4.5 V	V _I = 0, I _I = 64 mA	5	7	
		I _I = 30 mA	5	7	
		V _I = 2.4 V, I _I = 15 mA	10	15	

† All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

‡ The bus hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

§ The bus hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

¶ An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least I_{BHHO} to switch this node from high to low.

|| This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

★ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} □	A or B	B or A		0.35		0.25	ns
t _{pd}	BX	A or B		10.2	1	9.2	ns
t _{en}	$\overline{BE}$	A or B		9.6	1	8.6	ns
t _{dis}	$\overline{BE}$	A or B		8.5	1	7.5	ns

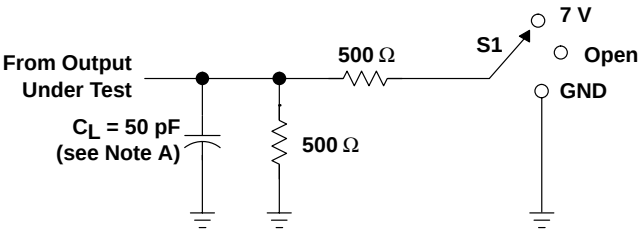
□ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



SN74CBTH3383
10-BIT FET BUS-EXCHANGE SWITCH
WITH BUS HOLD

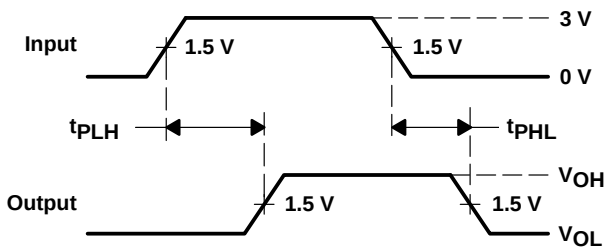
SCDS023G – MAY 1995 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION

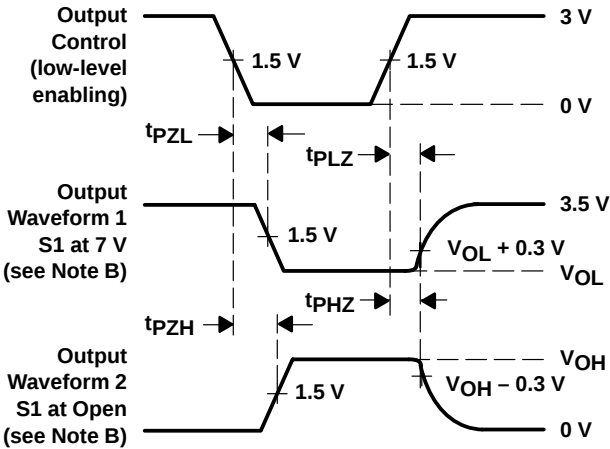


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Functionally Equivalent to QS3383 and QS3L383
- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), and Thin Shrink Small-Outline (PW) Packages

description

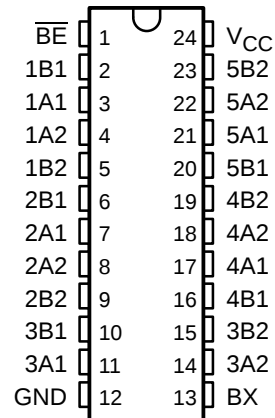
The SN74CBTR3383 device provides ten bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 10-bit bus switch or a 5-bit bus exchanger, which provides swapping of the A and B pairs of signals. The bus-exchange function is selected when BX is high. The switch is connected when $\overline{BE}$ is low.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR3383 is characterized for operation from 0°C to 70°C.

DB, DBQ, DW, OR PW PACKAGE
(TOP VIEW)



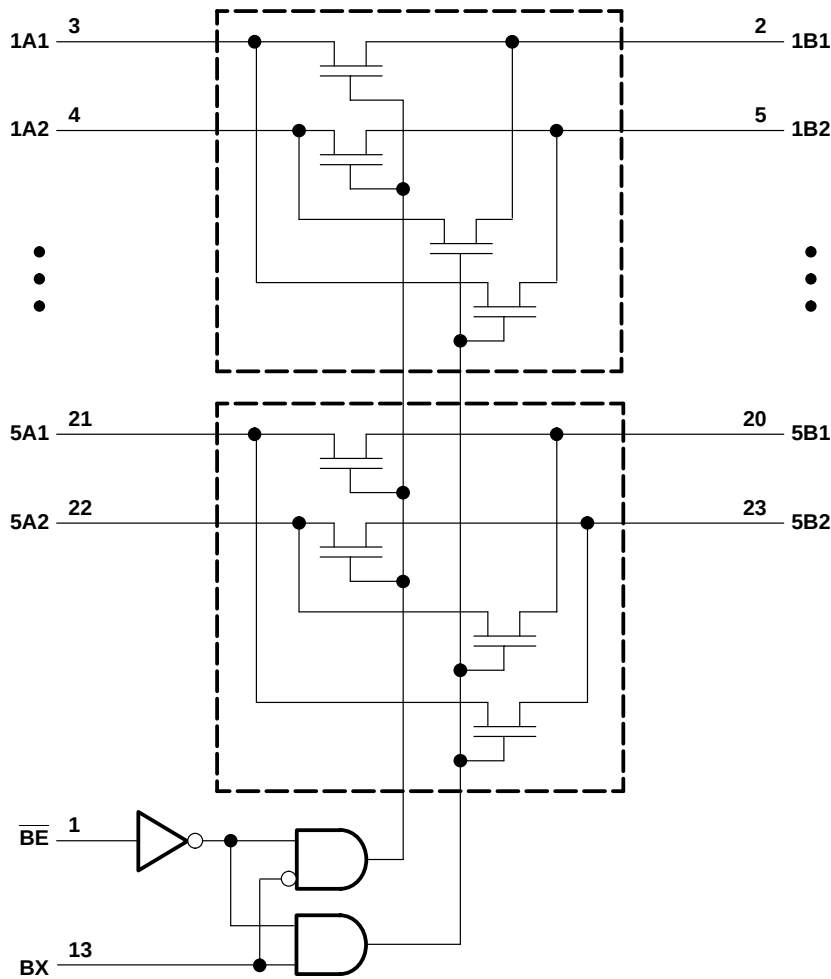
FUNCTION TABLE

INPUTS		INPUTS/OUTPUTS	
$\overline{BE}$	BX	1A1–5A1	1A2–5A2
L	L	1B1–5B1	1B2–5B2
L	H	1B2–5B2	1B1–5B1
H	X	Z	Z

SN74CBTR3383
10-BIT FET BUS-EXCHANGE SWITCH

SCDS082 – JULY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	104°C/W
DBQ package	113°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4.5	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	0	70	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA			–1.2	V
I _I	V _{CC} = 5.5 V, V _I = 5.5 V or GND			±1	μA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			50	μA
ΔI _{CC} [‡]	Control inputs V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA
C _i	Control inputs V _I = 3 V or 0				pF
C _{io(OFF)}	V _O = 3 V or 0, $\overline{BE}$ = V _{CC}				pF
r _{on} [§]	V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA		Ω
			I _I = 30 mA		
		V _I = 2.4 V, I _I = 15 mA			

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the input terminal and the output terminal at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

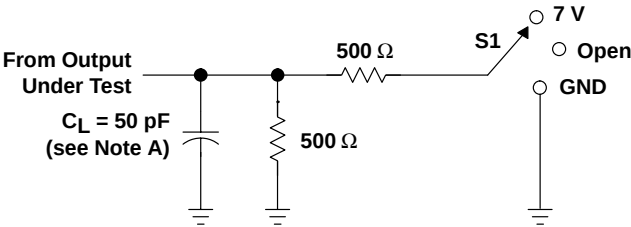
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t _{pd} [¶]	A or B	B or A			ns
t _{pd}	BX	A or B			ns
t _{en}	$\overline{BE}$	A or B			ns
t _{dis}	$\overline{BE}$	A or B			ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBTR3383 10-BIT FET BUS-EXCHANGE SWITCH

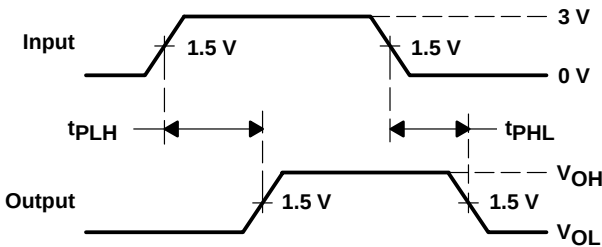
SCDS082 – JULY 1998

PARAMETER MEASUREMENT INFORMATION

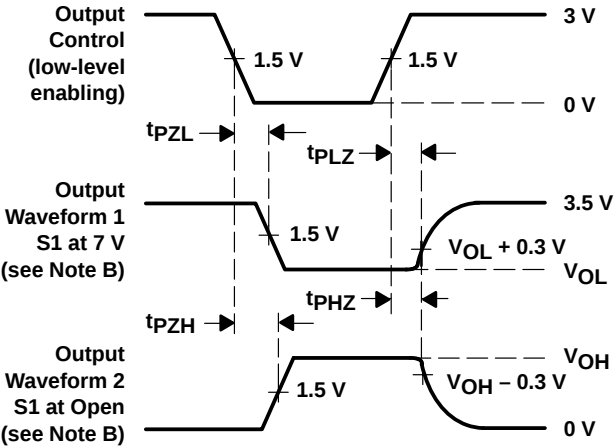


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



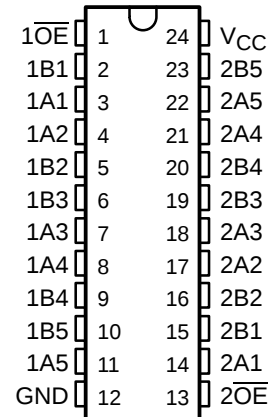
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Functionally Equivalent to QS3384 and QS3L384
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



description

The SN74CBT3384A provides ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

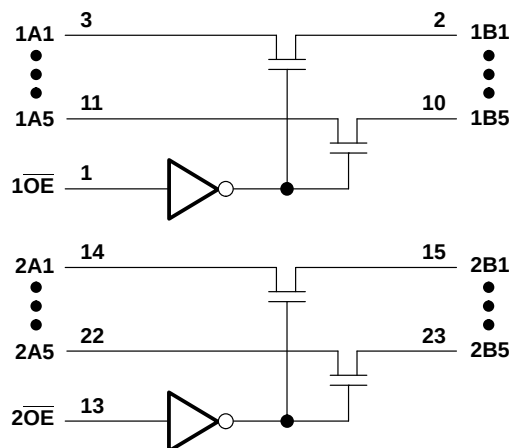
The device is organized as two 5-bit switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The SN74CBT3384A is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each 5-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
$\overline{1OE}$	$\overline{2OE}$	1B1–1B5	2B1–2B5
L	L	1A1–1A5	2A1–2A5
L	H	1A1–1A5	Z
H	L	Z	2A1–2A5
H	H	Z	Z

logic diagram (positive logic)



SN74CBT3384A

10-BIT FET BUS SWITCH

SCDS004I – NOVEMBER 1992 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
DBQ package	113°C/W
DGV package	139°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT		
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA				−1.2	V		
I _I		V _{CC} = 5.5 V, V _I = 5.5 V or GND				±1	μA		
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND				3	μA		
ΔI _{CC} [§]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				2.5	mA		
C _i	Control inputs	V _I = 3 V or 0				4	pF		
C _{iO} (OFF)		V _O = 3 V or 0, $\overline{OE}$ = V _{CC}				4.5	pF		
r _{on} [¶]		V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA			14	20	Ω	
		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA			5		7
				I _I = 30 mA			5		7
			V _I = 2.4 V, I _I = 15 mA			10	15		

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^S This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

^{||} Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

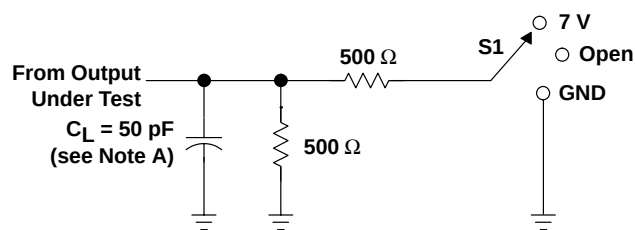


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.35		0.25		ns
t_{en}	$\overline{OE}$	A or B	6.2		1.9	5.7	ns
t_{dis}	$\overline{OE}$	A or B	5.5		2.1	5.2	ns

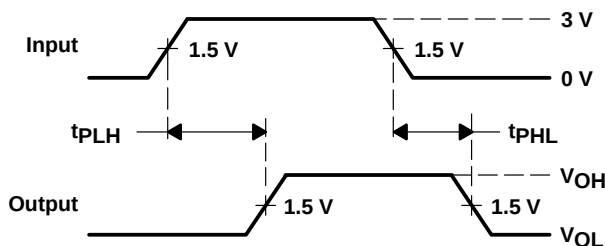
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

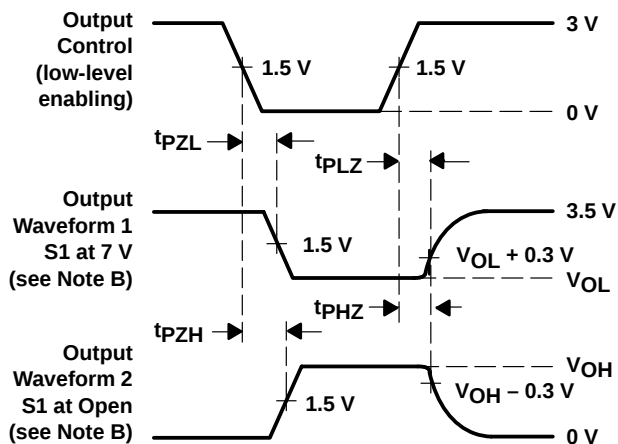


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Functionally Equivalent to QS3384 and QS3L384
- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

description

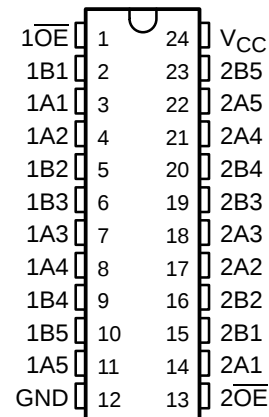
The SN74CBTR3384 provides ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 5-bit switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR3384 is characterized for operation from –40°C to 85°C.

DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



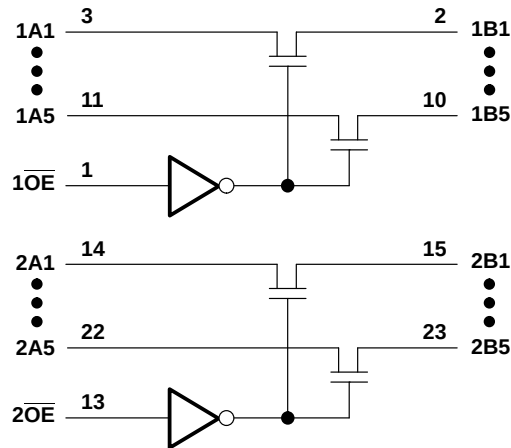
FUNCTION TABLE
(each 5-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
$\overline{1OE}$	$\overline{2OE}$	1B1–1B5	2B1–2B5
L	L	1A1–1A5	2A1–2A5
L	H	1A1–1A5	Z
H	L	Z	2A1–2A5
H	H	Z	Z

SN74CBTR3384 10-BIT FET BUS SWITCH

SCDS083 – JULY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
DBQ package	113°C/W
DGV package	139°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
I_I		$V_{CC} = 5.5\text{ V}$,	$V_I = 5.5\text{ V}$ or GND			± 1	μA
I_{CC}		$V_{CC} = 5.5\text{ V}$,	$I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
$\Delta I_{CC}^{\ddagger}$	Control inputs	$V_{CC} = 5.5\text{ V}$,	One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0					pF
$C_{io(OFF)}$		$V_O = 3\text{ V}$ or 0, $\overline{OE} = V_{CC}$					pF
$r_{on}^{\S}$		$V_{CC} = 4.5\text{ V}$	$V_I = 0$			$I_I = 64\text{ mA}$	Ω
						$I_I = 30\text{ mA}$	
			$V_I = 2.4\text{ V}$,			$I_I = 15\text{ mA}$	

[†] All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

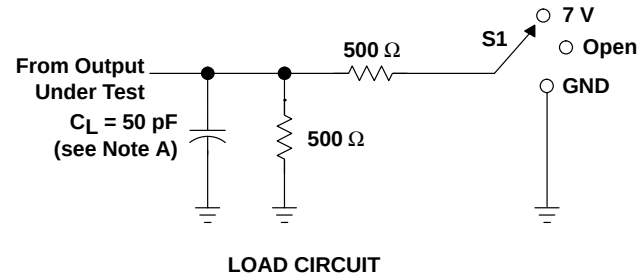
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

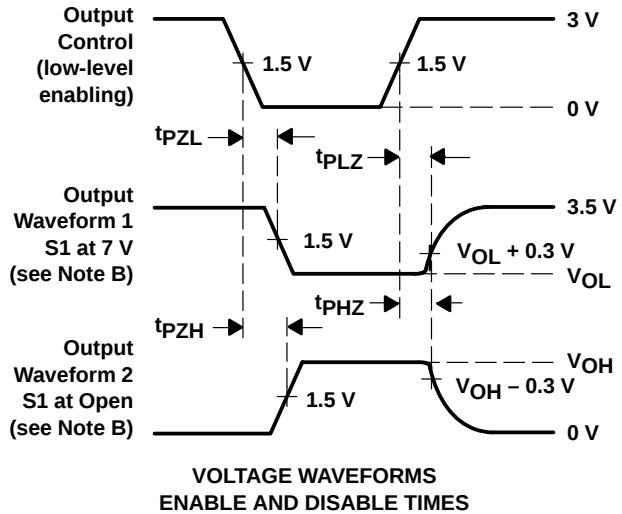
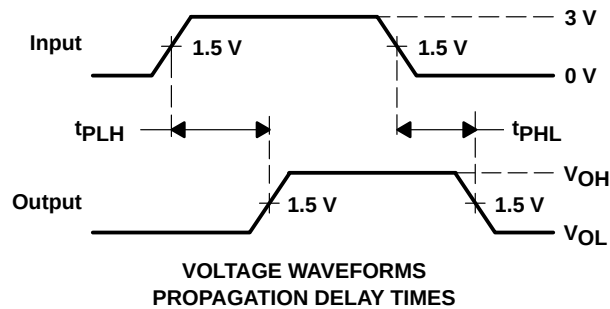
SN74CBTR3384
10-BIT FET BUS SWITCH

SCDS083 – JULY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT3386

10-BIT FET BUS-EXCHANGE SWITCH WITH EXTENDED VOLTAGE RANGE

SCDS022F – MAY 1995 – REVISED MAY 1998

- Functionally Equivalent to QS3386
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Uses V_{CC} of 5 V and V_{DD} of -2 V
- Package Options Include Plastic Shrink Small-Outline (DB), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

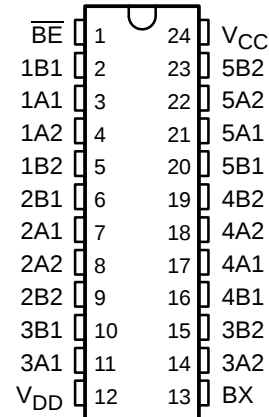
description

The SN74CBT3386 provides ten bits of high-speed TTL-compatible bus switching or exchanging. The input signals can range from -2 V to 5 V. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 10-bit bus switch or a 5-bit bus exchanger, which allows swapping of the A and B pairs of signals. The bus-exchange function is selected when BX is high. The switches are disconnected when $\overline{BE}$ is high.

The SN74CBT3386 is characterized for operation from -40°C to 85°C.

DB, DW, OR PW PACKAGE
(TOP VIEW)



FUNCTION TABLE

INPUTS		INPUTS/OUTPUTS	
$\overline{BE}$	BX	1A1-5A1	1A2-5A2
L	L	1B1-5B1	1B2-5B2
L	H	1B2-5B2	1B1-5B1
H	X	Z	Z

PRODUCT PREVIEW

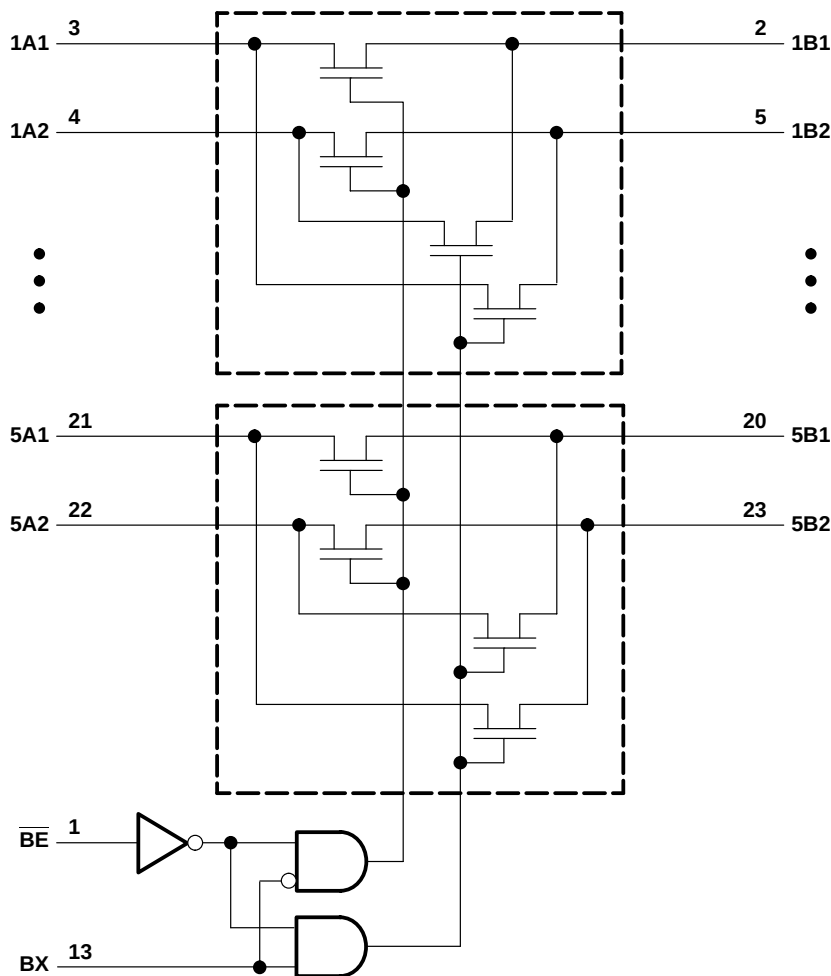
SN74CBT3386

10-BIT FET BUS-EXCHANGE SWITCH

WITH EXTENDED VOLTAGE RANGE

SCDS022F – MAY 1995 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} to V_{DD}	–0.5 V to 7 V
Supply voltage range, V_{DD}	–2.5 V to 7 V
Input voltage range, V_I (see Note 1)	$V_{DD} - 0.5$ V to $V_{DD} + 7.5$ V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA		V _{DD} –1.2		V
I _I	V _{CC} = 5.5 V, V _I = 5.5 V or GND		±1		μA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			3	μA
ΔI _{CC} [‡]	Control inputs V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			5	mA
C _i	Control inputs V _I = 3 V or 0				pF
C _{io} (OFF)	V _O = 3 V or 0, $\overline{BE}$ = V _{CC}				pF
r _{on} [§]	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4,	I _I = 15 mA		Ω
		V _I = 0	I _I = 64 mA		
	V _{CC} = 4.5 V		I _I = 30 mA		
		V _I = 2.4 V,	I _I = 15 mA		

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the input terminal and the output terminal at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

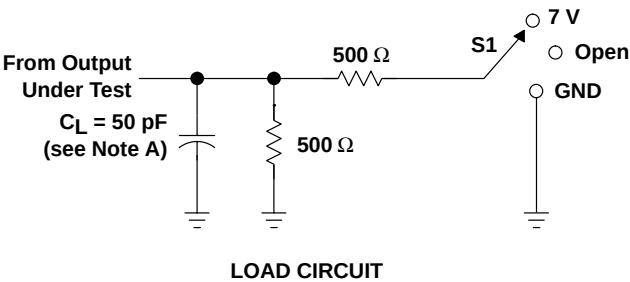
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A					ns
t _{en}	BX	A or B					ns
	$\overline{BE}$						
t _{dis}	$\overline{BE}$	A or B					ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

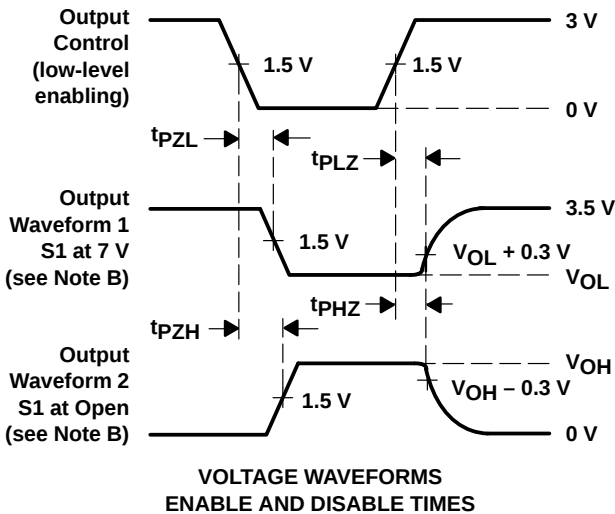
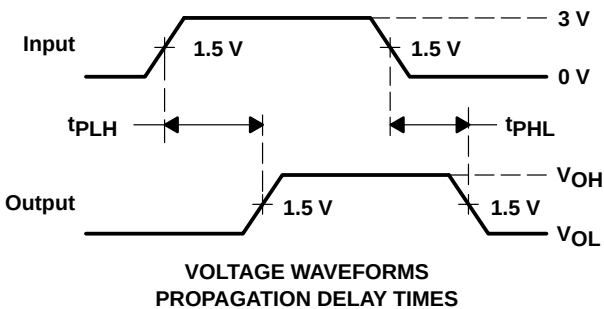
SN74CBT3386
10-BIT FET BUS-EXCHANGE SWITCH
WITH EXTENDED VOLTAGE RANGE

SCDS022F – MAY 1995 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT3390

8-BIT TO 16-BIT FET MULTIPLEXER/DEMULTIPLEXER BUS SWITCH

SCDS071 – JULY 1998

- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Shrink Small-Outline (DL) and Small-Outline (DW) Packages

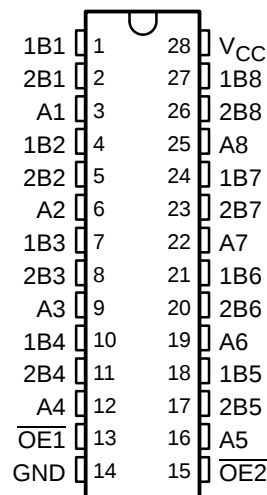
description

The SN74CBT3390 is an 8-bit to 16-bit switch used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single path. This device can be used for memory interleaving, in which two different banks of memory must be addressed simultaneously. This also can be used to connect or isolate the PCI bus to one or two slots simultaneously.

Two output enables ($\overline{OE1}$ and $\overline{OE2}$) control the data flow. When $\overline{OE1}$ is low, A port is connected to 1B port. When $\overline{OE2}$ is low, A port is connected to 2B port. When both $\overline{OE1}$ and $\overline{OE2}$ are low, the A port is connected to both 1B and 2B ports. The control inputs can be driven with a 5-V CMOS, 5-V TTL, or an LVTTTL driver.

The SN74CBT3390 is characterized for operation from -40°C to 85°C .

DL OR DW PACKAGE
(TOP VIEW)



FUNCTION TABLE

INPUTS		FUNCTION
OE1	OE2	
L	L	A = 1B and A = 2B
L	H	A = 1B
H	L	A = 2B
H	H	Isolation

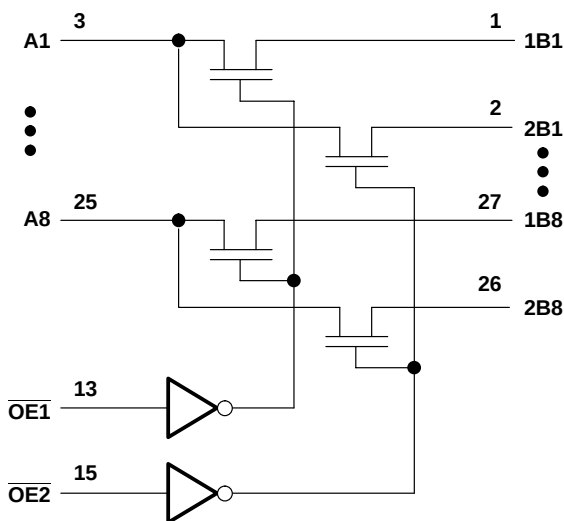
PRODUCT PREVIEW

SN74CBT3390

8-BIT TO 16-BIT FET MULTIPLEXER/DEMULTIPLEXER BUS SWITCH

SCDS071 – JULY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package	97°C/W
DW package	78°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74CBT3390

8-BIT TO 16-BIT FET MULTIPLEXER/DEMULTIPLEXER BUS SWITCH

SCDS071 – JULY 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA					−1.2	V
I _I		V _{CC} = 0 V _I = 5.5 V					10	μA
		V _{CC} = 5.5 V, V _I = 5.5 V or GND					±1	
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND					3	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other input at V _{CC} or GND					2.5	mA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)		V _O = 3 V or 0						pF
r _{on} [§]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				Ω
				I _I = 30 mA				
			V _I = 2.4 V, I _I = 15 mA					

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

^{||} The propagation delay is based on the RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).

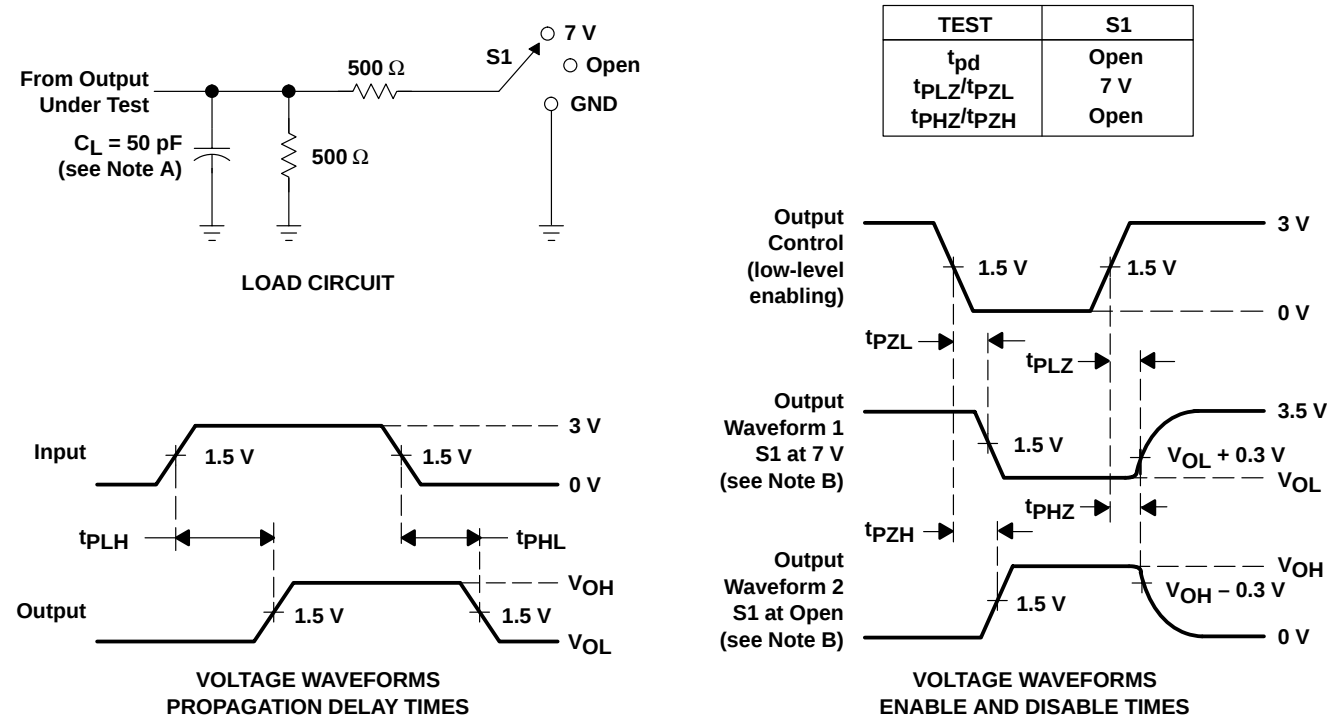
PRODUCT PREVIEW



SN74CBT3390 8-BIT TO 16-BIT FET MULTIPLEXER/DEMULTIPLEXER BUS SWITCH

SCDS071 – JULY 1998

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DBQ), and Thin Shrink Small-Outline (PW) Packages

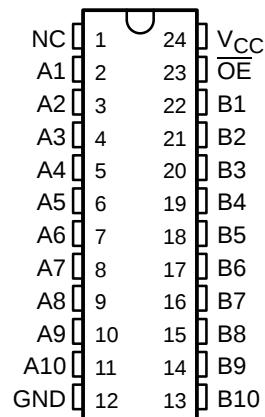
description

The SN74CBT3861 provides ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 10-bit switch with a single output-enable ($\overline{OE}$) input. When $\overline{OE}$ is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

The SN74CBT3861 is characterized for operation from -40°C to 85°C .

DBQ, DW, OR PW PACKAGE
(TOP VIEW)

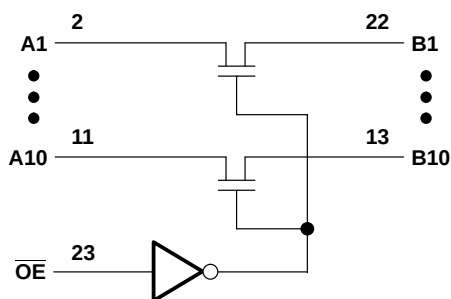


NC – No internal connection

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBT3861

10-BIT FET BUS SWITCH

SCDS061B – APRIL 1998 – REVISED AUGUST 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBQ package	113°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±1	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
ΔI_{CC} [§] Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i Control inputs	$V_I = 3$ V or 0			3	pF
$C_{io(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$			5	pF
r_{on} [¶]	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V, $I_I = 15$ mA		14	Ω
	$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA	5	
			$I_I = 30$ mA	5	
		$V_I = 2.4$ V, $I_I = 15$ mA		10	

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

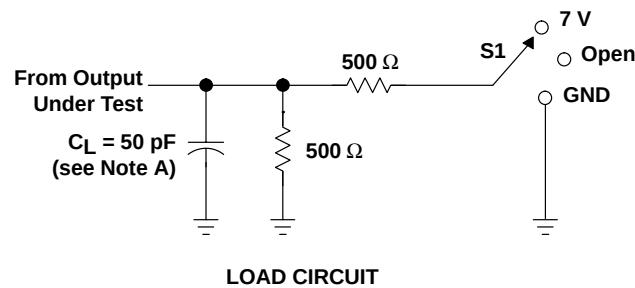


switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

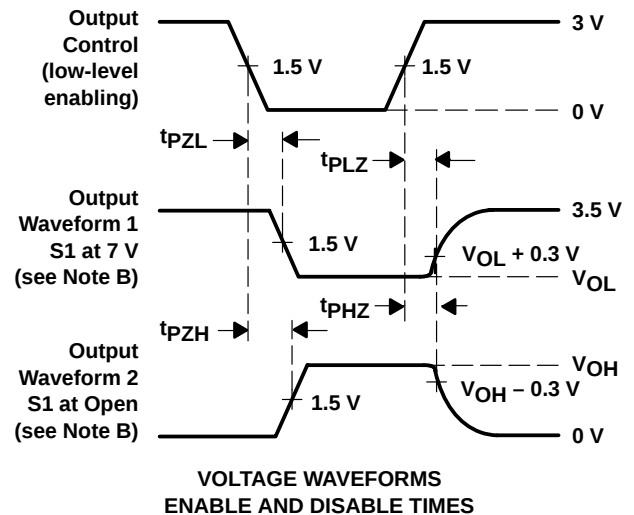
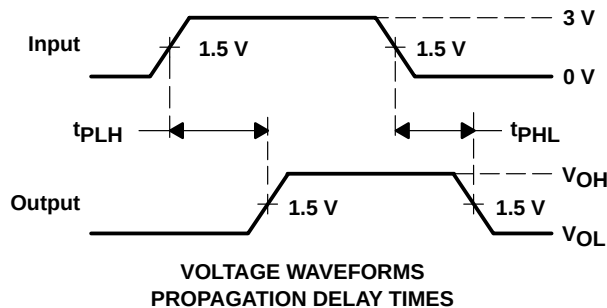
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger}$	A or B	B or A	0.35		0.25		ns
t_{en}	$\overline{OE}$	A or B	8.1		3.8	7.5	ns
t_{dis}	$\overline{OE}$	A or B	6.3		3.4	6.6	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT6800

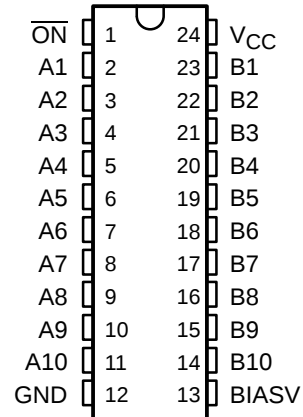
10-BIT FET BUS SWITCH

WITH PRECHARGED OUTPUTS FOR LIVE INSERTION

SCDS0051 – MARCH 1993 – REVISED MAY 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Outputs Are Precharged by Bias Voltage to Minimize Signal Distortion During Live Insertion
- Package Options Include Plastic Shrink Small-Outline (DB), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

DB, DW, OR PW PACKAGE
(TOP VIEW)



description

The SN74CBT6800 provides ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows bidirectional connections to be made while adding near-zero propagation delay. The device also precharges the B port to a user-selectable bias voltage (BIASV) to minimize live-insertion noise.

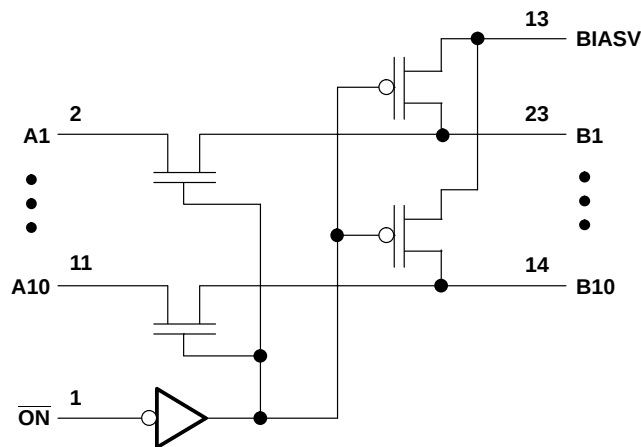
The SN74CBT6800 is organized as one 10-bit switch with a single enable ($\overline{\text{ON}}$) input. When $\overline{\text{ON}}$ is low, the switch is on and port A is connected to port B. When $\overline{\text{ON}}$ is high, the switch between port A and port B is open and the B port is precharged to BIASV through the equivalent of a 10-kΩ resistor.

The SN74CBT6800 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

$\overline{\text{ON}}$	B1–B10	FUNCTION
L	A1–A10	Connect
H	BIASV	Precharge

logic diagram (positive logic)



SN74CBT6800

10-BIT FET BUS SWITCH

WITH PRECHARGED OUTPUTS FOR LIVE INSERTION

SCDS0051 – MARCH 1993 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Bias voltage range, $BIASV$	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
$BIASV$ Supply voltage	1.3	V_{CC}	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA				−1.2	V
I _I		V _{CC} = 5.5 V, V _I = 5.5 V or GND				±5	μA
I _O		V _{CC} = 4.5 V, BIASV = 2.4 V, V _O = 0		0.25			mA
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND				50	μA
ΔI _{CC} [§]	Control inputs	V _{CC} = 3.6 V, One input at 2.7 V, Other inputs at V _{CC} or GND				2.5	mA
C _i	Control inputs	V _I = 3 V or 0			3.5		pF
C _O (OFF)		V _O = 3 V or 0, Switch off			4.5		pF
r _{on} [¶]	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA			14	20	Ω
		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA	5	7	
				I _I = 30 mA	5	7	
			V _I = 2.4 V, I _I = 15 mA			10	

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.



SN74CBT6800

10-BIT FET BUS SWITCH

WITH PRECHARGED OUTPUTS FOR LIVE INSERTION

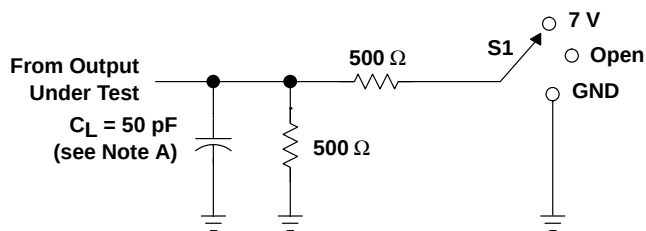
SCDS0051 – MARCH 1993 – REVISED MAY 1998

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	TEST CONDITIONS	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
				MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$		A or B	B or A	0.35		0.25		ns
t_{pZH}	BIASV = GND	$\overline{ON}$	A or B	9.1		3.1	8.1	ns
t_{pZL}	BIASV = 3 V			9.6		3.6	8.6	
t_{pHZ}	BIASV = GND	$\overline{ON}$	A or B	5.9		2.7	6.1	ns
t_{pLZ}	BIASV = 3 V			6.4		3	7.3	

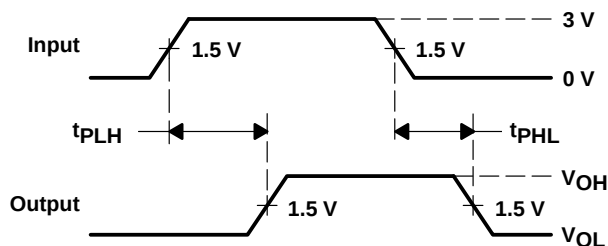
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

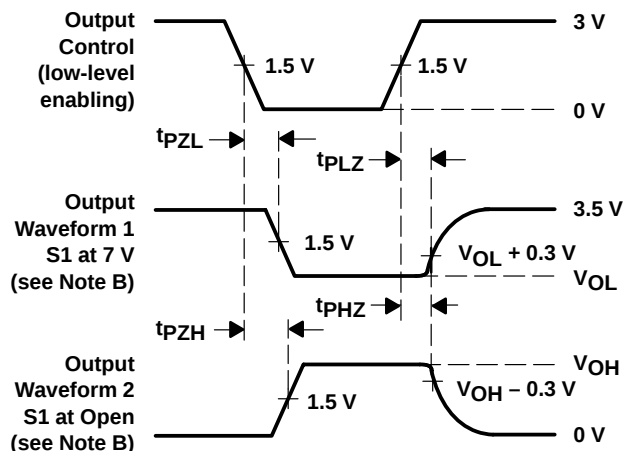


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{pLZ}/t_{pZL}	7 V
t_{pHZ}/t_{pZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{pLZ} and t_{pHZ} are the same as t_{dis} .
 - F. t_{pZL} and t_{pZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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SN54CBT16209, SN74CBT16209A 18-BIT FET BUS-EXCHANGE SWITCHES

SCDS006K – NOVEMBER 1992 – REVISED MAY 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), 300-mil Shrink Small-Outline (DL), and 380-mil Fine-Pitch Ceramic Flat (WD) Packages

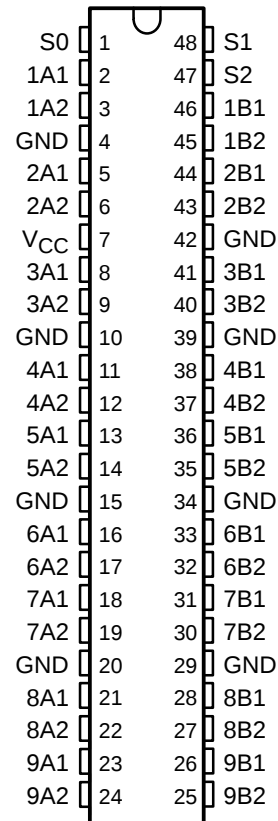
description

The SN54CBT16209 and SN74CBT16209A devices provide 18 bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switches allows connections to be made with minimal propagation delay.

The devices operate as an 18-bit bus switch or a 9-bit bus exchanger, which provides data exchanging between the four signal ports via the data-select (S0, S1, S2) terminals.

The SN54CBT16209 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74CBT16209A is characterized for operation from -40°C to 85°C.

SN54CBT16209 . . . WD PACKAGE
SN74CBT16209A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



FUNCTION TABLE

INPUTS			INPUTS/OUTPUTS		FUNCTION
S2	S1	S0	A1	A2	
L	L	L	Z	Z	Disconnect
L	L	H	B1	Z	A1 port = B1 port
L	H	L	B2	Z	A1 port = B2 port
L	H	H	Z	B1	A2 port = B1 port
H	L	L	Z	B2	A2 port = B2 port
H	L	H	Z	Z	Disconnect
H	H	L	B1	B2	A1 port = B1 port A2 port = B2 port
H	H	H	B2	B1	A1 port = B2 port A2 port = B1 port

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



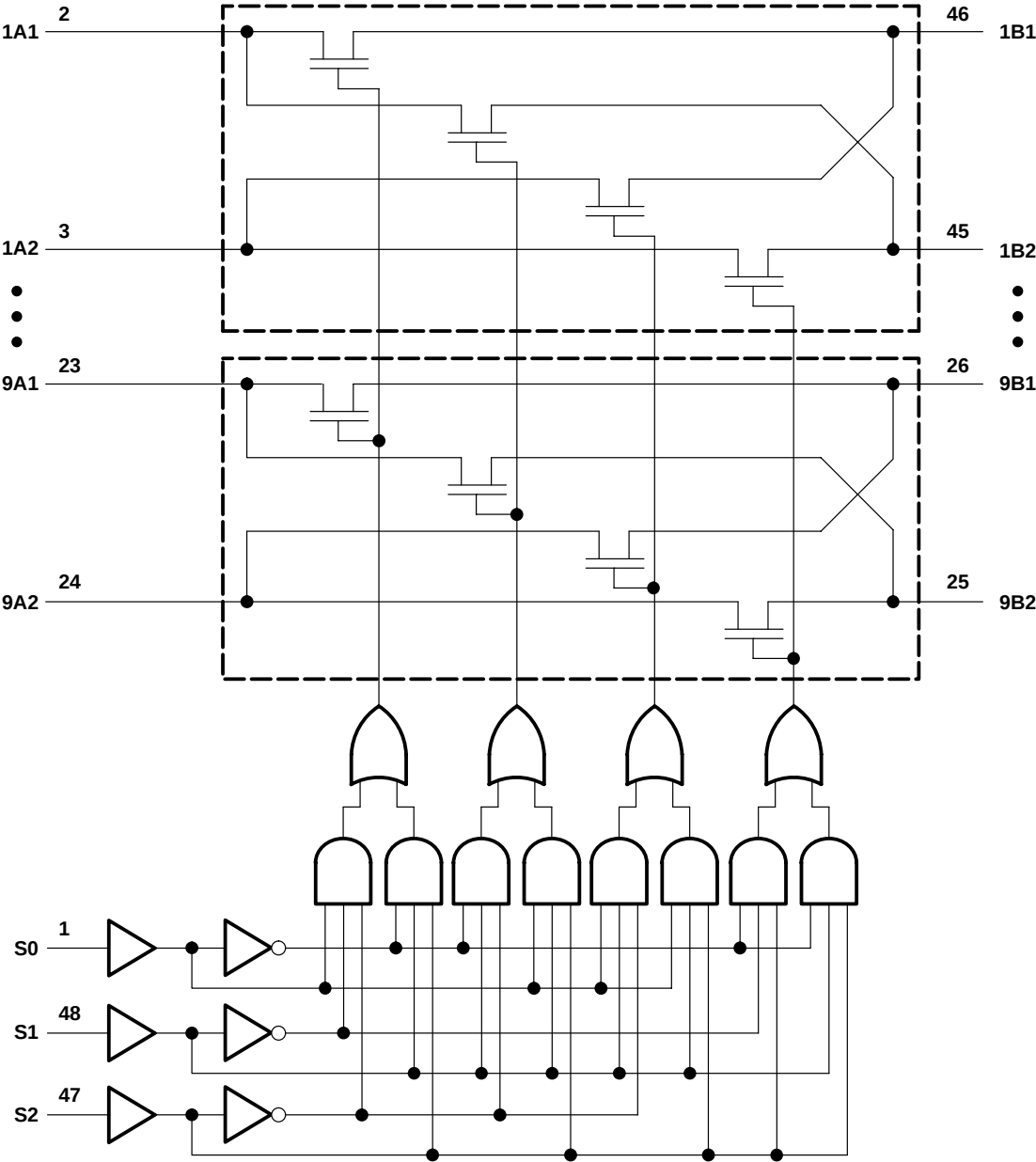
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SN54CBT16209, SN74CBT16209A
18-BIT FET BUS-EXCHANGE SWITCHES

SCDS006K – NOVEMBER 1992 – REVISED MAY 1998

logic diagram (positive logic)



SCDS006K – NOVEMBER 1992 – REVISED MAY 1998

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{Stg}	−65°C to 150°C

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51.

		SN54CBT16209		SN74CBT16209A		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4	5.5	4	5.5	V
V _{IH}	High-level control input voltage	2		2		V
V _{IL}	Low-level control input voltage		0.8		0.8	V
T _A	Operating free-air temperature	−55	125	−40	85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT	
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA				−1.2	V	
I _I		V _{CC} = 0, V _I = 5.5 V				10	μA	
		V _{CC} = 5.5 V, V _I = 5.5 V or GND				±1		
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND				3	μA	
ΔI _{CC} [§]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				2.5	mA	
C _i	Control inputs	V _I = 3 V or 0				4	pF	
C _{io} (OFF)		V _O = 3 V or 0, S ₀ , S ₁ , or S ₂ = V _{CC}				7.5	pF	
r _{on} [¶]		V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA				Ω	
		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA		4		8
				I _I = 30 mA		4		8
			V _I = 2.4 V, I _I = 15 mA					6

† Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

SN54CBT16209, SN74CBT16209A
18-BIT FET BUS-EXCHANGE SWITCHES

SCDS006K – NOVEMBER 1992 – REVISED MAY 1998

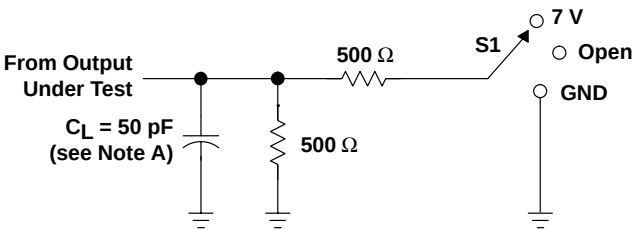
switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54CBT16209				SN74CBT16209A				UNIT
			V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd} [†]	A or B	B or A			0.8*		0.35		0.25		ns
t _{pd}	S	A or B	14		2 13.1		9.9		1.5 9		ns
t _{en}	S	A or B	16		1.7 15.3		10.3		1.5 9.8		ns
t _{dis}	S	A or B	14.5		1 13.2		9.3		1.5 8.8		ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

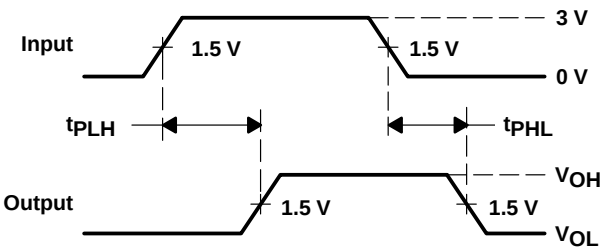
† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

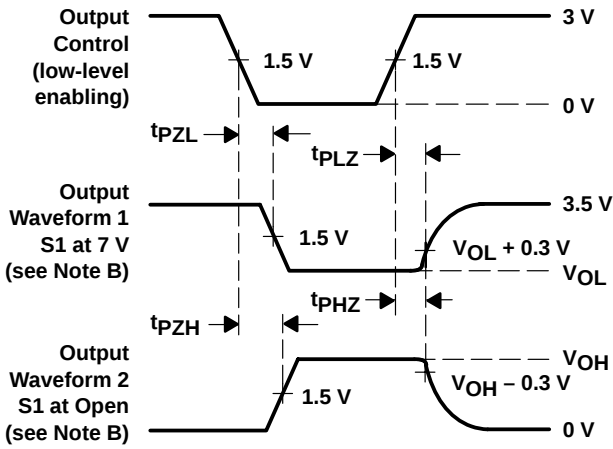


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
F. t_{PZL} and t_{PZH} are the same as t_{en} .
G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

The SN74CBT16210 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

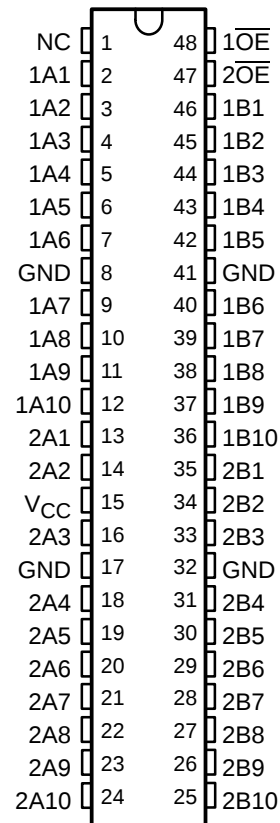
The device is organized as a dual 10-bit bus switch with separate output-enable ($\overline{OE}$) inputs. It can be used as two 10-bit bus switches or as one 20-bit bus switch. When $\overline{OE}$ is low, the associated 10-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the ports.

The SN74CBT16210 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each 10-bit bus switch)

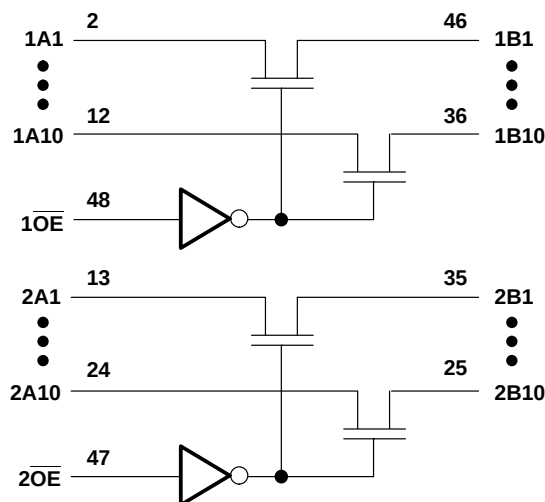
INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

logic diagram (positive logic)



SN74CBT16210

20-BIT FET BUS SWITCH

SCDS033C – APRIL 1997 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 0$ V, $V_I = 5.5$ V			10	μ A
	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			± 1	
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			3	μ A
ΔI_{CC} [§] Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i Control inputs	$V_I = 3$ V or 0			4.5	pF
$C_{io(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$			5.5	pF
r_{on} [¶]	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V,	$I_I = 15$ mA	14	Ω
	$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA	5	
			$I_I = 30$ mA	5	
		$V_I = 2.4$ V,	$I_I = 15$ mA	8	

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

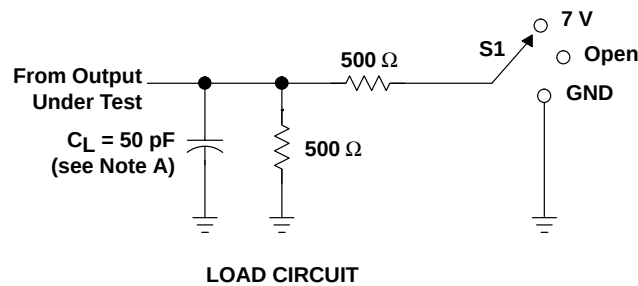


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

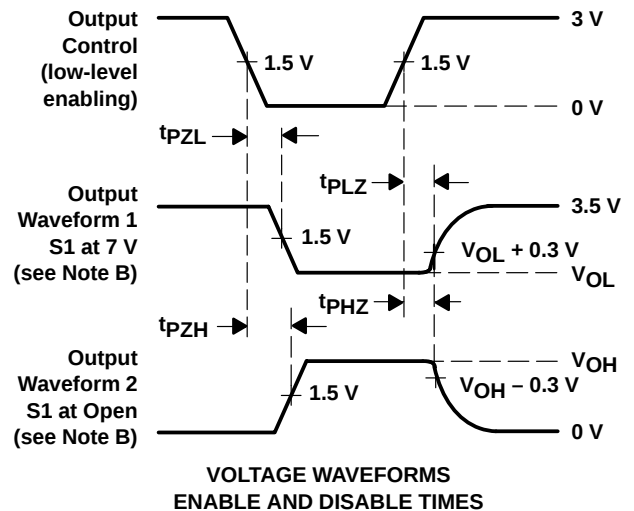
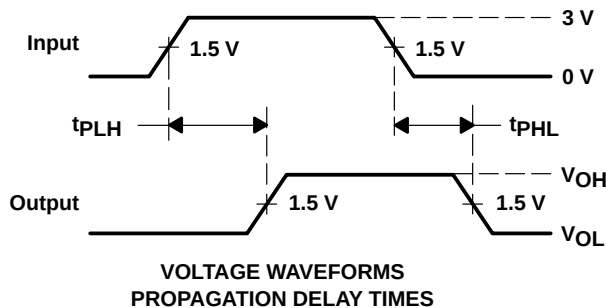
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.35		0.25		ns
t_{en}	$\overline{OE}$	A or B	9.3		3.3	8.6	ns
t_{dis}	$\overline{OE}$	A or B	7.1		2.8	7.9	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PHL}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PHL} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- 25- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

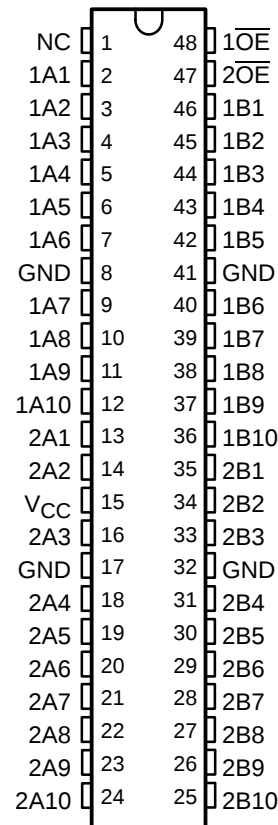
The SN74CBTR16210 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as a dual 10-bit bus switch with separate output-enable ($\overline{OE}$) inputs. It can be used as two 10-bit bus switches or as one 20-bit bus switch. When $\overline{OE}$ is low, the associated 10-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the ports.

The device has equivalent 25- Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR16210 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

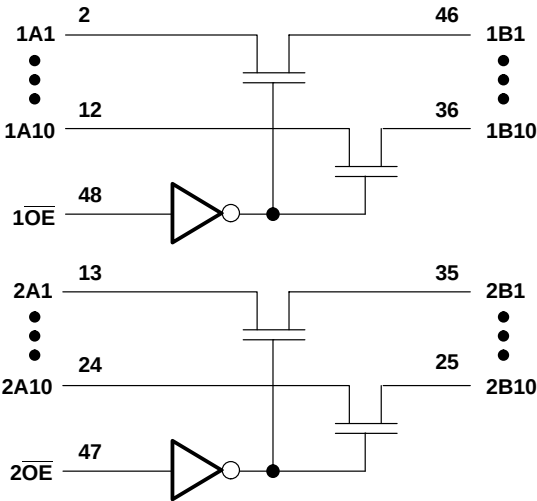
FUNCTION TABLE
(each 10-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

SN74CBTR16210
20-BIT FET BUS SWITCH

SCDS072 – JULY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = −18 mA				−1.2	V
I _I		V _{CC} = 0 V,	V _I = 5.5 V				10	μA
		V _{CC} = 5.5 V,	V _I = 5.5 V or GND				±1	
I _{CC}		V _{CC} = 5.5 V,	I _O = 0, V _I = V _{CC} or GND				3	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V, Other inputs at V _{CC} or GND				2.5	mA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)		V _O = 3 V or 0,	$\overline{OE}$ = V _{CC}					pF
r _{on} [§]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				Ω
				I _I = 30 mA				
			V _I = 2.4 V, I _I = 15 mA					

[†] All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

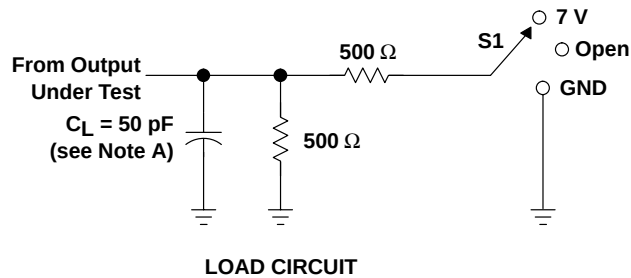
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^\parallel$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

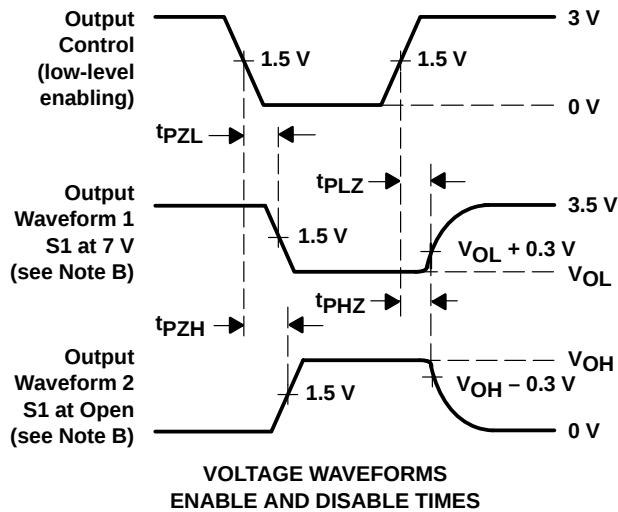
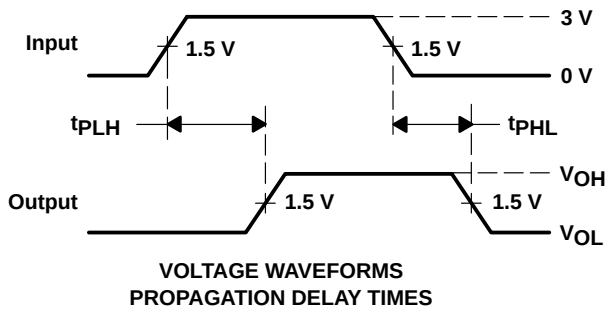
SN74CBTR16210 20-BIT FET BUS SWITCH

SCDS072 – JULY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT16211A 24-BIT FET BUS SWITCH

SCDS028H – JULY 1995 – REVISED MAY 1998

- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

The SN74CBT16211A provides 24 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

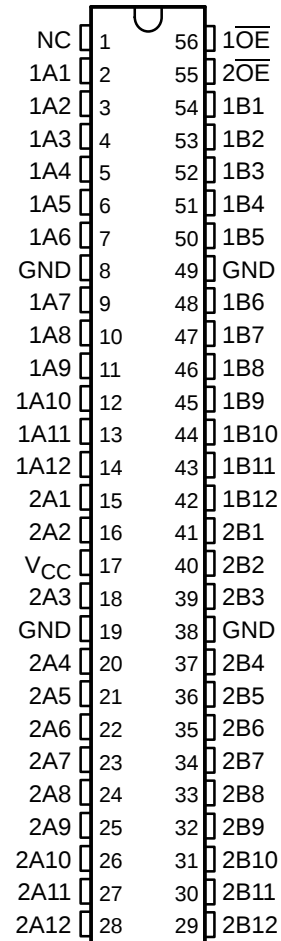
The device operates as a dual 12-bit bus switch or single 24-bit bus switch. When $\overline{1OE}$ is low, 1A is connected to 1B. When $\overline{2OE}$ is low, 2A is connected to 2B.

The SN74CBT16211A is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each 12-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
$\overline{1OE}$	$\overline{2OE}$	1A, 1B	2A, 2B
L	L	1A = 1B	2A = 2B
L	H	1A = 1B	Z
H	L	Z	2A = 2B
H	H	Z	Z

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

SCDS028H – JULY 1995 – REVISED MAY 1998

The schematic diagram illustrates a 2-to-4 decoder circuit. It consists of two 74VHC04 inverters and two 2N7000 NMOS transistors. The first inverter (top) has its input (pin 56) connected to the first input variable $1A_1$ (pin 2) and its output (pin 54) connected to the first output variable $1B_1$ (pin 54). The second inverter (bottom) has its input (pin 55) connected to the second input variable $2A_1$ (pin 15) and its output (pin 41) connected to the second output variable $2B_1$ (pin 41). The outputs of the inverters are connected to the gates of the NMOS transistors. The first NMOS transistor (top) has its gate connected to the output of the first inverter (pin 54) and its source connected to ground. The second NMOS transistor (bottom) has its gate connected to the output of the second inverter (pin 41) and its source connected to ground. The drains of the NMOS transistors are connected to the output variables $1B_{12}$ (pin 42) and $2B_{12}$ (pin 29) respectively. The inputs $1A_{12}$ (pin 14) and $2A_{12}$ (pin 28) are connected to the drains of the NMOS transistors. The inputs $1OE$ (pin 56) and $2OE$ (pin 55) are connected to the gates of the NMOS transistors. The inputs $1A_1$ (pin 2) and $2A_1$ (pin 15) are connected to the gates of the NMOS transistors. The inputs $1B_1$ (pin 54) and $2B_1$ (pin 41) are connected to the gates of the NMOS transistors. The inputs $1B_{12}$ (pin 42) and $2B_{12}$ (pin 29) are connected to the drains of the NMOS transistors. The inputs $1A_{12}$ (pin 14) and $2A_{12}$ (pin 28) are connected to the drains of the NMOS transistors. The inputs $1OE$ (pin 56) and $2OE$ (pin 55) are connected to the gates of the NMOS transistors.

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

NOTES:

1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51.

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4	5.5	V
V _{IH}	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
T _A	Operating free-air temperature	−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}		$V_{CC} = 4.5 \text{ V}$, $I_I = -18 \text{ mA}$				-1.2	V
I_I		$V_{CC} = 0 \text{ V}$, $V_I = 5.5 \text{ V}$				10	μA
		$V_{CC} = 5.5 \text{ V}$, $V_I = 5.5 \text{ V or GND}$				± 1	
I_{CC}		$V_{CC} = 5.5 \text{ V}$, $I_O = 0$, $V_I = V_{CC} \text{ or GND}$				3	μA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5 \text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND				2.5	mA
C_i	Control inputs	$V_I = 3 \text{ V or 0}$				3	pF
$C_{io(OFF)}$		$V_O = 3 \text{ V or 0}$, $\overline{OE} = V_{CC}$				5.5	pF
$r_{on}^§$		$V_{CC} = 4 \text{ V}$, TYP at $V_{CC} = 4 \text{ V}$	$V_I = 2.4 \text{ V}$, $I_I = 15 \text{ mA}$			14	Ω
		$V_{CC} = 4.5 \text{ V}$	$V_I = 0$, $I_I = 64 \text{ mA}$			5	
			$I_I = 30 \text{ mA}$			5	
			$V_I = 2.4 \text{ V}$, $I_I = 15 \text{ mA}$			8	

† All typical values are at $V_{CC} = 5 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

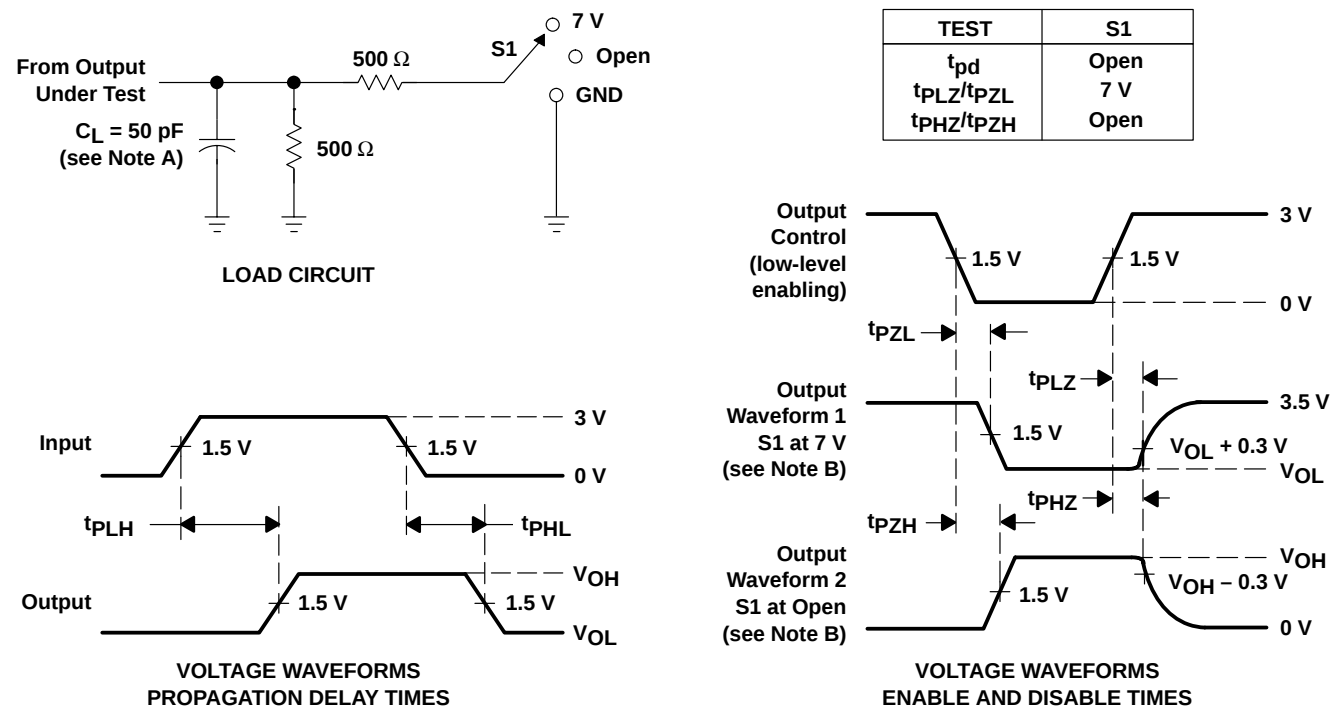
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4 \text{ V}$		$V_{CC} = 5 \text{ V}$ $\pm 0.5 \text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A		0.35		0.25	ns
t_{en}	$\overline{OE}$	A or B		9.3	3.3	8.6	ns
t_{dis}	$\overline{OE}$	A or B		7.1	2.8	7.9	ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBT16211A 24-BIT FET BUS SWITCH

SCDS028H – JULY 1995 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTH16211

24-BIT FET BUS SWITCH

WITH BUS HOLD

SCDS062A – JUNE 1998 – REVISED OCTOBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Bus Hold on Data Inputs/Outputs
Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

The SN74CBTH16211 provides 24 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as dual 12-bit bus switches with separate output-enable ($\overline{OE}$) inputs. It can be used as two 12-bit bus switches or one 24-bit bus switch. When $\overline{OE}$ is low, the associated 12-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

Active bus-hold circuitry is provided to hold unused or floating A and B ports at a valid logic level.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTH16211 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE (TOP VIEW)

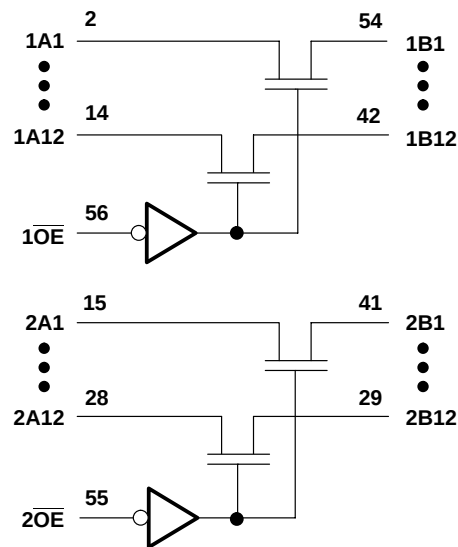
NC	1	56	$1\overline{OE}$
1A1	2	55	$2\overline{OE}$
1A2	3	54	1B1
1A3	4	53	1B2
1A4	5	52	1B3
1A5	6	51	1B4
1A6	7	50	1B5
GND	8	49	GND
1A7	9	48	1B6
1A8	10	47	1B7
1A9	11	46	1B8
1A10	12	45	1B9
1A11	13	44	1B10
1A12	14	43	1B11
2A1	15	42	1B12
2A2	16	41	2B1
V_{CC}	17	40	2B2
2A3	18	39	2B3
GND	19	38	GND
2A4	20	37	2B4
2A5	21	36	2B5
2A6	22	35	2B6
2A7	23	34	2B7
2A8	24	33	2B8
2A9	25	32	2B9
2A10	26	31	2B10
2A11	27	30	2B11
2A12	28	29	2B12

NC – No internal connection

FUNCTION TABLE
(each bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
V _{IK}		V _{CC} = 4.5 V,	I _I = −18 mA			−1.2	V	
I _I	Control inputs	V _{CC} = 0 V,	V _I = 5.5 V			±10	μA	
	All inputs	V _{CC} = 5.5 V,	V _I = 5.5 V or GND			±10		
I _{BHL} [‡]		V _{CC} = 4.5 V,	V _I = 0.8 V	100			μA	
I _{BHH} [§]		V _{CC} = 4.5 V,	V _I = 2 V	−100			μA	
I _{BHLO} [¶]		V _{CC} = 5.5 V,	V _I = 0 to 5.5 V	500			μA	
I _{BHHO} [#]		V _{CC} = 5.5 V,	V _I = 0 to 5.5 V	−500			μA	
I _{CC}		V _{CC} = 5.5 V,	I _O = 0, V _I = V _{CC} or GND			3	μA	
ΔI _{CC}	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA	
r _{on} [☆]		V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA		14	20	Ω	
		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA		5		7
				I _I = 30 mA		5		7
			V _I = 2.4 V, I _I = 15 mA		8	12		

† All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

‡ The bus hold circuit can sink at least the minimum low sustaining current at $V_{IL}\text{ max}$. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to $V_{IL}\text{ max}$.

§ The bus hold circuit can source at least the minimum high sustaining current at $V_{IH}\text{ min}$. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to $V_{IH}\text{ min}$.

¶ An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least I_{BHHO} to switch this node from high to low.

|| This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

☆ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V}$ $\pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\square$	A or B	B or A		0.35		0.25	ns
t_{en}	$\overline{OE}$	A or B		9.9	1	9.6	ns
t_{dis}	$\overline{OE}$	A or B		9.5	1	8.3	ns

□ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

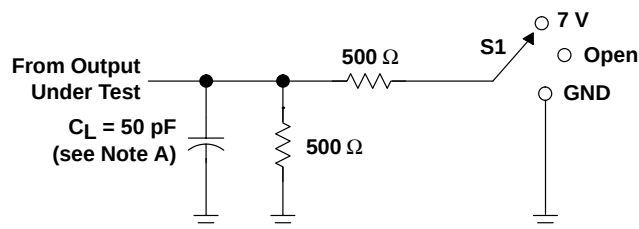
SN74CBTH16211

24-BIT FET BUS SWITCH

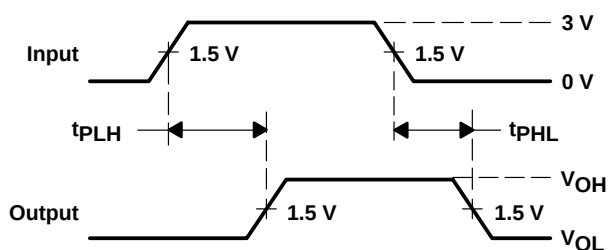
WITH BUS HOLD

SCDS062A – JUNE 1998 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION

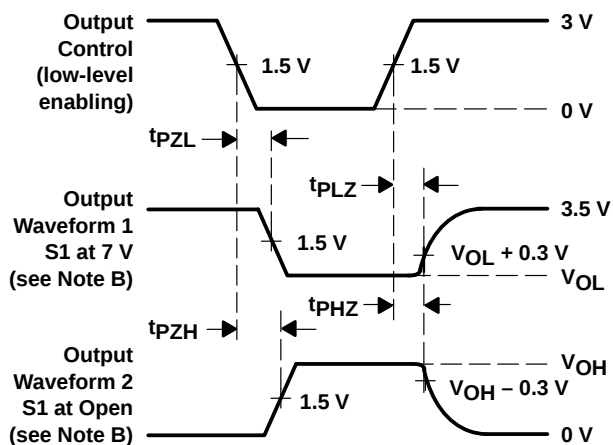


LOAD CIRCUIT



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

The SN74CBTR16211 provides 24 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a dual 12-bit bus switch or single 24-bit bus switch. When $1\overline{OE}$ is low, 1A is connected to 1B. When $2\overline{OE}$ is low, 2A is connected to 2B.

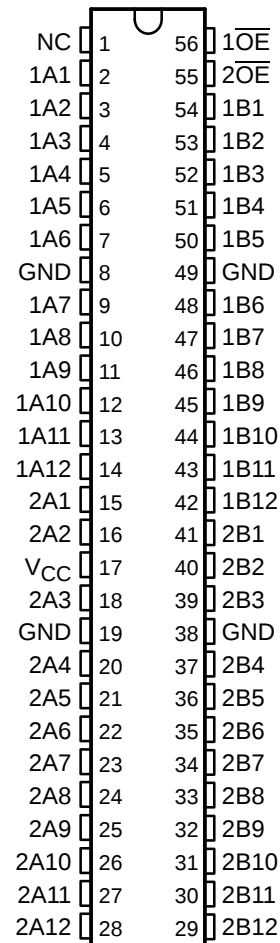
The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR16211 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE
(each 12-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
$1\overline{OE}$	$2\overline{OE}$	1A, 1B	2A, 2B
L	L	1A = 1B	2A = 2B
L	H	1A = 1B	Z
H	L	Z	2A = 2B
H	H	Z	Z

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

SCDS073 – JULY 1998

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{Stg}	−65°C to 150°C

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51.

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	V
V _{IH}	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
T _A	Operating free-air temperature	−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = −18 mA				−1.2	V
I _I		V _{CC} = 0 V,	V _I = 5.5 V				10	μA
		V _{CC} = 5.5 V,	V _I = 5.5 V or GND				±1	
I _{CC}		V _{CC} = 5.5 V,	I _O = 0, V _I = V _{CC} or GND				3	μA
ΔI _{CC} ‡	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V, Other inputs at V _{CC} or GND				2.5	mA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)		V _O = 3 V or 0,	$\overline{OE}$ = V _{CC}					pF
r _{on} [§]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				Ω
				I _I = 30 mA				
			V _I = 2.4 V, I _I = 15 mA					

[†] All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

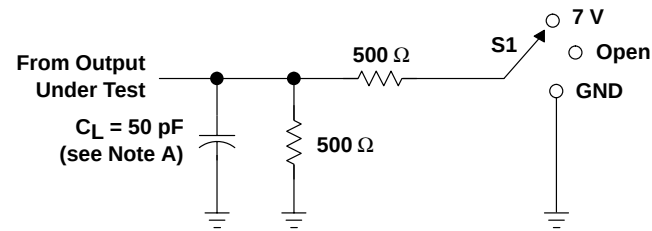
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd\parallel}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBTR16211
24-BIT FET BUS SWITCH

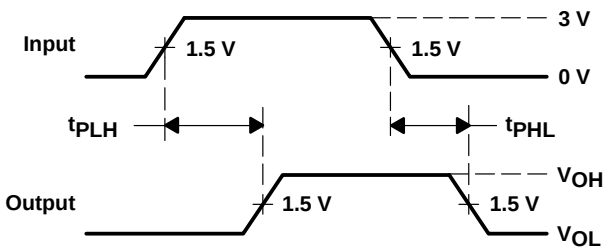
SCDS073 – JULY 1998

PARAMETER MEASUREMENT INFORMATION

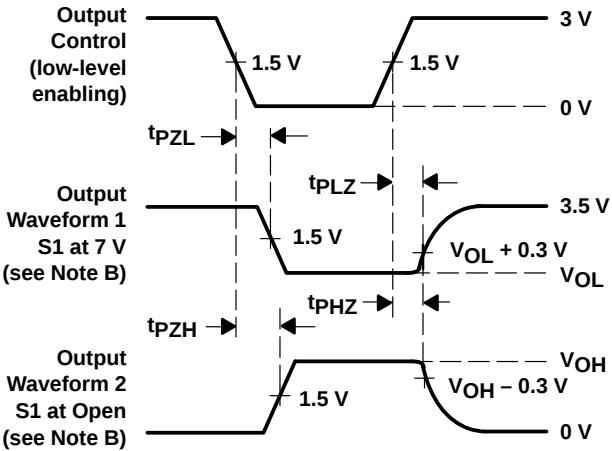


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

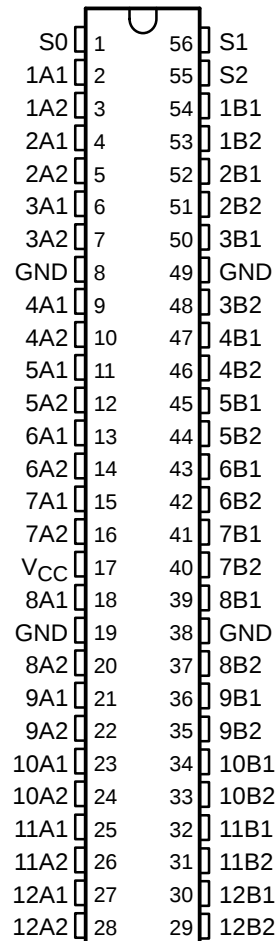
Figure 1. Load Circuit and Voltage Waveforms

SN54CBT16212A, SN74CBT16212A 24-BIT FET BUS-EXCHANGE SWITCHES

SCDS007M – NOVEMBER 1992 – REVISED SEPTEMBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages, and Ceramic Flat (WD) Package

SN54CBT16212A . . . WD PACKAGE
SN74CBT16212A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'CBT16212A devices provide 24 bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

Each device operates as a 24-bit bus switch or a 12-bit bus exchanger, which provides data exchanging between the four signal ports via the data-select (S0, S1, S2) terminals.

The SN54CBT16212A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74CBT16212A is characterized for operation from -40°C to 85°C.

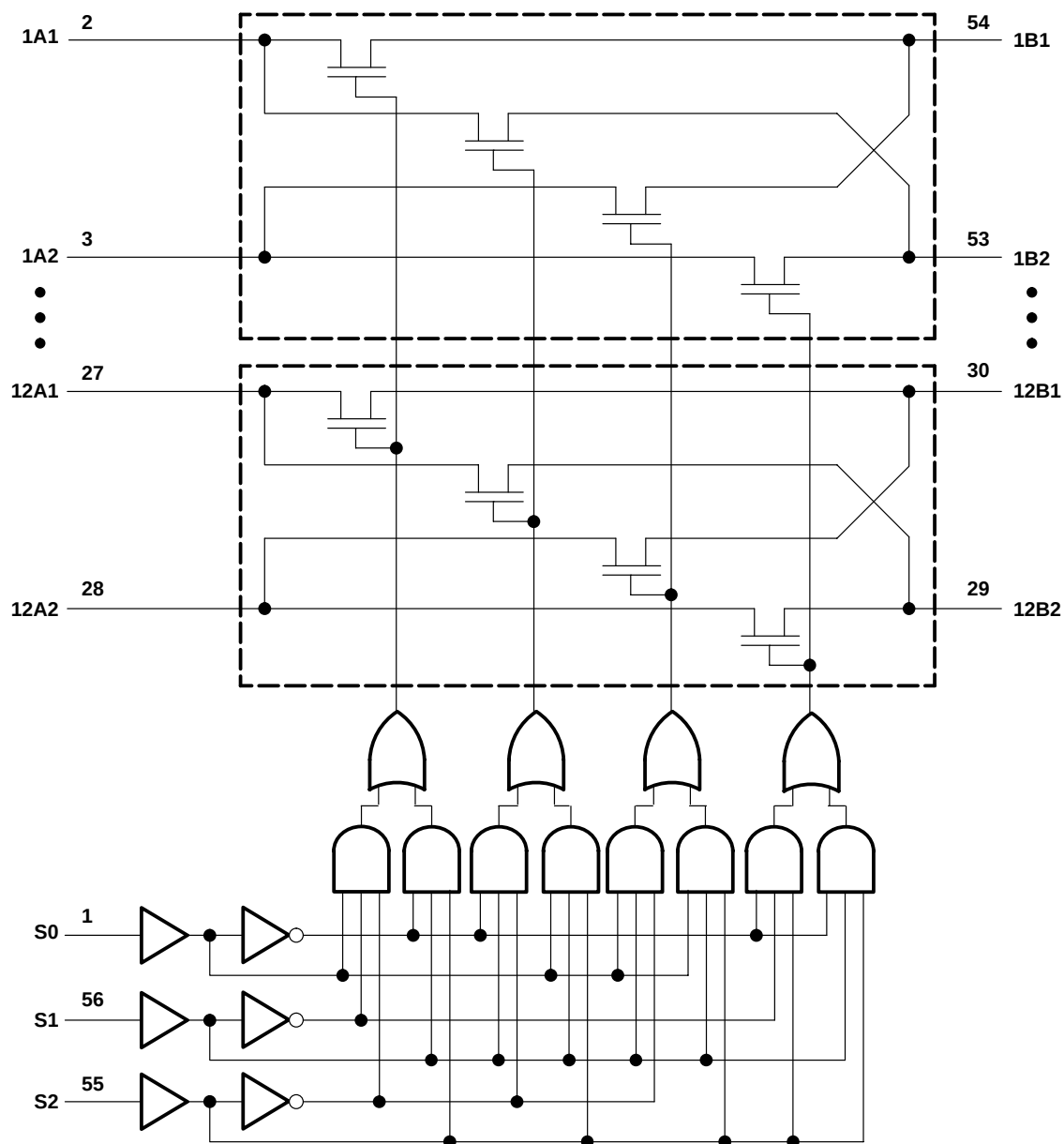
FUNCTION TABLE

INPUTS			INPUTS/OUTPUTS		FUNCTION
S2	S1	S0	A1	A2	
L	L	L	Z	Z	Disconnect
L	L	H	B1 port	Z	A1 port = B1 port
L	H	L	B2 port	Z	A1 port = B2 port
L	H	H	Z	B1 port	A2 port = B1 port
H	L	L	Z	B2 port	A2 port = B2 port
H	L	H	Z	Z	Disconnect
H	H	L	B1 port	B2 port	A1 port = B1 port A2 port = B2 port
H	H	H	B2 port	B1 port	A1 port = B2 port A2 port = B1 port

SN54CBT16212A, SN74CBT16212A 24-BIT FET BUS-EXCHANGE SWITCHES

SCDS007M – NOVEMBER 1992 – REVISED SEPTEMBER 1998

logic diagram (positive logic)



Pin numbers shown are for the DGG, DGV, and DL packages.

SCDS007M – NOVEMBER 1992 – REVISED SEPTEMBER 1998

4-29

SN54CBT16212A, SN74CBT16212A 24-BIT FET BUS-EXCHANGE SWITCHES

SCDS007M – NOVEMBER 1992 – REVISED SEPTEMBER 1998

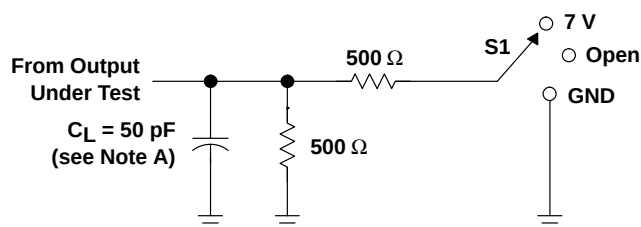
switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54CBT16212A				SN74CBT16212A				UNIT
			V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd} [†]	A or B	B or A			0.8*		0.35		0.25		ns
t _{pd}	S	A or B		14	1.5	13		10	1.5	9.1	ns
t _{en}	S	A or B		15	1.5	13.7		10.4	1.5	9.7	ns
t _{dis}	S	A or B		14.2	1.5	13.5		9.2	1.5	8.8	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

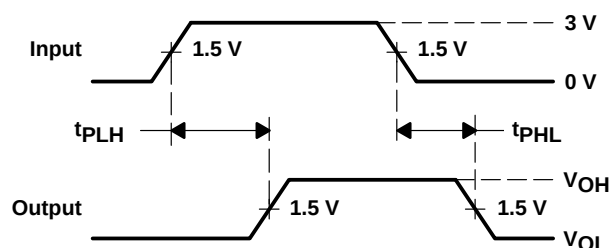
† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

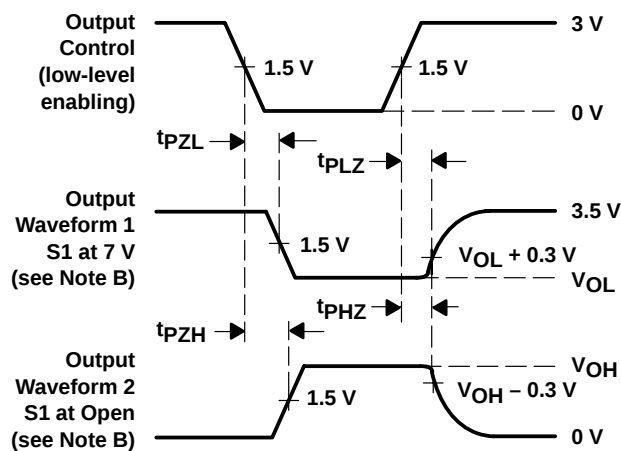


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

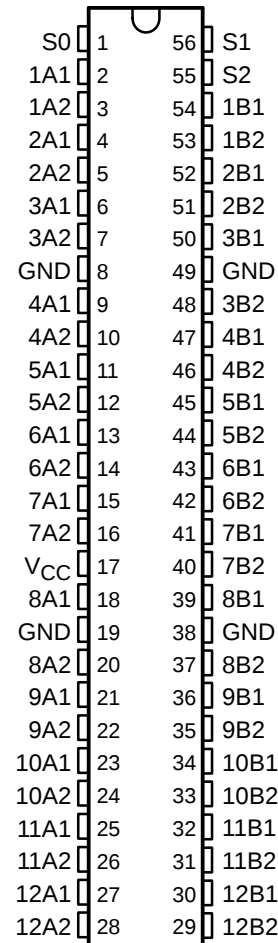
The SN74CBTR16212 provides 24 bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 24-bit bus switch or a 12-bit bus exchanger, which provides data exchanging between the four signal ports via the data-select (S0–S2) terminals.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR16212 is characterized for operation from –40°C to 85°C.

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



FUNCTION TABLE

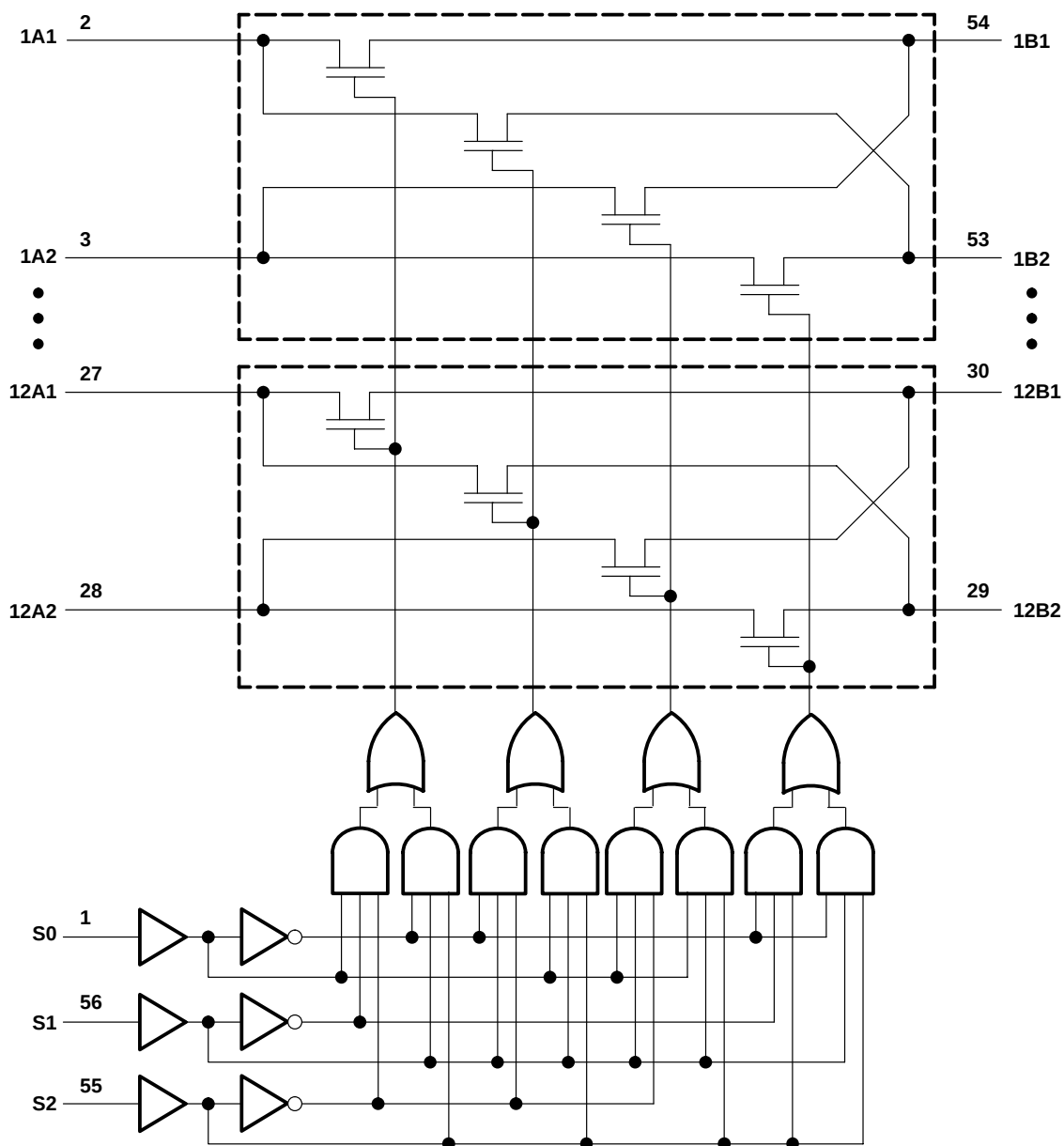
INPUTS			INPUTS/OUTPUTS		FUNCTION
S2	S1	S0	A1	A2	
L	L	L	Z	Z	Disconnect
L	L	H	B1 port	Z	A1 port = B1 port
L	H	L	B2 port	Z	A1 port = B2 port
L	H	H	Z	B1 port	A2 port = B1 port
H	L	L	Z	B2 port	A2 port = B2 port
H	L	H	Z	Z	Disconnect
H	H	L	B1 port	B2 port	A1 port = B1 port A2 port = B2 port
H	H	H	B2 port	B1 port	A1 port = B2 port A2 port = B1 port

SN74CBTR16212

24-BIT FET BUS-EXCHANGE SWITCH

SCDS074 – JULY 1998

logic diagram (positive logic)



PRODUCT PREVIEW

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V,	$I_I = -18$ mA			–1.2	V
I_I	$V_{CC} = 0$,	$V_I = 5.5$ V			10	μ A
	$V_{CC} = 5.5$ V,	$V_I = 5.5$ V or GND			± 1	
I_{CC}	$V_{CC} = 5.5$ V,	$I_O = 0$, $V_I = V_{CC}$ or GND			3	μ A
ΔI_{CC} [§] Control inputs	$V_{CC} = 5.5$ V,	One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i Control inputs	$V_I = 3$ V or 0					pF
$C_{iO(OFF)}$	$V_O = 3$ V or 0,	S_0, S_1 , or $S_2 = V_{CC}$				pF
r_{on} [¶]	$V_{CC} = 4.5$ V	$V_I = 0$				Ω
		$I_I = 64$ mA				
		$I_I = 30$ mA				
		$V_I = 2.4$ V, $I_I = 15$ mA				

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

SN74CBTR16212 24-BIT FET BUS-EXCHANGE SWITCH

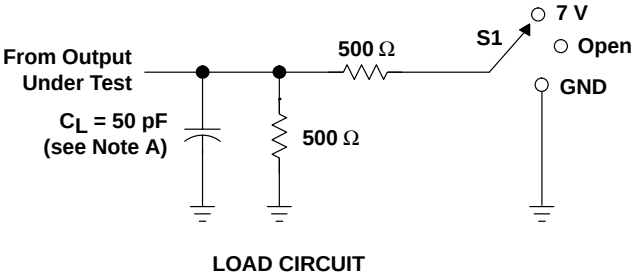
SCDS074 – JULY 1998

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

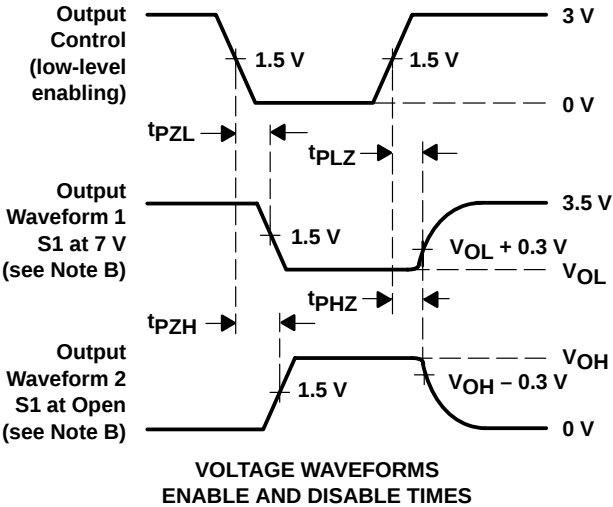
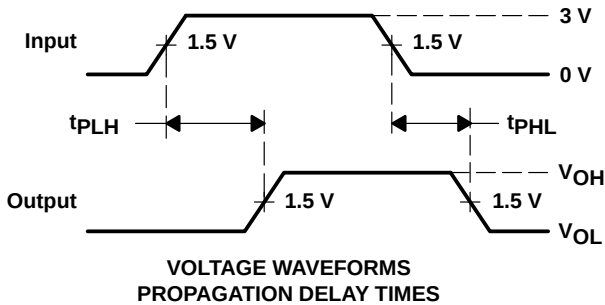
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^\dagger$	A or B	B or A			ns
t_{pd}	S	A or B			ns
t_{en}	S	A or B			ns
t_{dis}	S	A or B			ns

† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT16213 24-BIT FET BUS-EXCHANGE SWITCH

SCDS026F – MAY 1995 – REVISED MAY 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

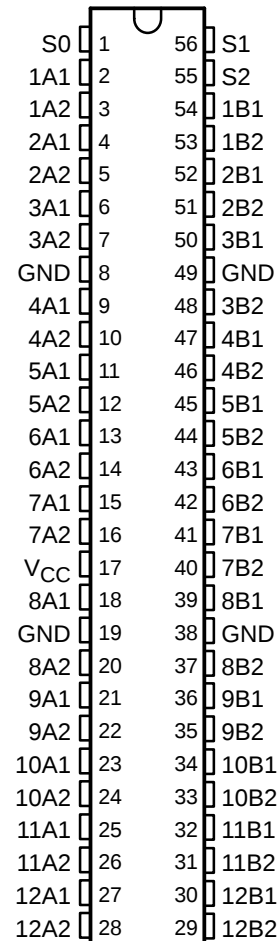
description

The SN74CBT16213 provides 24 bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 24-bit bus switch or a 12-bit bus exchanger that provides data exchanging between the four signal ports via the data-select (S0–S2) terminals.

The SN74CBT16213 is characterized for operation from –40°C to 85°C.

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



FUNCTION TABLE

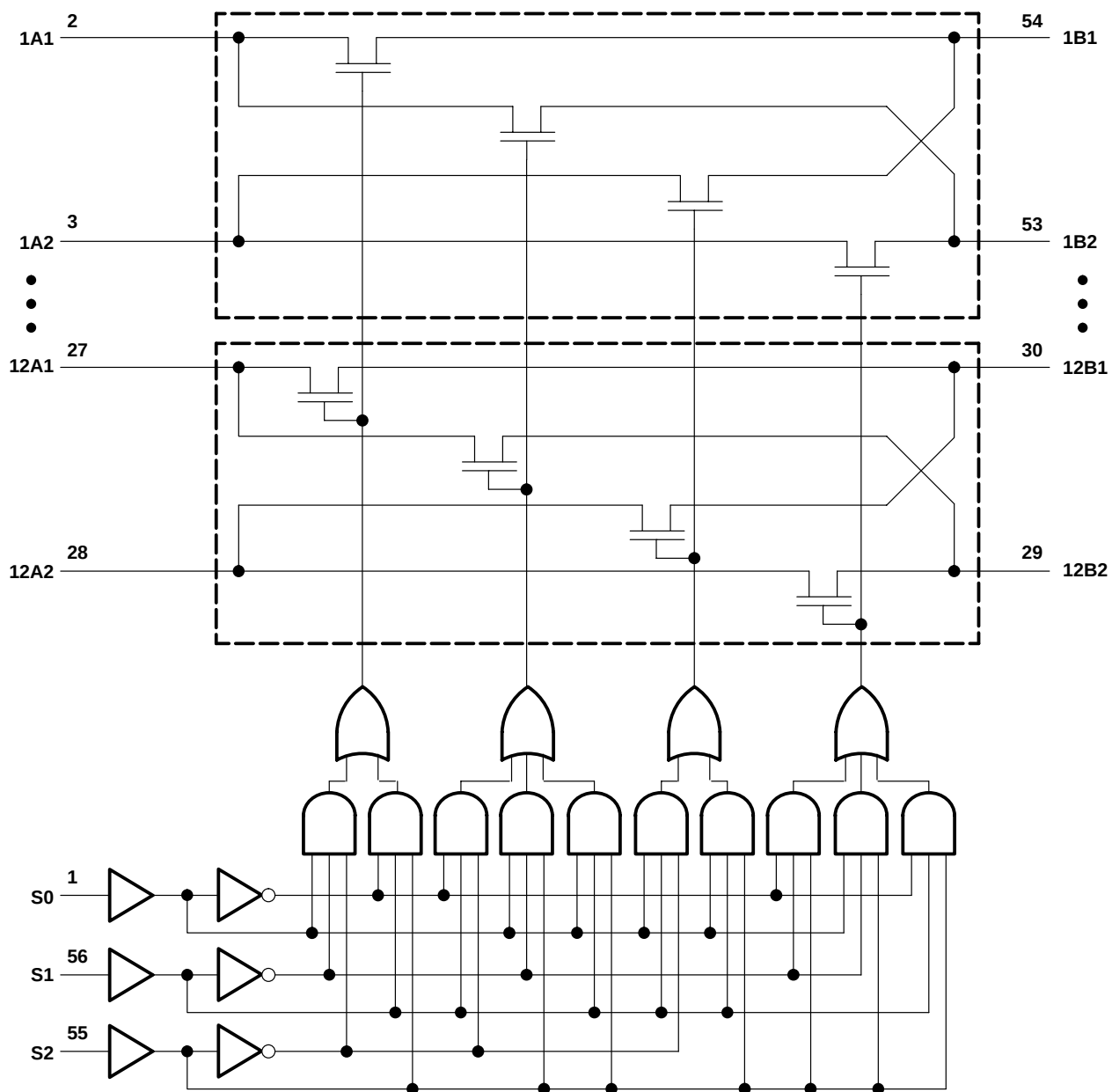
INPUTS			INPUTS/OUTPUTS		FUNCTION
S2	S1	S0	A1	A2	
L	L	L	Z	Z	Disconnect
L	L	H	B1	Z	A1 port = B1 port
L	H	L	B2	Z	A1 port = B2 port
L	H	H	Z	B1	A2 port = B1 port
H	L	L	Z	B2	A2 port = B2 port
H	L	H	A2 and B2	A1 and B2	A1 port = A2 port = B2 port
H	H	L	B1	B2	A1 port = B1 port A2 port = B2 port
H	H	H	B2	B1	A1 port = B2 port A2 port = B1 port

SN74CBT16213

24-BIT FET BUS-EXCHANGE SWITCH

SCDS026F – MAY 1995 – REVISED MAY 1998

logic diagram (positive logic)



Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{sta}	−65°C to 150°C

NOTES:

1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51.

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4	5.5	V
V _{IH}	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
T _A	Operating free-air temperature	−40	85	°C

PARAMETER		TEST CONDITIONS			MIN	TYP [‡]	MAX	UNIT			
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA					−1.2	V			
I _I		V _{CC} = 0, V _I = 5.5 V					10	μA			
		V _{CC} = 5.5 V, V _I = 5.5 V or GND					±1				
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND					3	μA			
ΔI _{CC} [§]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND					2.5	mA			
C _i	Control inputs	V _I = 3 V or 0					4.5	pF			
C _{io} (OFF)	B port	V _O = 3 V or 0, S0, S1, or S2 = V _{CC}					8.5	pF			
	A port						8				
r _{on} [¶]	A to B or B to A	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA				14	20	Ω		
		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				5		7	
				I _I = 30 mA				5		7	
	A1 to A2	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA				8	15			
			V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA					10	14
					I _I = 30 mA					10	14
		V _I = 2.4 V, I _I = 15 mA				16	22				

1 Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages drop of the two (A or B) terminals.

SN74CBT16213 24-BIT FET BUS-EXCHANGE SWITCH

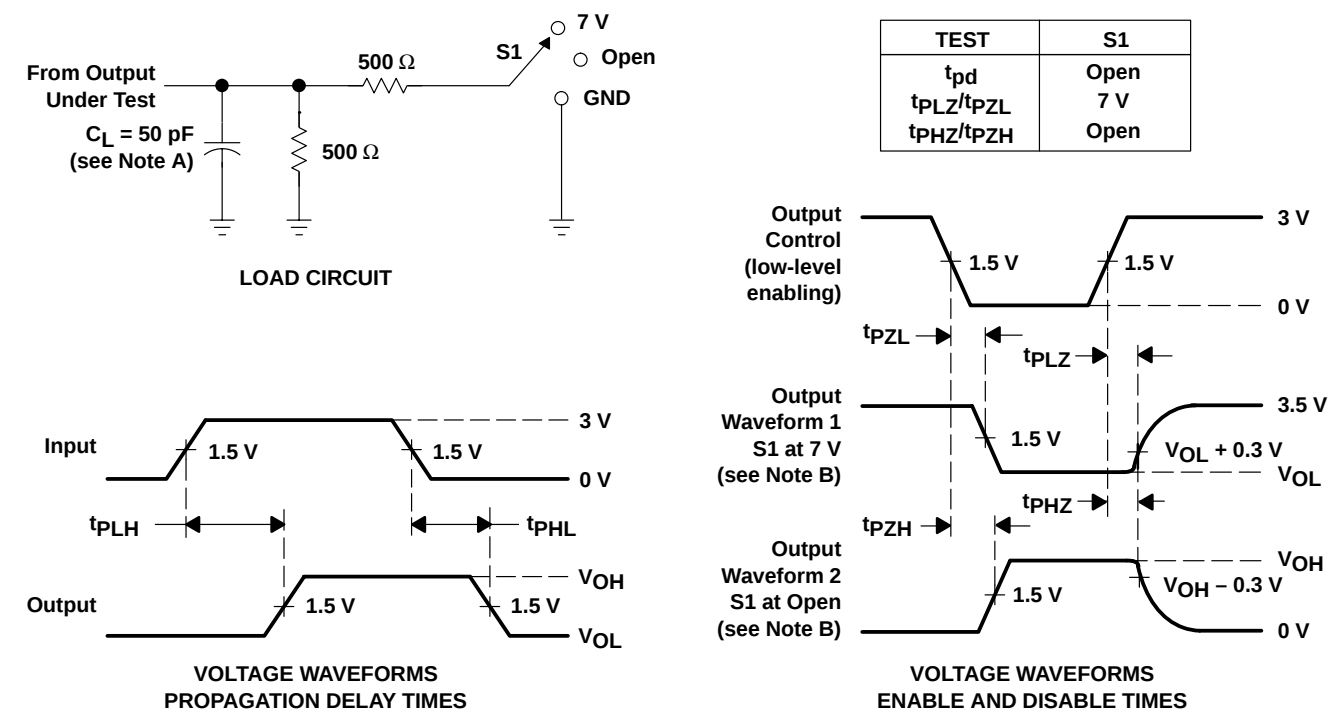
SCDS026F – MAY 1995 – REVISED MAY 1998

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ±0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [†]	A or B	B or A	0.35		0.25		ns
	A1	A2	0.5		0.5		
t _{en}	S	A or B	12.4		3.2	11.1	ns
t _{dis}	S	A or B	12.4		2.3	11.9	ns
t _{en}	S0	A2 and B2	11.5		4	10.9	ns
t _{dis}	S0	A2 and B2	12.8		5.7	12	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT16214

12-BIT 1-OF-3 FET MULTIPLEXER/DEMULTIPLEXER

SCDS008I – MAY 1993 – REVISED MAY 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and 300-mil Shrink Small-Outline (DL) Packages

description

The SN74CBT16214 provides 12 bits of high-speed TTL-compatible bus switching between three separate ports. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 12-bit bus-select switch via the data-select (S0–S2) terminals.

The SN74CBT16214 is characterized for operation from –40°C to 85°C.

DGG OR DL PACKAGE (TOP VIEW)

S0	1	56	S1
1A	2	55	S2
1B3	3	54	1B1
2A	4	53	1B2
2B3	5	52	2B1
3A	6	51	2B2
3B3	7	50	3B1
GND	8	49	GND
4A	9	48	3B2
4B3	10	47	4B1
5A	11	46	4B2
5B3	12	45	5B1
6A	13	44	5B2
6B3	14	43	6B1
7A	15	42	6B2
7B3	16	41	7B1
V _{CC}	17	40	7B2
8A	18	39	8B1
GND	19	38	GND
8B3	20	37	8B2
9A	21	36	9B1
9B3	22	35	9B2
10A	23	34	10B1
10B3	24	33	10B2
11A	25	32	11B1
11B3	26	31	11B2
12A	27	30	12B1
12B3	28	29	12B2

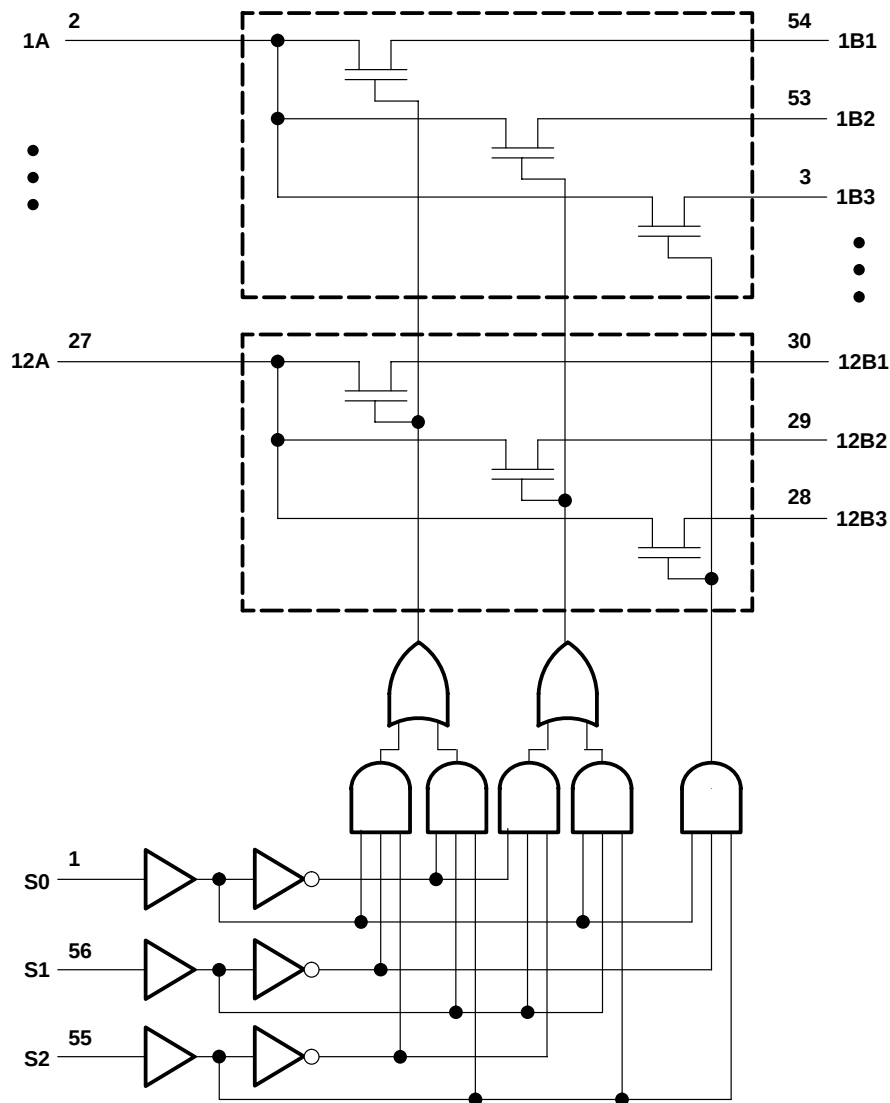
FUNCTION TABLE

INPUTS			INPUT/OUTPUT A	FUNCTION
S2	S1	S0		
L	L	L	Z	Disconnect
L	L	H	B1	A port = B1 port
L	H	L	B2	A port = B2 port
L	H	H	Z	Disconnect
H	L	L	Z	Disconnect
H	L	H	B3	A port = B3 port
H	H	L	B1	A port = B1 port
H	H	H	B2	A port = B2 port

SN74CBT16214
12-BIT 1-OF-3 FET MULTIPLEXER/DEMULTIPLEXER

SCDS008I – MAY 1993 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	-50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C
DL package	74°C
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

SN74CBT16214

12-BIT 1-OF-3 FET MULTIPLEXER/DEMULTIPLEXER

SCDS008I – MAY 1993 – REVISED MAY 1998

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA			–1.2	V
I _I	V _{CC} = 0, V _I = 5.5 V			10	μA
	V _{CC} = 5.5 V, V _I = 5.5 V or GND			±1	
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			3	μA
ΔI _{CC} [‡]	Control inputs V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA
C _i	Control inputs V _I = 3 V or 0			4	pF
C _{io(OFF)}	V _O = 3 V or 0, A = Z			7.5	pF
r _{on} [§]	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA			Ω
	V _{CC} = 4.5 V	V _I = 0, I _I = 64 mA	4	7	
		I _I = 30 mA	4	7	
		V _I = 2.4 V, I _I = 15 mA	6	12	

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

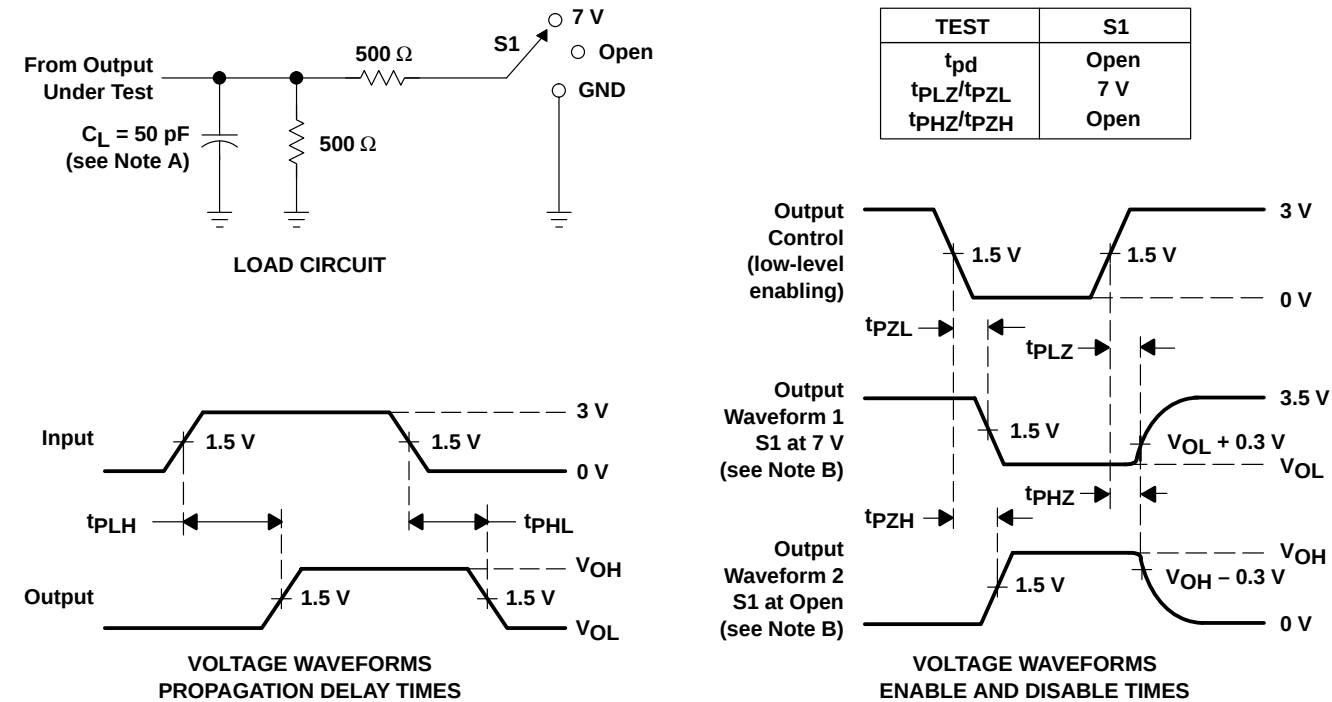
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A	0.35		0.25		ns
t _{pd}	S	B or A	15.3		5.5	13.9	ns
t _{en}	S	A or B	16		5.1	14.5	ns
t _{dis}	S	A or B	12.1		3.6	11.7	ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBT16214 12-BIT 1-OF-3 FET MULTIPLEXER/DEMULTIPLEXER

SCDS008I – MAY 1993 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT16232 SYNCHRONOUS 16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS009I – MAY 1995 – REVISED OCTOBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input and Output Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and 300-mil Shrink Small-Outline (DL) Packages

description

The SN74CBT16232 is a synchronous 16-bit 1-of-2 FET multiplexer/demultiplexer used in applications in which two separate datapaths must be multiplexed onto, or demultiplexed from, a single path.

Two select (S0 and S1) inputs control the data flow. A clock (CLK) and a clock enable (CLKEN) synchronize the device operation. When CLKEN is high, the bus switch remains in the last clocked function.

The SN74CBT16232 is characterized for operation from –40°C to 85°C.

DGG OR DL PACKAGE (TOP VIEW)			
1A	1	56	1B1
2B1	2	55	1B2
2B2	3	54	2A
3A	4	53	3B1
4B1	5	52	3B2
4B2	6	51	4A
5A	7	50	5B1
6B1	8	49	5B2
6B2	9	48	6A
7A	10	47	7B1
8B1	11	46	7B2
8B2	12	45	8A
GND	13	44	GND
V _{CC}	14	43	V _{CC}
9A	15	42	9B1
10B1	16	41	9B2
10B2	17	40	10A
11A	18	39	11B1
12B1	19	38	11B2
12B2	20	37	12A
13A	21	36	13B1
14B1	22	35	13B2
14B2	23	34	14A
15A	24	33	15B1
16B1	25	32	15B2
16B2	26	31	16A
CLK	27	30	S0
CLKEN	28	29	S1

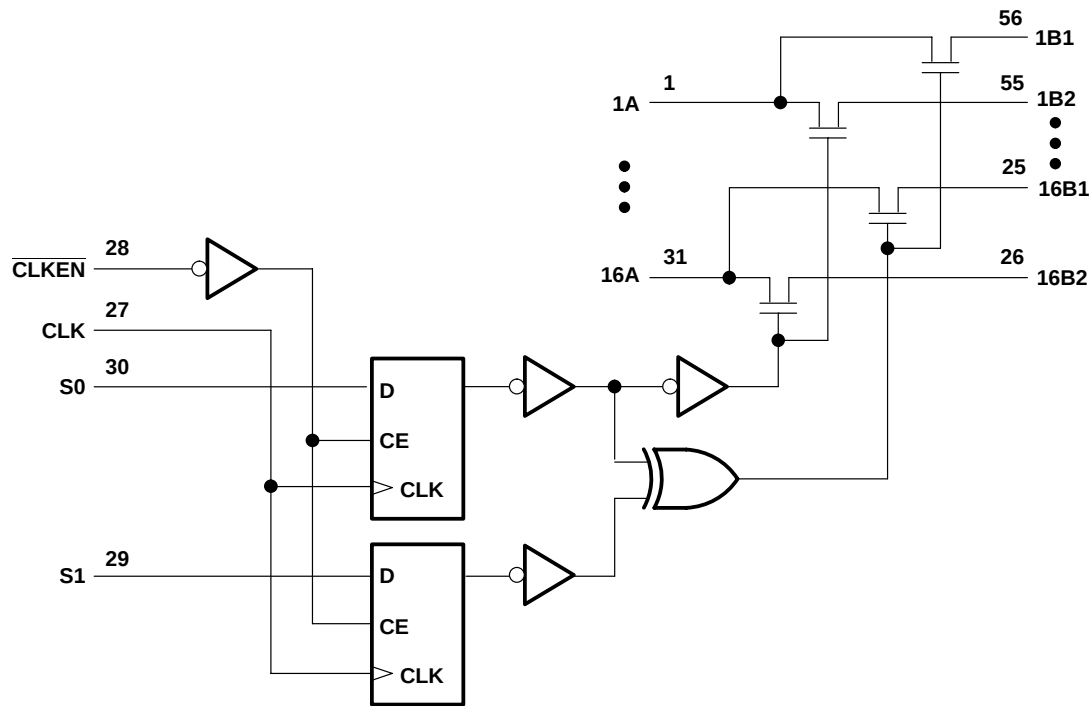
FUNCTION TABLE

INPUTS				FUNCTION
S1	S0	CLK	CLKEN	
X	X	X	H	Last state
L	L	↑	L	Disconnect
L	H	↑	L	A = B1 and A = B2
H	L	↑	L	A = B1
H	H	↑	L	A = B2

SN74CBT16232
SYNCHRONOUS 16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS009I – MAY 1995 – REVISED OCTOBER 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74CBT16232

SYNCHRONOUS 16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS009I – MAY 1995 – REVISED OCTOBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA					−1.2	V
I _I		V _{CC} = 5.5 V, V _I = 5.5 V or GND					±1	μA
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND					3	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND					2.5	mA
C _i	Control inputs	V _I = 3 V or 0				4.5		pF
C _{io} (OFF)	A port	V _O = 3 V or 0, $\overline{\text{CLKEN}}$ = 0, S0 = 0, S1 = 0				6.5		pF
	B port					4		
r _{on} [§]		V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA			14	20	Ω
		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA		5	7	
				I _I = 30 mA		5	7	
			V _I = 2.4 V, I _I = 15 mA			10	15	

[†] All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER			$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			150		150	MHz
t_W	Pulse duration	CLK high or low	3.3		3.3		ns
t_{su}	Setup time	S0, S1 before CLK $\uparrow$	2.2		1.9		ns
		CLKEN before CLK $\uparrow$	2.4		1.9		
t_h	Hold time	S0, S1 after CLK $\uparrow$	0.5		1		ns
		CLKEN after CLK $\uparrow$	1.9		1.8		

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
f _{max}			150		150		MHz
t _{pd} [¶]	A or B	B or A	0.35		0.25		ns
t _{pd}	CLK	A or B	6.1		2	5.8	ns
t _{en}	CLK	A, B1, B2	6.8		1.8	6.2	ns
		B1 or B2	8.5		3.1	7.9	
t _{dis}	CLK	A or B	5.8		1.9	6.2	ns

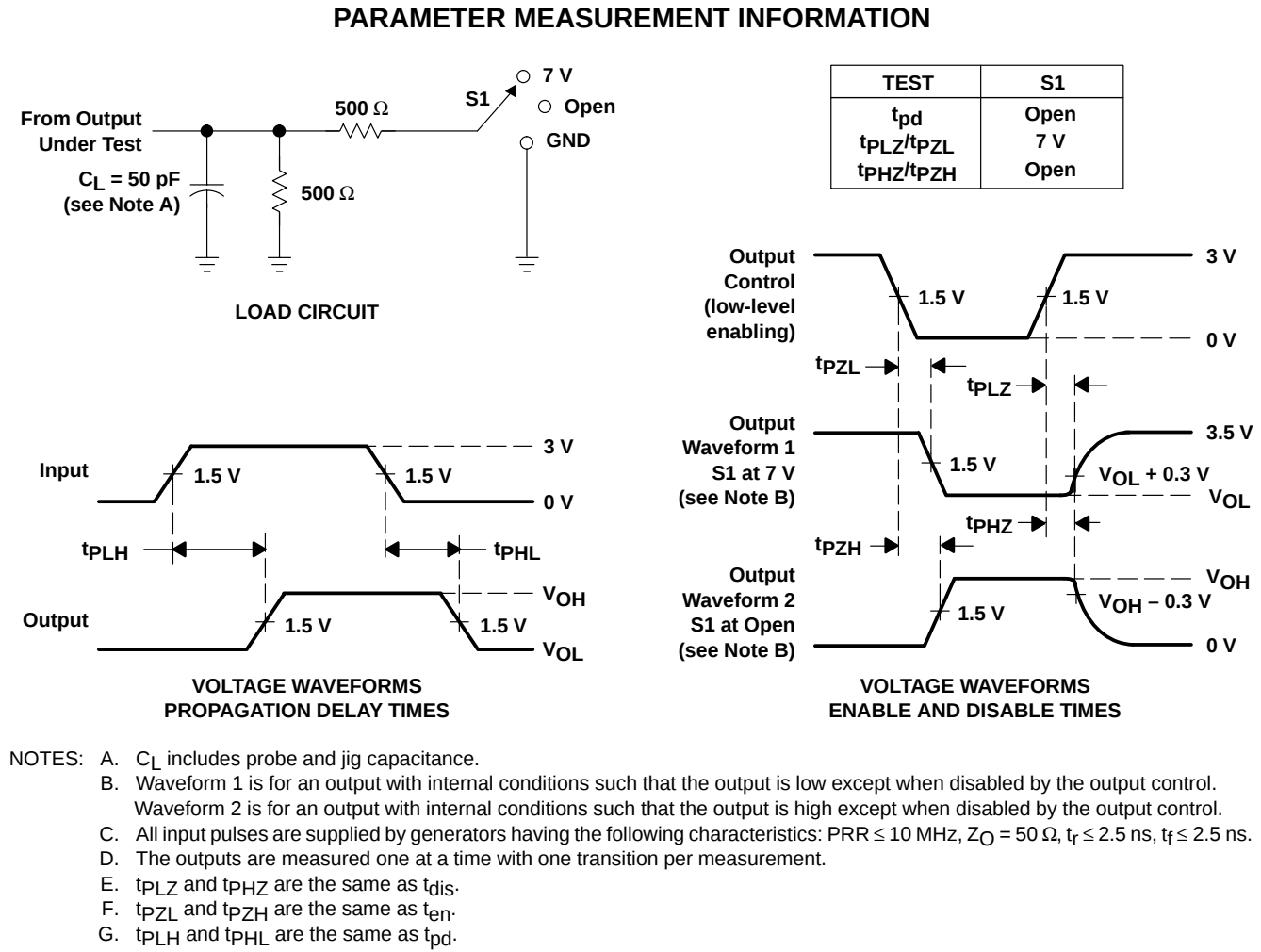
^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



SN74CBT16232

SYNCHRONOUS 16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS009I – MAY 1995 – REVISED OCTOBER 1998



SN74CBT16233

16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS010H – MAY 1995 – REVISED OCTOBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

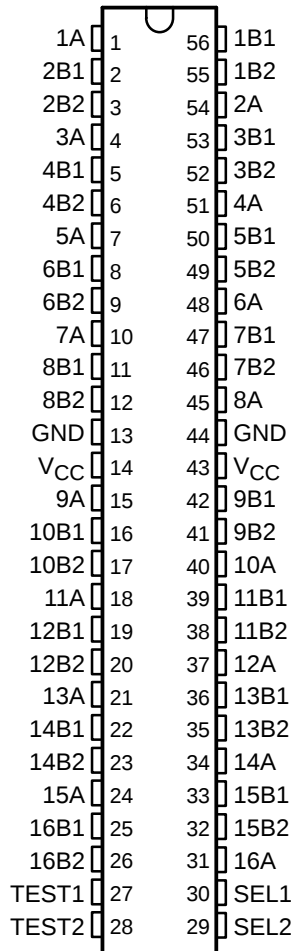
The SN74CBT16233 is a 16-bit 1-of-2 FET multiplexer/demultiplexer used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single path. This device can be used for memory interleaving, where two different banks of memory need to be addressed simultaneously. The device can be used as two 8-bit to 16-bit multiplexers or as one 16-bit to 32-bit multiplexer.

Two select (SEL1 and SEL2) inputs control the data flow. When the TEST inputs are asserted, the A port is connected to both the B1 and the B2 ports. SEL1, SEL2, and the TEST inputs can be driven with a 5-V CMOS, a 5-V TTL, or a low-voltage TTL driver.

The device is specified by design not to have through current when switching directions.

The SN74CBT16233 is characterized for operation from 0°C to 70°C.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



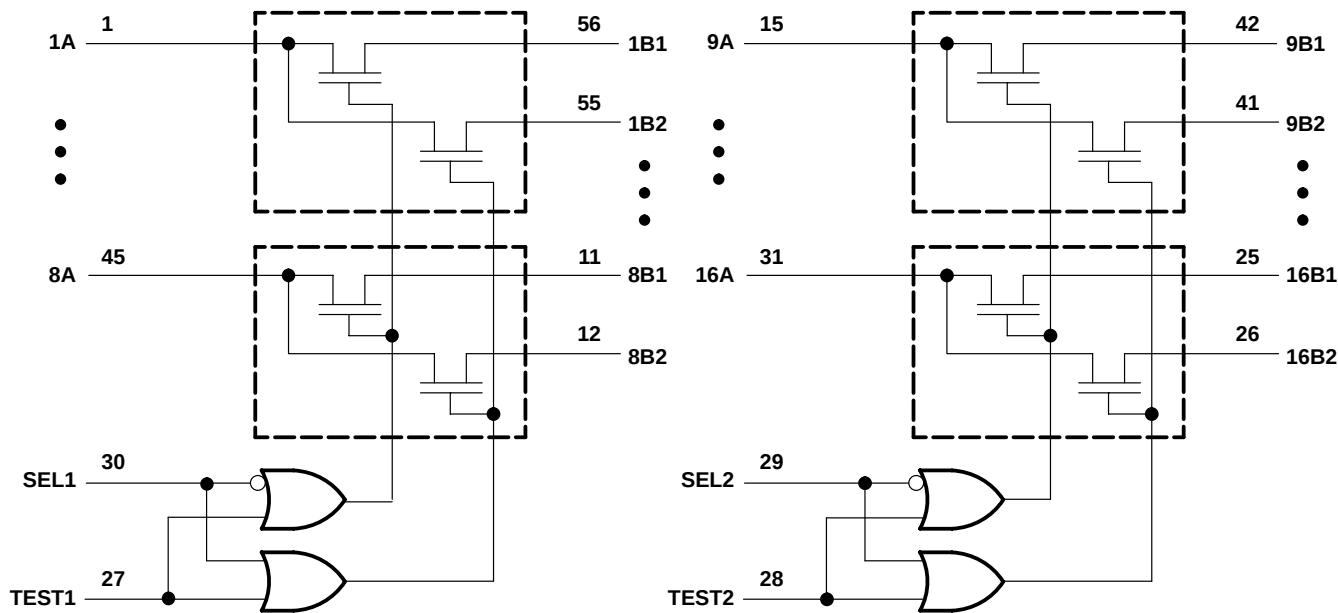
FUNCTION TABLE
(each multiplexer/demultiplexer)

INPUTS		FUNCTION
SEL	TEST	
L	L	A = B1
H	L	A = B2
X	H	A = B1 and A = B2

SN74CBT16233
16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS010H – MAY 1995 – REVISED OCTOBER 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.75	5.25	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	0	70	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN74CBT16233

16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT	
V _{IK}		V _{CC} = 4.75 V, I _I = −18 mA					−1.2	V	
I _I		V _{CC} = 0, V _I = 5.25 V					10	μA	
		V _{CC} = 5.25 V, V _I = 5.25 V or GND					±1	μA	
I _{CC}		V _{CC} = 5.25 V, I _O = 0, V _I = V _{CC} or GND					3	μA	
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND					2.5	mA	
C _i	Control inputs	V _I = 3 V or 0					4.5	pF	
C _{io} (OFF)		V _O = 3 V or 0					4	pF	
r _{on} [§]		V _{CC} = 4.75 V	V _I = 0	I _I = 64 mA			5	7	Ω
				I _I = 30 mA			5	7	
			V _I = 2.4 V, I _I = 15 mA				7	12	

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A		0.25	ns
t_{pd}	SEL	A	1.6	5.3	ns
t_{en}	TEST or SEL	B	1.3	5.2	ns
t_{dis}	TEST or SEL	B	1	5.3	ns

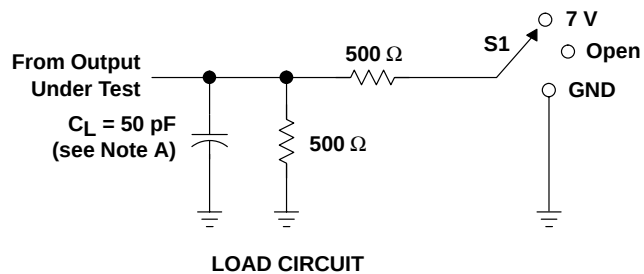
^{$\parallel$} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBT16233

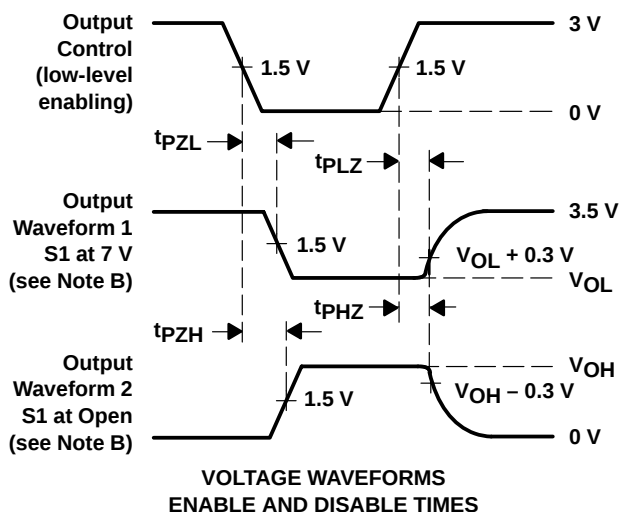
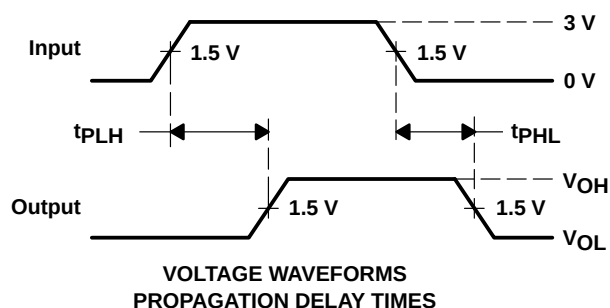
16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS010H – MAY 1995 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTR16233

16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS075A – JULY 1998 – REVISED OCTOBER 1998

- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

The SN74CBTR16233 is a 16-bit 1-of-2 FET multiplexer/demultiplexer used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single path. This device can be used for memory interleaving, where two different banks of memory need to be addressed simultaneously. The device can be used as two 8-bit to 16-bit multiplexers or as one 16-bit to 32-bit multiplexer.

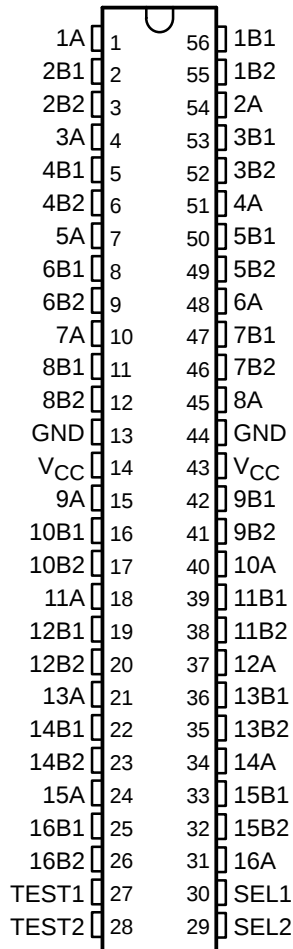
Two select (SEL1 and SEL2) inputs control the data flow. When the TEST inputs are asserted, the A port is connected to both the B1 and the B2 ports. SEL1, SEL2, and the TEST inputs can be driven with a 5-V CMOS, a 5-V TTL, or a low-voltage TTL driver.

The SN74CBTR16233 is specified by design not to have through current when switching directions.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR16233 is characterized for operation from 0°C to 70°C.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



FUNCTION TABLE
(each multiplexer/demultiplexer)

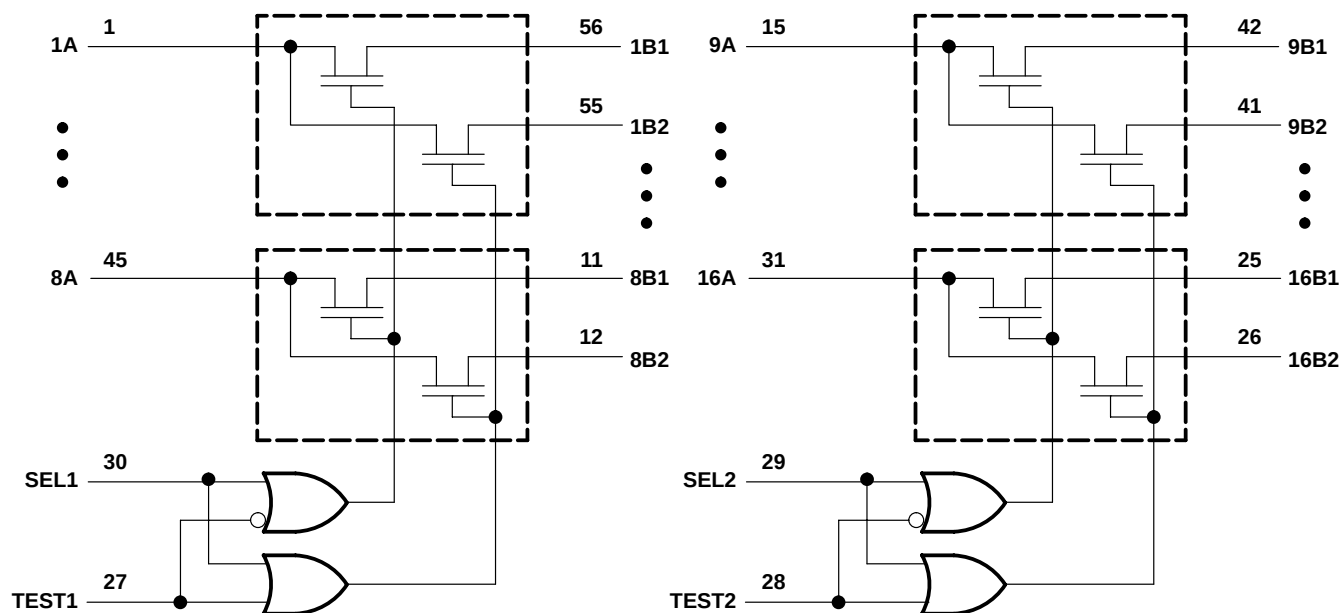
INPUTS		FUNCTION
SEL	TEST	
L	L	A = B1
H	L	A = B2
X	H	A = B1 and A = B2

SN74CBTR16233

16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS075A – JULY 1998 – REVISED OCTOBER 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.75	5.25	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	0	70	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.75\text{ V}$, $I_I = -18\text{ mA}$			-1.2	V
I_I		$V_{CC} = 0$, $V_I = 5.25\text{ V}$			10	μA
		$V_{CC} = 5.25\text{ V}$, $V_I = 5.25\text{ V or GND}$			± 1	μA
I_{CC}		$V_{CC} = 5.25\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$			3	μA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at $V_{CC}\text{ or GND}$			2.5	mA
C_i	Control inputs	$V_I = 3\text{ V or 0}$				pF
$C_{io(OFF)}$		$V_O = 3\text{ V or 0}$				pF
$r_{on}^\S$		$V_{CC} = 4.75\text{ V}$, $V_I = 0$, $I_I = 64\text{ mA}$				Ω
		$V_{CC} = 4.75\text{ V}$, $V_I = 0$, $I_I = 30\text{ mA}$				
		$V_{CC} = 4.75\text{ V}$, $V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$				

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

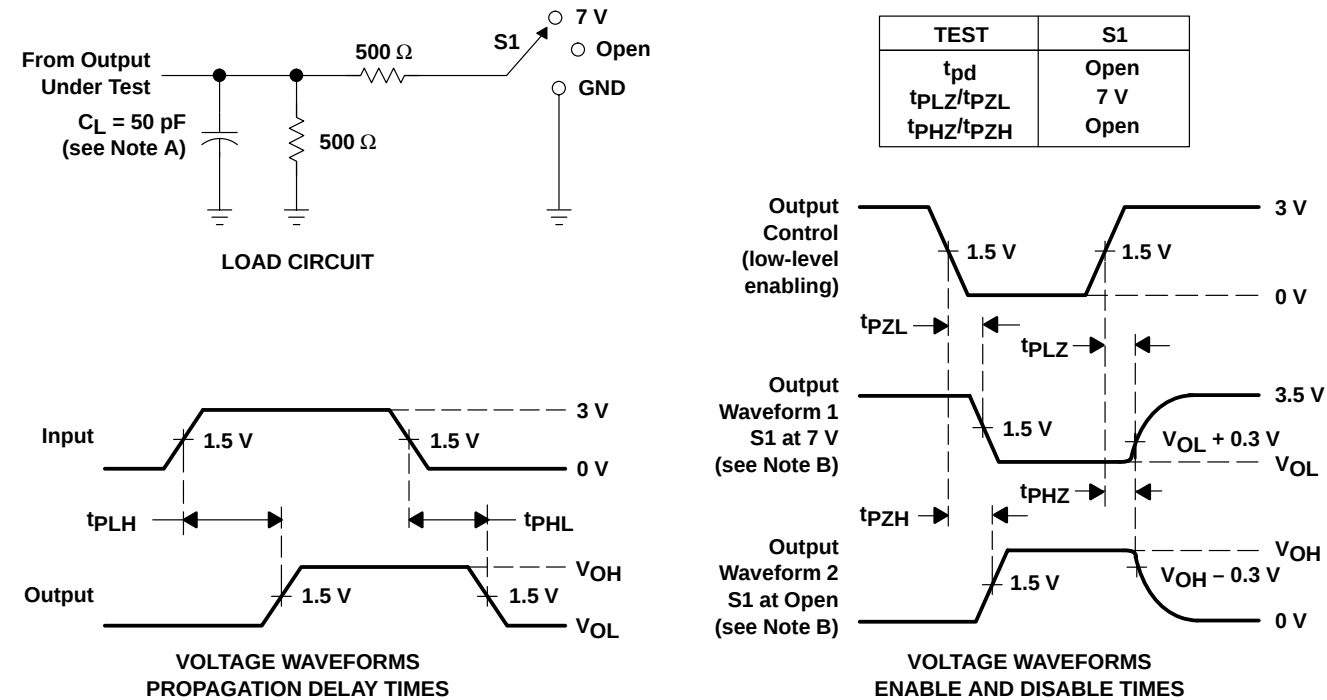
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A			ns
t_{pd}	SEL	A			ns
t_{en}	TEST or SEL	B			ns
t_{dis}	TEST or SEL	B			ns

^{$\parallel$} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBTR16233
16-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS075A – JULY 1998 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN54CBT16244, SN74CBT16244 16-BIT FET BUS SWITCHES

SCDS031G – MAY 1996 – REVISED SEPTEMBER 1998

- Standard '16244-Type Pinout
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages, and Ceramic Flat (WD) Package

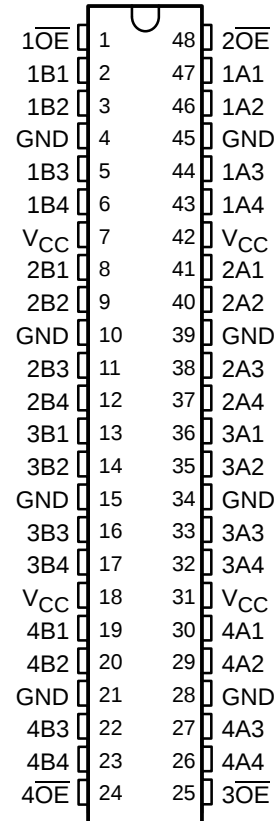
description

The 'CBT16244 devices provide 16 bits of high-speed TTL-compatible bus switching in a standard '16244 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

These devices are organized as four 4-bit low-impedance switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and data can flow from port A to port B, or vice versa. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The SN54CBT16244 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74CBT16244 is characterized for operation from -40°C to 85°C .

SN54CBT16244 . . . WD PACKAGE
SN74CBT16244 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



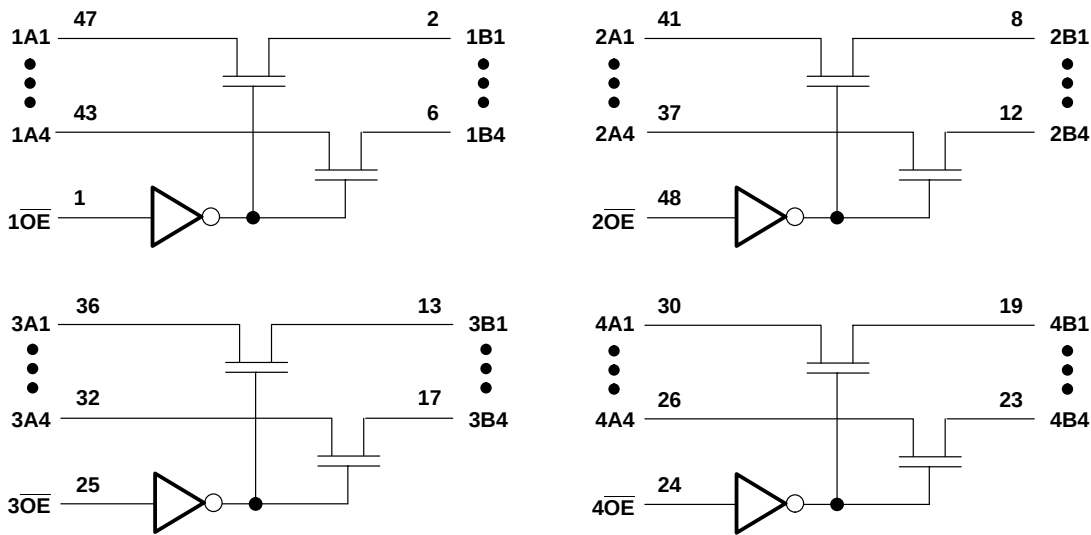
FUNCTION TABLE
(each 4-bit bus switch)

INPUT $\overline{OE}$	OUTPUTS A, B
L	A port = B port
H	Z

SN54CBT16244, SN74CBT16244
16-BIT FET BUS SWITCHES

SCDS031G – MAY 1996 – REVISED SEPTEMBER 1998

logic diagram (positive logic)



Pin numbers shown are for the DGG, DGV, and DL packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		SN54CBT16244		SN74CBT16244		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4	5.5	4	5.5	V
V_{IH}	High-level control input voltage	2		2		V
V_{IL}	Low-level control input voltage		0.8		0.8	V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54CBT16244			SN74CBT16244			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2			-1.2	V
I_I	$V_{CC} = 0$ $V_I = 5.5\text{ V}$			10			10	μA
	$V_{CC} = 5.5\text{ V}$ $V_I = 5.5\text{ V or GND}$			± 1			± 1	
I_{CC}	$V_{CC} = 5.5\text{ V}$, $V_I = V_{CC}\text{ or GND}$ $I_O = 0$,			3.2			3	μA
$\Delta I_{CC}^\ddagger$	Control inputs $V_{CC} = 5.5\text{ V}$, Other inputs at $V_{CC}\text{ or GND}$ One input at 3.4 V,			2.5			2.5	mA
C_i	Control inputs $V_I = 3\text{ V or } 0$			2.5			2.5	pF
$C_{io}(\text{OFF})$	$V_O = 3\text{ V or } 0$, $\overline{OE} = V_{CC}$			4.5			4.5	pF
$r_{on}^\S$	$V_{CC} = 4\text{ V}$, $V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$			20			20	Ω
	$V_{CC} = 4.5\text{ V}$ $V_I = 0$			5	10		5	7
				5	10		5	7
				8	14		8	12

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54CBT16244				SN74CBT16244				UNIT
			V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A				0.8*		0.35		0.25	ns
t _{en}	$\overline{OE}$	A or B		10.3	1	9.2		5.5	1	5.1	ns
t _{dis}	$\overline{OE}$	A or B		9.7	1	8.2		5.2	1	5.4	ns

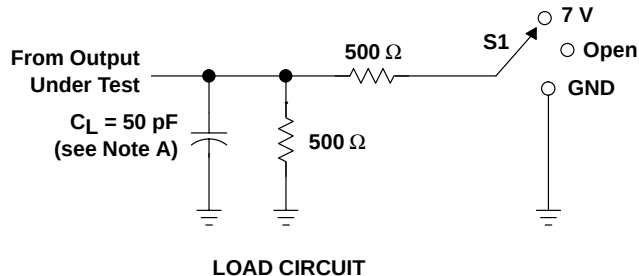
* On products compliant to MIL-PRF-38535, this parameter is not production tested.

$\parallel$ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN54CBT16244, SN74CBT16244 16-BIT FET BUS SWITCHES

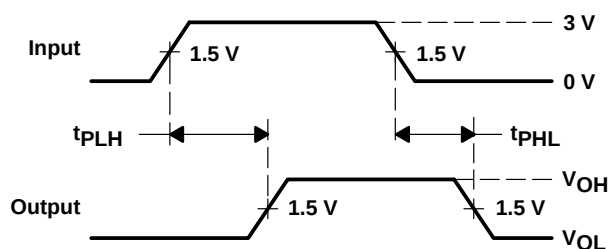
SCDS031G – MAY 1996 – REVISED SEPTEMBER 1998

PARAMETER MEASUREMENT INFORMATION

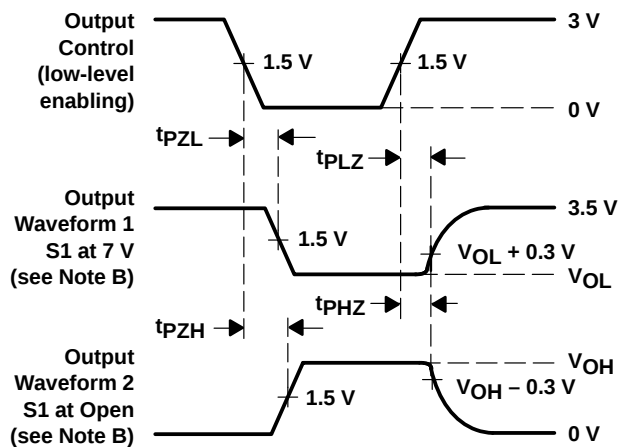


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Standard '16244-Type Pinout
- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

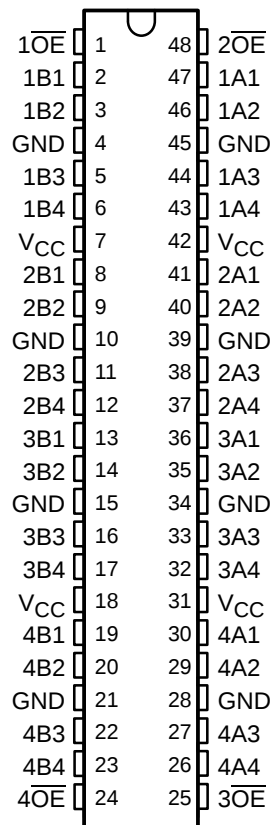
The SN74CBTR16244 provides 16 bits of high-speed TTL-compatible bus switching in a standard '16244 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as four 4-bit low-impedance switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and data can flow from port A to port B, or vice versa. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR16244 is characterized for operation from -40°C to 85°C.

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each 4-bit bus switch)

INPUT $\overline{OE}$	OUTPUTS A, B
L	A port = B port
H	Z

SCDS076 – JULY 1998

The figure displays four circuit diagrams, each representing a different input combination for a 4-to-1 multiplexer. Each diagram shows a 74VHC04 inverter (represented by a triangle with a circle) and a network of 1N4148 diodes. The input lines are labeled 1A1, 1A4, 1OE, 2A1, 2A4, 2OE, 3A1, 3A4, 3OE, 4A1, 4A4, and 4OE. The output lines are labeled 1B1, 1B4, 3B1, 3B4, 4B1, and 4B4. The diagrams illustrate how the selected input is routed to the output through the diode network and the inverter.

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51.

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	V
V _{IH}	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
T _A	Operating free-air temperature	−40	85	°C

PRODUCT PREVIEW

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA					−1.2	V
I _I		V _{CC} = 0	V _I = 5.5 V				10	μA
		V _{CC} = 5.5 V	V _I = 5.5 V or GND				±1	
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND					3	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND					2.5	mA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)		V _O = 3 V or 0, $\overline{OE}$ = V _{CC}						pF
r _{on} [§]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				Ω
				I _I = 30 mA				
			V _I = 2.4 V, I _I = 15 mA					

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

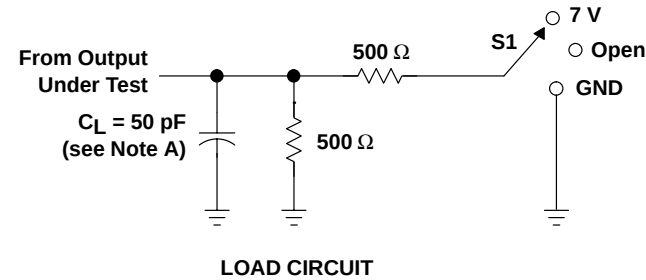
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

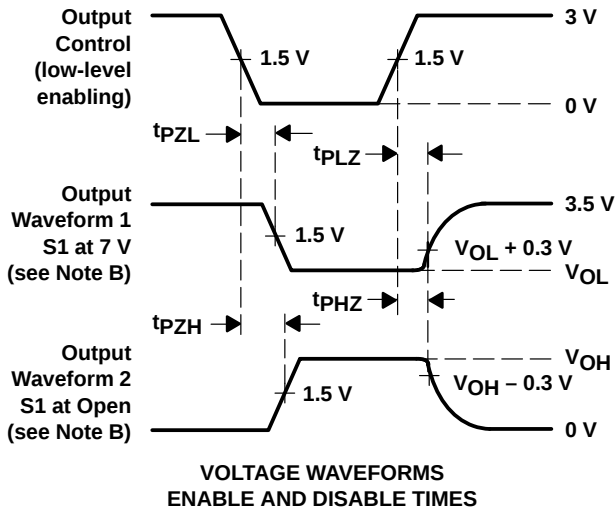
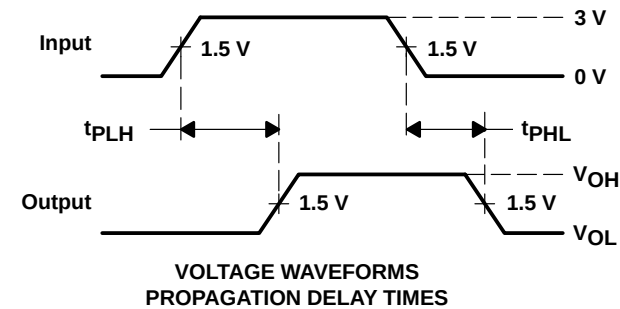
SN74CBTR16244 16-BIT FET BUS SWITCH

SCDS076 – JULY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Standard '16245-Type Pinout
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages

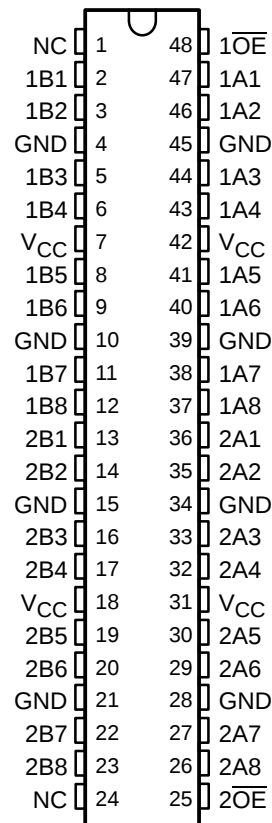
description

The SN74CBT16245 provides 16 bits of high-speed TTL-compatible bus switching in a standard '16245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 8-bit low-impedance switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and data can flow from port A to port B, or vice versa. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The SN74CBT16245 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE
(each 8-bit bus switch)

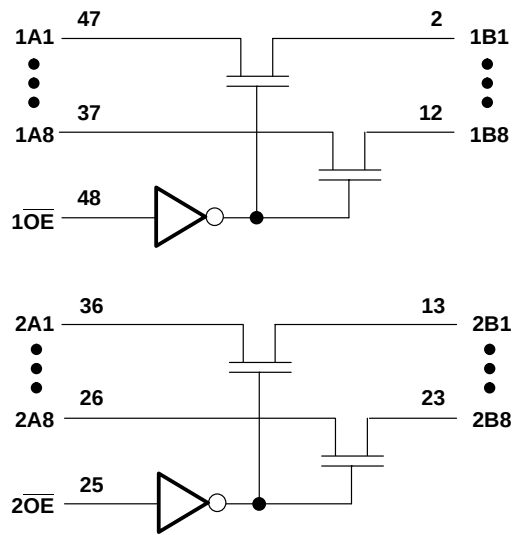
INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

PRODUCT PREVIEW

SN74CBT16245
16-BIT FET BUS SWITCH

SCDS070 – JULY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA					−1.2	V
I _I		V _{CC} = 0, V _I = 5.5 V					10	μA
		V _{CC} = 5.5 V, V _I = 5.5 V or GND					±1	
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND					3	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND					2.5	mA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)		V _O = 3 V or 0, $\overline{OE}$ = V _{CC}						pF
r _{on} [§]		V _{CC} = 4 V, V _I = 2.4 V, I _I = 15 mA						Ω
		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				
				I _I = 30 mA				
			V _I = 2.4 V, I _I = 15 mA					

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

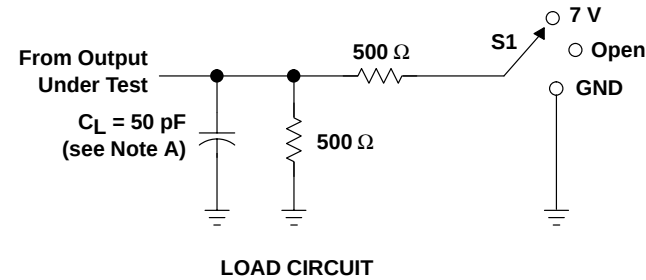
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

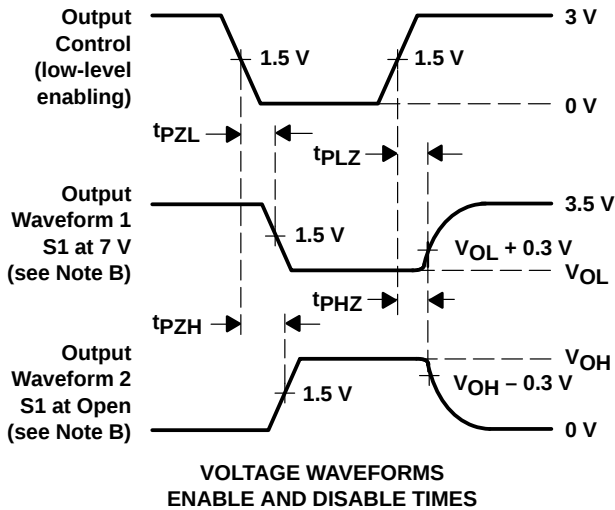
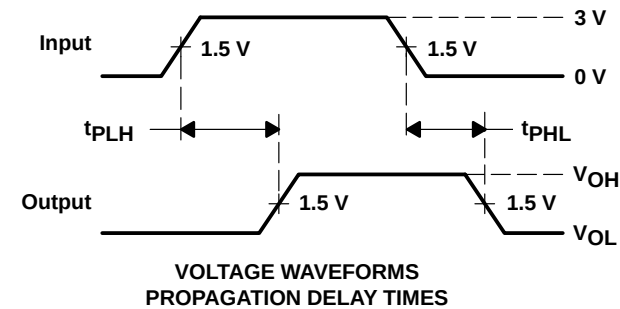
SN74CBT16245 16-BIT FET BUS SWITCH

SCDS070 – JULY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- Standard '16245-Type Pinout
- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages

description

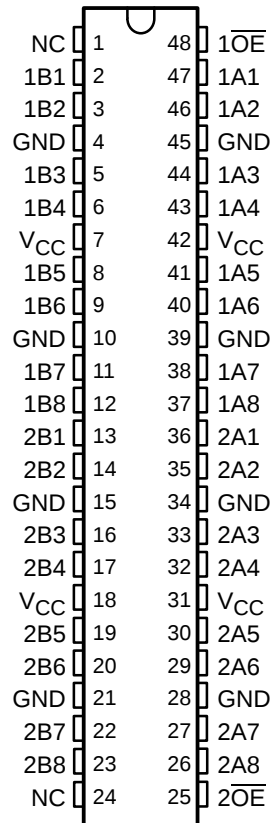
The SN74CBTR16245 provides 16 bits of high-speed TTL-compatible bus switching in a standard '16245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 8-bit low-impedance switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and data can flow from port A to port B, or vice versa. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR16245 is characterized for operation from -40°C to 85°C.

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE
(each 8-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

PRODUCT PREVIEW

SCDS077 – JULY 1998

Supply voltage range, V _{CC}	-0.5 V to 7 V
Input voltage range, V _I (see Note 1)	-0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I _{IK} (V _{I/O} < 0)	-50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T _{stg}	-65°C to 150°C

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51.

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	V
V _{IH}	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
T _A	Operating free-air temperature	−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA					−1.2	V
I _I		V _{CC} = 0	V _I = 5.5 V				10	μA
		V _{CC} = 5.5 V	V _I = 5.5 V or GND				±1	
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND					3	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)		V _O = 3 V or 0, $\overline{OE}$ = V _{CC}						pF
r _{on} [§]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				Ω
				I _I = 30 mA				
			V _I = 2.4 V, I _I = 15 mA					

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

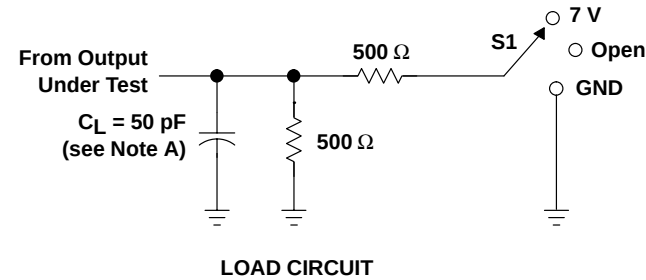
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

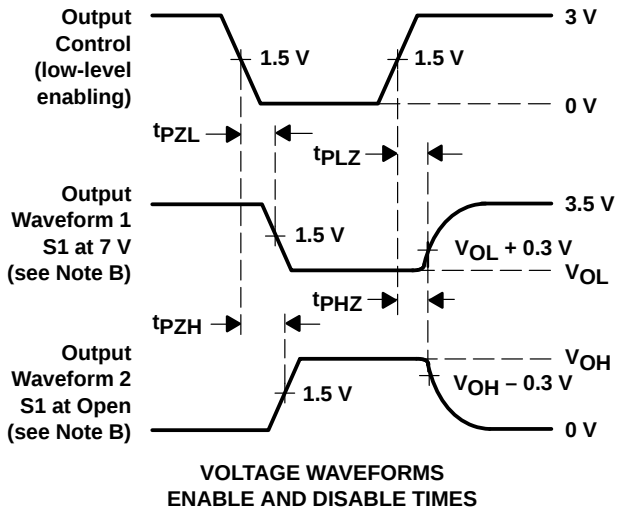
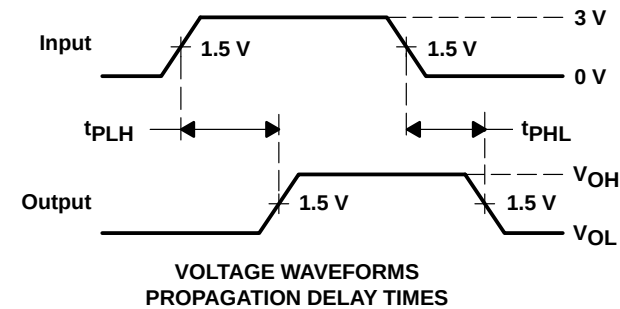
SN74CBTR16245 16-BIT FET BUS SWITCH

SCDS077 – JULY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT16292

12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS053B – MARCH 1998 – REVISED MAY 1998

- 4- Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Make-Before-Break Feature
- Internal 500- Ω Pulldown Resistors to Ground
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

The SN74CBT16292 is a 12-bit 1-of-2 high-speed TTL-compatible FET multiplexer/ demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

When the select (S) input is low, port A is connected to port B1 and R_{INT} is connected to port B2. When S is high, port A is connected to port B2 and R_{INT} is connected to port B1.

The SN74CBT16292 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE (TOP VIEW)

S	1	56	NC
1A	2	55	NC
NC	3	54	1B1
2A	4	53	1B2
NC	5	52	2B1
3A	6	51	2B2
NC	7	50	3B1
GND	8	49	GND
4A	9	48	3B2
NC	10	47	4B1
5A	11	46	4B2
NC	12	45	5B1
6A	13	44	5B2
NC	14	43	6B1
7A	15	42	6B2
NC	16	41	7B1
V _{CC}	17	40	7B2
8A	18	39	8B1
GND	19	38	GND
NC	20	37	8B2
9A	21	36	9B1
NC	22	35	9B2
10A	23	34	10B1
NC	24	33	10B2
11A	25	32	11B1
NC	26	31	11B2
12A	27	30	12B1
NC	28	29	12B2

NC – No internal connection

FUNCTION TABLE

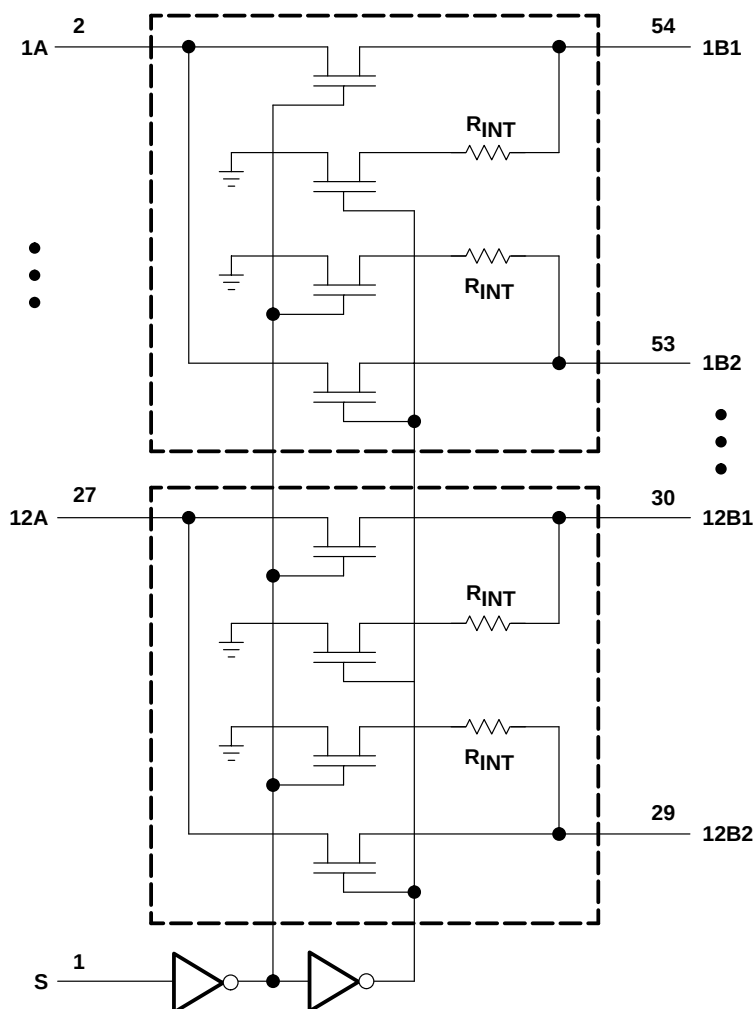
INPUT S	FUNCTION
L	A port = B1 port R_{INT} = B2 port
H	A port = B2 port R_{INT} = B1 port

SN74CBT16292

12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS053B – MARCH 1998 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.



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SN74CBT16292
12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER
WITH INTERNAL PULLDOWN RESISTORS

SCDS053B – MARCH 1998 – REVISED MAY 1998

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA			–1.2	V
I _I	V _{CC} = 5.5 V, V _I = V _{CC} or GND			±5	μA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			3	μA
ΔI _{CC} [‡]	Control input V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA
C _i	Control input V _I = 3 V or 0		3		pF
C _{io}	V _{CC} = 0, V _O = 3 V or 0		8		pF
r _{on} [§]	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA	10	20	Ω
	V _{CC} = 4.5 V	V _I = 0, I _I = 64 mA	3	7	
		I _I = 30 mA	3	7	
		V _I = 2.4 V, I _I = 15 mA	5	15	

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A	0.5		0.25		ns
t _{en}	S	A or B	6.8		1	6	ns
t _{dis}	S	A or B	7		1	6.3	ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	DESCRIPTION	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
		MIN	MAX	MIN	MAX	
t _{mbb} [#]	Make-before-break time	0	2	0	2	ns

[#] The make-before-break time is the time interval between make and break, during the transition from one selected port to the other.



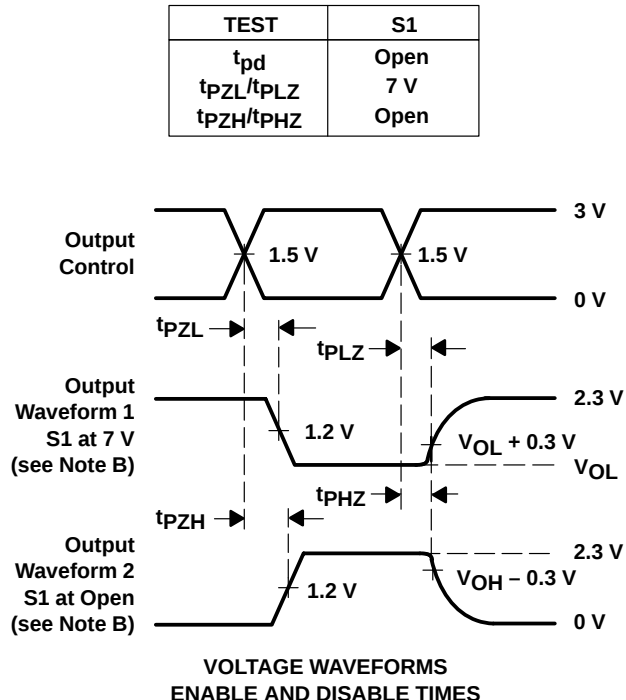
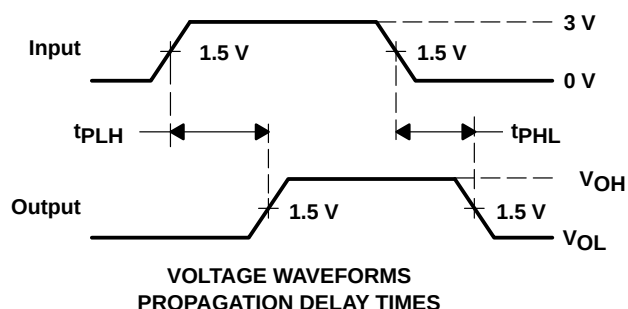
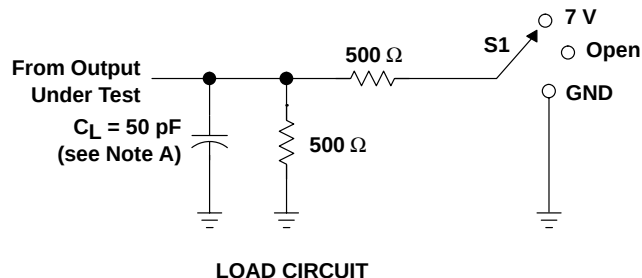
SN74CBT16292

12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

WITH INTERNAL PULLDOWN RESISTORS

SCDS053B – MARCH 1998 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when connected to the internal 500- Ω pulldown resistor. Waveform 2 is for an output with internal conditions such that the output is high except when connected to the internal 500- Ω pulldown resistor.
 - All pulse inputs and DC inputs are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{pLZ} and t_{pHZ} are the same as t_{dis} . $Z = R_{INT} = 500 \Omega$
 - t_{pZL} and t_{pZH} are the same as t_{en} . $Z = R_{INT} = 500 \Omega$
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT162292

12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS052C – MARCH 1998 – REVISED MAY 1998

- TTL-Compatible Control Input Levels
- Isolation Under Power-Off Conditions
- Make-Before-Break Feature
- Internal 500- Ω Pulldown Resistors to Ground
- A-Port Inputs/Outputs Have Equivalent 25- Ω Series Resistors, So No External Resistors Are Required
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

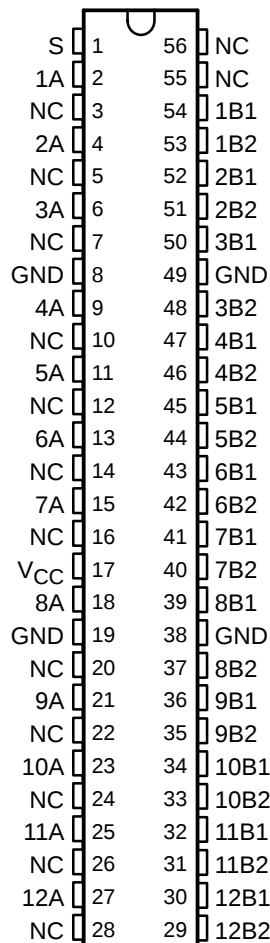
The SN74CBT162292 is a 12-bit 1-of-2 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

When the select (S) input is low, port A is connected to port B1 and R_{INT} is connected to port B2. When S is high, port A is connected to port B2 and R_{INT} is connected to port B1.

The A-port inputs/outputs include equivalent 25- Ω series resistors to reduce overshoot and undershoot.

The SN74CBT162292 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

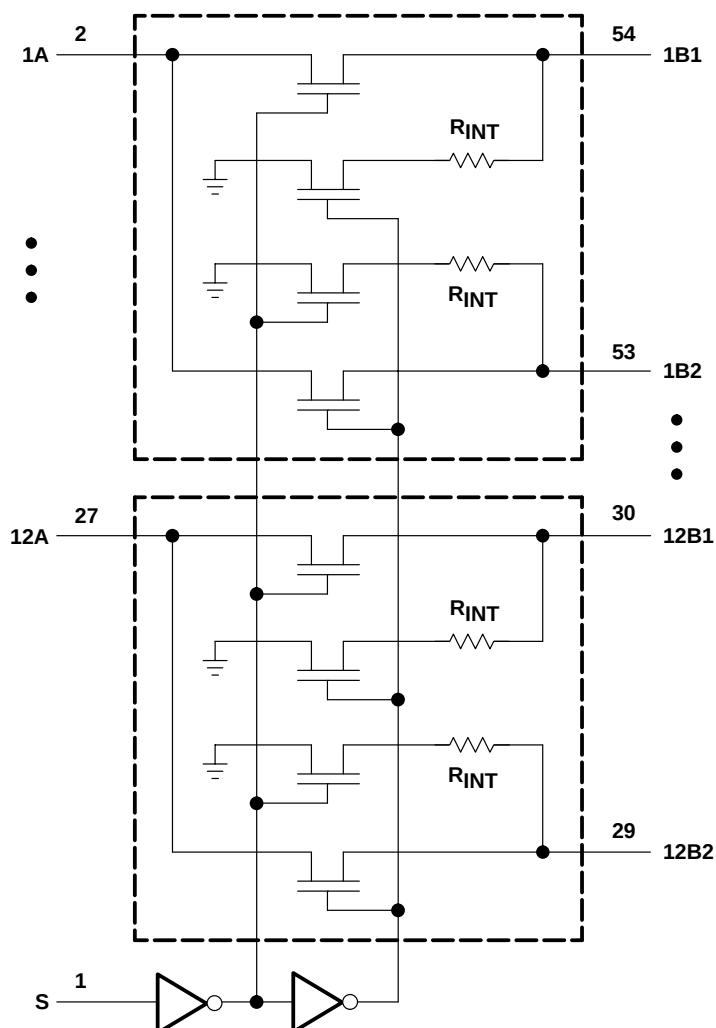
INPUT S	FUNCTION
L	A port = B1 port R_{INT} = B2 port
H	A port = B2 port R_{INT} = B1 port

SN74CBT162292

12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS052C – MARCH 1998 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.



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SN74CBT162292
12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER
WITH INTERNAL PULLDOWN RESISTORS

SCDS052C – MARCH 1998 – REVISED MAY 1998

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V _{CC} Supply voltage	4	5.5	V
V _{IH} High-level control input voltage	2		V
V _{IL} Low-level control input voltage		0.8	V
T _A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA			–1.2	V
I _I	V _{CC} = 5.5 V, V _I = V _{CC} or GND			±5	μA
I _{off}	V _{CC} = 0, V _I or V _O = 0 to 7 V			10	μA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			3	μA
ΔI _{CC} [‡]	Control input V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA
C _i	Control input V _I = 3 V or 0		3.5		pF
C _{io}	V _{CC} = 0, V _O = 3 V or 0		8		pF
r _{on} [§]	V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA	38	55	Ω
	V _{CC} = 4.5 V	V _I = 0, I _I = 45 mA	39	63	
		I _I = 30 mA	37	55	
		V _I = 2.4 V, I _I = 15 mA	37	55	

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF, (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A		1.9		1.85	ns
t _{en}	S	A or B	1	10.7	1	9.5	ns
t _{dis}	S	A or B	1	10.9	1	9.7	ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF, (unless otherwise noted) (see Figure 1)

PARAMETER	DESCRIPTION	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
		MIN	MAX	MIN	MAX	
t _{mbb} [#]	Make-before-break time	0	2	0	2	ns

[#] The make-before-break time is the time interval between make and break, during the transition from one selected port to the other.

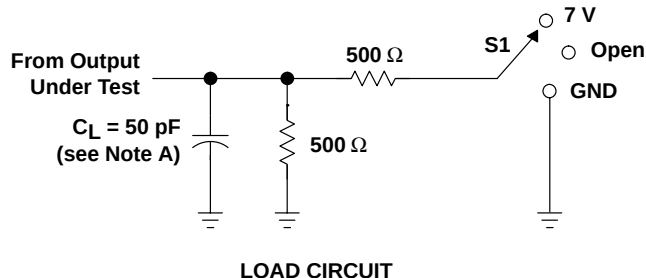


SN74CBT162292

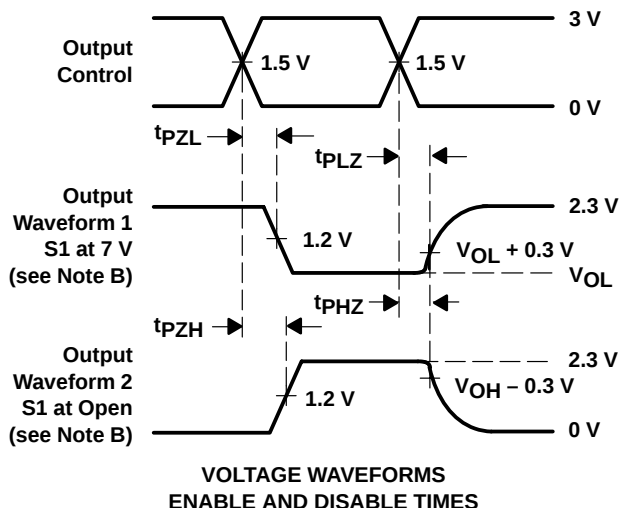
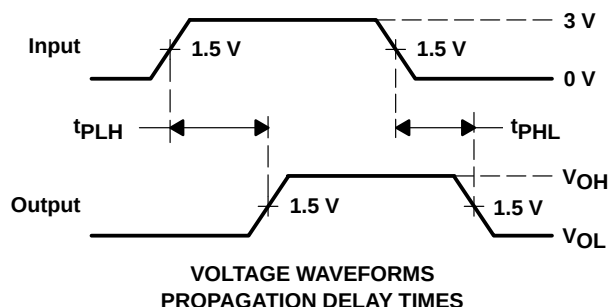
12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS052C – MARCH 1998 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{pZL}/t_{pLZ}	7 V
t_{pZH}/t_{pHZ}	Open



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when connected to the internal 500- Ω pulldown resistor. Waveform 2 is for an output with internal conditions such that the output is high except when connected to the internal 500- Ω pulldown resistor.
 - All pulse inputs and DC inputs are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} . $Z = R_{INT} = 500 \Omega$.
 - t_{PZL} and t_{PZH} are the same as t_{en} . $Z = R_{INT} = 500 \Omega$.
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBT16390

16-BIT TO 32-BIT FET MULTIPLEXER/DEMULTIPLEXER BUS SWITCH

SCDS035C – OCTOBER 1997 – REVISED OCTOBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

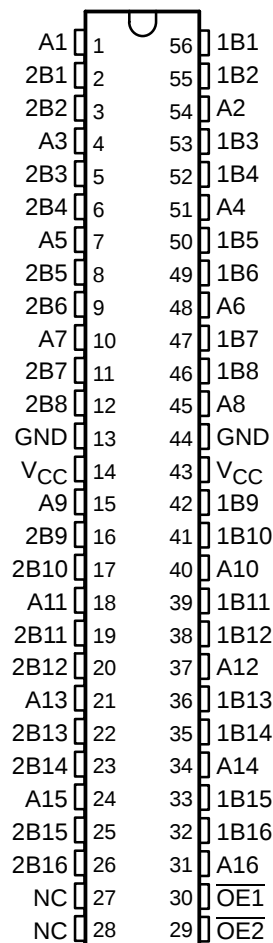
description

The SN74CBT16390 is a 16-bit to 32-bit switch used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single path. This device can be used for memory interleaving, in which two different banks of memory must be addressed simultaneously. This also can be used to connect or isolate the PCI bus to one or two slots simultaneously.

Two output enables ($\overline{OE1}$ and $\overline{OE2}$) control the data flow. When $\overline{OE1}$ is low, A port is connected to 1B port. When $\overline{OE2}$ is low, A port is connected to 2B port. When both $\overline{OE1}$ and $\overline{OE2}$ are low, the A port is connected to both 1B and 2B ports. The control inputs can be driven with a 5-V CMOS, 5-V TTL, or an LVTTTL driver.

The SN74CBT16390 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

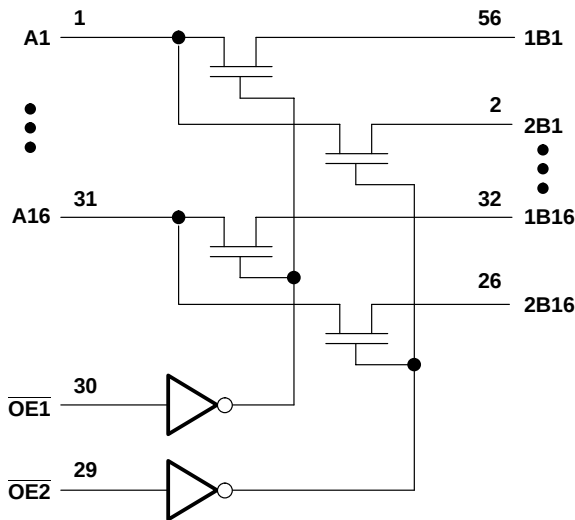
FUNCTION TABLE

INPUTS		FUNCTION
OE1	OE2	
L	L	A = 1B and A = 2B
L	H	A = 1B
H	L	A = 2B
H	H	Isolation

SN74CBT16390
16-BIT TO 32-BIT FET MULTIPLEXER/DEMULTIPLEXER BUS SWITCH

SCDS035C – OCTOBER 1997 – REVISED OCTOBER 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74CBT16390

16-BIT TO 32-BIT FET MULTIPLEXER/DEMULTIPLEXER BUS SWITCH

SCDS035C – OCTOBER 1997 – REVISED OCTOBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT	
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA					−1.2	V	
I _I		V _{CC} = 0, V _I = 5.5 V					10	μA	
		V _{CC} = 5.5 V, V _I = 5.5 V or GND					±1		
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND					3	μA	
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other input at V _{CC} or GND					2.5	mA	
C _i	Control inputs	V _I = 3 V or 0					5	pF	
C _{io} (OFF)		V _O = 3 V or 0					5.5	pF	
r _{on} [§]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA			5	7	Ω
				I _I = 30 mA			5	7	
			V _I = 2.4 V, I _I = 15 mA					7	

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A		0.25	ns
t_{en}	$\overline{OE}$	A or B	1.3	5.9	ns
t_{dis}	$\overline{OE}$	A or B	1	5.3	ns

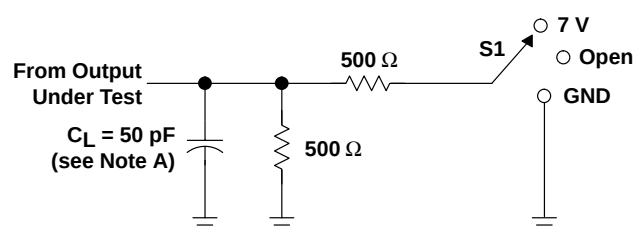
^{||} The propagation delay is based on the RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).

SN74CBT16390

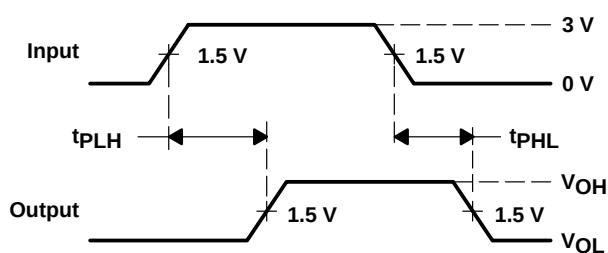
16-BIT TO 32-BIT FET MULTIPLEXER/DEMULTIPLEXER BUS SWITCH

SCDS035C – OCTOBER 1997 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION

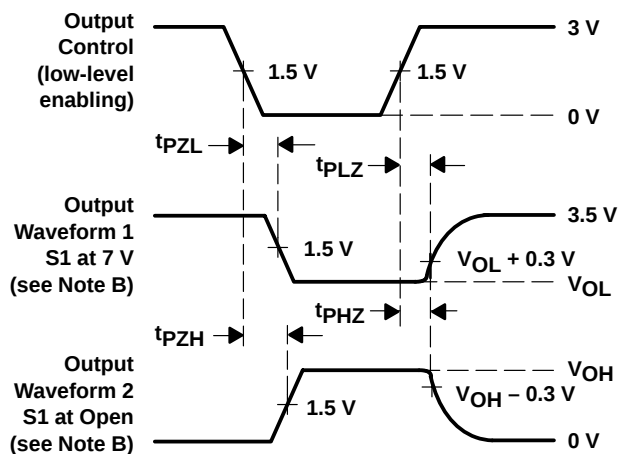


LOAD CIRCUIT



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Shrink Small-Outline (DL) Packages

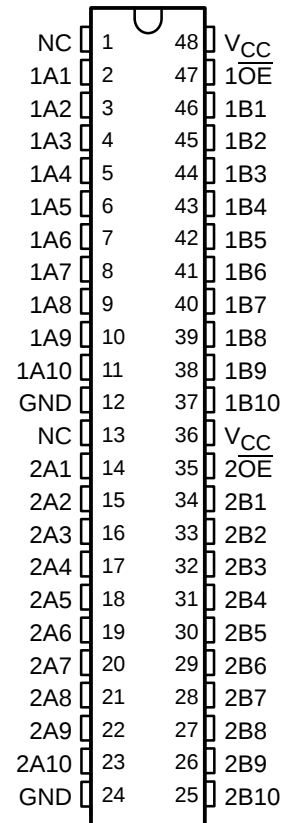
description

The SN74CBT16861 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one dual 10-bit switch with separate output-enable ($\overline{OE}$) input. When $\overline{OE}$ is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

The SN74CBT16861 is characterized for operation from -40°C to 85°C .

DGG OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

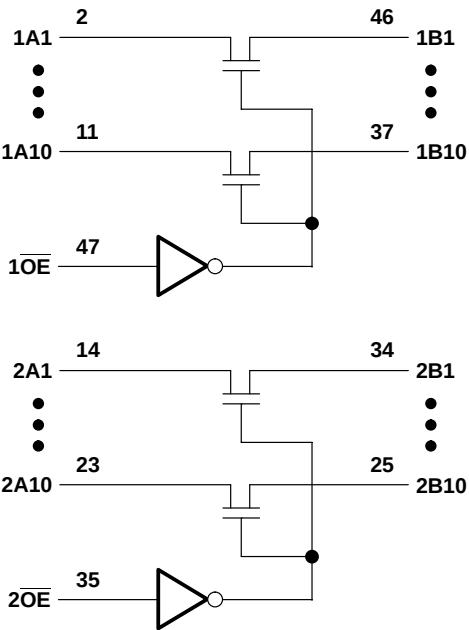
FUNCTION TABLE
(each 10-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

SN74CBT16861 20-BIT FET BUS SWITCH

SCDS068 – JULY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
I_I		$V_{CC} = 0$	$V_I = 5.5\text{ V}$			10	μA
		$V_{CC} = 5.5\text{ V}$	$V_I = 5.5\text{ V or GND}$			± 1	
I_{CC}		$V_{CC} = 5.5\text{ V}$,	$I_O = 0$, $V_I = V_{CC}\text{ or GND}$			3	μA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$,	One input at 3.4 V, Other inputs at $V_{CC}\text{ or GND}$			2.5	mA
C_i	Control inputs	$V_I = 3\text{ V or 0}$					pF
$C_{io(OFF)}$		$V_O = 3\text{ V or 0}$, $\overline{OE} = V_{CC}$					pF
$r_{on}^\S$		$V_{CC} = 4\text{ V}$, TYP at $V_{CC} = 4\text{ V}$	$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$				Ω
		$V_{CC} = 4.5\text{ V}$	$V_I = 0$, $I_I = 64\text{ mA}$				
			$I_I = 30\text{ mA}$				
			$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$				

[†] All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBT16861
20-BIT FET BUS SWITCH

SCDS068 – JULY 1998

PARAMETER MEASUREMENT INFORMATION

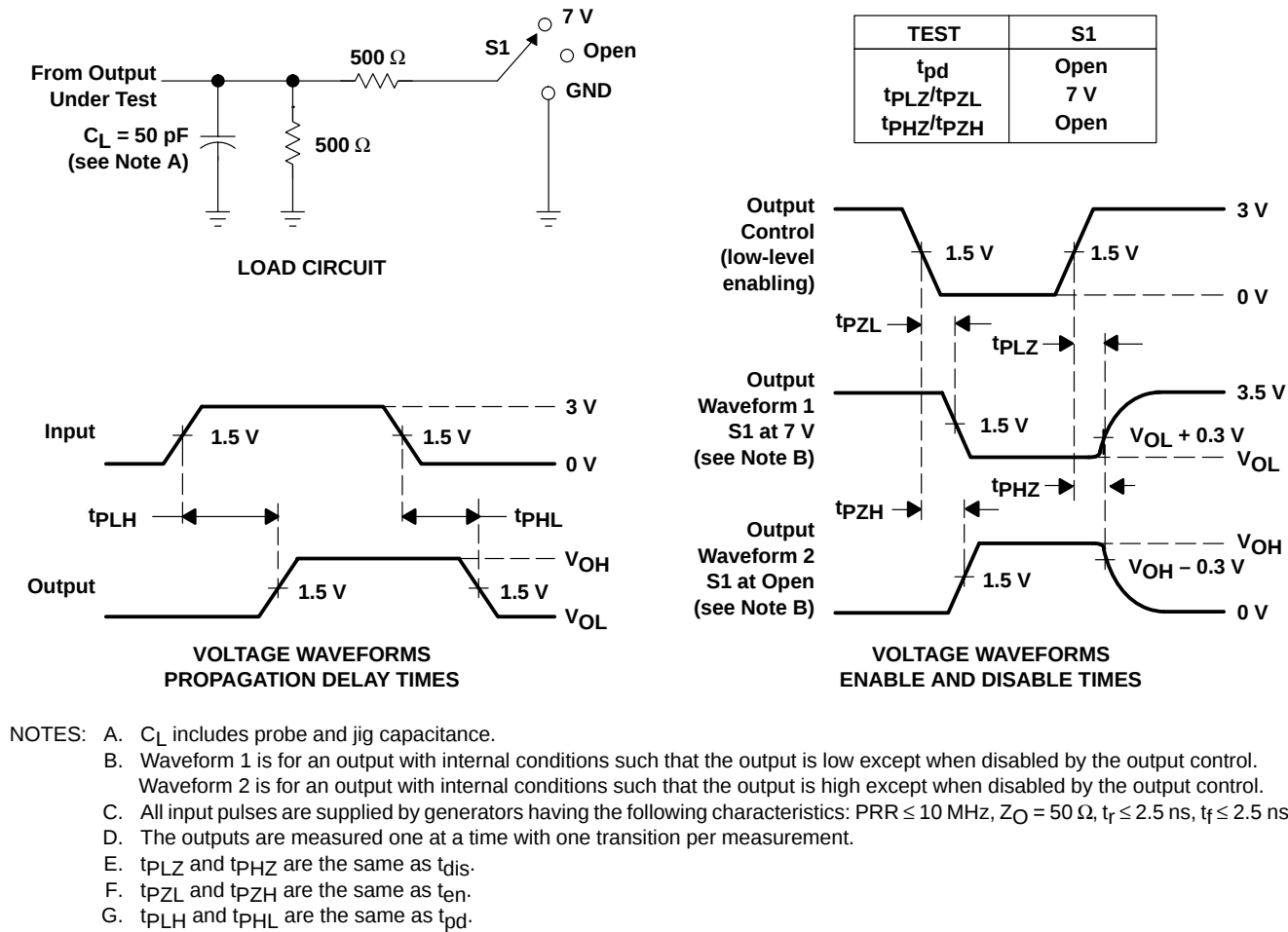


Figure 1. Load Circuit and Voltage Waveforms

- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Shrink Small-Outline (DL) Packages

description

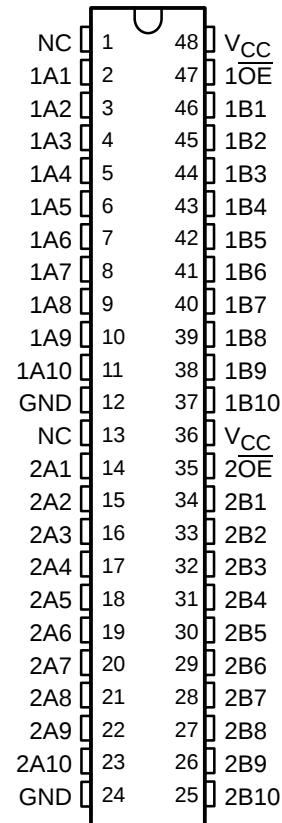
The SN74CBTR16861 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one dual 10-bit switch with separate output-enable ($\overline{OE}$) input. When $\overline{OE}$ is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

The device has equivalent 25-Ω series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR16861 is characterized for operation from -40°C to 85°C.

DGG OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

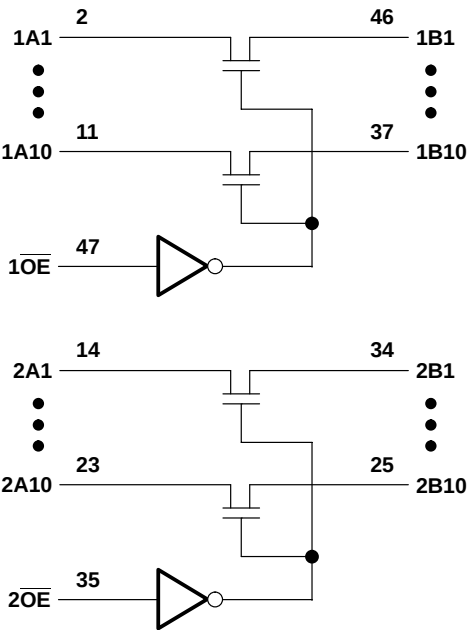
FUNCTION TABLE
(each 10-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

SN74CBTR16861 20-BIT FET BUS SWITCH

SCDS078 – JULY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = −18 mA				−1.2	V
I _I		V _{CC} = 0,	V _I = 5.5 V				10	μA
		V _{CC} = 5.5 V,	V _I = 5.5 V or GND				±1	
I _{CC}		V _{CC} = 5.5 V,	I _O = 0, V _I = V _{CC} or GND				3	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V, Other inputs at V _{CC} or GND				2.5	mA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)		V _O = 3 V or 0,	OE = V _{CC}					pF
r _{on} [§]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				Ω
				I _I = 30 mA				
			V _I = 2.4 V, I _I = 15 mA					

[†] All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

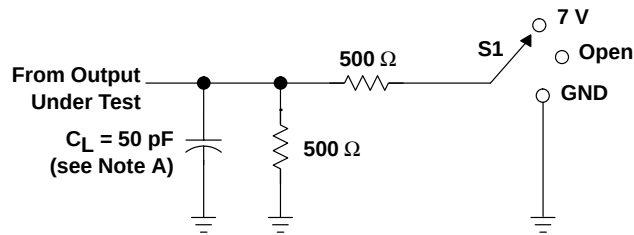
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBTR16861 20-BIT FET BUS SWITCH

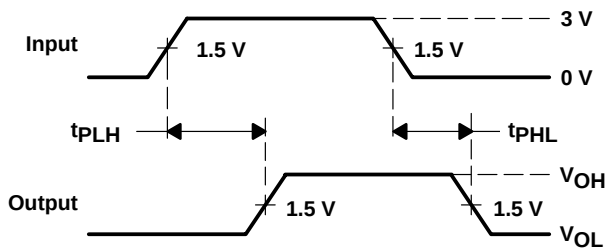
SCDS078 – JULY 1998

PARAMETER MEASUREMENT INFORMATION

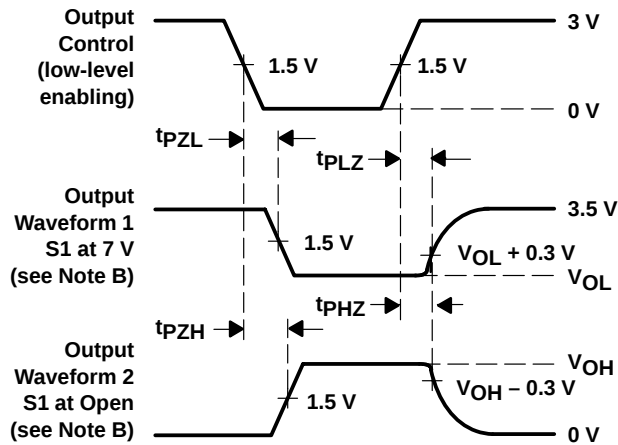


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

General Information	1
CBT Single Gates	2
CBT (2 to 10 Bit)	3
CBT Widebus™	4
CBT With Integrated Diodes	5
CBTLV Single Gates	6
CBTLV (2 to 10 Bit)	7
CBTLV Widebus™	8
Application Reports	9
Mechanical Data	10

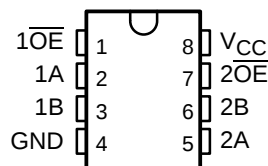
	Contents	Page
	SN74CBTD3306 Dual FET Bus Switch With Level Shifting	5-3
	SN74CBTS3306 Dual FET Bus Switch With Schottky Diode Clamping	5-7
SN54CBTD3384	SN74CBTD3384 10-Bit FET Bus Switches With Level Shifting	5-11
	SN74CBTS3384 10-Bit FET Bus Switch With Schottky Diode Clamping	5-17
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	SN74CBTD16210 20-Bit FET Bus Switch With Level Shifting	5-25
	SN74CBTD16211 24-Bit FET Bus Switch With Level Shifting	5-31
	SN74CBTS16211 24-Bit FET Bus Switch With Schottky Diode Clamping	5-37
	SN74CBTS16212 24-Bit FET Bus-Exchange Switch With Schottky Diode Clamping	5-41
	SN74CBTS16213 24-Bit FET Bus-Exchange Switch With Schottky Diode Clamping	5-45
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SN74CBTD3306 DUAL FET BUS SWITCH WITH LEVEL SHIFTING

SCDS030F – JANUARY 1996 – REVISED MAY 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Designed to Be Used in Level-Shifting Applications
- Package Options Include Plastic Small-Outline (D) and Thin Shrink Small-Outline (PW) Packages

D OR PW PACKAGE
(TOP VIEW)



description

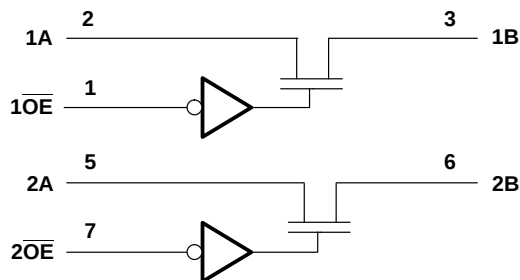
The SN74CBTD3306 features two independent line switches. Each switch is disabled when the associated output-enable ($\overline{OE}$) input is high. A diode to V_{CC} is integrated on the chip to allow for level shifting between 5-V inputs and 3.3-V outputs.

The SN74CBTD3306 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBTD3306

DUAL FET BUS SWITCH

WITH LEVEL SHIFTING

SCDS030F – JANUARY 1996 – REVISED MAY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	197°C/W
PW package	243°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
V_{OH}	See Figure 2				
I_I	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±1	μA
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			1.5	mA
ΔI_{CC} [§]	Control inputs $V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i	Control inputs $V_I = 3$ V or 0			3	pF
$C_{iO(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$			4	pF
r_{on} [¶]	$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA	5	7
			$I_I = 30$ mA	5	7
		$V_I = 2.4$ V,	$I_I = 15$ mA	35	50

[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

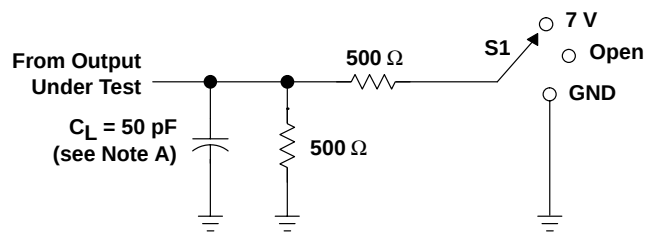


switching characteristics over recommended ranges of supply voltage and operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^\dagger$	A or B	B or A		0.25	ns
t_{en}	$\overline{OE}$	A or B	2.1	5.4	ns
t_{dis}	$\overline{OE}$	A or B	1	4.7	ns

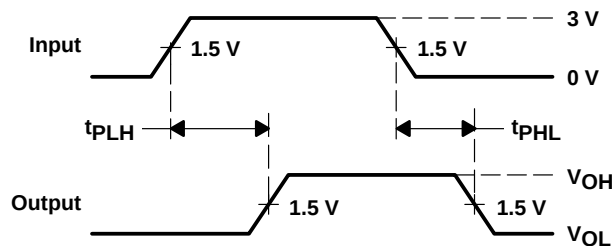
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

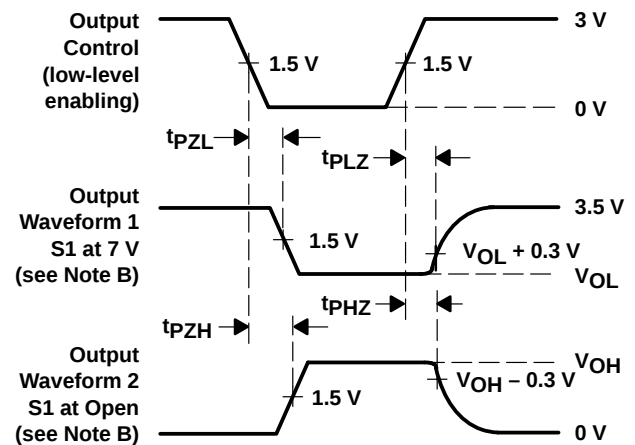


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PHL}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

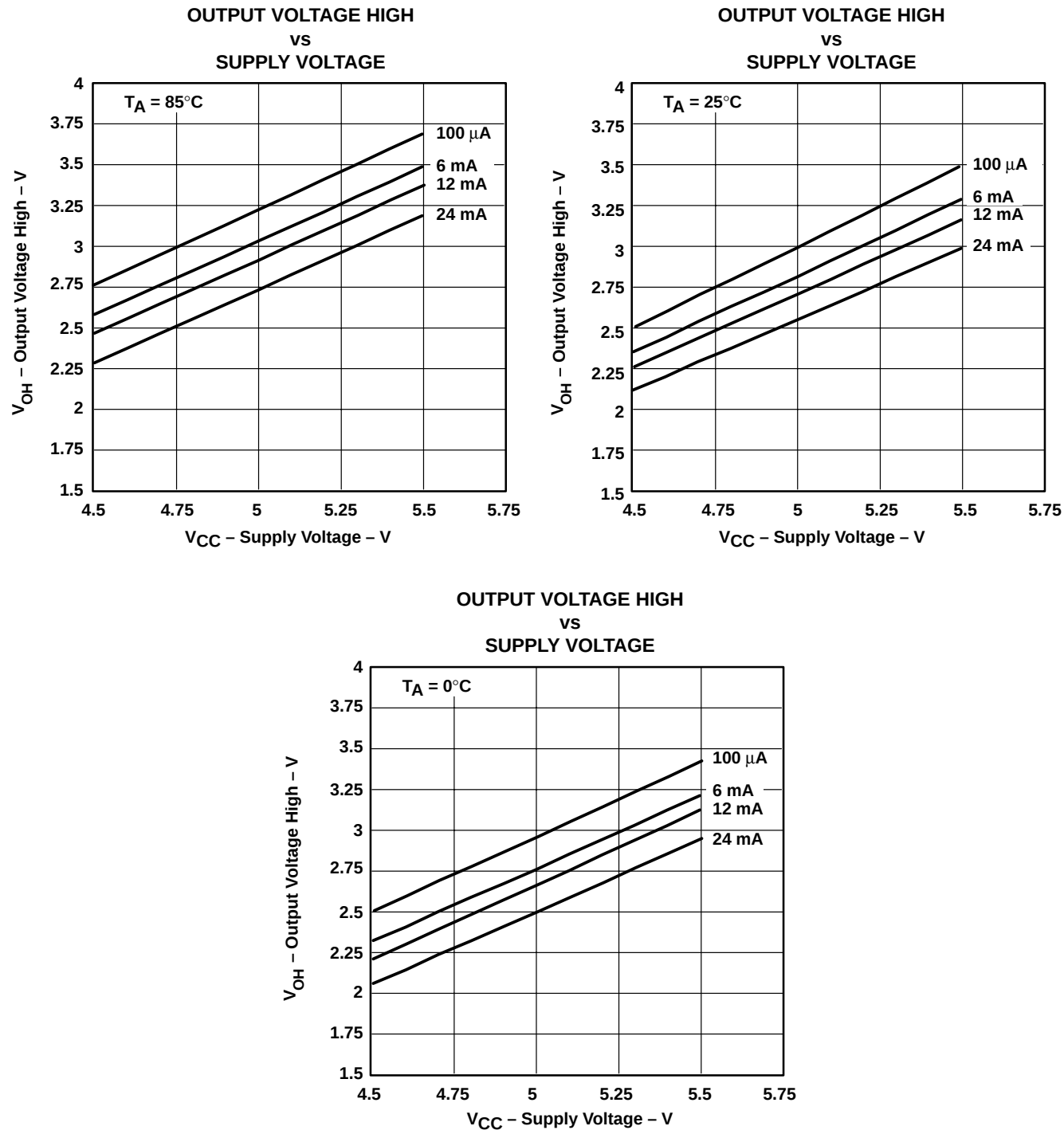


VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

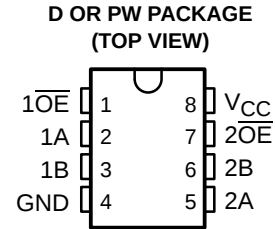
- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PHL} and t_{PLH} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS



- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (D) and Thin Shrink Small-Outline (PW) Packages



description

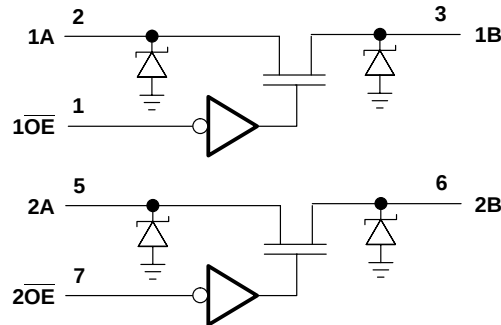
The SN74CBTS3306 features independent line switches with Schottky diodes on the I/Os to clamp undershoot. Each switch is disabled when the associated output-enable ($\overline{\text{OE}}$) input is high.

The SN74CBTS3306 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each bus switch)

INPUT $\overline{\text{OE}}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBTS3306

DUAL FET BUS SWITCH

WITH SCHOTTKY DIODE CLAMPING

SCDS029E – JANUARY 1996 – REVISED NOVEMBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	197°C/W
PW package	243°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	A or B inputs Control inputs	$V_{CC} = 4.5$ V, $I_I = -18$ mA		–0.7 –1.2	V
I_I	I_{IL} I_{IH}	$V_{CC} = 5.5$ V, $V_I = GND$ $V_{CC} = 5.5$ V, $V_I = 5.5$ V		–1 50	μ A
I_{CC}		$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND		3	μ A
ΔI_{CC} [§]	Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND		2.5	mA
C_i	Control inputs	$V_I = 3$ V or 0		5	pF
$C_{io(OFF)}$		$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$		6	pF
r_{on} [¶]	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V, $I_I = 15$ mA	14	20	Ω
	$V_{CC} = 4.5$ V	$V_I = 0$, $I_I = 64$ mA	5	7	
		$I_I = 30$ mA	5	7	
		$V_I = 2.4$ V, $I_I = 15$ mA	10	15	

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B pin at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) pins.

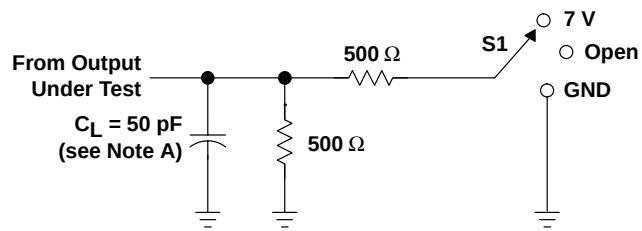


switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.35		0.25		ns
t_{en}	$\overline{OE}$	A or B	5.6		1.8	5	ns
t_{dis}	$\overline{OE}$	A or B	4.6		1	4.3	ns

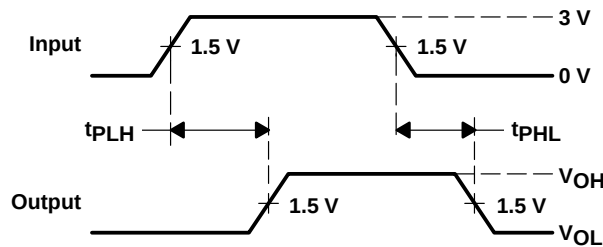
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

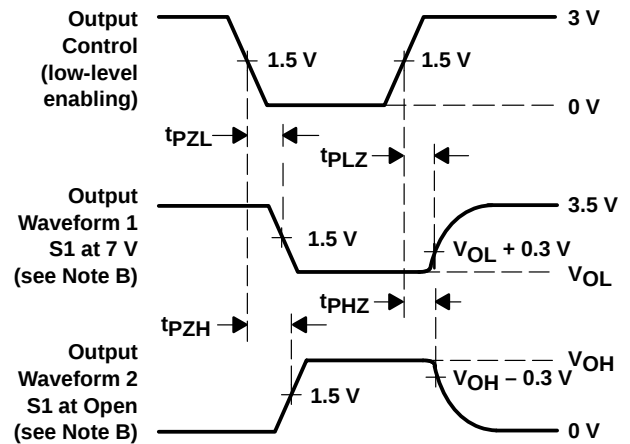


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PHL} and t_{PLH} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

SCDS025K – MAY 1995 – REVISED NOVEMBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Designed to Be Used in Level-Shifting Applications
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages, Ceramic Flat (W) Package, Ceramic DIPs (JT), and Ceramic Chip Carriers (FK)

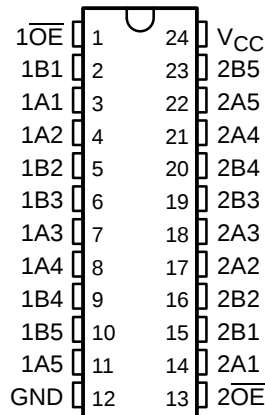
description

The 'CBTD3384 devices provide ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switches allows connections to be made without adding propagation delay. A diode to V_{CC} is integrated on the die to allow for level shifting between 5-V inputs and 3.3-V outputs.

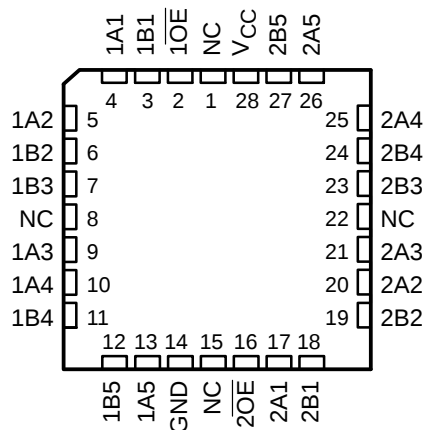
These devices are organized as two 5-bit switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The SN54CBTD3384 is characterized for operation over the full military temperature range from -55°C to 125°C . The SN74CBTD3384 is characterized for operation from -40°C to 85°C .

SN54CBTD3384 . . . JT OR W PACKAGE
SN74CBTD3384 . . . DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



SN54CBTD3384 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

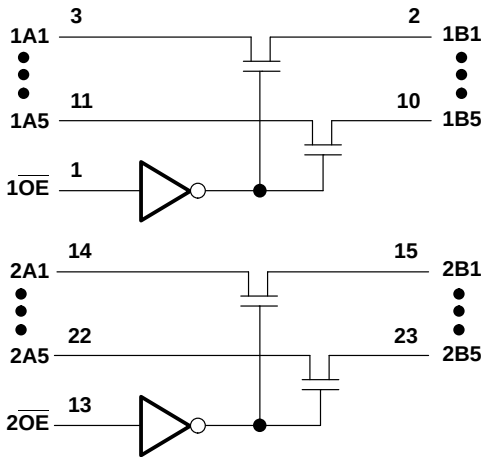
FUNCTION TABLE
(each 5-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
$\overline{1OE}$	$\overline{2OE}$	1B1–1B5	2B1–2B5
L	L	1A1–1A5	2A1–2A5
L	H	1A1–1A5	Z
H	L	Z	2A1–2A5
H	H	Z	Z

SN54CBTD3384, SN74CBTD3384
10-BIT FET BUS SWITCHES
WITH LEVEL SHIFTING

SCDS025K – MAY 1995 – REVISED NOVEMBER 1998

logic diagram (positive logic)



Pin numbers shown are for the DB, DBQ, DGV, DW, JT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
DBQ package	113°C/W
DGV package	139°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	SN54CBTD3384		SN74CBTD3384		UNIT
	MIN	MAX	MIN	MAX	
V_{CC} Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH} High-level control input voltage	2		2		V
V_{IL} Low-level control input voltage		0.8		0.8	V
T_A Operating free-air temperature	−55	125	−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54CBTD3384, SN74CBTD3384
10-BIT FET BUS SWITCHES
WITH LEVEL SHIFTING

SCDS025K – MAY 1995 – REVISED NOVEMBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	SN54CBTD3384			SN74CBTD3384			UNIT
			MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	
V_{IK}		$V_{CC} = 4.5 \text{ V}$, $I_I = -18 \text{ mA}$			-1.2			-1.2	V
V_{OH}		See Figure 2							
I_I		$V_{CC} = 5.5 \text{ V}$, $V_I = 5.5 \text{ V}$ or GND			± 1			± 1	μA
I_{CC}		$V_{CC} = 5.5 \text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND			1.5			1.5	mA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5 \text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5			2.5	mA
C_i	Control inputs	$V_I = 3 \text{ V}$ or 0			3			3	pF
$C_{io(OFF)}$		$V_O = 3 \text{ V}$ or 0, $\overline{OE} = V_{CC}$			3.5			3.5	pF
$r_{on}^\S$		$V_{CC} = 4.5 \text{ V}$, $V_I = 0$, $I_I = 64 \text{ mA}$			5			5 7	Ω
		$V_I = 0$, $I_I = 30 \text{ mA}$			5			5 7	
		$V_I = 2.4 \text{ V}$, $I_I = 15 \text{ mA}$			35			35 50	

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54CBTD3384		SN74CBTD3384		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A		0.25		0.25	ns
t_{en}	$\overline{OE}$	A or B	2.2	9.7	2.3	7	ns
t_{dis}	$\overline{OE}$	A or B	1.5	8.6	1.7	5.3	ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

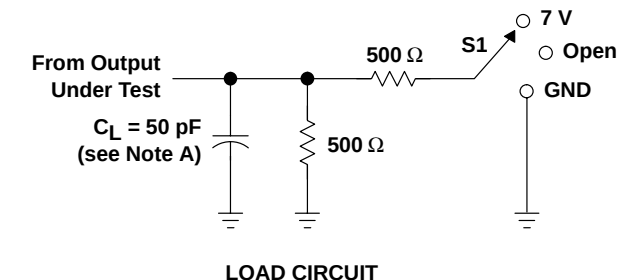
SN54CBTD3384, SN74CBTD3384

10-BIT FET BUS SWITCHES

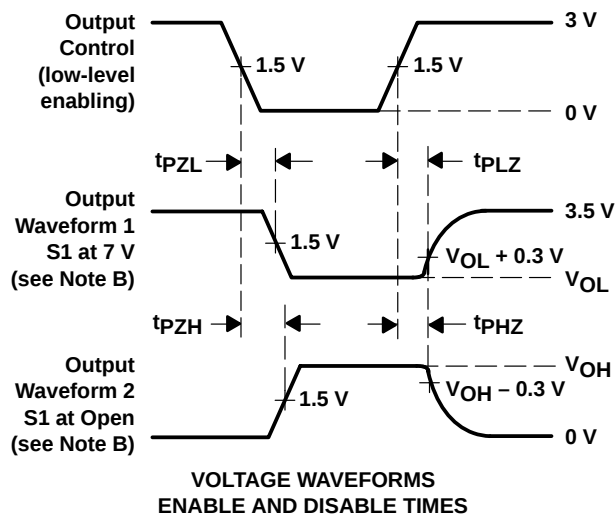
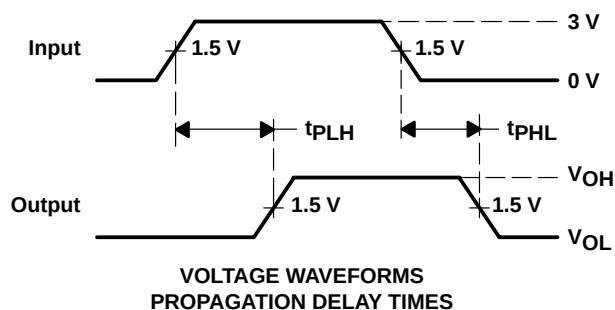
WITH LEVEL SHIFTING

SCDS025K – MAY 1995 – REVISED NOVEMBER 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

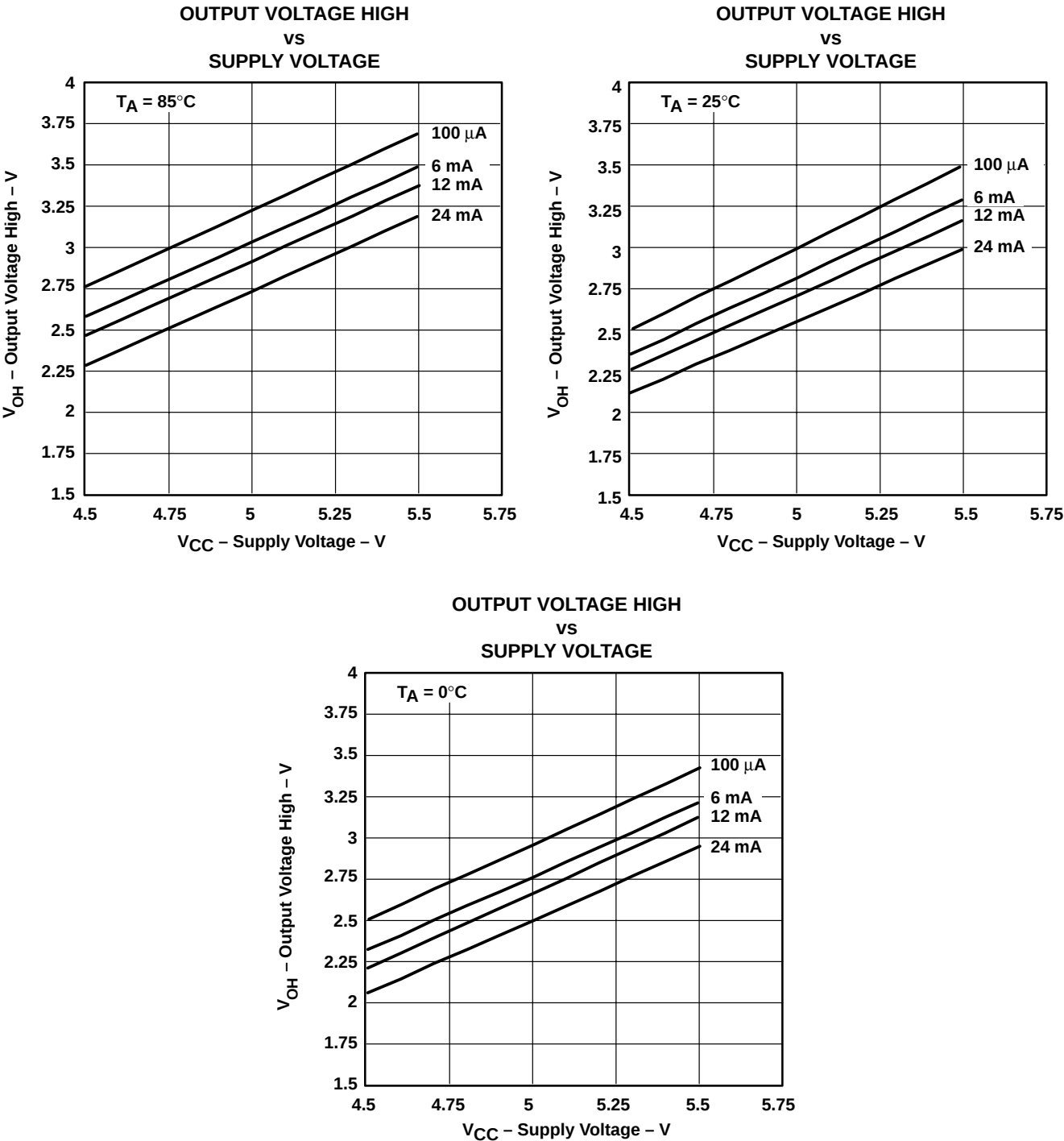
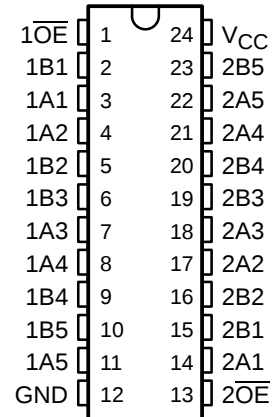


Figure 2. V_{OH} Values

SN74CBTS3384
10-BIT FET BUS SWITCH
WITH SCHOTTKY DIODE CLAMPING
SCDS024G – MAY 1995 – REVISED MAY 1998

- Functionally Equivalent to QS3384 and QS3L384
- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



description

The SN74CBTS3384 provides ten bits of high-speed TTL-compatible bus switching with Schottky diodes on the I/Os to clamp undershoot. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 5-bit bus switches with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

The SN74CBTS3384 is characterized for operation from -40°C to 85°C .

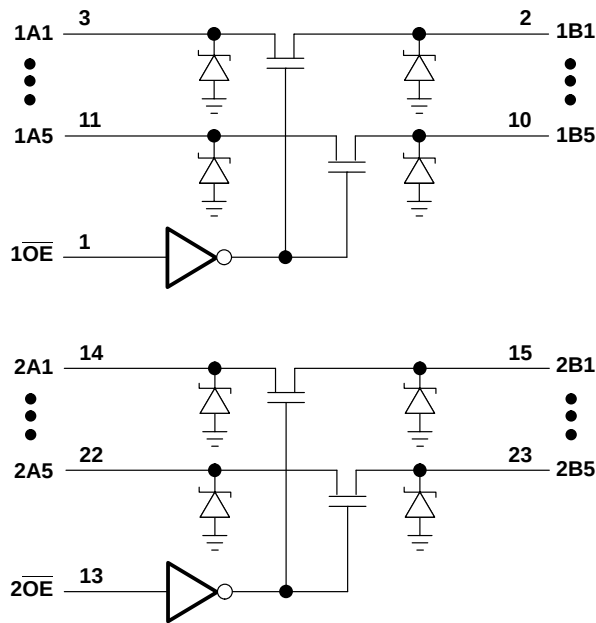
FUNCTION TABLE
(each 5-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
$\overline{1OE}$	$\overline{2OE}$	1B1–1B5	2B1–2B5
L	L	1A1–1A5	2A1–2A5
L	H	1A1–1A5	Z
H	L	Z	2A1–2A5
H	H	Z	Z

SN74CBTS3384
10-BIT FET BUS SWITCH
WITH SCHOTTKY DIODE CLAMPING

SCDS024G – MAY 1995 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.3 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	104°C/W
DBQ package	113°C/W
DGV package	139°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-0.6	V
I_I	I_{IL}	$V_{CC} = 5.5\text{ V}$,	$V_I = \text{GND}$			-1	μA
	I_{IH}	$V_{CC} = 5.5\text{ V}$,	$V_I = 5.5\text{ V}$			150	
I_{CC}		$V_{CC} = 5.5\text{ V}$,	$I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$,	One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0				6	pF
$C_{io}(\text{OFF})$		$V_O = 3\text{ V}$ or 0,	$\overline{OE} = V_{CC}$			6.5	pF
$r_{on}^\S$	$V_{CC} = 4\text{ V}$, TYP at $V_{CC} = 4\text{ V}$		$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$			14	Ω
	$V_{CC} = 4.5\text{ V}$		$V_I = 0$, $I_I = 64\text{ mA}$			5	
			$I_I = 30\text{ mA}$			5	
			$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$			10	

[†] All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A	0.35		0.25		ns
t_{en}	$\overline{OE}$	A or B	6.2		1.9	5.7	ns
t_{dis}	$\overline{OE}$	A or B	5.5		2.1	5.2	ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

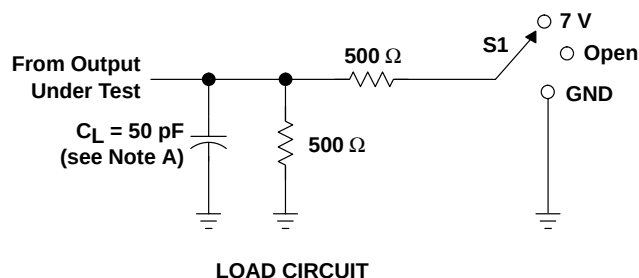
SN74CBTS3384

10-BIT FET BUS SWITCH

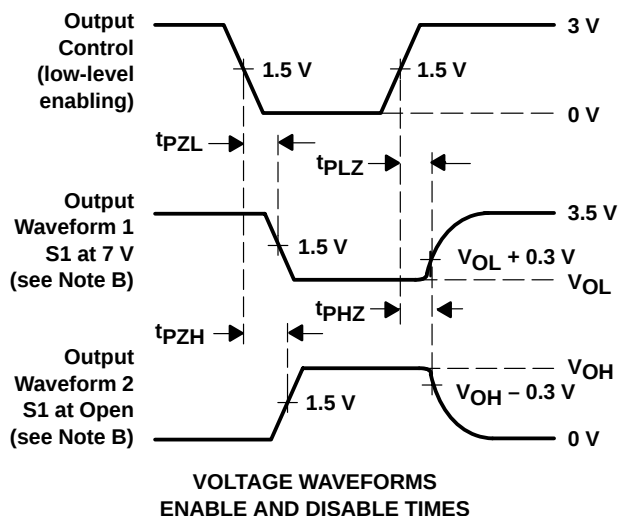
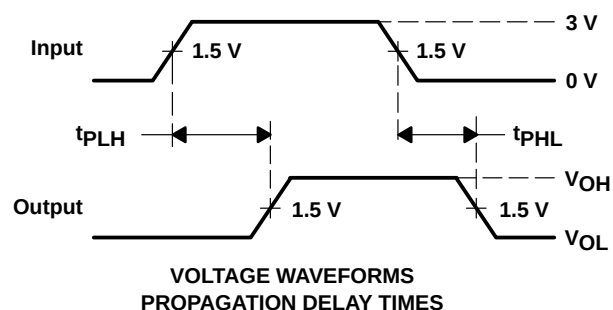
WITH SCHOTTKY DIODE CLAMPING

SCDS024G – MAY 1995 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTD3861 10-BIT FET BUS SWITCH WITH LEVEL SHIFTING

SCDS084A – JULY 1998 – REVISED OCTOBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Designed to Be Used in Level-Shifting Applications
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

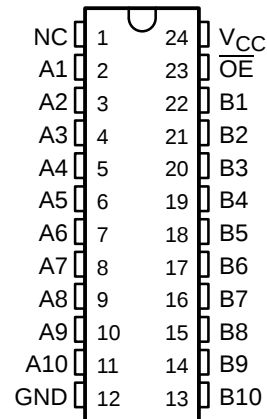
description

The SN74CBTD3861 provides ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. A diode to V_{CC} is integrated on the die to allow for level shifting between 5-V inputs and 3.3-V outputs.

The device is organized as one 10-bit switch with a single output-enable ($\overline{OE}$) input. When $\overline{OE}$ is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

The SN74CBTD3861 is characterized for operation from -40°C to 85°C .

DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)

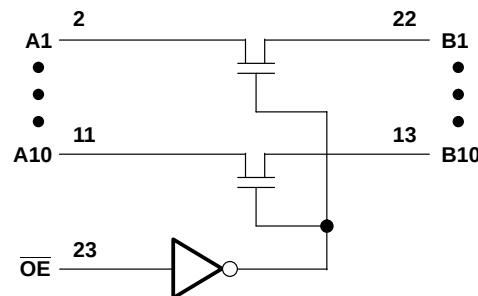


NC – No internal connection

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



SN74CBTD3861

10-BIT FET BUS SWITCH

WITH LEVEL SHIFTING

SCDS084A – JULY 1998 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBQ package	113°C/W
DGV package	139°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [‡]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA					−1.2	V
V _{OH}		See Figure 2						
I _I		V _{CC} = 5.5 V, V _I = 5.5 V or GND					±1	μA
I _{CC}		V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND					3	μA
ΔI _{CC} [§]	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND					2.5	mA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{IO} (OFF)		V _O = 3 V or 0, $\overline{OE}$ = V _{CC}						pF
r _{on} [¶]		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA				Ω
				I _I = 30 mA				
			V _I = 2.4 V, I _I = 15 mA					

[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

PRODUCT PREVIEW

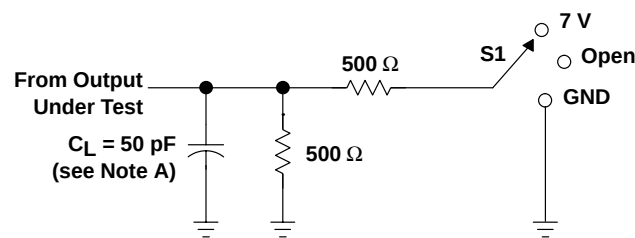


switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

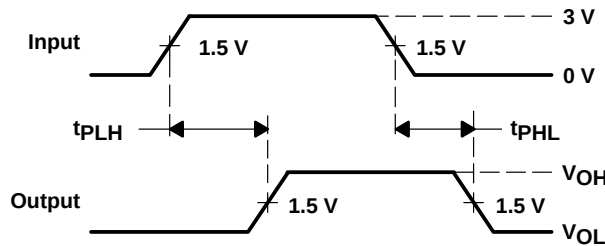
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\dagger}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

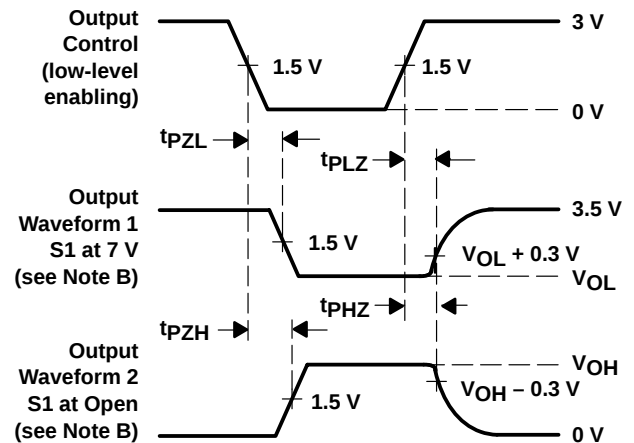


LOAD CIRCUIT



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

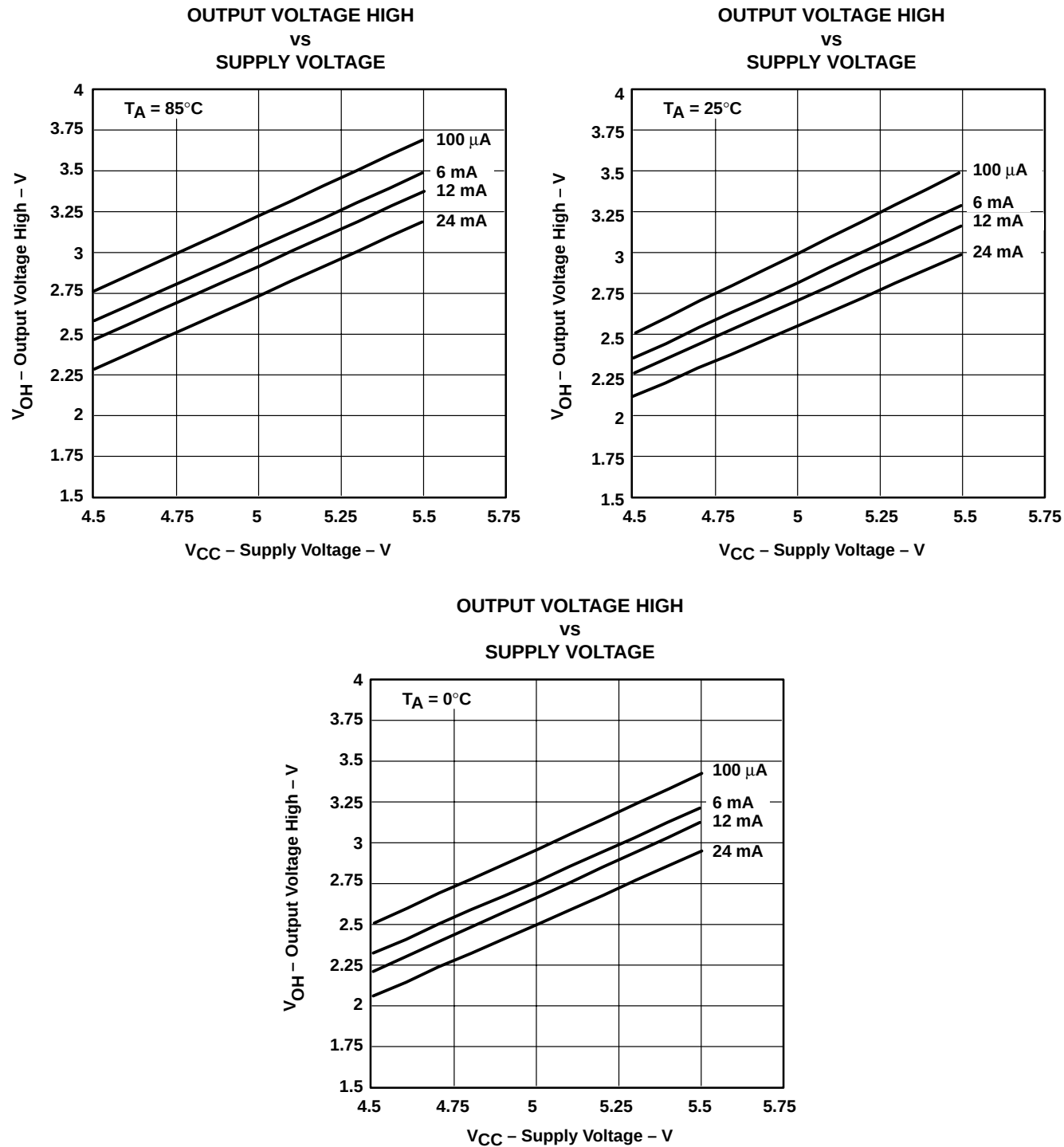


Figure 2. VOH Values

SN74CBTD16210 20-BIT FET BUS SWITCH WITH LEVEL SHIFTING

SCDS049C – MARCH 1998 – REVISED MAY 1998

- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Designed to Be Used in Level-Shifting Applications
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

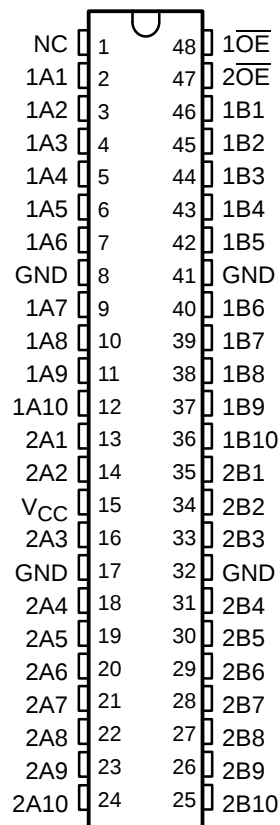
description

The SN74CBTD16210 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. A diode to V_{CC} is integrated in the circuit to allow for level shifting between 5-V inputs and 3.3-V outputs.

The device is organized as a dual 10-bit bus switch with separate output-enable ($\overline{OE}$) inputs. It can be used as two 10-bit bus switches or as one 20-bit bus switch. When $\overline{OE}$ is low, the associated 10-bit bus switch is on and A port is connected to B port. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the ports.

The SN74CBTD16210 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE (TOP VIEW)

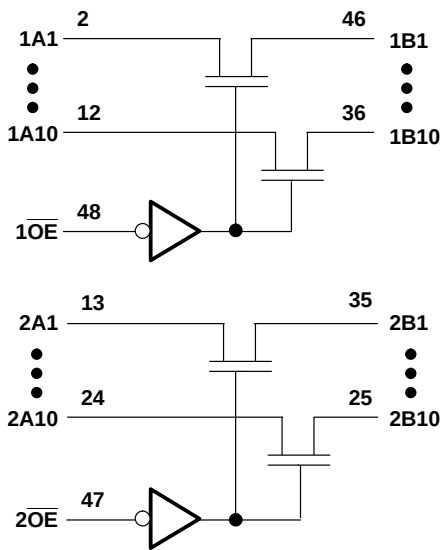


NC – No internal connection

FUNCTION TABLE
(each 10-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2	V
V_{OH}		See Figure 2				
I_I		$V_{CC} = 0\text{ V}$, $V_I = 5.5\text{ V}$			10	μA
		$V_{CC} = 5.5\text{ V}$, $V_I = 5.5\text{ V or GND}$			± 1	
I_{CC}		$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$			1.5	mA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at $V_{CC}\text{ or GND}$			2.5	mA
C_i	Control inputs	$V_I = 3\text{ V or 0}$			4.5	pF
$C_{io(OFF)}$		$V_O = 3\text{ V or 0}$, $\overline{OE} = V_{CC}$			5.5	pF
$r_{on}^\S$		$V_{CC} = 4.5\text{ V}$, $V_I = 0$, $I_I = 64\text{ mA}$		5	7	Ω
		$V_{CC} = 4.5\text{ V}$, $V_I = 0$, $I_I = 30\text{ mA}$		5	7	
		$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$		35	50	

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^\parallel$	A or B	B or A		0.25	ns
t_{en}	$\overline{OE}$	A or B	1.5	9.8	ns
t_{dis}	$\overline{OE}$	A or B	1.5	8.9	ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

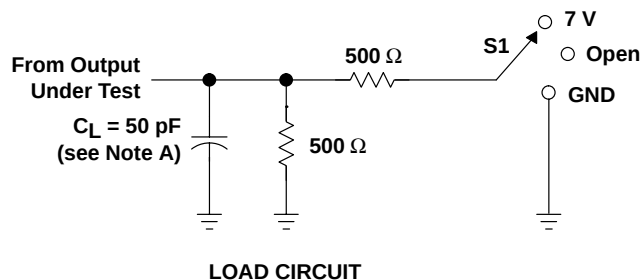
SN74CBTD16210

20-BIT FET BUS SWITCH

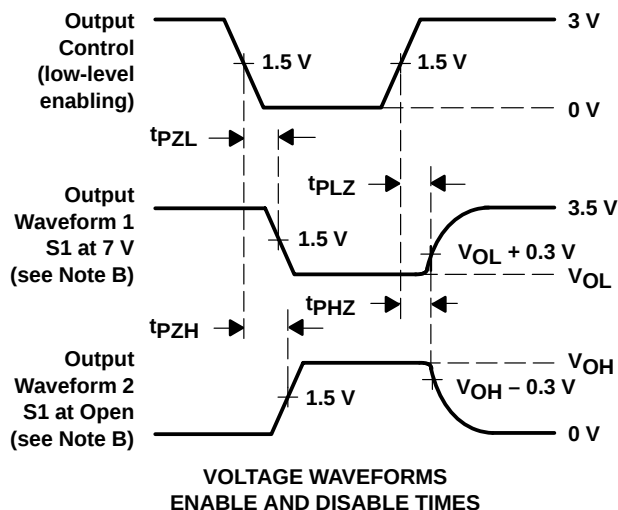
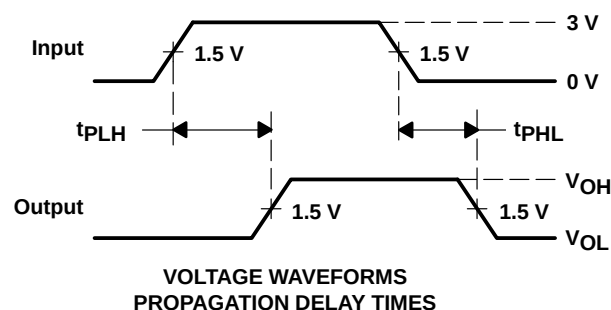
WITH LEVEL SHIFTING

SCDS049C – MARCH 1998 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

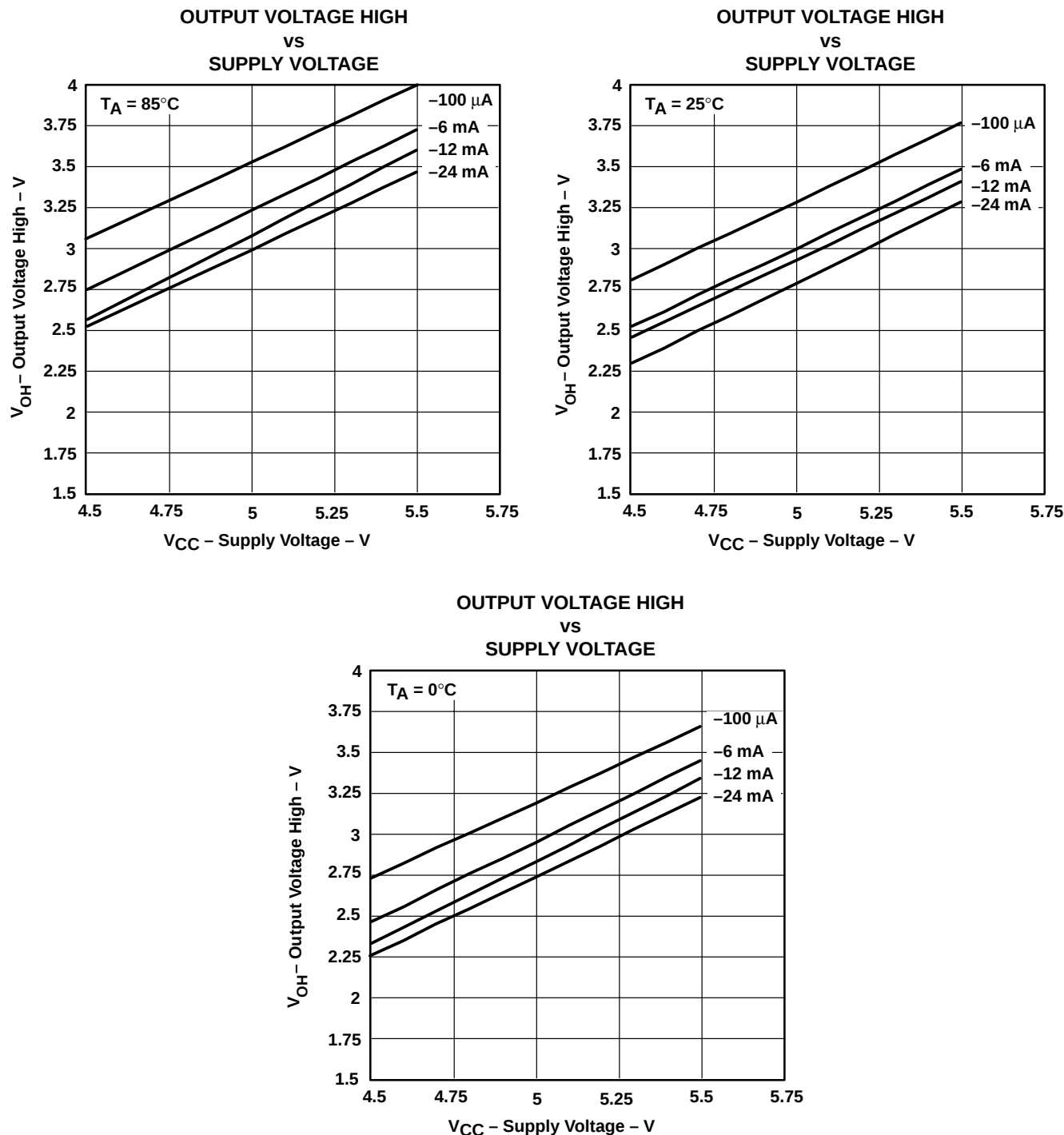


Figure 2. VOH Values

SN74CBTD16211

24-BIT FET BUS SWITCH

WITH LEVEL SHIFTING

SCDS048C – MARCH 1998 – REVISED MAY 1998

- 5- Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Designed to Be Used in Level-Shifting Applications
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

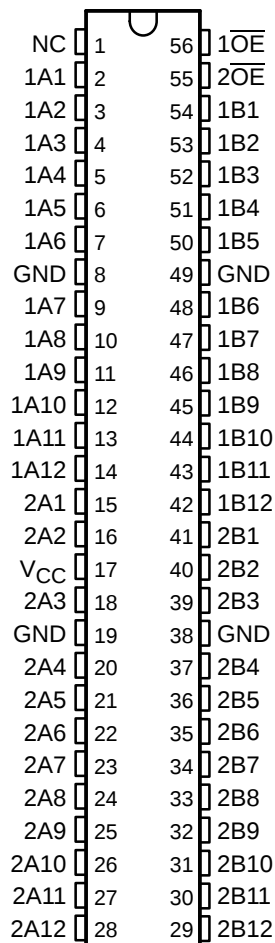
description

The SN74CBTD16211 provides 24 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. A diode to V_{CC} is integrated in the circuit to allow for level shifting between 5-V inputs and 3.3-V outputs.

The device is organized as a dual 12-bit bus switch with separate output-enable ($\overline{OE}$) inputs. It can be used as two 12-bit bus switches or as one 24-bit bus switch. When $\overline{OE}$ is low, the associated 12-bit bus switch is on and A port is connected to B port. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the ports.

The SN74CBTD16211 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE (TOP VIEW)

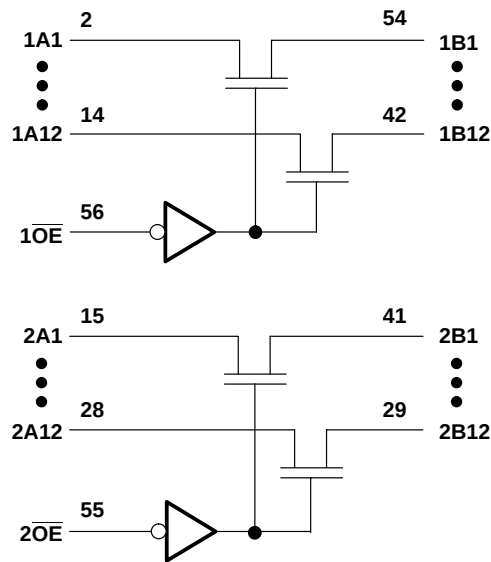


NC – No internal connection

FUNCTION TABLE
(each 12-bit bus switch)

INPUT OE	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}		−0.5 V to 7 V
Input voltage range, V_I (see Note 1)		−0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_I < 0$)		−50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DGG package	81°C/W
	DGV package	86°C/W
	DL package	74°C/W
Storage temperature range, T_{stg}		−65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2	V
V_{OH}		See Figure 2				
I_I		$V_{CC} = 5.5\text{ V}$, $V_I = 5.5\text{ V or GND}$			± 1	μA
I_{CC}		$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$			1.5	mA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at $V_{CC}\text{ or GND}$			2.5	mA
C_i	Control inputs	$V_I = 3\text{ V or 0}$			3	pF
$C_{io(OFF)}$		$V_O = 3\text{ V or 0}$, $\overline{OE} = V_{CC}$			5.5	pF
$r_{on}^\S$		$V_{CC} = 4.5\text{ V}$, $V_I = 0$, $I_I = 64\text{ mA}$			5	Ω
		$V_{CC} = 4.5\text{ V}$, $V_I = 0$, $I_I = 30\text{ mA}$			5	
		$V_{CC} = 4.5\text{ V}$, $V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$			35	

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{ }$	A or B	B or A		0.25	ns
t_{en}	$\overline{OE}$	A or B	1.5	9.8	ns
t_{dis}	$\overline{OE}$	A or B	1.5	8.9	ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

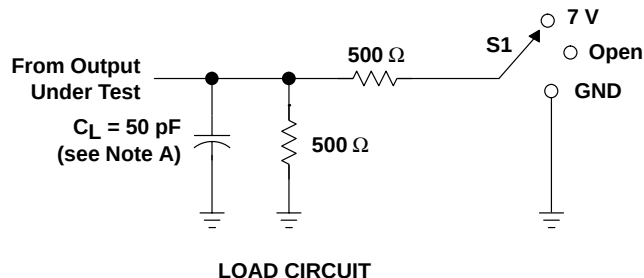
SN74CBTD16211

24-BIT FET BUS SWITCH

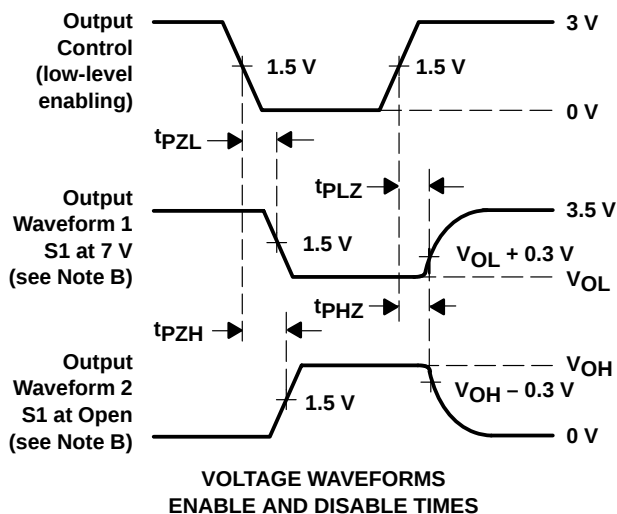
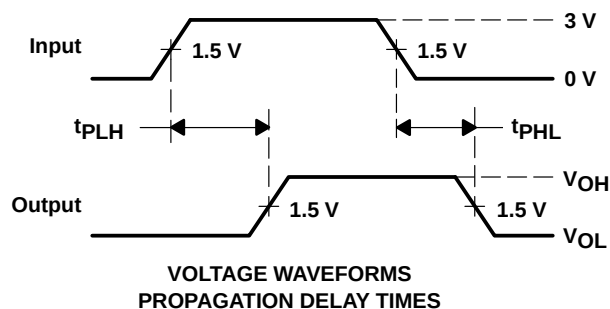
WITH LEVEL SHIFTING

SCDS048C – MARCH 1998 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

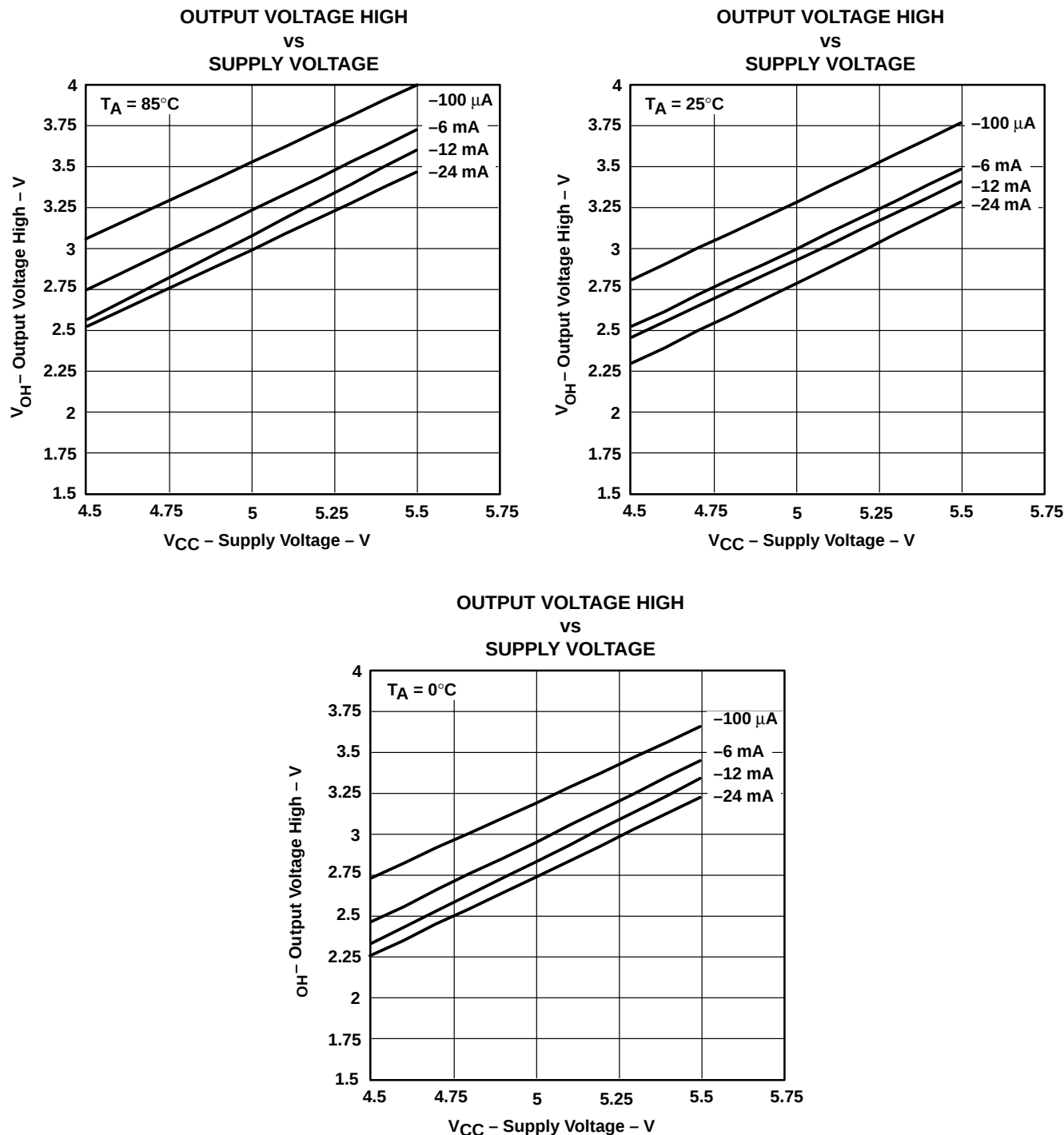


Figure 2. VOH Values

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input and Output Levels
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

The SN74CBTS16211 provides 24 bits of high-speed TTL-compatible bus switching with Schottky diodes on the I/Os to clamp undershoot. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

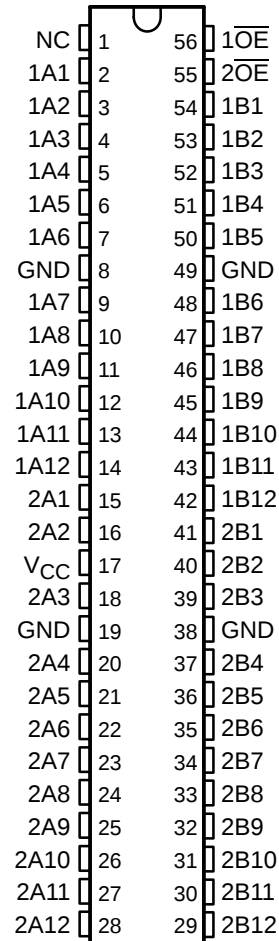
The device can operate as a dual 12-bit bus switch or a single 24-bit bus switch. When $\overline{1OE}$ is low, 1A is connected to 1B. When $\overline{2OE}$ is low, 2A is connected to 2B.

The SN74CBTS16211 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each 12-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

DGG, DGV, OR DL PACKAGE
(TOP VIEW)

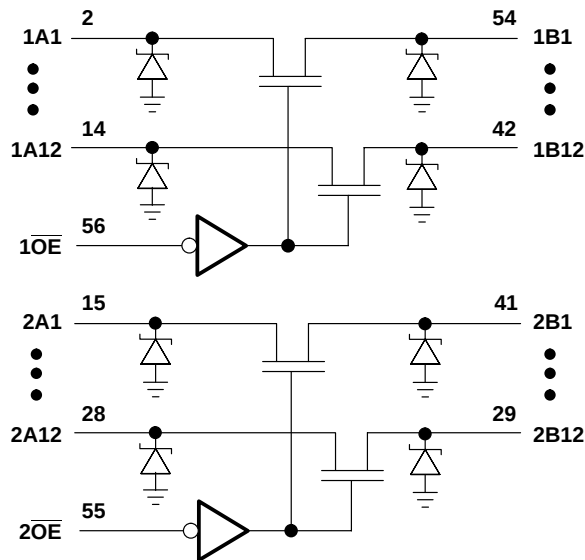


NC – No internal connection

SN74CBTS16211
24-BIT FET BUS SWITCH
WITH SCHOTTKY DIODE CLAMPING

SCDS050B – MARCH 1998 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
I_I	I_{IL}	$V_{CC} = 5.5\text{ V}$,	$V_I = \text{GND}$			-1	μA
	I_{IH}	$V_{CC} = 5.5\text{ V}$,	$V_I = 5.5\text{ V}$			150	
I_{CC}		$V_{CC} = 5.5\text{ V}$,	$I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 5.5\text{ V}$,	One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0				3	pF
$C_{io}(\text{OFF})$		$V_O = 3\text{ V}$ or 0,	$\overline{OE} = V_{CC}$			5.5	pF
$r_{on}^\S$	$V_{CC} = 4\text{ V}$, TYP at $V_{CC} = 4\text{ V}$		$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$		14	20	Ω
	$V_{CC} = 4.5\text{ V}$		$V_I = 0$, $I_I = 64\text{ mA}$		5	7	
			$I_I = 30\text{ mA}$		5	7	
			$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$		8	12	

[†] All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V}$ $\pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\P$	A or B	B or A		0.35		0.25	ns
t_{en}	$\overline{OE}$	A or B		9.3	3.3	8.6	ns
t_{dis}	$\overline{OE}$	A or B		7.1	2.8	7.9	ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

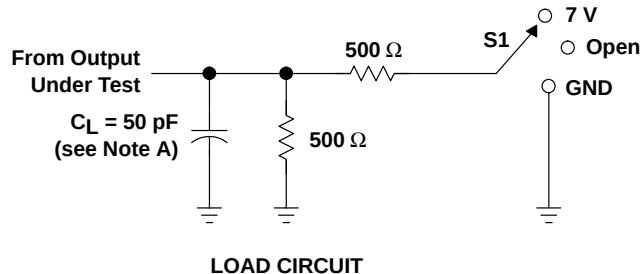
SN74CBTS16211

24-BIT FET BUS SWITCH

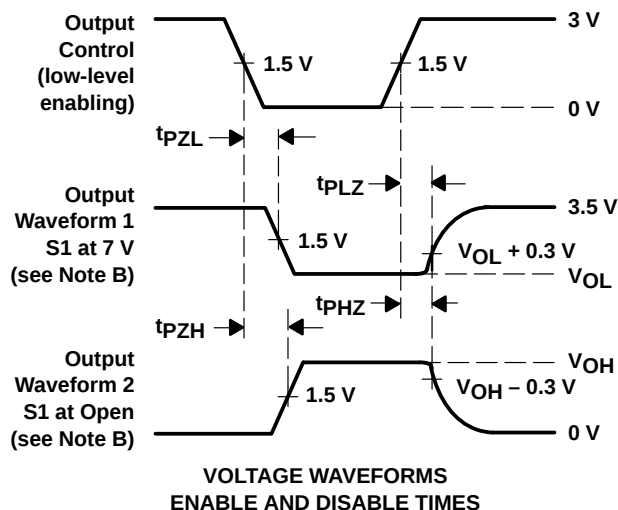
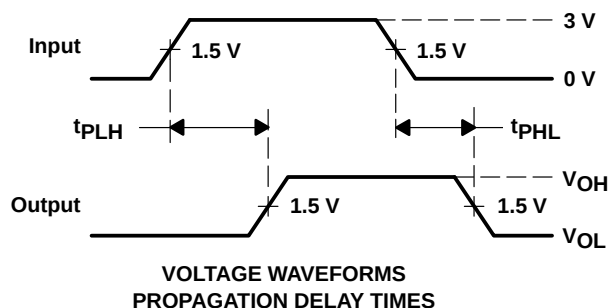
WITH SCHOTTKY DIODE CLAMPING

SCDS050B – MARCH 1998 – REVISED MAY 1998

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTS16212

24-BIT FET BUS-EXCHANGE SWITCH WITH SCHOTTKY DIODE CLAMPING

SCDS036B – DECEMBER 1997 – REVISED MAY 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

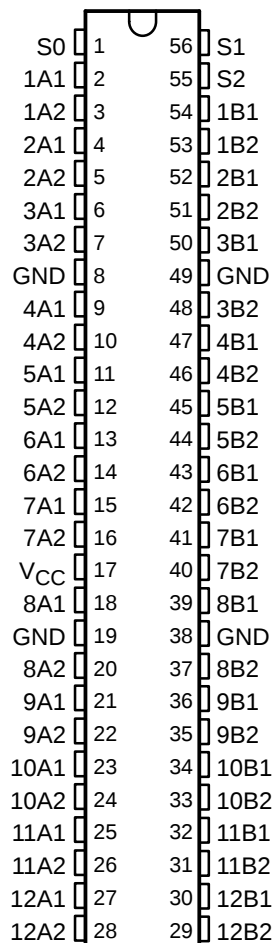
description

The SN74CBTS16212 provides 24 bits of high-speed TTL-compatible bus switching or exchanging with Schottky diodes on the I/Os to clamp undershoot. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 24-bit bus switch or a 12-bit bus exchanger, which provides data exchanging between the four signal ports via the data-select (S0–S2) terminals.

The SN74CBTS16212 is characterized for operation from –40°C to 85°C.

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



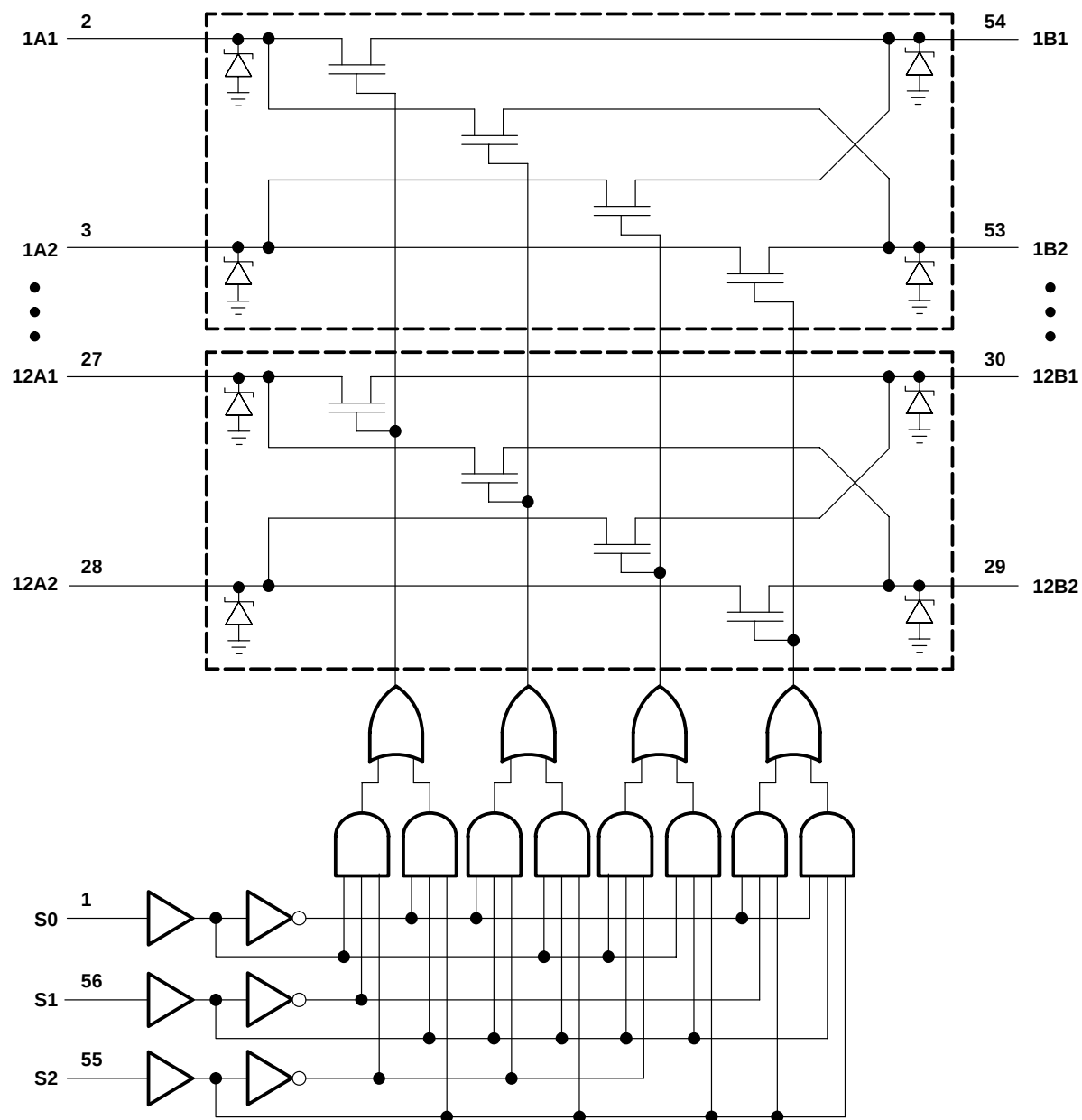
FUNCTION TABLE

INPUTS			INPUTS/OUTPUTS		FUNCTION
S2	S1	S0	A1	A2	
L	L	L	Z	Z	Disconnect
L	L	H	B1	Z	A1 port = B1 port
L	H	L	B2	Z	A1 port = B2 port
L	H	H	Z	B1	A2 port = B1 port
H	L	L	Z	B2	A2 port = B2 port
H	L	H	Z	Z	Disconnect
H	H	L	B1	B2	A1 port = B1 port A2 port = B2 port
H	H	H	B2	B1	A1 port = B2 port A2 port = B1 port

SN74CBTS16212 **24-BIT FET BUS-EXCHANGE SWITCH** **WITH SCHOTTKY DIODE CLAMPING**

SCDS036B – DECEMBER 1997 – REVISED MAY 1998

logic diagram (positive logic)



5-43

SN74CBTS16212

24-BIT FET BUS-EXCHANGE SWITCH

WITH SCHOTTKY DIODE CLAMPING

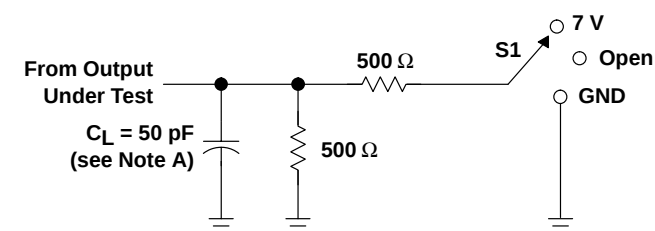
SCDS036B – DECEMBER 1997 – REVISED MAY 1998

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.35		0.25		ns
t_{pd}	S	A or B	10		1.5	9.1	ns
t_{en}	S	A or B	10.4		1.5	9.7	ns
t_{dis}	S	A or B	9.2		1.5	8.8	ns

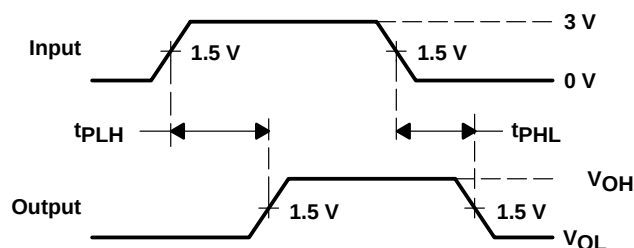
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

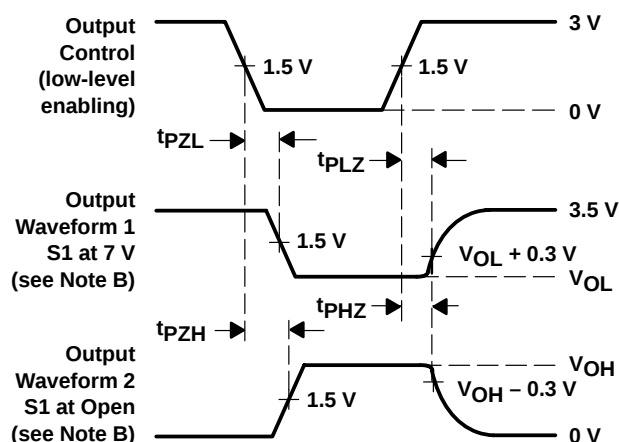


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTS16213

24-BIT FET BUS-EXCHANGE SWITCH WITH SCHOTTKY DIODE CLAMPING

SCDS051A – MARCH 1998 – REVISED MAY 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and 300-mil Shrink Small-Outline (DL) Packages

description

The SN74CBTS16213 provides 24 bits of high-speed TTL-compatible bus switching or exchanging with Schottky diodes on the I/Os to clamp undershoot. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 24-bit bus switch or a 12-bit bus exchanger that provides data exchanging between the four signal ports via the data-select (S0–S2) terminals.

The SN74CBTS16213 is characterized for operation from –40°C to 85°C.

DGG OR DL PACKAGE
(TOP VIEW)

S0	1	56	S1
1A1	2	55	S2
1A2	3	54	1B1
2A1	4	53	1B2
2A2	5	52	2B1
3A1	6	51	2B2
3A2	7	50	3B1
GND	8	49	GND
4A1	9	48	3B2
4A2	10	47	4B1
5A1	11	46	4B2
5A2	12	45	5B1
6A1	13	44	5B2
6A2	14	43	6B1
7A1	15	42	6B2
7A2	16	41	7B1
V _{CC}	17	40	7B2
8A1	18	39	8B1
GND	19	38	GND
8A2	20	37	8B2
9A1	21	36	9B1
9A2	22	35	9B2
10A1	23	34	10B1
10A2	24	33	10B2
11A1	25	32	11B1
11A2	26	31	11B2
12A1	27	30	12B1
12A2	28	29	12B2

FUNCTION TABLE

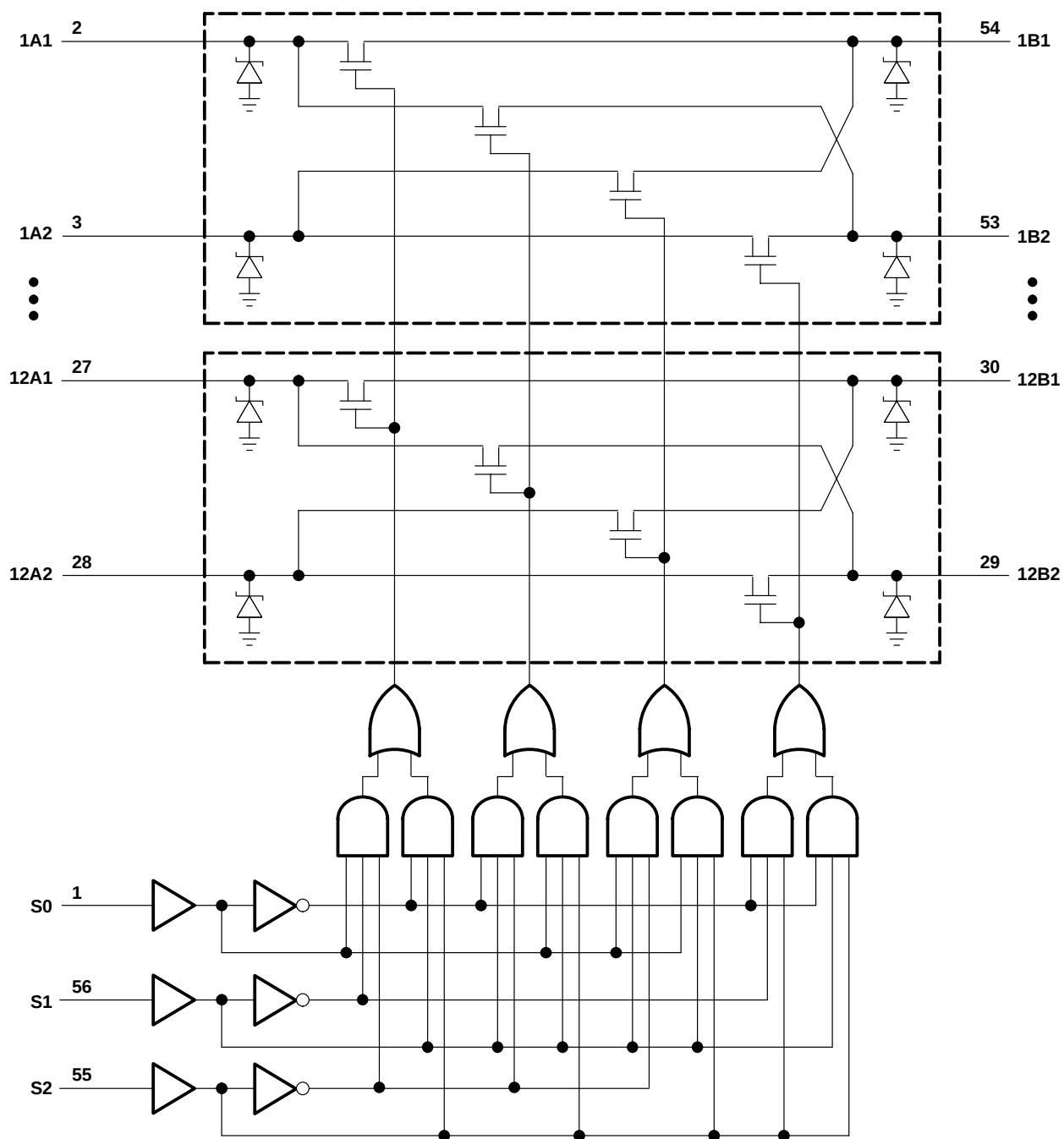
INPUTS			INPUTS/OUTPUTS		FUNCTION
S2	S1	S0	A1	A2	
L	L	L	Z	Z	Disconnect
L	L	H	B1 port	Z	A1 port = B1 port
L	H	L	B2 port	Z	A1 port = B2 port
L	H	H	Z	B1 port	A2 port = B1 port
H	L	L	Z	B2 port	A2 port = B2 port
H	L	H	Z	Z	Disconnect
H	H	L	B1 port	B2 port	A1 port = B1 port A2 port = B2 port
H	H	H	B2 port	B1 port	A1 port = B2 port A2 port = B1 port

SN74CBTS16213

24-BIT FET BUS-EXCHANGE SWITCH WITH SCHOTTKY DIODE CLAMPING

SCDS051A – MARCH 1998 – REVISED MAY 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
I_I	I_{IL} $V_{CC} = 5.5$ V, $V_I = \text{GND}$			–1	μA
	I_{IH} $V_{CC} = 5.5$ V, $V_I = 5.5$ V			50	
I_{CC}	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND			3	μA
$\Delta I_{CC}^{\S}$	Control inputs $V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND			2.5	mA
C_i	Control inputs $V_I = 3$ V or 0			4.5	pF
$C_{io}(\text{OFF})$	B port			8.5	pF
	A port			8	
$r_{on}^{\parallel}$	A to B or B to A	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V, $I_I = 15$ mA	14	Ω
		$V_{CC} = 4.5$ V	$V_I = 0$, $I_I = 64$ mA	5	
			$I_I = 30$ mA	5	
			$V_I = 2.4$ V, $I_I = 15$ mA	8	
	A1 to A2	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V, $I_I = 15$ mA	22	
		$V_{CC} = 4.5$ V	$V_I = 0$, $I_I = 64$ mA	10	
			$I_I = 30$ mA	10	
			$V_I = 2.4$ V, $I_I = 15$ mA	16	

[‡] All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

^{\parallel} Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

SN74CBTS16213 24-BIT FET BUS-EXCHANGE SWITCH WITH SCHOTTKY DIODE CLAMPING

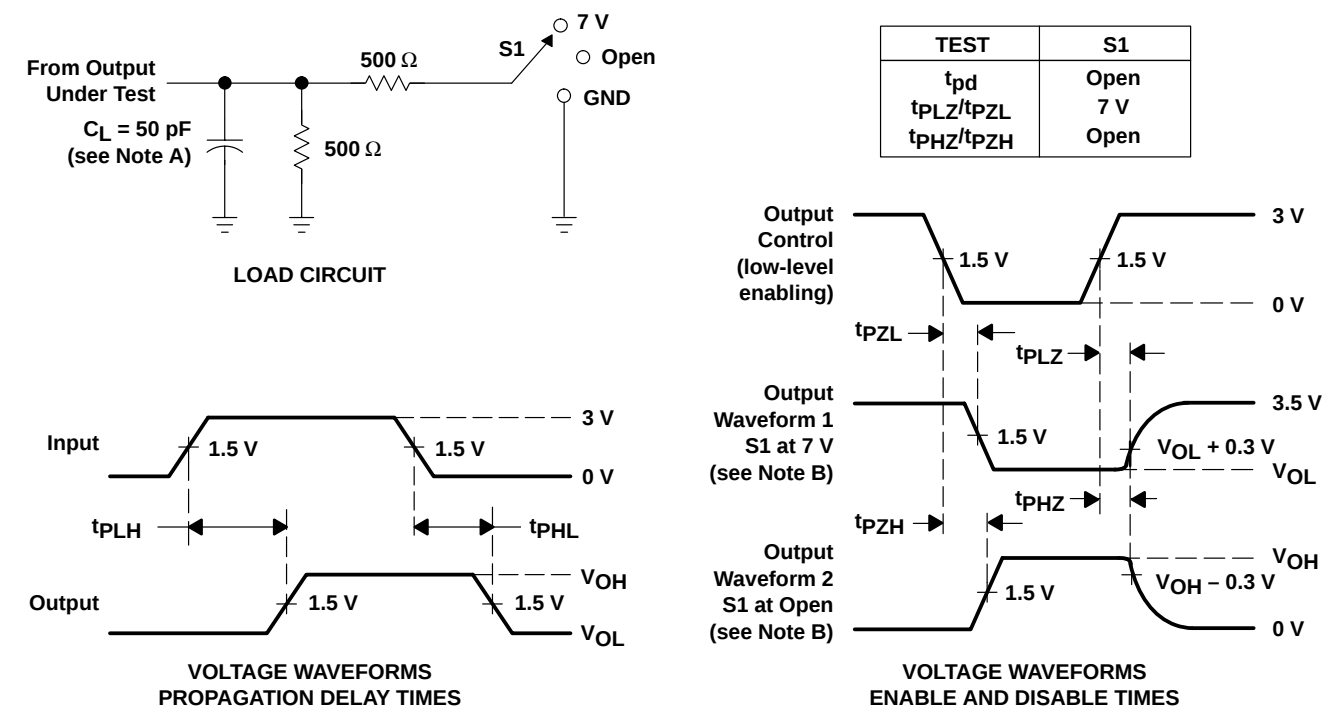
SCDS051A – MARCH 1998 – REVISED MAY 1998

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [†]	A or B	B or A	0.35		0.25		ns
	A1	A2	0.5		0.5		
t _{en}	S	A or B	12.4		3.2	11.1	ns
t _{dis}	S	A or B	12.4		2.3	11.9	ns
t _{en}	S0	A2 and B2	11.5		4	10.9	ns
t _{dis}	S0	A2 and B2	12.8		5.7	12	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTD16861 20-BIT FET BUS SWITCH WITH LEVEL SHIFTING

SCDS069B – JULY 1998 – REVISED OCTOBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Shrink Small-Outline (DL) Packages

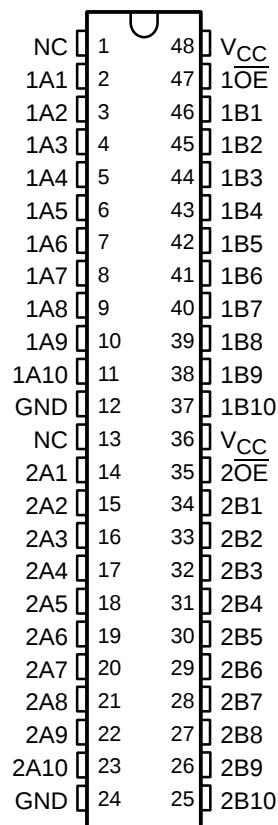
description

The SN74CBTD16861 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. A diode to V_{CC} is integrated on the die to allow for level shifting between 5-V inputs and 3.3-V outputs.

The device is organized as one dual 10-bit switch with separate output-enable ($\overline{OE}$) input. When $\overline{OE}$ is low, the switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

The SN74CBTD16861 is characterized for operation from -40°C to 85°C .

DGG OR DL PACKAGE (TOP VIEW)



NC – No internal connection

FUNCTION TABLE
(each 10-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

PRODUCT PREVIEW

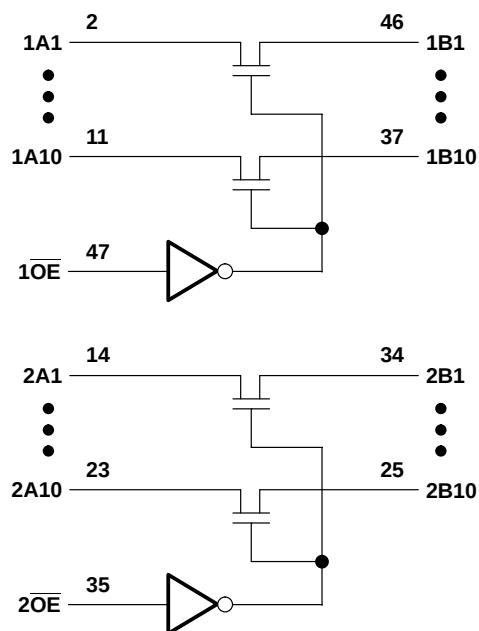
SN74CBTD16861

20-BIT FET BUS SWITCH

WITH LEVEL SHIFTING

SCDS069B – JULY 1998 – REVISED OCTOBER 1998

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4.5	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$				-1.2	V
V_{OH}		See Figure 2					
I_I		$V_{CC} = 5.5\text{ V}$, $V_I = 5.5\text{ V or GND}$				± 1	μA
I_{CC}		$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$				1.5	μA
$\Delta I_{CC}^{\ddagger}$	Control inputs	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at $V_{CC}\text{ or GND}$				2.5	mA
C_i	Control inputs	$V_I = 3\text{ V or 0}$					pF
$C_{io(OFF)}$		$V_O = 3\text{ V or 0}$, $\overline{OE} = V_{CC}$					pF
$r_{on}^{\S}$		$V_{CC} = 4.5\text{ V}$	$V_I = 0$			$I_I = 64\text{ mA}$	Ω
						$I_I = 30\text{ mA}$	
			$V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$				

[†] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

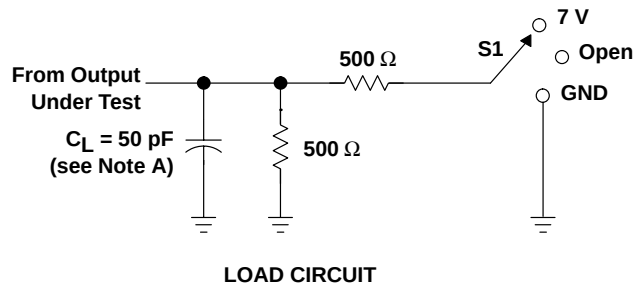
[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

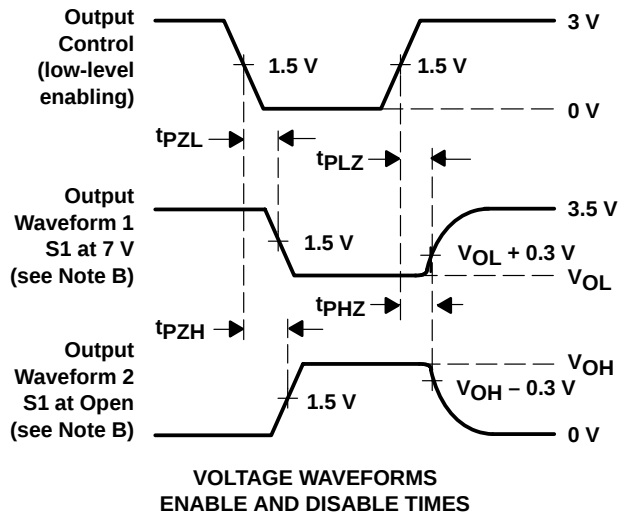
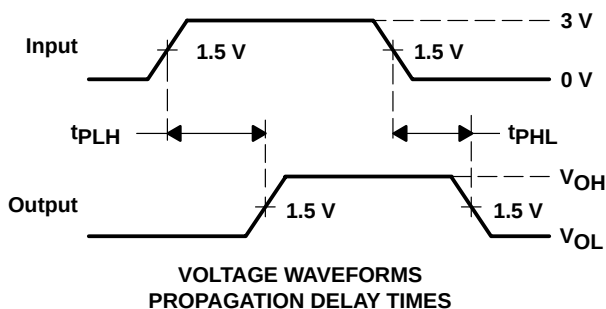
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^{\parallel}$	A or B	B or A			ns
t_{en}	$\overline{OE}$	A or B			ns
t_{dis}	$\overline{OE}$	A or B			ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

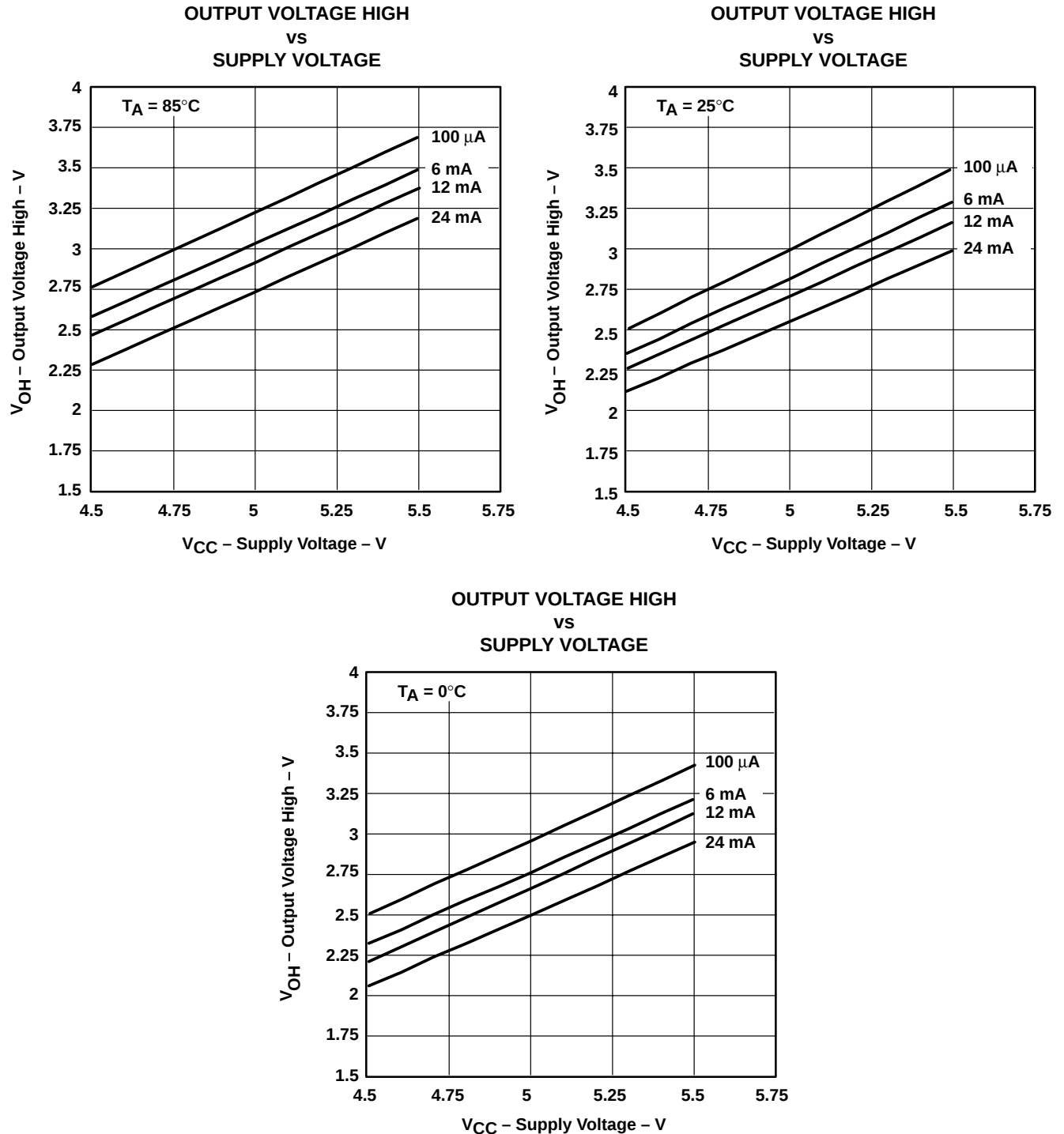


Figure 2. VOH Values

General Information	1
CBT Single Gates	2
CBT (2 to 10 Bit)	3
CBT Widebus™	4
CBT With Integrated Diodes	5
CBTLV Single Gates	6
CBTLV (2 to 10 Bit)	7
CBTLV Widebus™	8
Application Reports	9
Mechanical Data	10

Contents

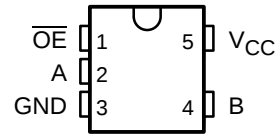
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SN74CBTLV1G125 LOW-VOLTAGE SINGLE FET BUS SWITCH

SCDS057B – MARCH 1998 – REVISED OCTOBER 1998

- 5- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Packaged in Plastic Small-Outline Transistor Package

DBV PACKAGE
(TOP VIEW)



description

The SN74CBTLV1G125 features a single high-speed line switch. The switch is disabled when the output-enable ($\overline{\text{OE}}$) input is high.

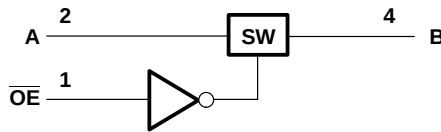
To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV1G125 is characterized for operation from -40°C to 85°C .

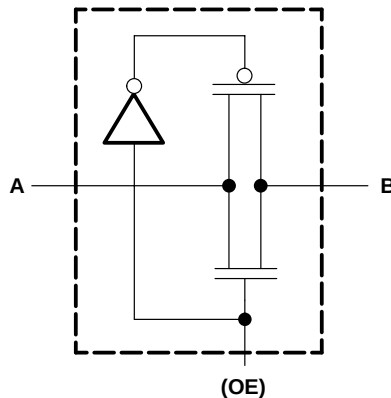
FUNCTION TABLE

INPUT $\overline{\text{OE}}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



simplified schematic, each FET switch



PRODUCT PREVIEW

SN74CBTLV1G125

LOW-VOLTAGE SINGLE FET BUS SWITCH

SCDS057B – MARCH 1998 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2)	347°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.3	3.6	V
V_{IH}	High-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2	
V_{IL}	Low-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	0.8	
T_A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 3 \text{ V}$,	$I_I = -18 \text{ mA}$			–1.2	V
I_I	$V_{CC} = 3.6 \text{ V}$,	$V_I = V_{CC}$ or GND			±1	μA
I_{off}	$V_{CC} = 0$,	V_I or $V_O = 0$ to 3.6 V			10	μA
I_{CC}	$V_{CC} = 3.6 \text{ V}$,	$I_O = 0$, $V_I = V_{CC}$ or GND			10	μA
ΔI_{CC} [§]	Control inputs	$V_{CC} = 3.6 \text{ V}$, One input at 3 V, Other inputs at V_{CC} or GND			300	μA
C_i	Control inputs	$V_I = 3 \text{ V}$ or 0				pF
$C_{io(OFF)}$	$V_O = 3 \text{ V}$ or 0,	$\overline{OE} = V_{CC}$				pF
r_{on} [¶]	$V_{CC} = 2.3 \text{ V}$, TYP at $V_{CC} = 2.5 \text{ V}$	$V_I = 0$			$I_I = 64 \text{ mA}$	Ω
					$I_I = 24 \text{ mA}$	
		$V_I = 1.7 \text{ V}$,			$I_I = 15 \text{ mA}$	
	$V_{CC} = 3 \text{ V}$	$V_I = 0$			$I_I = 64 \text{ mA}$	
					$I_I = 24 \text{ mA}$	
		$V_I = 2.4 \text{ V}$,			$I_I = 15 \text{ mA}$	

[‡] All typical values are at $V_{CC} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[§] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.



SN74CBTLV1G125

LOW-VOLTAGE SINGLE FET BUS SWITCH

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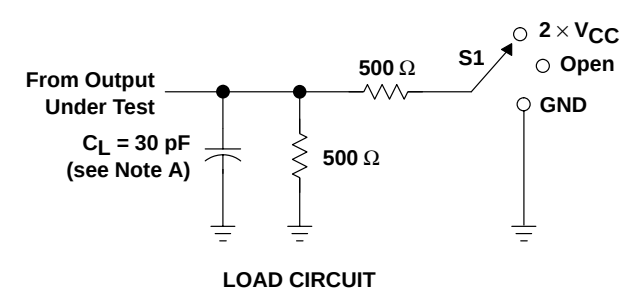
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger}$	A or B	B or A					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

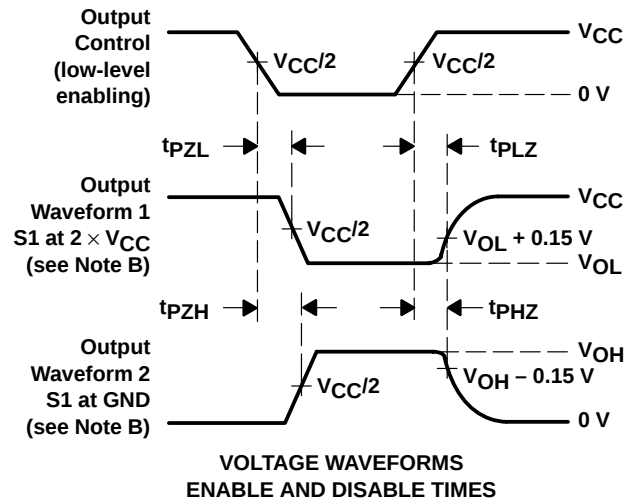
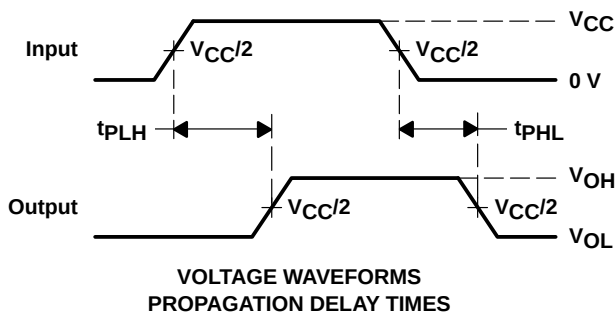
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



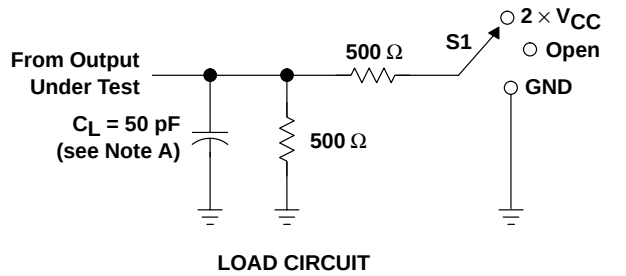
- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

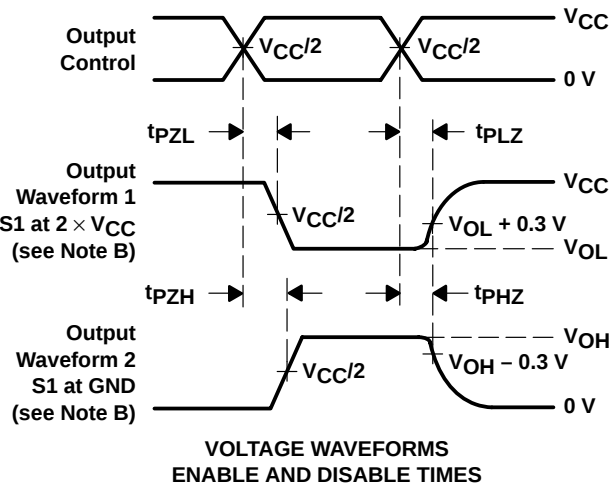
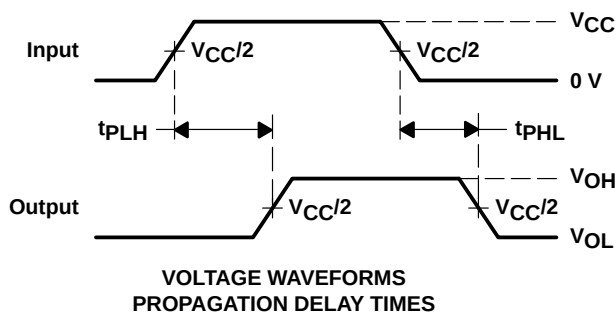
SN74CBTLV1G125
LOW-VOLTAGE SINGLE FET BUS SWITCH

SCDS057B – MARCH 1998 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 2 $\times V_{CC}$ GND



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

General Information	1
CBT Single Gates	2
CBT (2 to 10 Bit)	3
CBT Widebus™	4
CBT With Integrated Diodes	5
CBTLV Single Gates	6
CBTLV (2 to 10 Bit)	7
CBTLV Widebus™	8
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SN74CBTLV3125 LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

SCDS037C – DECEMBER 1997 – REVISED OCTOBER 1998

- Standard '125-Type Pinout
- 5- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Package Options Include Plastic Small-Outline (D), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

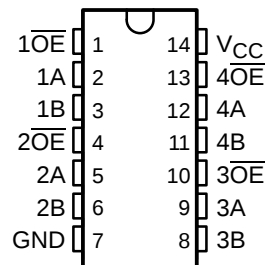
description

The SN74CBTLV3125 quadruple FET bus switch features independent line switches. Each switch is disabled when the associated output-enable ($\overline{\text{OE}}$) input is high.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV3125 is characterized for operation from -40°C to 85°C .

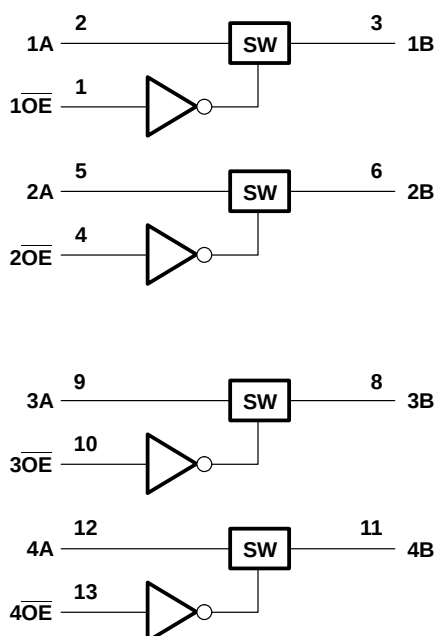
D, DGV, OR PW PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each bus switch)

INPUT $\overline{\text{OE}}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



PRODUCT PREVIEW

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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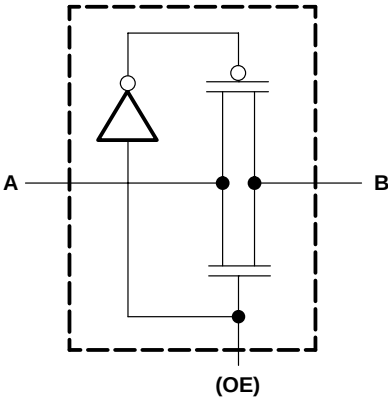
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SN74CBTLV3125

LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

SCDS037C – DECEMBER 1997 – REVISED OCTOBER 1998

simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	127°C/W
DGV package	182°C/W
PW package	170°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.3	3.6	V
V_{IH}	High-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2	
V_{IL}	Low-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	0.8	
T_A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74CBTLV3125

LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

SCDS037C – DECEMBER 1997 – REVISED OCTOBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 3\text{ V}$, $I_I = -18\text{ mA}$				-1.2	V
I_I		$V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}$ or GND				± 5	μA
I_{off}		$V_{CC} = 0$, V_I or $V_O = 0$ to 4.5 V				10	μA
I_{CC}		$V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND				10	μA
$\Delta I_{CC}^{\ddagger}$	Control inputs	$V_{CC} = 3.6\text{ V}$, One input at 3 V, Other inputs at V_{CC} or GND				300	μA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0					pF
$C_{io(OFF)}$		$V_O = 3\text{ V}$ or 0, $\overline{OE} = V_{CC}$					pF
$r_{on}^{\S}$	$V_{CC} = 2.3\text{ V}$, TYP at $V_{CC} = 2.5\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$				Ω
			$I_I = 24\text{ mA}$				
		$V_I = 1.7\text{ V}$	$I_I = 15\text{ mA}$				
	$V_{CC} = 3\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$				
			$I_I = 24\text{ mA}$				
		$V_I = 2.4\text{ V}$	$I_I = 15\text{ mA}$				

[†] All typical values are at $V_{CC} = 3.3\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

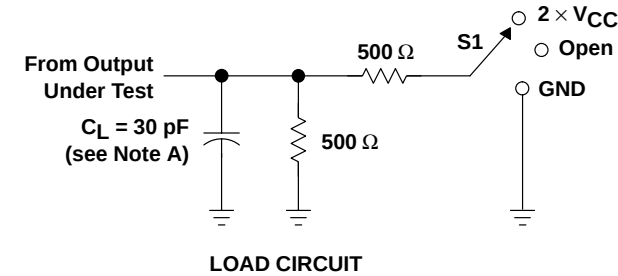
PRODUCT PREVIEW



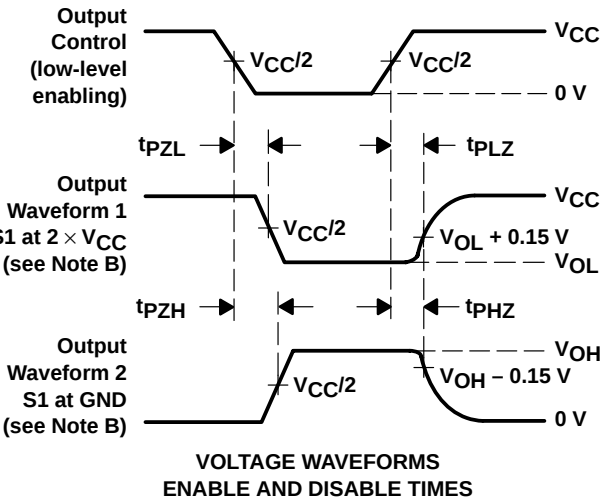
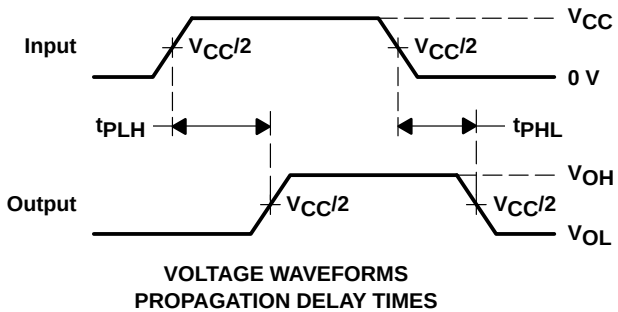
SN74CBTLV3125
LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

SCDS037C – DECEMBER 1997 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open $2 \times V_{CC}$ GND

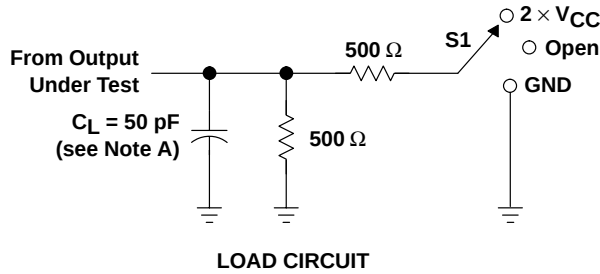


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

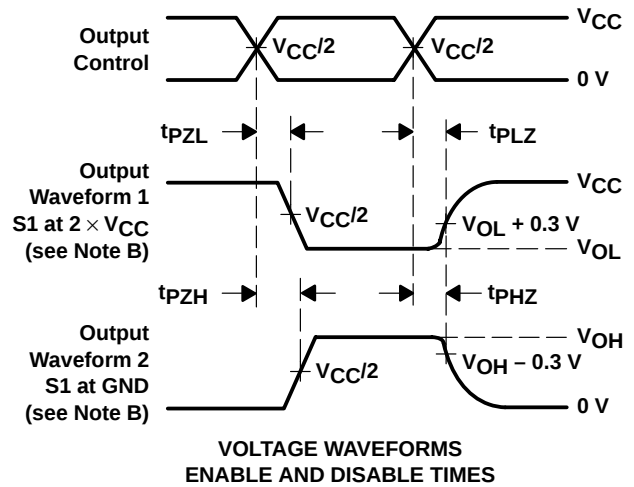
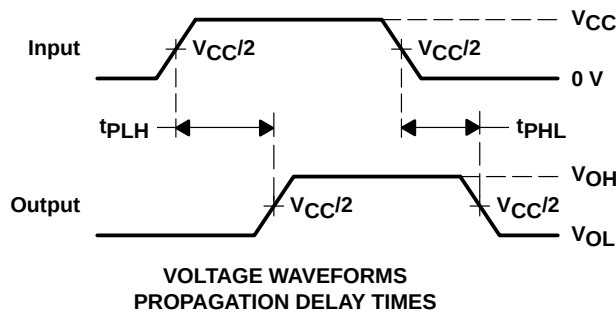
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open $2 \times V_{CC}$ GND



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV3126 LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

SCDS038C – DECEMBER 1997 – REVISED OCTOBER 1998

- Standard '126-Type Pinout
- 5- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Package Options Include Plastic Small-Outline (D), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

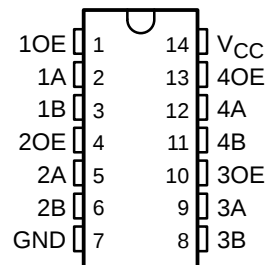
description

The SN74CBTLV3126 quadruple FET bus switch features independent line switches. Each switch is disabled when the associated output-enable (OE) input is low.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV3126 is characterized for operation from -40°C to 85°C .

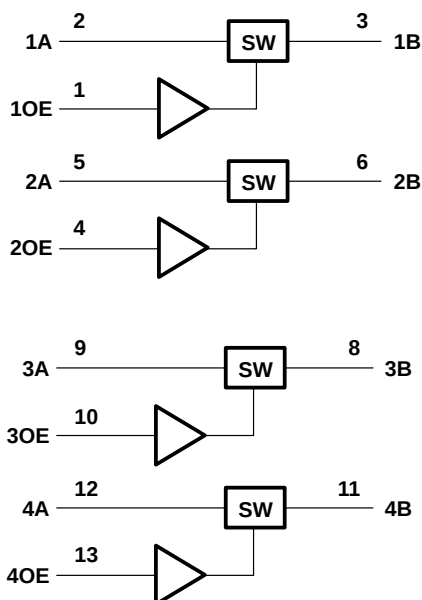
D, DGV, OR PW PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each bus switch)

INPUT OE	FUNCTION
L	Disconnect
H	A port = B port

logic diagram (positive logic)



PRODUCT PREVIEW

PRODUCT PREVIEW

simplified schematic, each FET switch



† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74CBTLV3126

LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

SCDS038C – DECEMBER 1997 – REVISED OCTOBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 3\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
I_I		$V_{CC} = 3.6\text{ V}$,	$V_I = V_{CC}$ or GND			± 5	μA
I_{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V			10	μA
I_{CC}		$V_{CC} = 3.6\text{ V}$,	$I_O = 0$, $V_I = V_{CC}$ or GND			10	μA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 3.6\text{ V}$,	One input at 3 V, Other inputs at V_{CC} or GND			300	μA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0					pF
$C_{io(OFF)}$		$V_O = 3\text{ V}$ or 0, $OE = V_{CC}$					pF
$r_{on}^\S$	$V_{CC} = 2.3\text{ V}$, TYP at $V_{CC} = 2.5\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$				Ω
			$I_I = 24\text{ mA}$				
		$V_I = 1.7\text{ V}$,	$I_I = 15\text{ mA}$				
	$V_{CC} = 3\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$				
			$I_I = 24\text{ mA}$				
		$V_I = 2.4\text{ V}$,	$I_I = 15\text{ mA}$				

[†] All typical values are at $V_{CC} = 3.3\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\parallel$	A or B	B or A					ns
t_{en}	OE	A or B					ns
t_{dis}	OE	A or B					ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

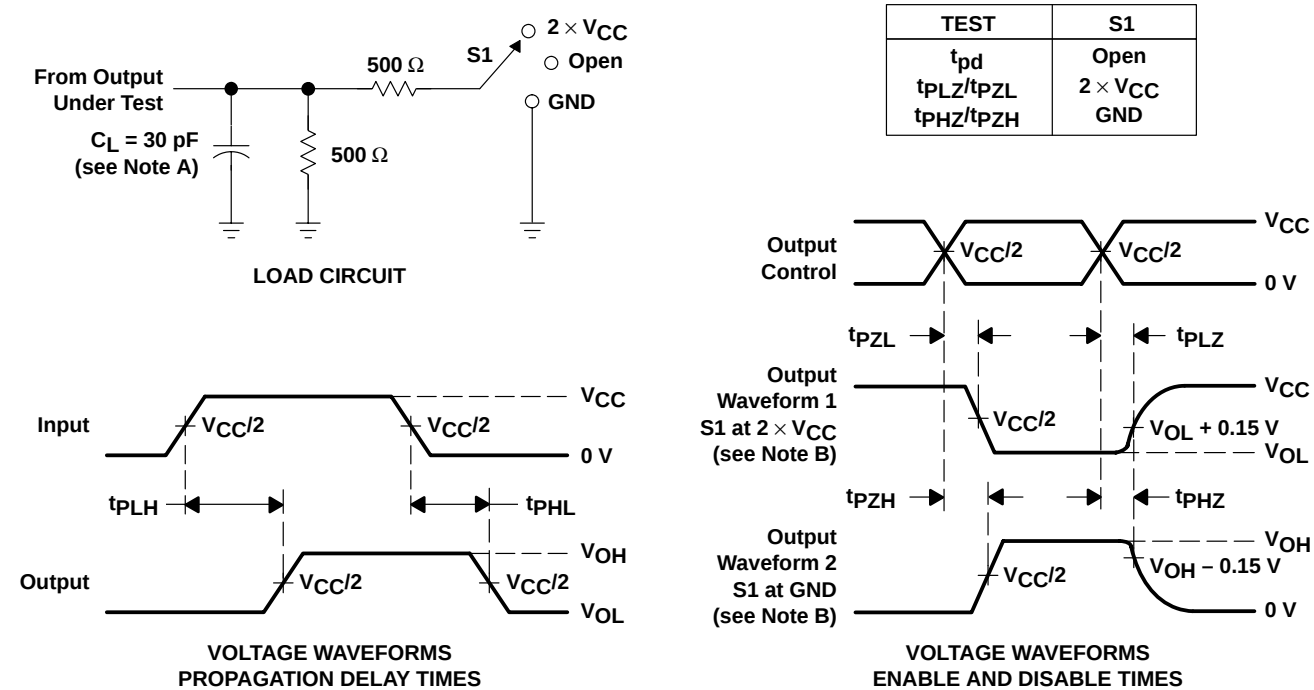
PRODUCT PREVIEW



SN74CBTLV3126 LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

SCDS038C – DECEMBER 1997 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

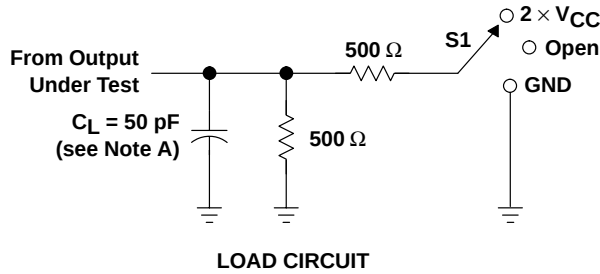


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

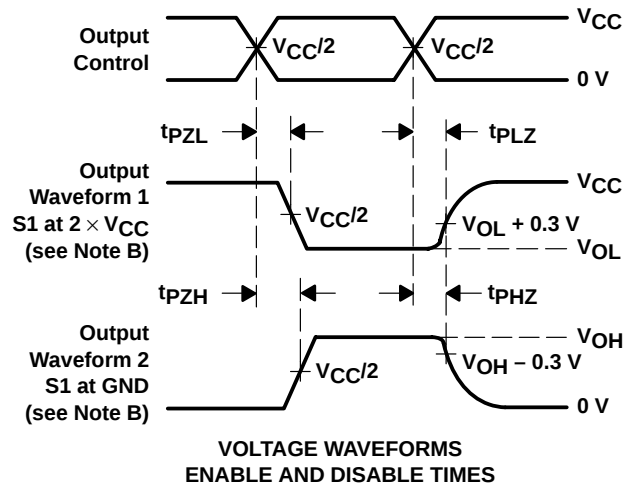
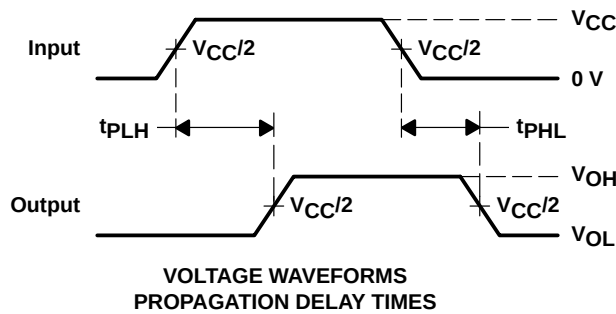
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

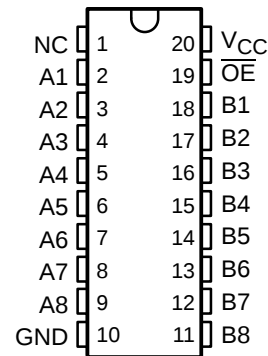
Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV3245A LOW-VOLTAGE OCTAL FET BUS SWITCH

SCDS034G – JULY 1997 – REVISED SEPTEMBER 1998

- Standard '245-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Shrink Small-Outline (DBQ), Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



NC – No internal connection

description

The SN74CBTLV3245A provides eight bits of high-speed bus switching in a standard '245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 8-bit switch. When output enable ($\overline{OE}$) is low, the 8-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

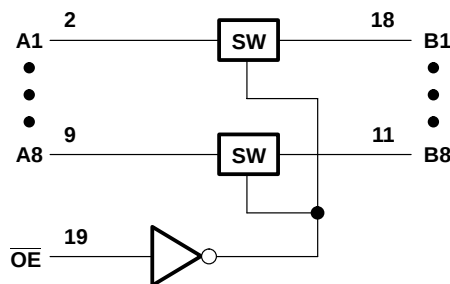
To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV3245A is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

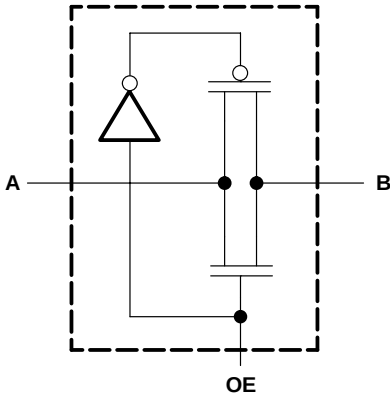
logic diagram (positive logic)



SN74CBTLV3245A
LOW-VOLTAGE OCTAL FET BUS SWITCH

SCDS034G – JULY 1997 – REVISED SEPTEMBER 1998

simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBQ package	113°C/W
DGV package	146°C/W
DW package	97°C/W
PW package	128°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2.3	3.6	V
V _{IH}	High-level control input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level control input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V
		V _{CC} = 2.7 V to 3.6 V		0.8	
T _A	Operating free-air temperature		−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74CBTLV3245A

LOW-VOLTAGE OCTAL FET BUS SWITCH

SCDS034G – JULY 1997 – REVISED SEPTEMBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}	Control inputs	$V_{CC} = 3\text{ V}$, $I_I = -18\text{ mA}$				-1.2	V
	Data inputs					-0.8	
I_I		$V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}$ or GND				±60	μA
I_{off}		$V_{CC} = 0$, V_I or $V_O = 0$ to 3.6 V				40	μA
I_{CC}		$V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND				20	μA
$\Delta I_{CC}^\ddagger$	Control inputs	$V_{CC} = 3.6\text{ V}$, One input at 3 V , Other inputs at V_{CC} or GND				300	μA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0				4	pF
$C_{io(OFF)}$		$V_O = 3\text{ V}$ or 0 , $\overline{OE} = V_{CC}$				9	pF
$r_{on}^\S$	$V_{CC} = 2.3\text{ V}$, TYP at $V_{CC} = 2.5\text{ V}$	$V_I = 0$	$I_O = 64\text{ mA}$			5	Ω
			$I_O = 24\text{ mA}$			5	
		$V_I = 1.7\text{ V}$	$I_O = 15\text{ mA}$			27	
	$V_{CC} = 3\text{ V}$	$V_I = 0$	$I_O = 64\text{ mA}$			5	
			$I_O = 24\text{ mA}$			5	
		$V_I = 2.4\text{ V}$	$I_O = 15\text{ mA}$			10	

[†] All typical values are at $V_{CC} = 3.3\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A		0.15		0.25	ns
t_{en}	$\overline{OE}$	A or B	1	6	1	4.7	ns
t_{dis}	$\overline{OE}$	A or B	1	6.1	1	6.4	ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).

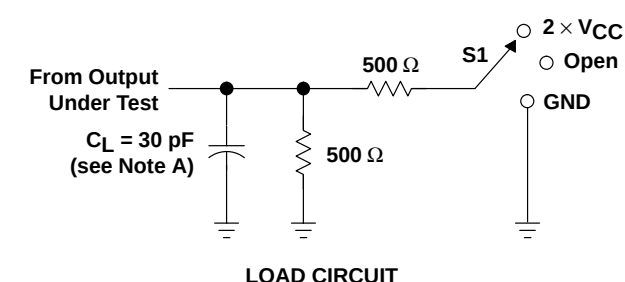
SN74CBTLV3245A

LOW-VOLTAGE OCTAL FET BUS SWITCH

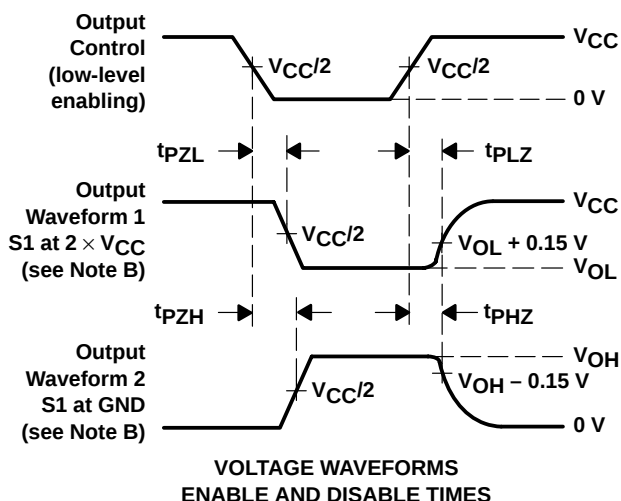
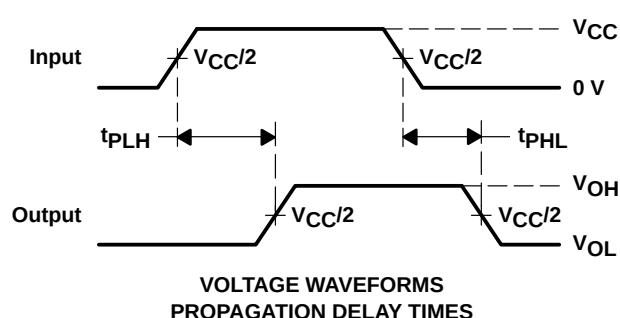
SCDS034G – JULY 1997 – REVISED SEPTEMBER 1998

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND

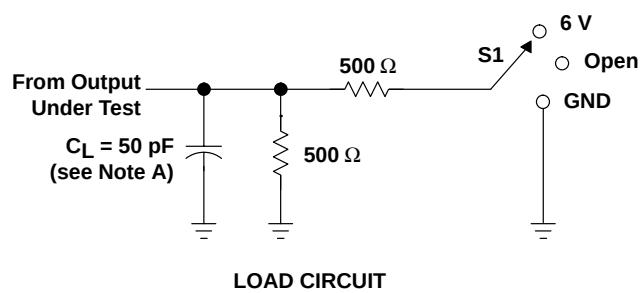


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

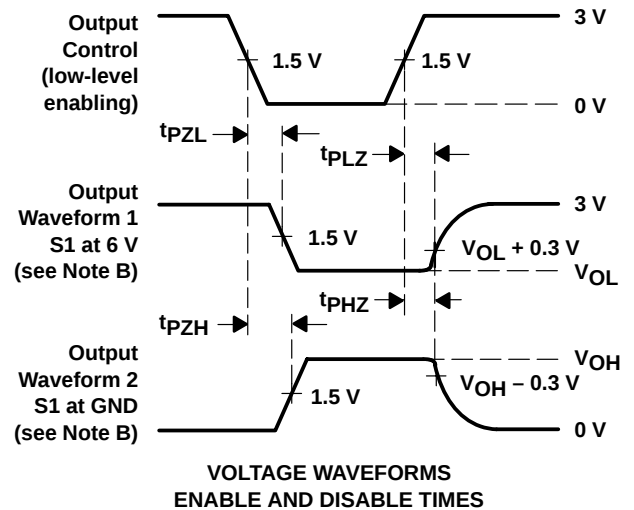
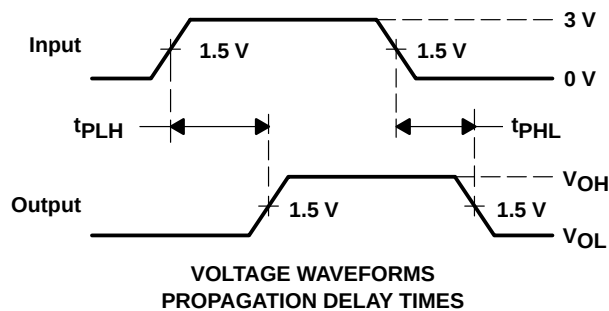
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR $\leq 0 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV3251 LOW-VOLTAGE 1-OF-8 FET MULTIPLEXER/DEMULTIPLEXER

SCDS054B – MARCH 1998 – REVISED OCTOBER 1998

- Functionally Equivalent to QS3251
- 5- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Package Options Include Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

description

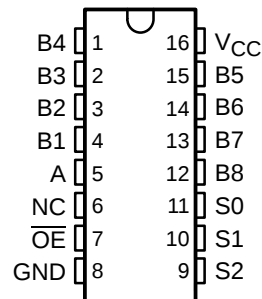
The SN74CBTLV3251 device is a 1-of-8 high-speed FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The select inputs (S0, S1, S2) control the data flow. The FET multiplexers/demultiplexers are disabled when the output-enable ($\overline{OE}$) input is high.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV3251 is characterized for operation from -40°C to 85°C .

DGV, DW, OR PW PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

INPUTS				FUNCTION
$\overline{OE}$	S2	S1	S0	
L	L	L	L	A port = B1 port
L	L	L	H	A port = B2 port
L	L	H	L	A port = B3 port
L	L	H	H	A port = B4 port
L	H	L	L	A port = B5 port
L	H	L	H	A port = B6 port
L	H	H	L	A port = B7 port
L	H	H	H	A port = B8 port
H	X	X	X	Disconnect

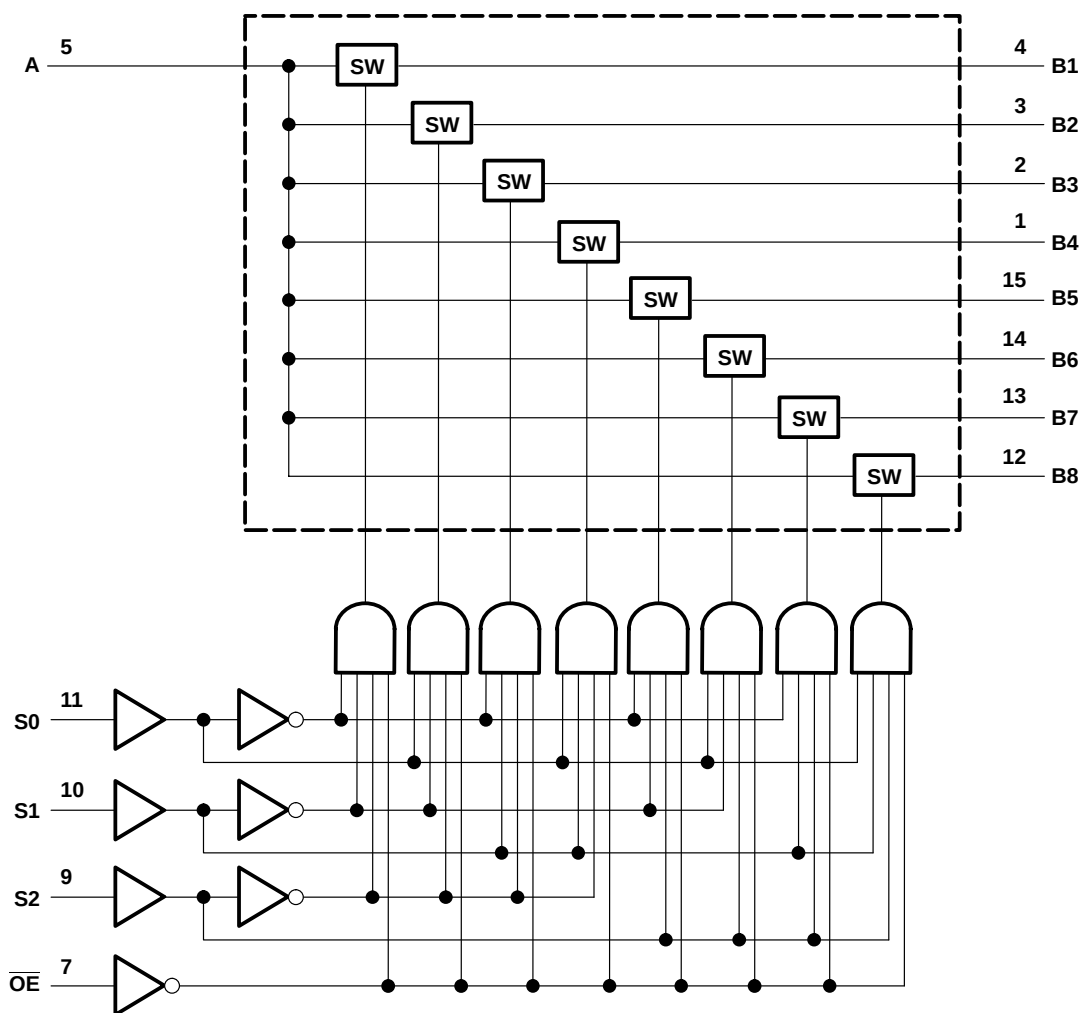
PRODUCT PREVIEW

SN74CBTLV3251

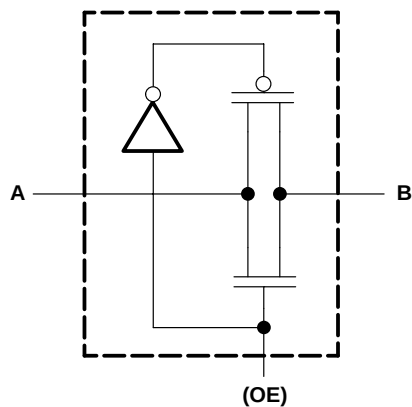
LOW-VOLTAGE 1-OF-8 FET MULTIPLEXER/DEMULTIPLEXER

SCDS054B – MARCH 1998 – REVISED OCTOBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



PRODUCT PREVIEW

SN74CBTLV3251

LOW-VOLTAGE 1-OF-8 FET MULTIPLEXER/DEMULTIPLEXER

SCDS054B – MARCH 1998 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_K ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGV package	180°C/W
DW package	105°C/W
PW package	149°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.3	3.6	V
V_{IH}	High-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ 1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ 2		
V_{IL}	Low-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ 0.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ 0.8		
T_A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [‡]	MAX	UNIT
V _{IK}		V _{CC} = 3 V, I _I = −18 mA					−1.2	V
I _I		V _{CC} = 3.6 V, V _I = V _{CC} or GND					±1	μA
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V					10	μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND					10	μA
ΔI _{CC} [§]	Control inputs	V _{CC} = 3.6 V, One input at 3 V, Other inputs at V _{CC} or GND					300	μA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)	A port	V _O = 3 V or 0, $\overline{OE}$ = V _{CC}						pF
	B port							
r _{on} [¶]	V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V	V _I = 0	I _I = 64 mA					Ω
			I _I = 24 mA					
		V _I = 1.7 V, I _I = 15 mA						
	V _{CC} = 3 V	V _I = 0	I _I = 64 mA					
			I _I = 24 mA					
		V _I = 2.4 V, I _I = 15 mA						

[‡] All typical values are at $V_{CC} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

^{\parallel} Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PRODUCT PREVIEW



SN74CBTLV3251 LOW-VOLTAGE 1-OF-8 FET MULTIPLEXER/DEMULTIPLEXER

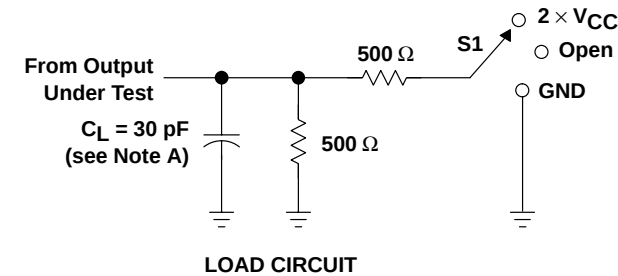
SCDS054B – MARCH 1998 – REVISED OCTOBER 1998

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

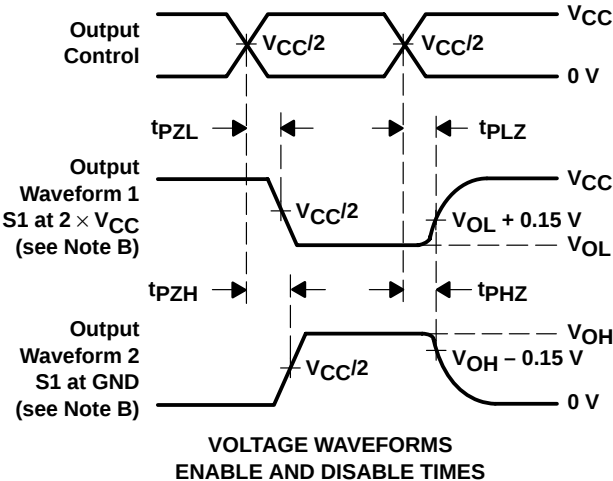
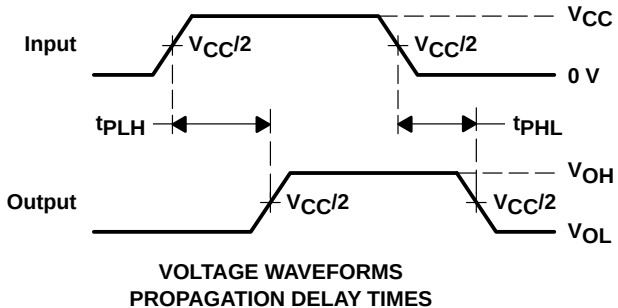
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
t_{pd}	A or B [†]	B or A					ns
	S	A					
t_{en}	S	B					ns
t_{dis}	S	B					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

[†] The propagation delay is based on the RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 2 $\times V_{CC}$ GND

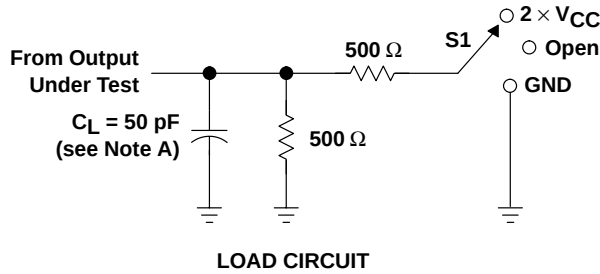


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

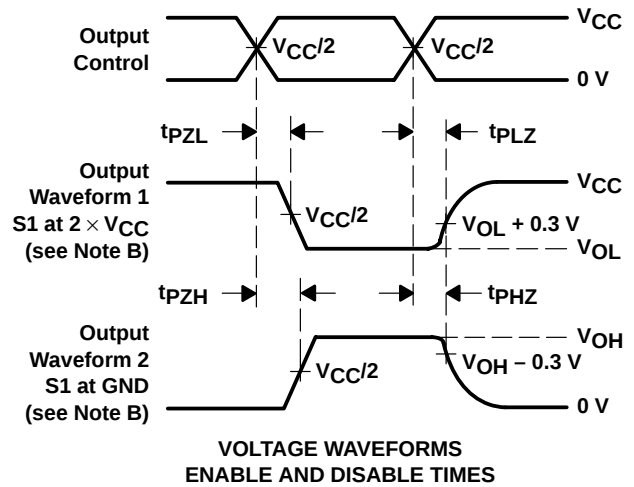
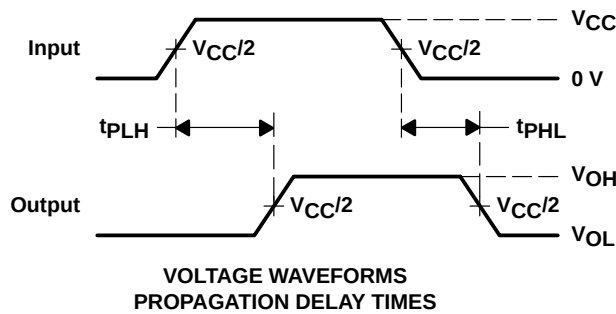
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV3253

LOW-VOLTAGE DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS039C – DECEMBER 1997 – REVISED OCTOBER 1998

- Functionally Equivalent to QS3253
- 5- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Package Options Include Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

description

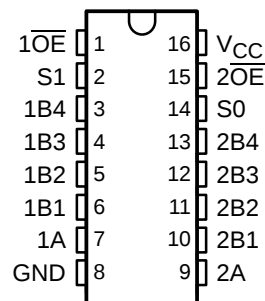
The SN74CBTLV3253 is a dual 1-of-4 high-speed FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The select (S0, S1) inputs control the data flow. The FET multiplexers/demultiplexers are disabled when the associated output-enable ($\overline{OE}$) input is high.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV3253 is characterized for operation from -40°C to 85°C .

DGV, DW, OR PW PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each multiplexer/demultiplexer)

INPUTS			FUNCTION
$\overline{OE}$	S1	S0	
L	L	L	A port = B1 port
L	L	H	A port = B2 port
L	H	L	A port = B3 port
L	H	H	A port = B4 port
H	X	X	Disconnect

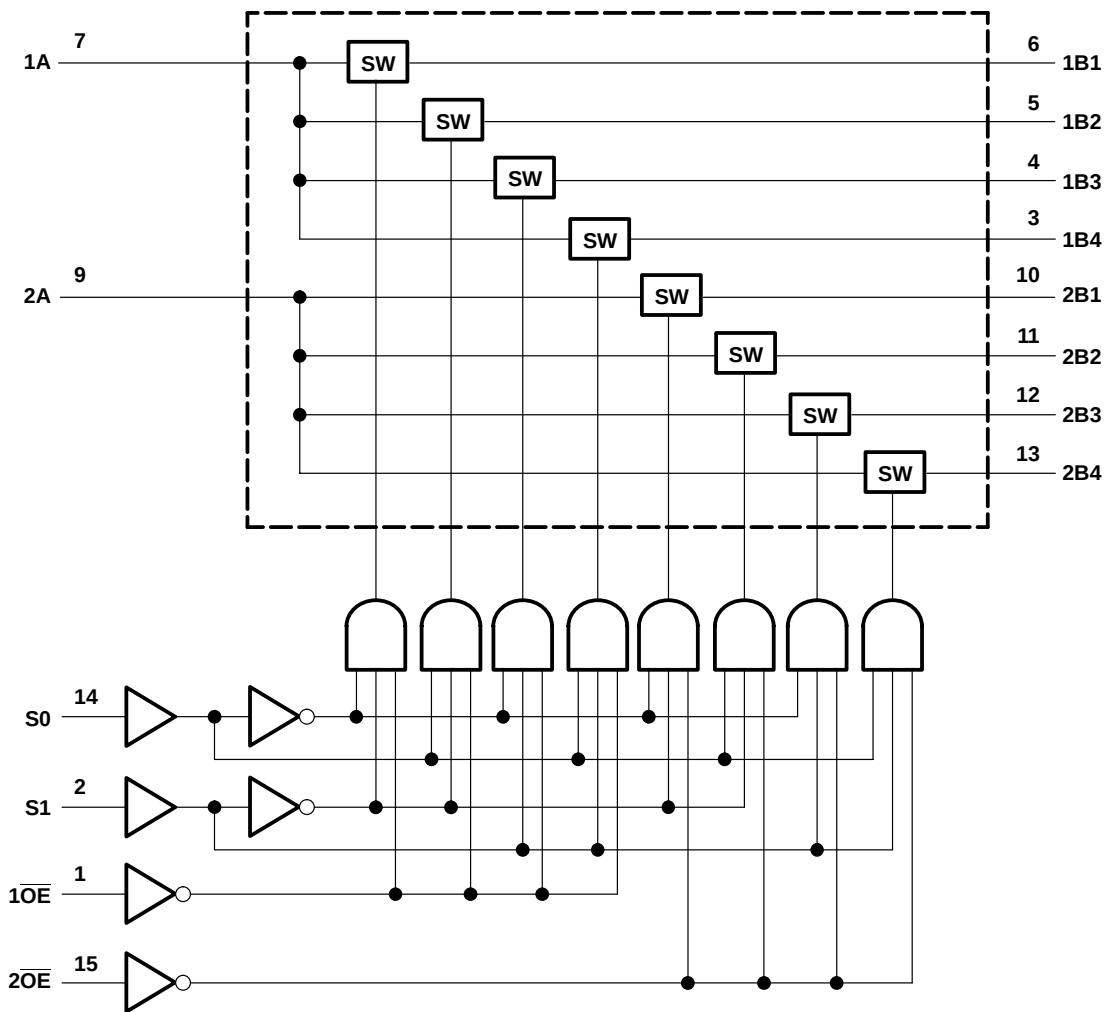
PRODUCT PREVIEW

SN74CBTLV3253

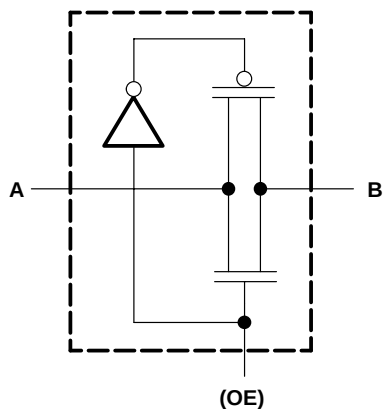
LOW-VOLTAGE DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS039C – DECEMBER 1997 – REVISED OCTOBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



PRODUCT PREVIEW

SN74CBTLV3253

LOW-VOLTAGE DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

SCDS039C – DECEMBER 1997 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGV package	180°C/W
DW package	105°C/W
PW package	149°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.3	3.6	V
V_{IH}	High-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	1.7 2	V
V_{IL}	Low-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	0.7 0.8	V
T_A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP‡	MAX	UNIT
V _{IK}		V _{CC} = 3 V, I _I = −18 mA					−1.2	V
I _I		V _{CC} = 3.6 V, V _I = V _{CC} or GND					±1	μA
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V					10	μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND					10	μA
ΔI _{CC} [§]	Control inputs	V _{CC} = 3.6 V, One input at 3 V, Other inputs at V _{CC} or GND					300	μA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)	A port	V _O = 3 V or 0, $\overline{OE}$ = V _{CC}						pF
	B port							
r _{on} [¶]	V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V	V _I = 0	I _I = 64 mA				Ω	
			I _I = 24 mA					
		V _I = 1.7 V, I _I = 15 mA						
	V _{CC} = 3 V	V _I = 0	I _I = 64 mA					
			I _I = 24 mA					
		V _I = 2.4 V, I _I = 15 mA						

[‡] All typical values are at $V_{CC} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

^{\parallel} Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PRODUCT PREVIEW



SN74CBTLV3253 LOW-VOLTAGE DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

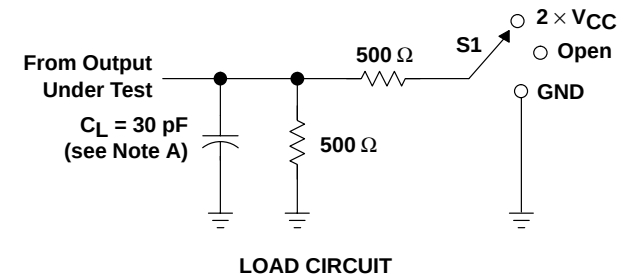
SCDS039C – DECEMBER 1997 – REVISED OCTOBER 1998

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

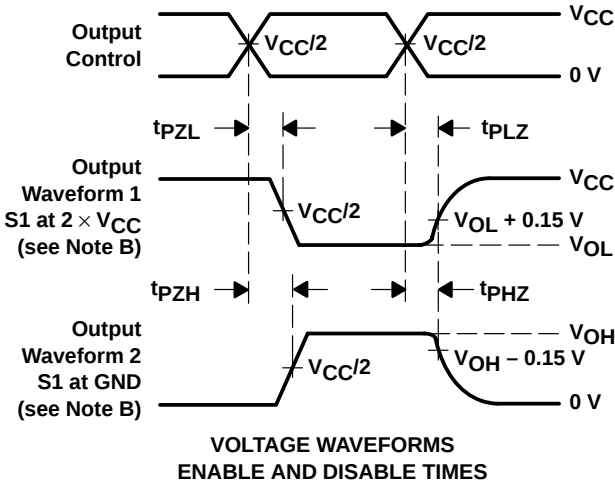
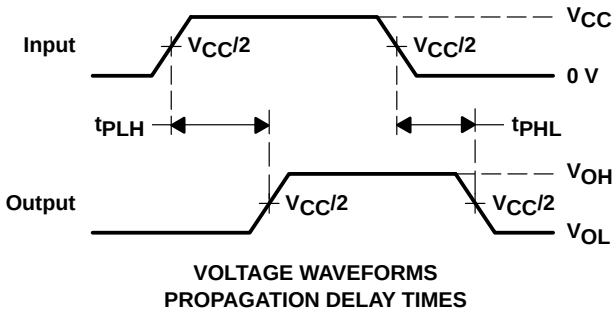
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
t_{pd}	A or B [†]	B or A					ns
	S	A or B					
t_{en}	S	A or B					ns
t_{dis}	S	A or B					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 2 $\times V_{CC}$ GND

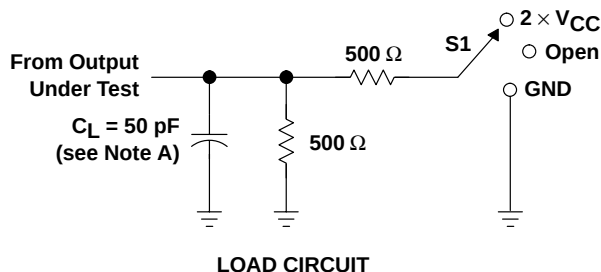


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

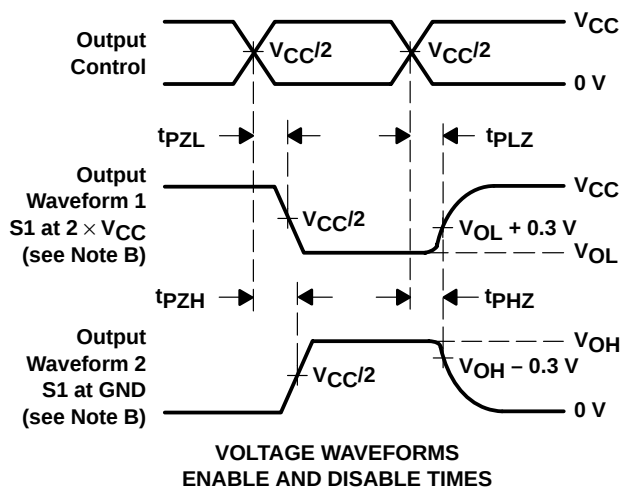
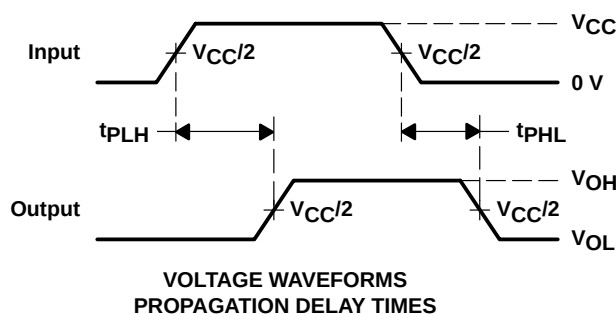
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV3257
LOW-VOLTAGE 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS040C – DECEMBER 1997 – REVISED OCTOBER 1998

- Functionally Equivalent to QS3257
- 5-Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Package Options Include Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

description

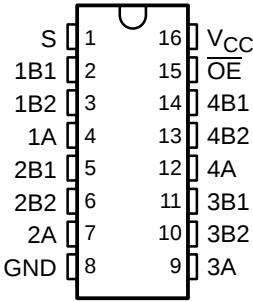
The SN74CBTLV3257 is a 4-bit 1-of-2 high-speed FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The select (S) input controls the data flow. The FET multiplexers/demultiplexers are disabled when the output-enable ($\overline{OE}$) input is high.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV3257 is characterized for operation from -40°C to 85°C .

DGV, DW, OR PW PACKAGE
(TOP VIEW)



FUNCTION TABLE

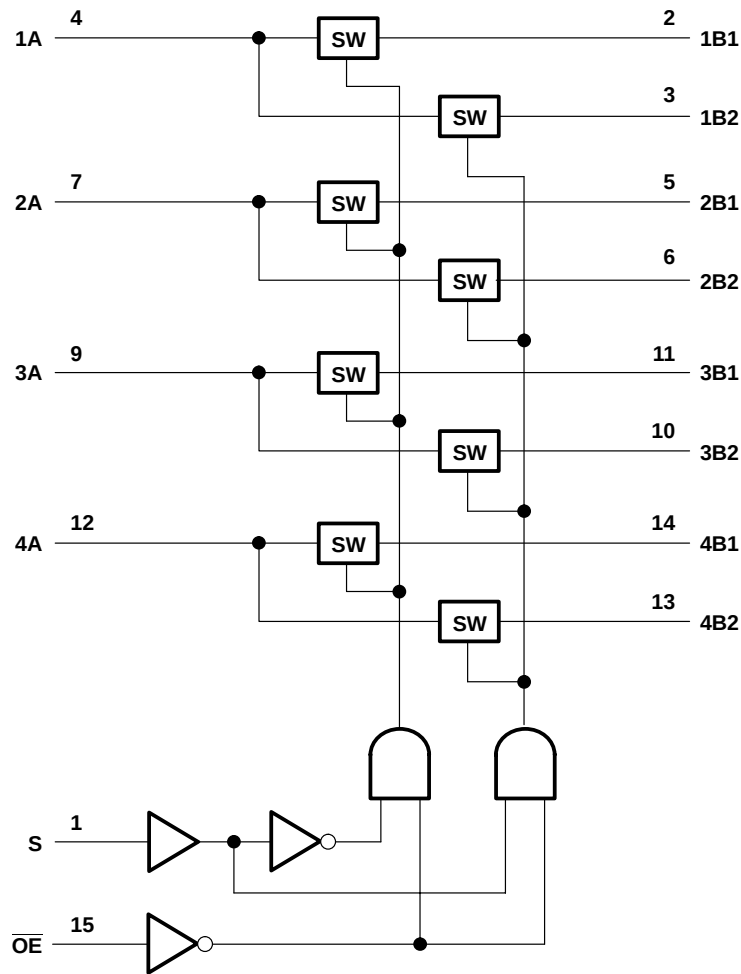
INPUTS		FUNCTION
$\overline{OE}$	S	
L	L	A port = B1 port
L	H	A port = B2 port
H	X	Disconnect

PRODUCT PREVIEW

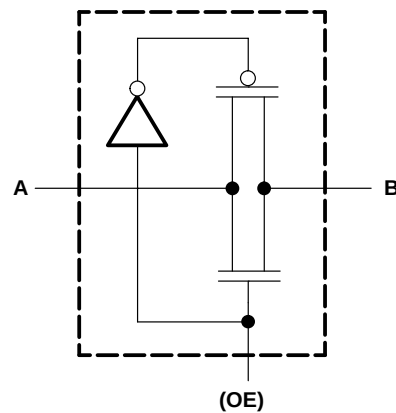
SN74CBTLV3257 LOW-VOLTAGE 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS040C – DECEMBER 1997 – REVISED OCTOBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



SN74CBTLV3257

LOW-VOLTAGE 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS040C – DECEMBER 1997 – REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGV package	180°C/W
DW package	105°C/W
PW package	149°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.3	3.6	V
V_{IH}	High-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ 1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ 2		
V_{IL}	Low-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ 0.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ 0.8		
T_A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP‡	MAX	UNIT
V _{IK}		V _{CC} = 3 V, I _I = –18 mA					–1.2	V
I _I		V _{CC} = 3.6 V, V _I = V _{CC} or GND					±1	μA
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V					10	μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND					10	μA
ΔI _{CC} [§]	Control inputs	V _{CC} = 3.6 V, One input at 3 V, Other inputs at V _{CC} or GND					300	μA
C _i	Control inputs	V _I = 3 V or 0						pF
C _{io} (OFF)	A port	V _O = 3 V or 0, $\overline{OE}$ = V _{CC}						pF
	B port							
r _{on}	V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V	V _I = 0	I _I = 64 mA				Ω	
			I _I = 24 mA					
		V _I = 1.7 V, I _I = 15 mA						
	V _{CC} = 3 V	V _I = 0	I _I = 64 mA					
			I _I = 24 mA					
		V _I = 2.4 V, I _I = 15 mA						

[‡] All typical values are at $V_{CC} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

^{\parallel} Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PRODUCT PREVIEW



SN74CBTLV3257 LOW-VOLTAGE 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

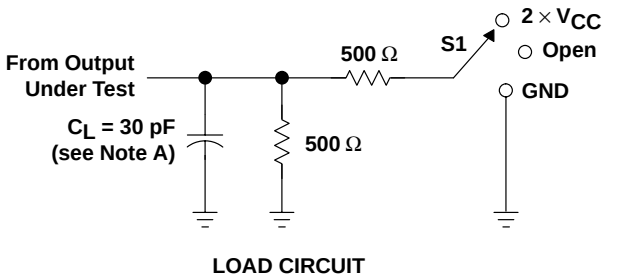
SCDS040C – DECEMBER 1997 – REVISED OCTOBER 1998

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

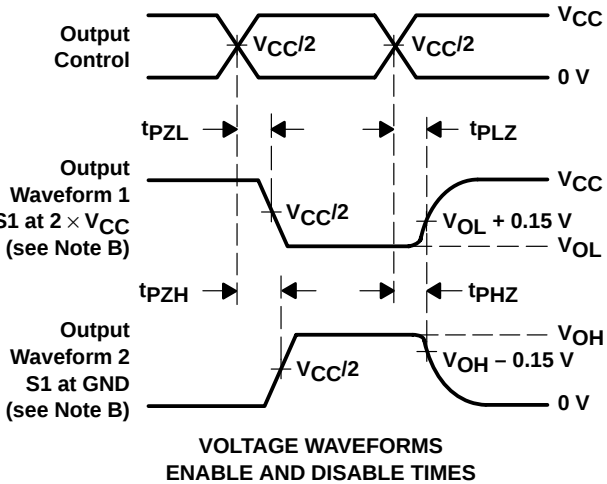
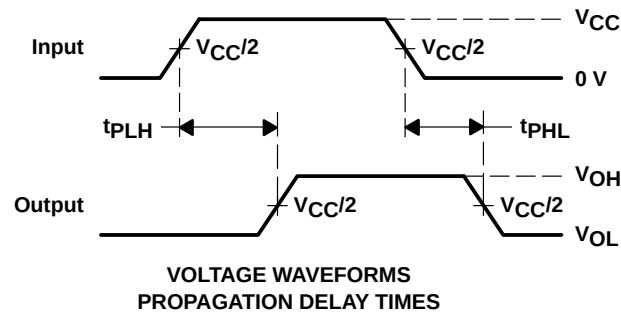
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
t_{pd}	A or B [†]	B or A					ns
	S	A or B					
t_{en}	S	A or B					ns
t_{dis}	S	A or B					ns
t_{en}	$\overline{OE}$	A or B					ns
t_{dis}	$\overline{OE}$	A or B					ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 2 $\times V_{CC}$ GND



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

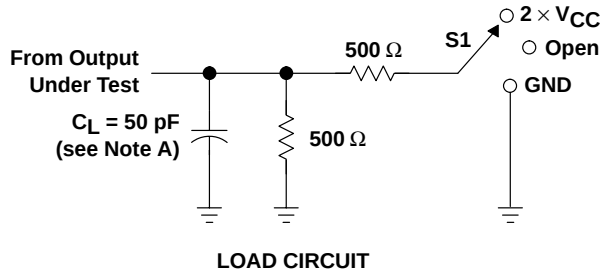
SN74CBTLV3257

LOW-VOLTAGE 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

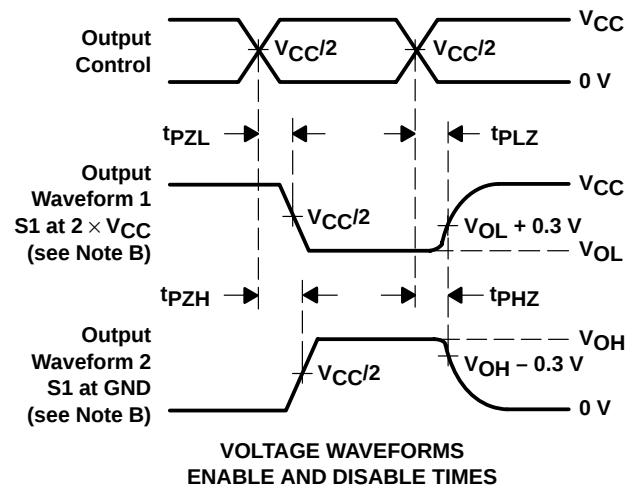
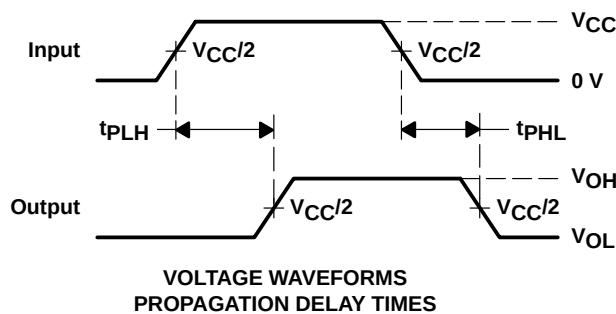
SCDS040C – DECEMBER 1997 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

PRODUCT PREVIEW

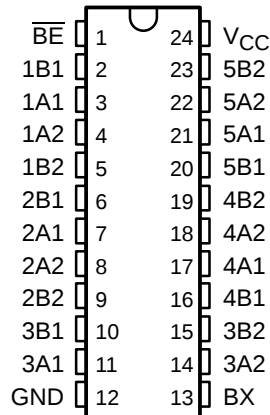
SN74CBTLV3383

LOW-VOLTAGE 10-BIT FET BUS-EXCHANGE SWITCH

SCDS047C – MARCH 1998 – REVISED NOVEMBER 1998

- Functionally Equivalent to QS3383 and QS3L383
- 5-Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Shrink Small-Outline (DBQ), Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



description

The SN74CBTLV3383 provides ten bits of high-speed bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 10-bit bus switch or a 5-bit bus exchanger, which provides swapping of the A and B pairs of signals. The bus-exchange function is selected when BX is high and $\overline{BE}$ is low.

The SN74CBTLV3383 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

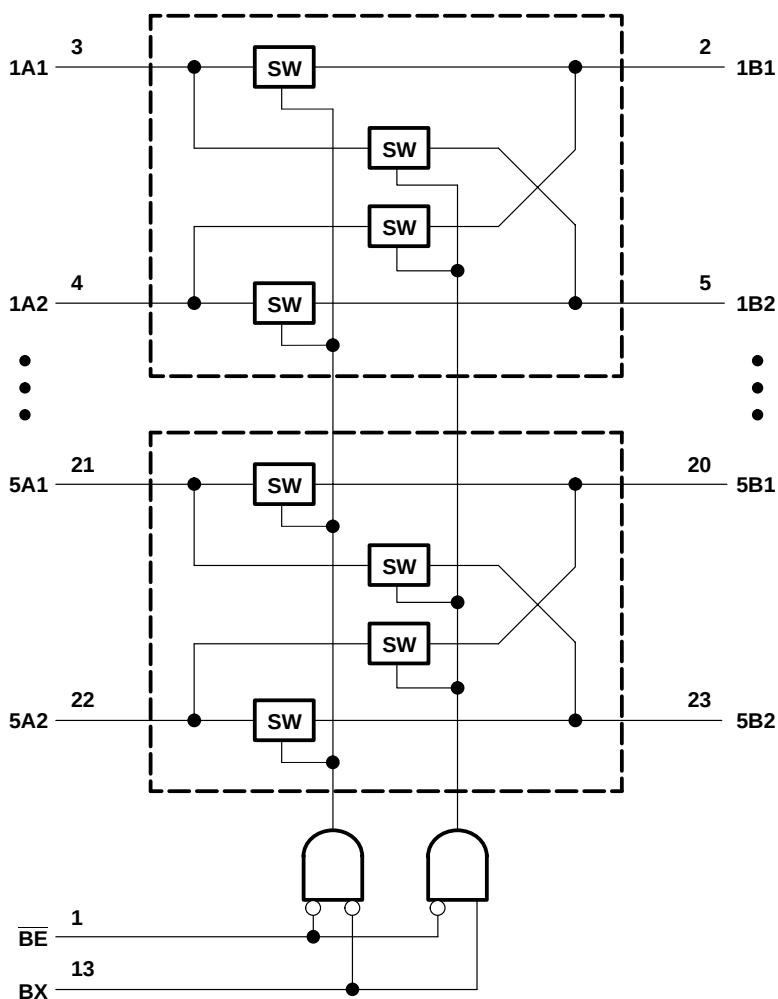
INPUTS		INPUTS/OUTPUTS	
$\overline{BE}$	BX	1A1–5A1	1A2–5A2
L	L	1B1–5B1	1B2–5B2
L	H	1B2–5B2	1B1–5B1
H	X	Z	Z

SN74CBTLV3383

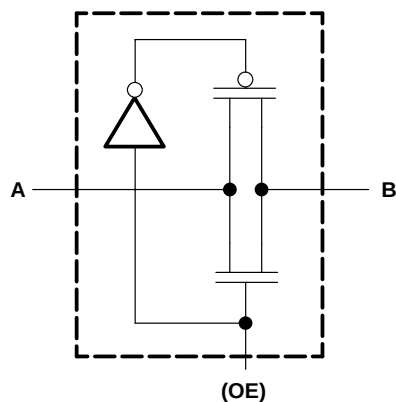
LOW-VOLTAGE 10-BIT FET BUS-EXCHANGE SWITCH

SCDS047C – MARCH 1998 – REVISED NOVEMBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



7-41

SN74CBTLV3383
LOW-VOLTAGE 10-BIT FET BUS-EXCHANGE SWITCH

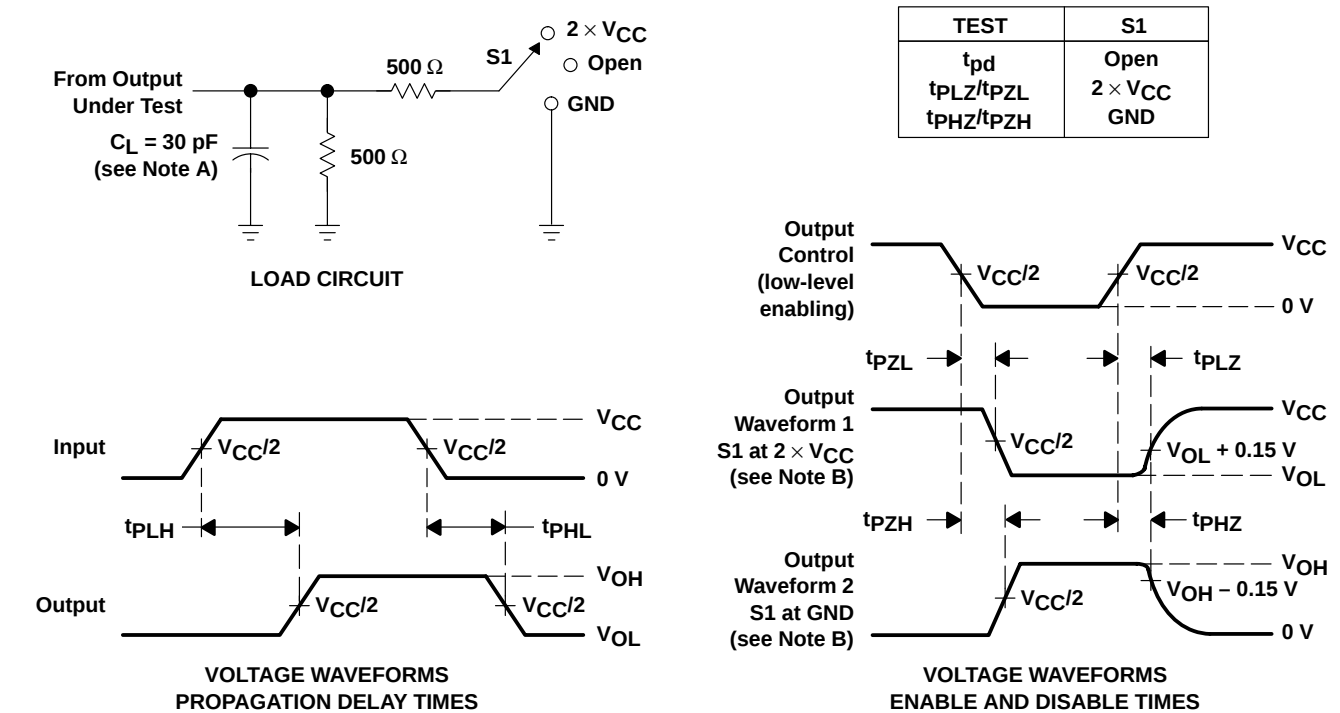
SCDS047C – MARCH 1998 – REVISED NOVEMBER 1998

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger}$	A or B	B or A	0.15		0.25		ns
t_{pd}	BX	A or B	1.5	5.8	1.5	4.7	ns
t_{en}	$\overline{BE}$	A or B	1.5	5.3	1.5	4.7	ns
t_{dis}	$\overline{BE}$	A or B	1	6	1	6	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

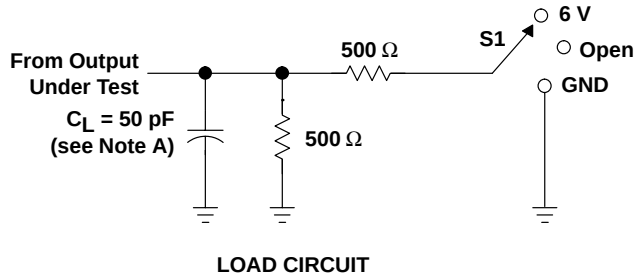


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

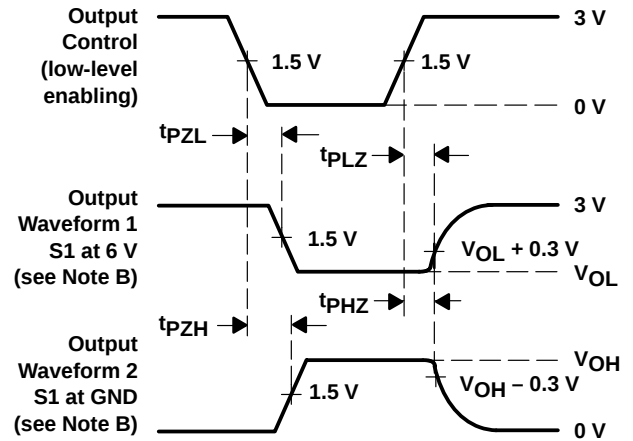
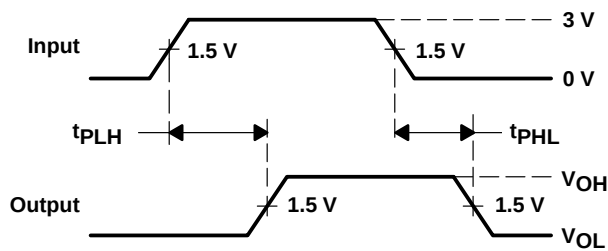
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

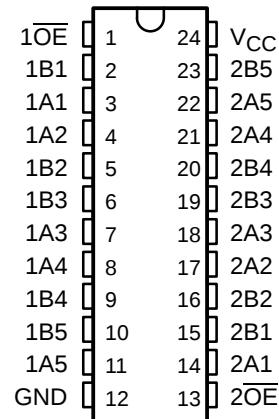
Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV3384 LOW-VOLTAGE 10-BIT FET BUS SWITCH

SCDS059B – MARCH 1998 – REVISED SEPTEMBER 1998

- Functionally Equivalent to QS3384 and QS3L384
- 5-Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Shrink Small-Outline (DBQ), Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



description

The SN74CBTLV3384 provides ten bits of high-speed bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as dual 5-bit bus switches with separate output-enable ($\overline{OE}$) inputs. It can be used as two 5-bit bus switches or one 10-bit bus switch. When $\overline{OE}$ is low, the associated 5-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV3384 is characterized for operation from -40°C to 85°C .

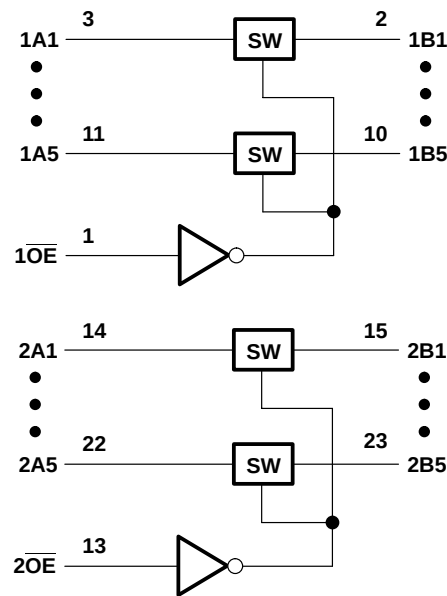
FUNCTION TABLE
(each 5-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
$\overline{1OE}$	$\overline{2OE}$	1B1–1B5	2B1–2B5
L	L	1A1–1A5	2A1–2A5
L	H	1A1–1A5	Z
H	L	Z	2A1–2A5
H	H	Z	Z

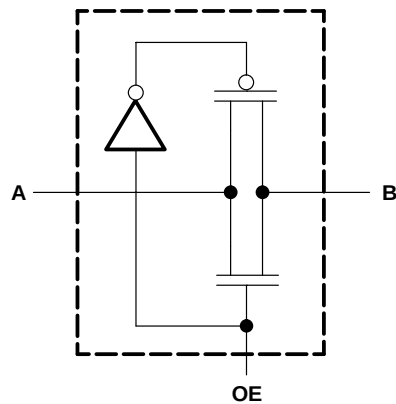
SN74CBTLV3384
LOW-VOLTAGE 10-BIT FET BUS SWITCH

SCDS059B – MARCH 1998 – REVISED SEPTEMBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{IO} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DBQ package	103°C/W
DGV package	139°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{Stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2.3	3.6	V
V _{IH}	High-level control input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level control input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V
		V _{CC} = 2.7 V to 3.6 V		0.8	
T _A	Operating free-air temperature		–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 3 V, I _I = –18 mA				–1.2	V
I _I		V _{CC} = 3.6 V, V _I = V _{CC} or GND				±1	μA
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 3.6 V				10	μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND				10	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 3.6 V, One input at 3 V, Other inputs at V _{CC} or GND				300	μA
C _i	Control inputs	V _I = 3 V or 0				4.5	pF
C _{io(OFF)}		V _O = 3 V or 0, $\overline{\text{OE}}$ = V _{CC}				10	pF
r _{on} [§]	V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V	V _I = 0	I _I = 64 mA			5	Ω
			I _I = 24 mA			5	
		V _I = 1.7 V,	I _I = 15 mA			27	
	V _{CC} = 3 V	V _I = 0	I _I = 64 mA			5	
			I _I = 24 mA			5	
		V _I = 2.4 V,	I _I = 15 mA			10	

[†] All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A		0.35		0.25	ns
t _{en}	$\overline{\text{OE}}$	A or B	1	5	1	4.3	ns
t _{dis}	$\overline{\text{OE}}$	A or B	1	5.5	1	5.5	ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

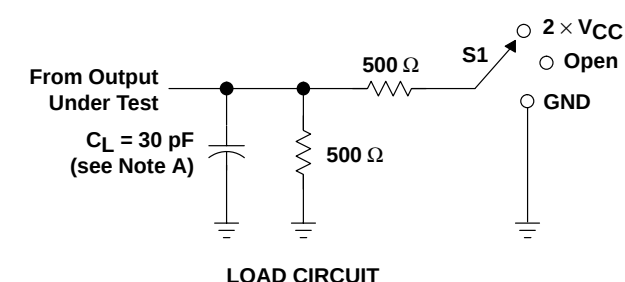
SN74CBTLV3384

LOW-VOLTAGE 10-BIT FET BUS SWITCH

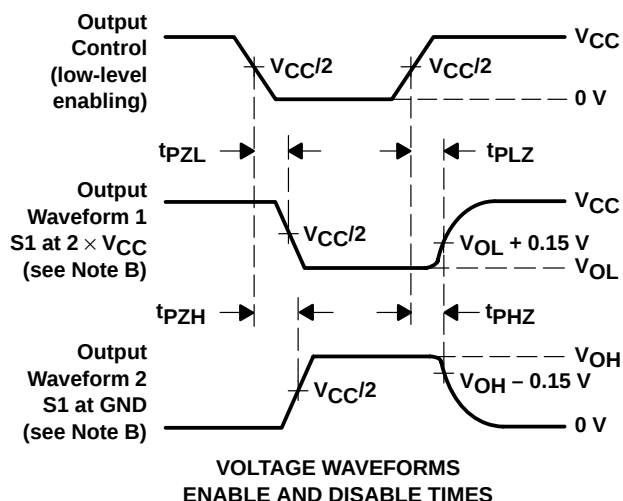
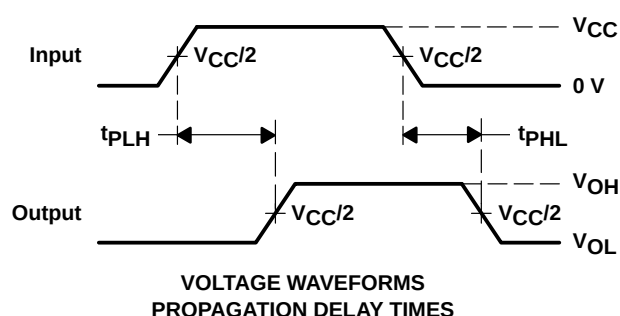
SCDS059B – MARCH 1998 – REVISED SEPTEMBER 1998

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND

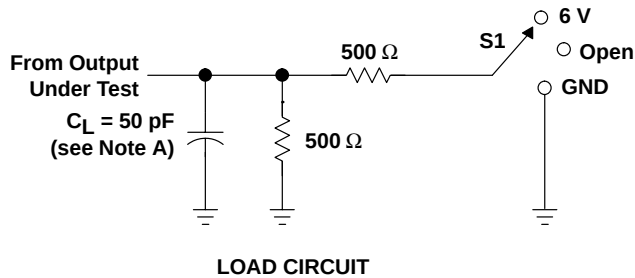


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

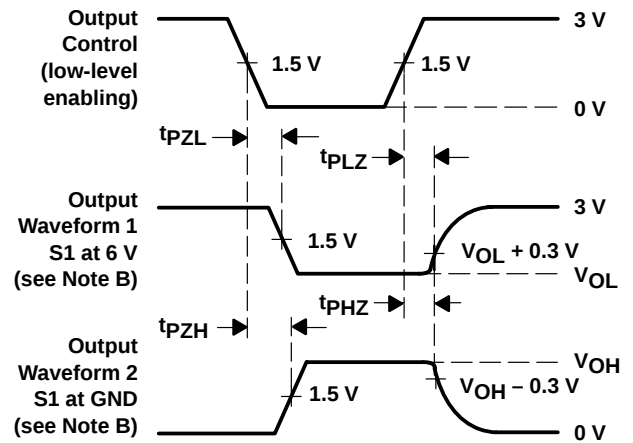
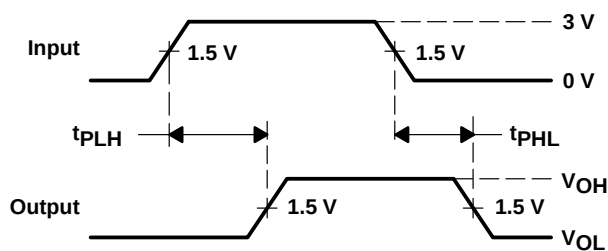
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

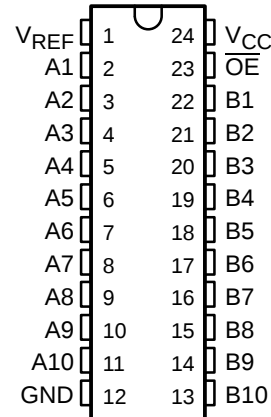
Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV3857 LOW-VOLTAGE 10-BIT FET BUS SWITCH WITH INTERNAL PULLDOWN RESISTORS

SCDS085 – OCTOBER 1998

- Enable Signal Is SSTL_2 Compatible
- Flow-Through Architecture Optimizes PCB Layout
- Designed to Be Used With 200 Mbit/s Double Data Rate (DDR) SDRAM Applications
- Switch On-State Resistance Is Designed to Eliminate the Series Resistor to the DDR SDRAM
- Internal 10-k Ω Pulldown Resistors to Ground on the B Port
- Internal 50-k Ω Pullup Resistor on the Output-Enable Input
- Package Options Include Shrink Small-Outline (DBQ), Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



description

This 10-bit FET bus switch is designed for 3-V to 3.6-V V_{CC} operation and SSTL_2 output-enable ($\overline{OE}$) input levels.

When $\overline{OE}$ is low, the 10-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

The FET switch on-state resistance is designed to replace the series terminating resistor in the SSTL_2 data path.

The CBTLV3857 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

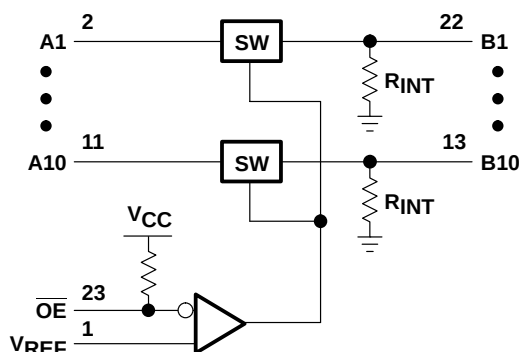
INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

PRODUCT PREVIEW

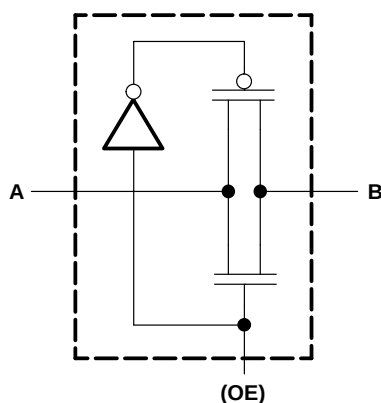
SN74CBTLV3857 LOW-VOLTAGE 10-BIT FET BUS SWITCH WITH INTERNAL PULLDOWN RESISTORS

SCDS085 – OCTOBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range (OE only), V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input voltage range (except OE), V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	48 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DBQ package	103°C/W
DGV package	139°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	3	3.3	3.6	V
V _{REF}	Reference voltage (0.38 × V _{CC})	1.15	1.25	1.35	V
V _{IH}	AC high-level control input voltage	V _{REF} + 350 mV			V
V _{IL}	AC low-level control input voltage	V _{REF} – 350 mV			V
V _{IH}	DC high-level control input voltage	V _{REF} + 180 mV			V
V _{IL}	DC low-level control input voltage	V _{REF} – 180 mV			V
T _A	Operating free-air temperature	–40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 3 V,	I _I = –18 mA			–1.2	V
I _I	$\overline{\text{OE}}$	V _{CC} = 3.6 V,	V _I = V _{CC} or GND			±1	mA
	A port					±5	μA
	B port					±1	mA
	V _{REF}					±5	μA
I _{CC}		V _{CC} = 3.6 V,	I _O = 0, V _I = V _{CC} or GND				mA
C _i	Control inputs	V _I = 3 V or 0					pF
C _{io(OFF)}		V _O = 3 V or 0,	$\overline{\text{OE}}$ = V _{CC}				pF
r _{on} [‡]		V _{CC} = 3 V	V _I = 0, I _I = 24 mA				Ω
			V _I = 0.9 V, I _I = 24 mA				
			V _I = 1.25 V, I _I = 24 mA				
			V _I = 1.6 V, I _I = 24 mA				
r _{off}		V _{CC} = 0					MΩ
		V _{CC} = 3 V to 3.6 V,	V _I = 1.65 V				

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[‡] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	
t _{pd} [§]	A or B	B or A			ns
t _{en}	$\overline{\text{OE}}$	A or B			ns
t _{dis}	$\overline{\text{OE}}$	A or B			ns

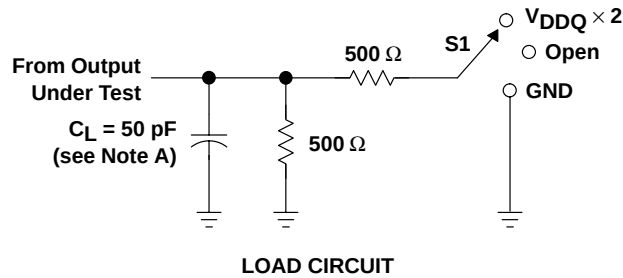
[§] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).

SN74CBTLV3857 LOW-VOLTAGE 10-BIT FET BUS SWITCH WITH INTERNAL PULLDOWN RESISTORS

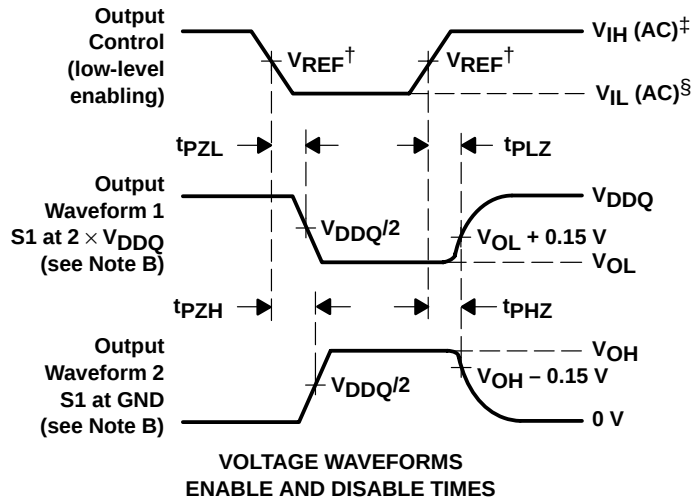
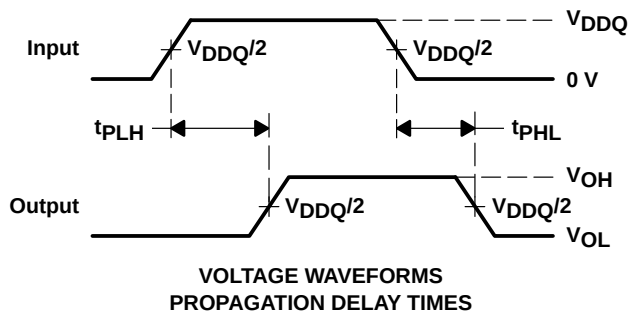
SCDS085 – OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ AND $V_{DDQ} = 2.5 \pm 0.2 \text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open $V_{DDQ} \times 2$ GND



$^{\dagger} V_{REF} = 0.38 \times V_{CC}$

$^{\ddagger} V_{IH} (AC) = V_{REF} + 350 \text{ mV}$

$^{\S} V_{IL} (AC) = V_{REF} - 350 \text{ mV}$

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 1.25 \text{ ns/V}$, $t_f \leq 1.25 \text{ ns/V}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTLV3861
LOW-VOLTAGE 10-BIT FET BUS SWITCH

SCDS041C – DECEMBER 1997 – REVISED OCTOBER 1998

- Functionally Equivalent to QS3861
- 5- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Thin Very Small-Outline (DGV), Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

description

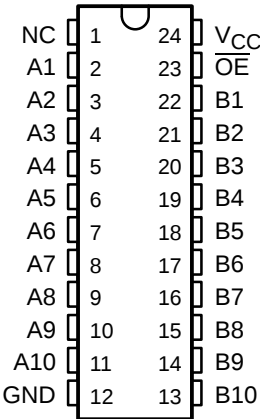
The SN74CBTLV3861 provides ten bits of high-speed bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 10-bit bus switch. When output enable ($\overline{OE}$) is low, the 10-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open and a high-impedance state exists between the two ports.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV3861 is characterized for operation from -40°C to 85°C .

DGV, DW, OR PW PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

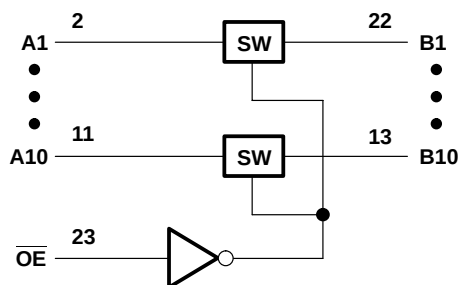
PRODUCT PREVIEW

SN74CBTLV3861

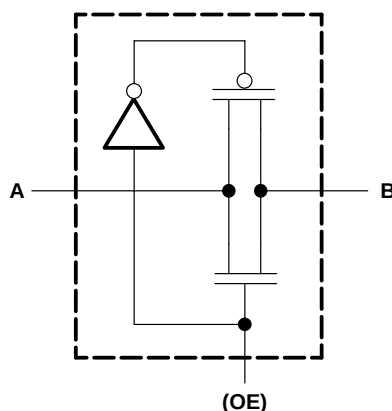
LOW-VOLTAGE 10-BIT FET BUS SWITCH

SCDS041C – DECEMBER 1997 – REVISED OCTOBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGV package	139°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	2.3	3.6	V
V _{IH}	High-level control input voltage	V _{CC} = 2.3 V to 2.7 V 1.7		V
		V _{CC} = 2.7 V to 3.6 V 2		
V _{IL}	Low-level control input voltage	V _{CC} = 2.3 V to 2.7 V 0.7		V
		V _{CC} = 2.7 V to 3.6 V 0.8		
T _A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 3 V, I _I = –18 mA			–1.2	V
I _I	V _{CC} = 3.6 V, V _I = V _{CC} or GND			±1	μA
I _{off}	V _{CC} = 0, V _I or V _O = 0 to 3.6 V			10	μA
I _{CC}	V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND			10	μA
ΔI _{CC} [‡]	Control inputs V _{CC} = 3.6 V, One input at 3 V, Other inputs at V _{CC} or GND			300	μA
C _i	Control inputs V _I = 3 V or 0				pF
C _{io(OFF)}	V _O = 3 V or 0, $\overline{OE}$ = V _{CC}				pF
r _{on} [§]	V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V	V _I = 0	I _I = 64 mA		Ω
			I _I = 24 mA		
		V _I = 1.7 V,	I _I = 15 mA		
	V _{CC} = 3 V	V _I = 0	I _I = 64 mA		
			I _I = 24 mA		
		V _I = 2.4 V,	I _I = 15 mA		

[†] All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

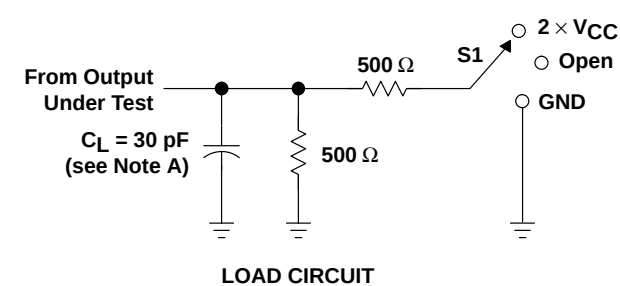
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A					ns
t _{en}	$\overline{OE}$	A or B					ns
t _{dis}	$\overline{OE}$	A or B					ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

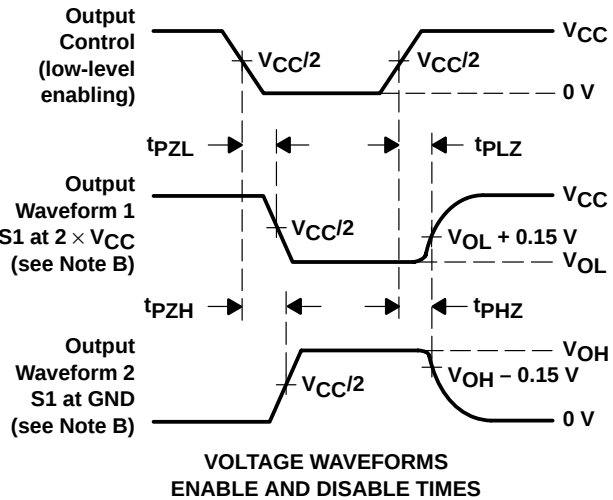
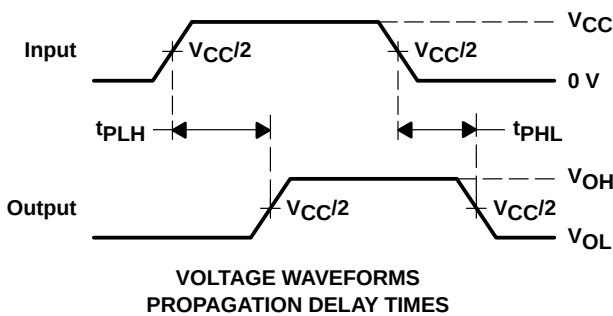
SN74CBTLV3861
LOW-VOLTAGE 10-BIT FET BUS SWITCH

SCDS041C – DECEMBER 1997 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open $2 \times V_{CC}$ GND

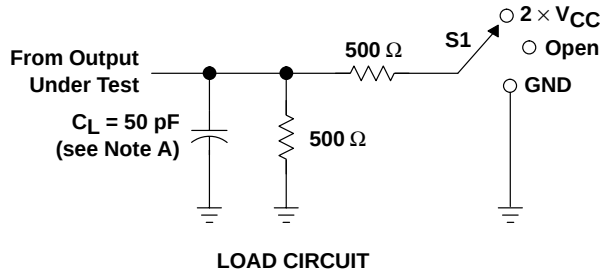


- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
F. t_{PZL} and t_{PZH} are the same as t_{en} .
G. t_{PLH} and t_{PHL} are the same as t_{pd} .

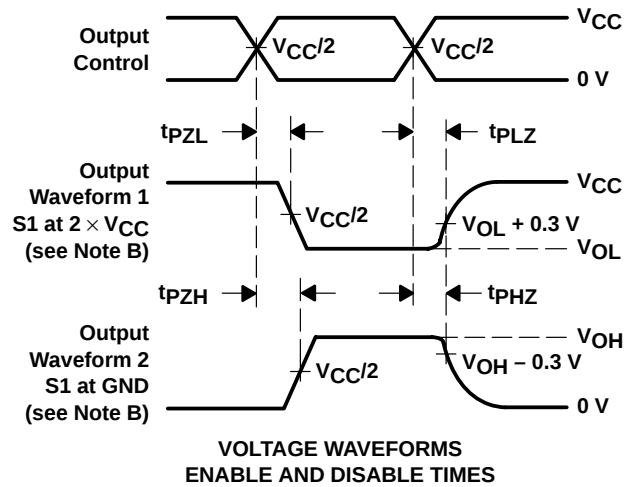
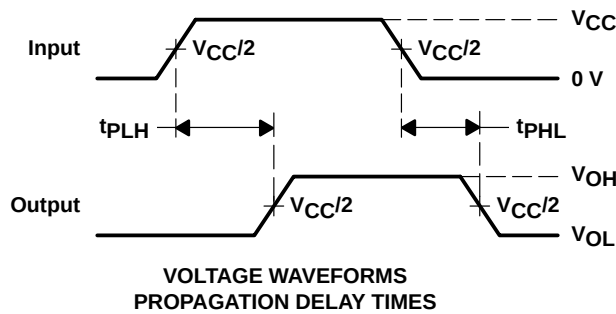
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

General Information	1
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CBT Widebus™	4
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CBTLV Widebus™

SN74CBTLV16210 LOW-VOLTAGE 20-BIT FET BUS SWITCH

SCDS042D – DECEMBER 1997 – REVISED NOVEMBER 1998

- 5- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

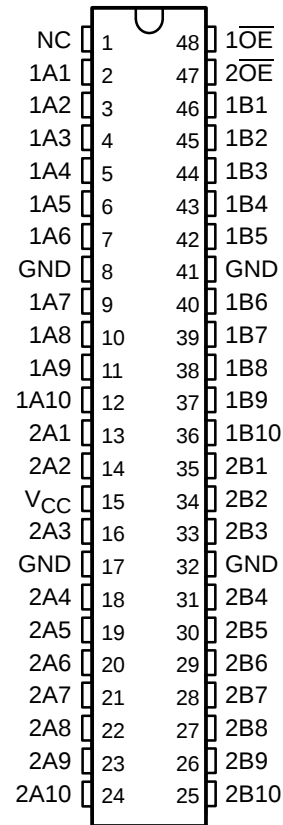
The SN74CBTLV16210 provides 20 bits of high-speed bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as dual 10-bit bus switches with separate output-enable ($\overline{OE}$) inputs. It can be used as two 10-bit bus switches or one 20-bit bus switch. When $\overline{OE}$ is low, the associated 10-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV16210 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE
(each 10-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

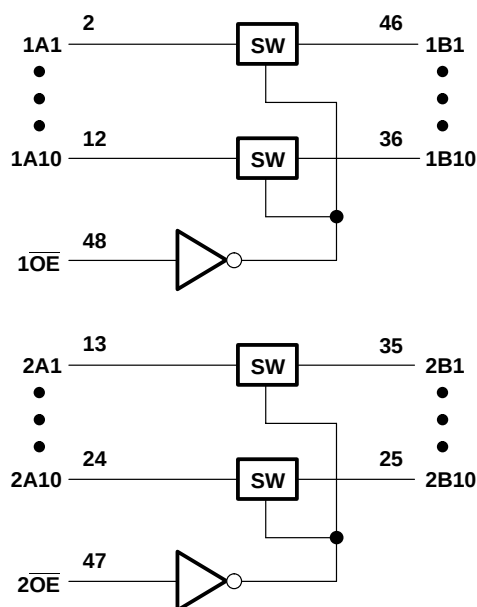
PRODUCT PREVIEW

SN74CBTLV16210

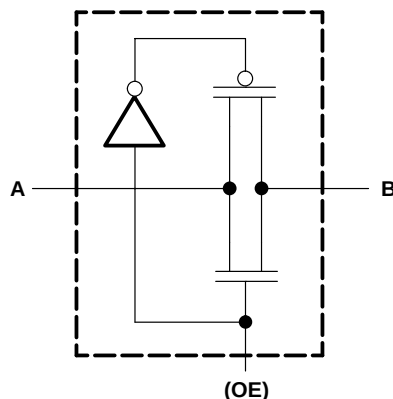
LOW-VOLTAGE 20-BIT FET BUS SWITCH

SCDS042D – DECEMBER 1997 – REVISED NOVEMBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	2.3	3.6	V
V _{IH}	High-level control input voltage	V _{CC} = 2.3 V to 2.7 V	1.7	V
		V _{CC} = 2.7 V to 3.6 V	2	
V _{IL}	Low-level control input voltage	V _{CC} = 2.3 V to 2.7 V	0.7	V
		V _{CC} = 2.7 V to 3.6 V	0.8	
T _A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 3 V, I _I = –18 mA				–1.2	V
I _I		V _{CC} = 3.6 V, V _I = V _{CC} or GND				±1	μA
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 3.6 V				10	μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND				10	μA
ΔI _{CC} [‡]	Control inputs	V _{CC} = 3.6 V, One input at 3 V, Other inputs at V _{CC} or GND				300	μA
C _i	Control inputs	V _I = 3 V or 0					pF
C _{io} (OFF)		V _O = 3 V or 0, $\overline{\text{OE}}$ = V _{CC}					pF
r _{on} [§]	V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V	V _I = 0	I _I = 64 mA				Ω
			I _I = 24 mA				
		V _I = 1.7 V	I _I = 15 mA				
	V _{CC} = 3 V	V _I = 0	I _I = 64 mA				
			I _I = 24 mA				
		V _I = 2.4 V	I _I = 15 mA				

[†] All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

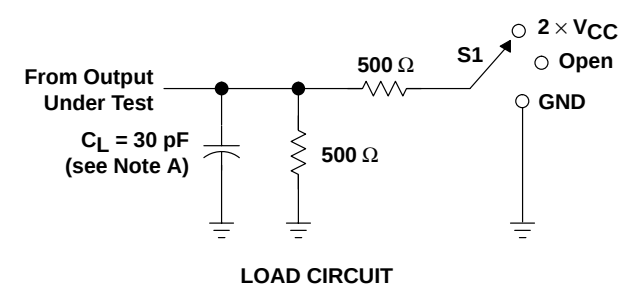
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A					ns
t _{en}	$\overline{\text{OE}}$	A or B					ns
t _{dis}	$\overline{\text{OE}}$	A or B					ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

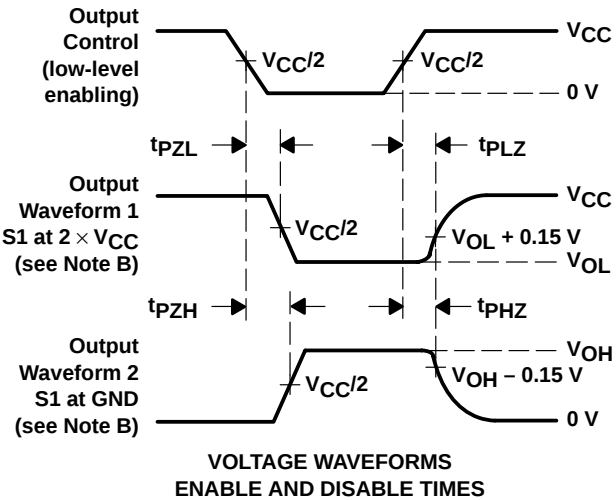
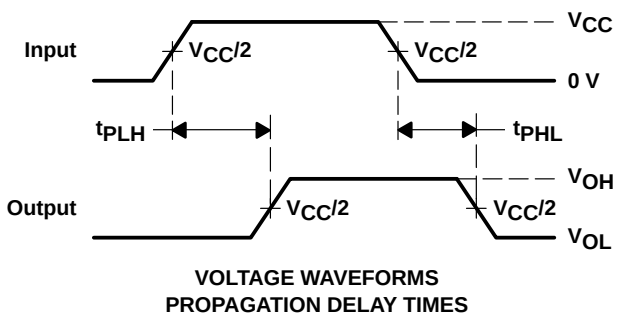
SN74CBTLV16210 LOW-VOLTAGE 20-BIT FET BUS SWITCH

SCDS042D – DECEMBER 1997 – REVISED NOVEMBER 1998

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZH}	Open 2 $\times V_{CC}$ GND

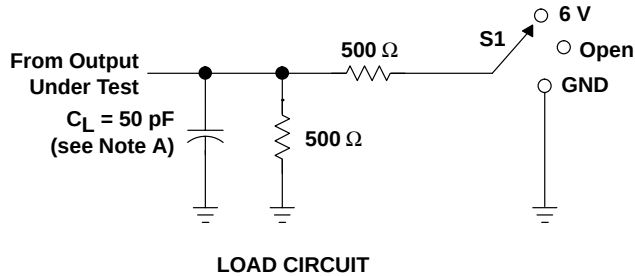


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

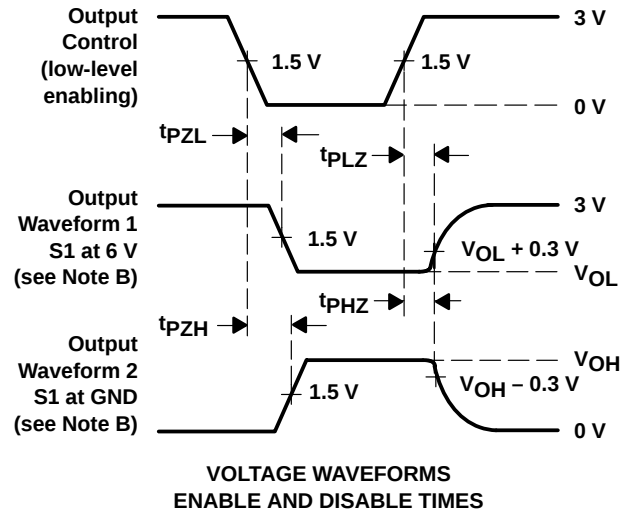
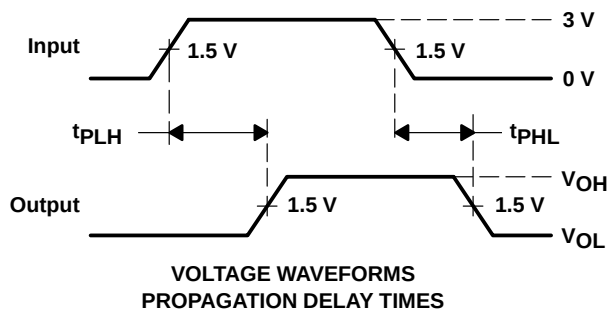
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV16211 LOW-VOLTAGE 24-BIT FET BUS SWITCH

SCDS043D – DECEMBER 1997 – REVISED NOVEMBER 1998

- 5- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

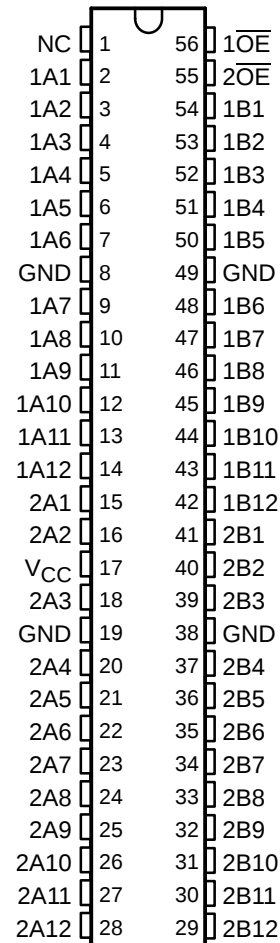
The SN74CBTLV16211 provides 24 bits of high-speed bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as dual 12-bit bus switches with separate output-enable ($\overline{OE}$) inputs. It can be used as two 12-bit bus switches or one 24-bit bus switch. When $\overline{OE}$ is low, the associated 12-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and a high-impedance state exists between the two ports.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV16211 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE
(each 12-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

PRODUCT PREVIEW

logic diagram (positive logic)



† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	2.3	3.6	V
V _{IH}	High-level control input voltage	V _{CC} = 2.3 V to 2.7 V 1.7		V
		V _{CC} = 2.7 V to 3.6 V 2		
V _{IL}	Low-level control input voltage	V _{CC} = 2.3 V to 2.7 V 0.7		V
		V _{CC} = 2.7 V to 3.6 V 0.8		
T _A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 3 V, I _I = –18 mA			–1.2	V
I _I	V _{CC} = 3.6 V, V _I = V _{CC} or GND			±1	μA
I _{off}	V _{CC} = 0, V _I or V _O = 0 to 3.6 V			10	μA
I _{CC}	V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND			10	μA
ΔI _{CC} [‡]	Control inputs V _{CC} = 3.6 V, One input at 3 V, Other inputs at V _{CC} or GND			300	μA
C _i	Control inputs V _I = 3 V or 0				pF
C _{io} (OFF)	V _O = 3 V or 0, $\overline{OE}$ = V _{CC}				pF
r _{on} [§]	V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V	V _I = 0	I _I = 64 mA		Ω
			I _I = 24 mA		
		V _I = 1.7 V,	I _I = 15 mA		
	V _{CC} = 3 V	V _I = 0	I _I = 64 mA		
			I _I = 24 mA		
		V _I = 2.4 V,	I _I = 15 mA		

[†] All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

[‡] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

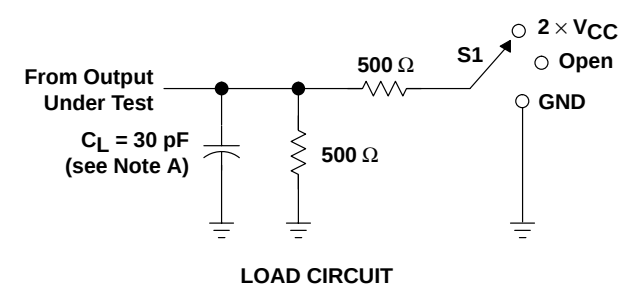
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [¶]	A or B	B or A					ns
t _{en}	$\overline{OE}$	A or B					ns
t _{dis}	$\overline{OE}$	A or B					ns

[¶] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

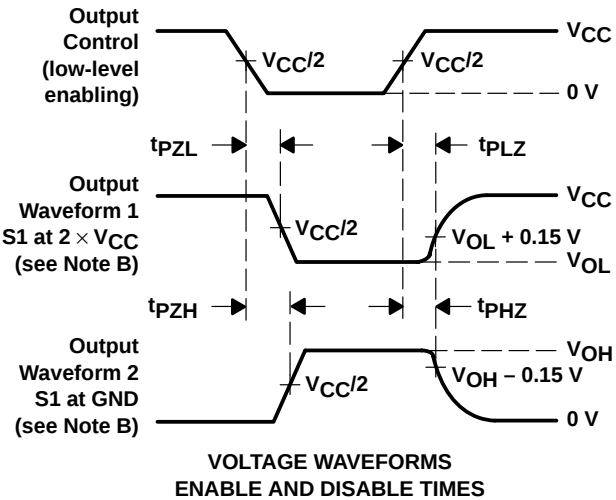
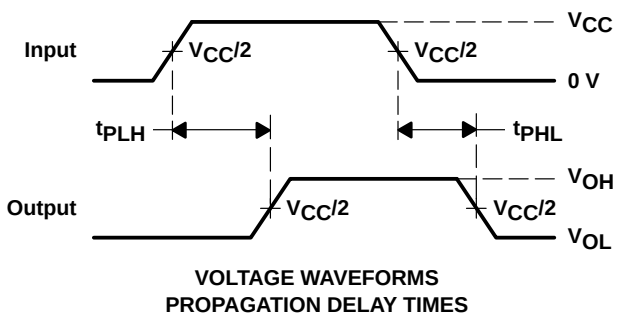
SN74CBTLV16211
LOW-VOLTAGE 24-BIT FET BUS SWITCH

SCDS043D – DECEMBER 1997 – REVISED NOVEMBER 1998

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZH}	Open $2 \times V_{CC}$ GND

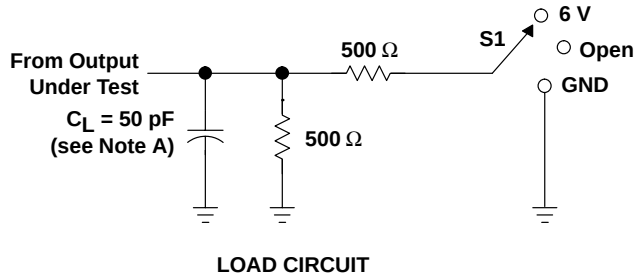


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

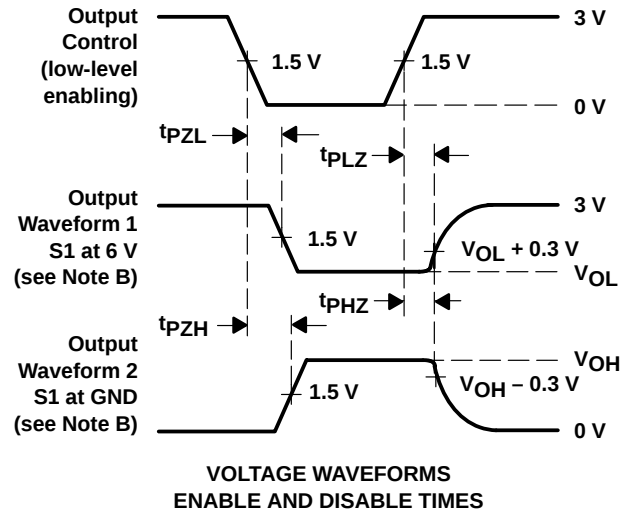
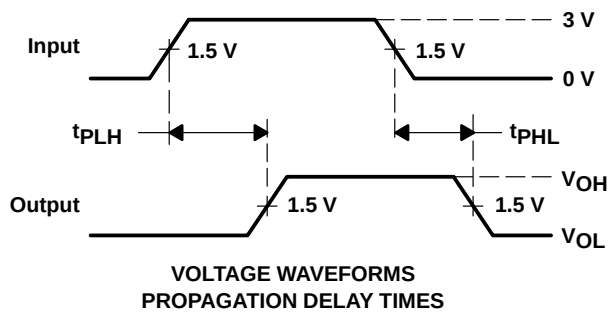
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV16212

LOW-VOLTAGE 24-BIT FET BUS-EXCHANGE SWITCH

SCDS044D – DECEMBER 1997 – REVISED NOVEMBER 1998

- 4-Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Break-Before-Make Feature
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

The SN74CBTLV16212 provides 24 bits of high-speed bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 24-bit bus switch or a 12-bit bus exchanger, which provides data exchanging between the four signal ports via the data-select (S0, S1, S2) terminals.

The SN74CBTLV16212 is specified by the break-before-make design to have no through current when switching directions.

The SN74CBTLV16212 is characterized for operation from –40°C to 85°C.

DGG, DGV, OR DL PACKAGE
(TOP VIEW)

S0	1	56	S1
1A1	2	55	S2
1A2	3	54	1B1
2A1	4	53	1B2
2A2	5	52	2B1
3A1	6	51	2B2
3A2	7	50	3B1
GND	8	49	GND
4A1	9	48	3B2
4A2	10	47	4B1
5A1	11	46	4B2
5A2	12	45	5B1
6A1	13	44	5B2
6A2	14	43	6B1
7A1	15	42	6B2
7A2	16	41	7B1
V _{CC}	17	40	7B2
8A1	18	39	8B1
GND	19	38	GND
8A2	20	37	8B2
9A1	21	36	9B1
9A2	22	35	9B2
10A1	23	34	10B1
10A2	24	33	10B2
11A1	25	32	11B1
11A2	26	31	11B2
12A1	27	30	12B1
12A2	28	29	12B2

FUNCTION TABLE

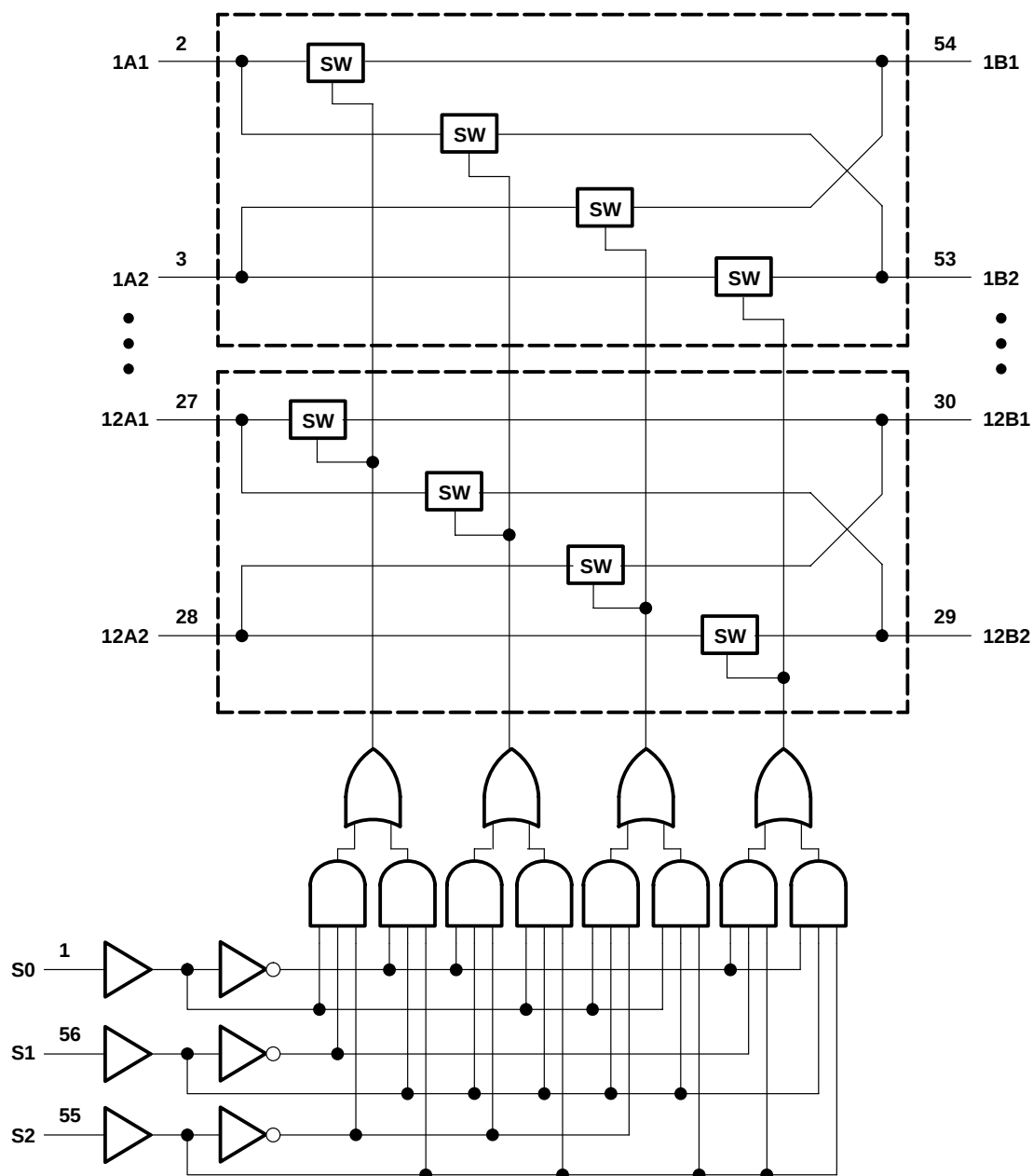
INPUTS			INPUTS/OUTPUTS		FUNCTION
S2	S1	S0	A1	A2	
L	L	L	Z	Z	Disconnect
L	L	H	B1	Z	A1 port = B1 port
L	H	L	B2	Z	A1 port = B2 port
L	H	H	Z	B1	A2 port = B1 port
H	L	L	Z	B2	A2 port = B2 port
H	L	H	Z	Z	Disconnect
H	H	L	B1	B2	A1 port = B1 port A2 port = B2 port
H	H	H	B2	B1	A1 port = B2 port A2 port = B1 port

SN74CBTLV16212

LOW-VOLTAGE 24-BIT FET BUS-EXCHANGE SWITCH

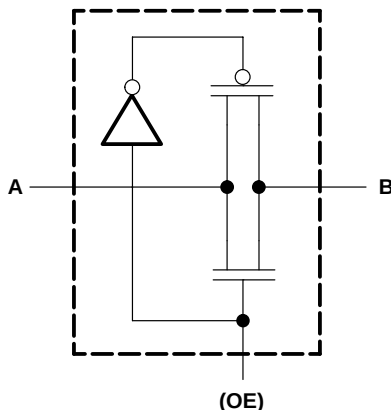
SCDS044D – DECEMBER 1997 – REVISED NOVEMBER 1998

logic diagram (positive logic)



PRODUCT PREVIEW

simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	−0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	−0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	−50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DGG package	81°C/W
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T_{sta}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES:

1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2.3	3.6	V
V _{IH}	High-level control input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level control input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V
		V _{CC} = 2.7 V to 3.6 V		0.8	
T _A	Operating free-air temperature		−40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74CBTLV16212

LOW-VOLTAGE 24-BIT FET BUS-EXCHANGE SWITCH

SCDS044D – DECEMBER 1997 – REVISED NOVEMBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 3\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
I_I		$V_{CC} = 3.6\text{ V}$,	$V_I = V_{CC}$ or GND			± 1	μA
I_{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 3.6 V			10	μA
I_{CC}		$V_{CC} = 3.6\text{ V}$,	$I_O = 0$, $V_I = V_{CC}$ or GND			10	μA
$\Delta I_{CC}^{\ddagger}$	Control inputs	$V_{CC} = 3.6\text{ V}$,	One input at 3 V , Other inputs at V_{CC} or GND			300	μA
C_i	Control inputs	$V_I = 3\text{ V}$ or 0					pF
$C_{io(OFF)}$		$V_O = 3\text{ V}$ or 0 , $\overline{OE} = V_{CC}$					pF
$r_{on}^{\S}$	$V_{CC} = 2.3\text{ V}$, TYP at $V_{CC} = 2.5\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$				Ω
			$I_I = 24\text{ mA}$				
		$V_I = 1.7\text{ V}$,	$I_I = 15\text{ mA}$				
	$V_{CC} = 3\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$				
			$I_I = 24\text{ mA}$				
		$V_I = 2.4\text{ V}$,	$I_I = 15\text{ mA}$				

[†] All typical values are at $V_{CC} = 3.3\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

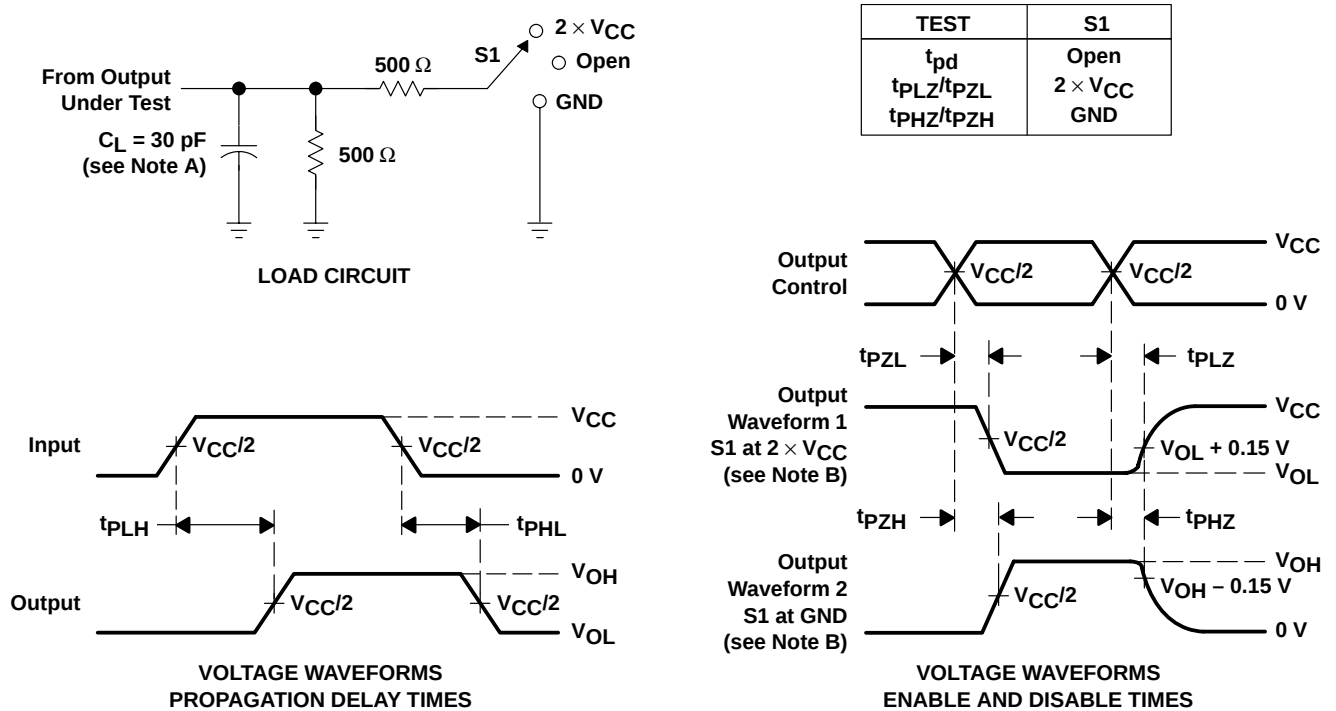
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A					ns
t_{pd}	S	B or A					ns
t_{en}	S	A or B					ns
t_{dis}	S	A or B					ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74CBTLV16212
LOW-VOLTAGE 24-BIT FET BUS-EXCHANGE SWITCH

SCDS044D – DECEMBER 1997 – REVISED NOVEMBER 1998

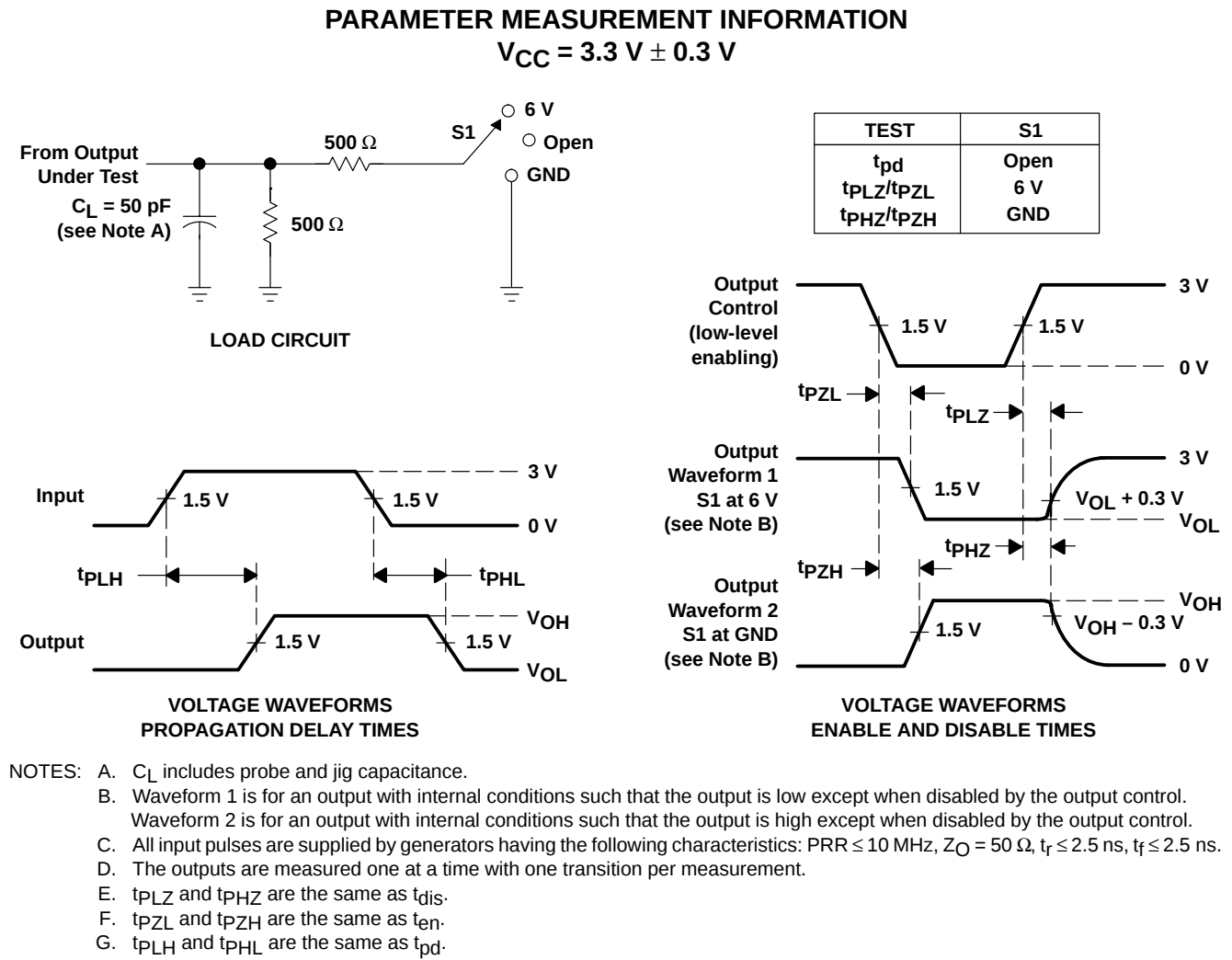


Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV16235 LOW-VOLTAGE 18-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS060B – MARCH 1998 – REVISED OCTOBER 1998

- 4-Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Break-Before-Make Feature
- Packaged in Plastic Thin Shrink Small-Outline Package

description

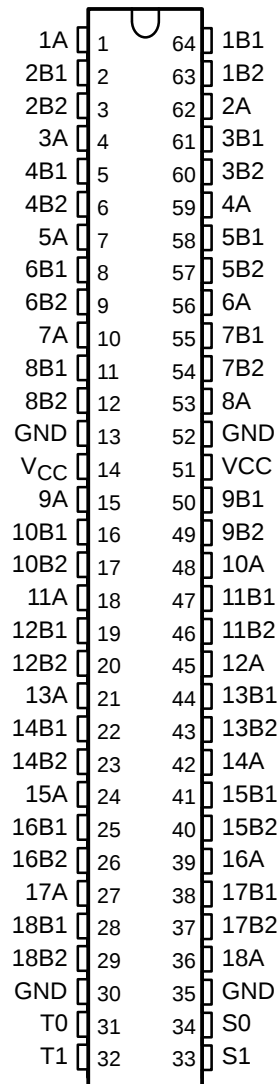
The SN74CBTLV16235 is an 18-bit 1-of-2 FET multiplexer/demultiplexer used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single path. This device can be used for memory interleaving, where two different banks of memory need to be addressed simultaneously.

The device is organized as a dual 9-bit 1-of-2 multiplexer/demultiplexer with separate control inputs. It can be used as two 9-bit multiplexer/demultiplexers or as one 18-bit multiplexer/demultiplexer. Two select (S0 and S1) inputs control the data flow. When the test (T0 and T1) inputs are asserted, port A is connected to both ports B1 and B2. The control inputs can be driven with a 5-V CMOS, a 5-V TTL, a low-voltage TTL, or an SSTL_3 driver.

The SN74CBTLV16235 is specified by the break-before-make design to have no through current when switching directions.

The SN74CBTLV16235 is characterized for operation from –40°C to 85°C.

DGG PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each 9-bit multiplexer/demultiplexer)

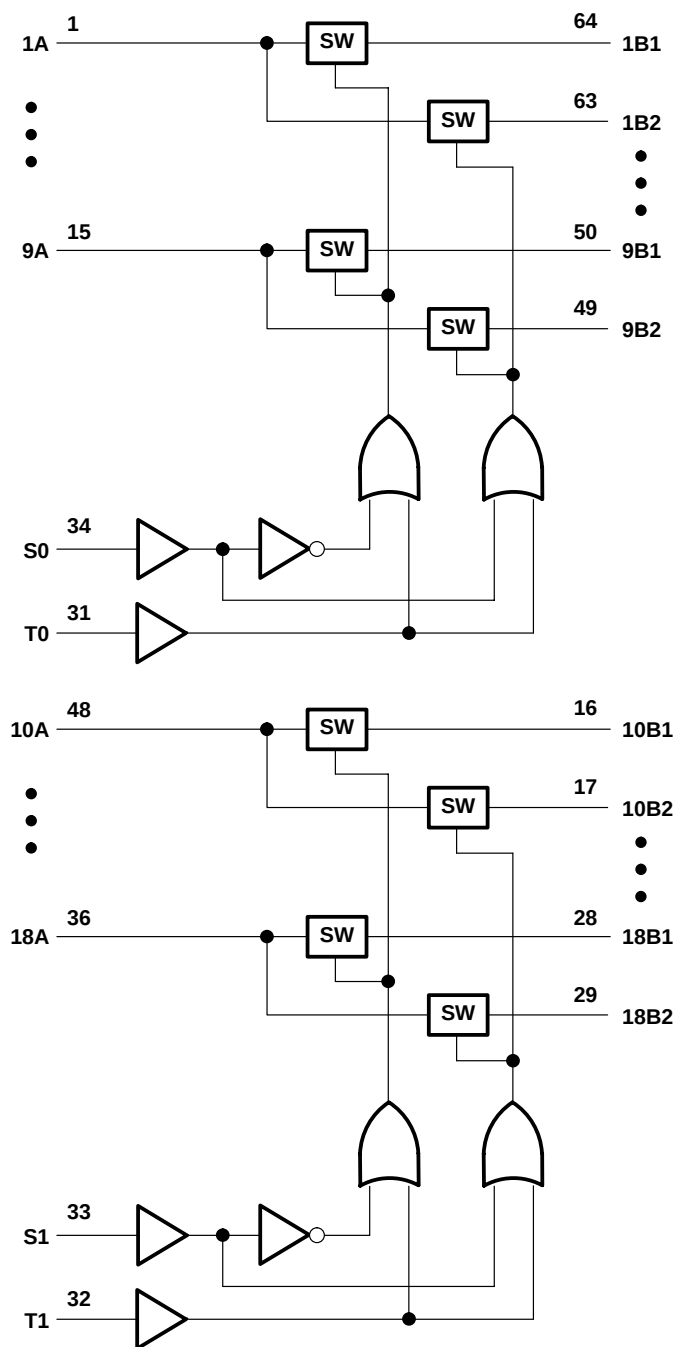
INPUTS		FUNCTION
T	S	
L	L	A port = B1 port
L	H	A port = B2 port
H	X	A port = B1 port = B2 port

SN74CBTLV16235

LOW-VOLTAGE 18-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS060B – MARCH 1998 – REVISED OCTOBER 1998

logic diagram (positive logic)

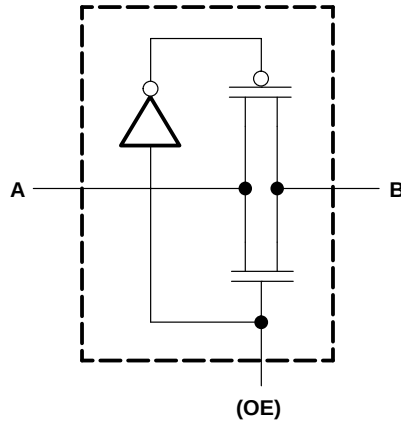


SN74CBTLV16235

LOW-VOLTAGE 18-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS060B – MARCH 1998 – REVISED OCTOBER 1998

simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2)	73°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.3	3.6	V
V_{IH}	High-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
V_{IL}	Low-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
T_A	Operating free-air temperature		–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

PRODUCT PREVIEW

SN74CBTLV16235

LOW-VOLTAGE 18-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS060B – MARCH 1998 – REVISED OCTOBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}		$V_{CC} = 3\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
I_I		$V_{CC} = 3.6\text{ V}$,	$V_I = V_{CC}$ or GND			± 5	μA
I_{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 3.6 V			10	μA
I_{CC}		$V_{CC} = 3.6\text{ V}$,	$I_O = 0$, $V_I = V_{CC}$ or GND			10	μA
$\Delta I_{CC}^{\ddagger}$	Control input	$V_{CC} = 3.6\text{ V}$,	One input at 3 V, Other inputs at V_{CC} or GND			300	μA
C_i	Control input	$V_I = 3\text{ V}$ or 0					pF
$C_{io(OFF)}$		$V_O = 3\text{ V}$ or 0					pF
$r_{on}^{\S}$	$V_{CC} = 2.3\text{ V}$, TYP at $V_{CC} = 2.5\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$				Ω
			$I_I = 24\text{ mA}$				
		$V_I = 1.7\text{ V}$,	$I_I = 15\text{ mA}$				
	$V_{CC} = 3\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$				
			$I_I = 24\text{ mA}$				
		$V_I = 2.4\text{ V}$,	$I_I = 15\text{ mA}$				

[†] All typical values are at $V_{CC} = 3.3\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

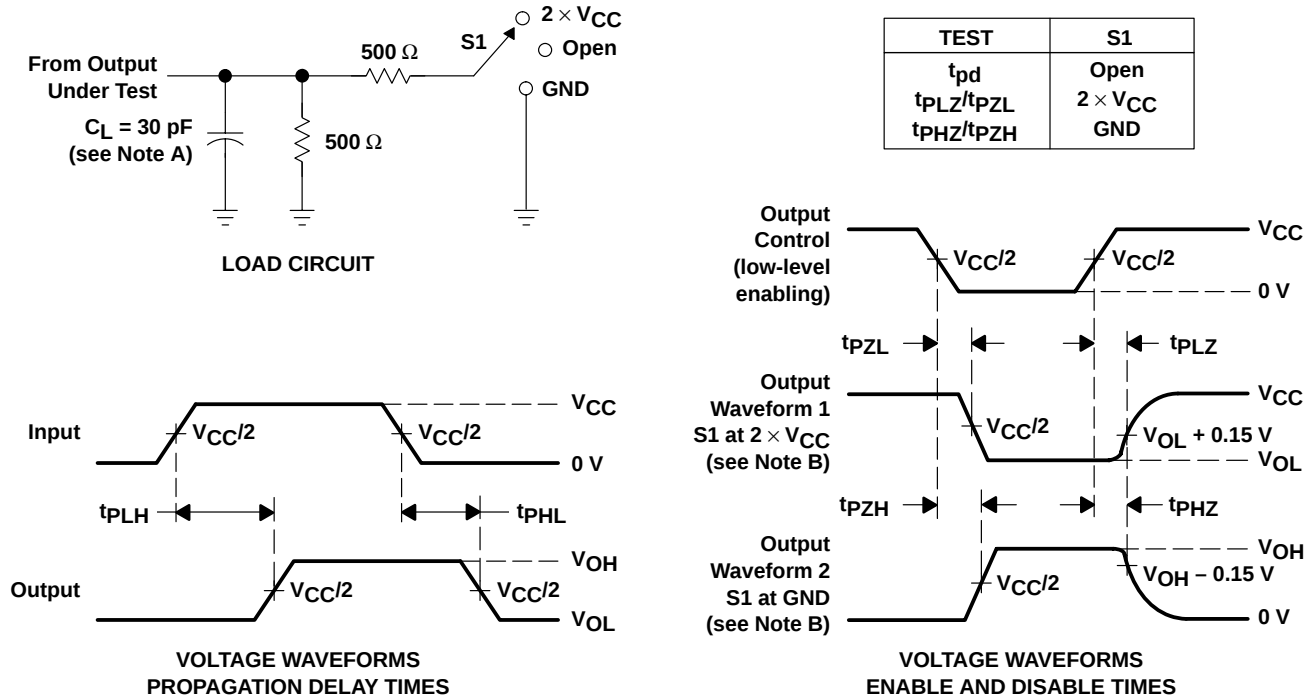
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A					ns
t_{en}	S	A or B					ns
t_{dis}	S	A or B					ns
t_{en}	T	A or B					ns
t_{dis}	T	A or B					ns

^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$



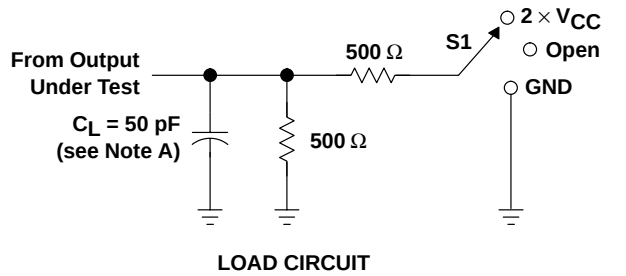
- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

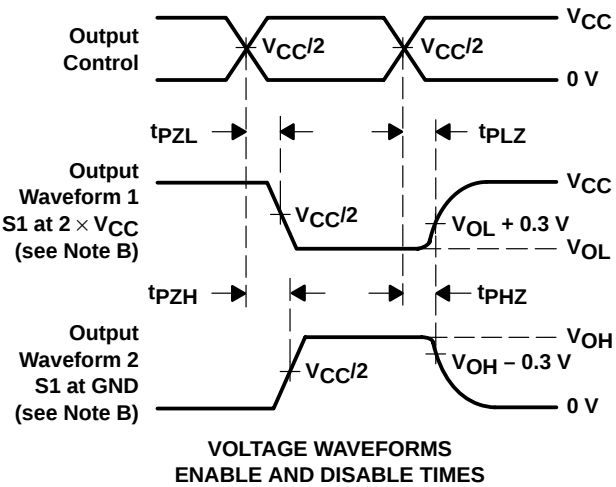
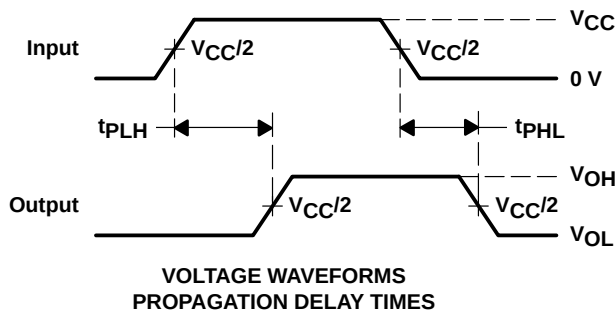
SN74CBTLV16235
LOW-VOLTAGE 18-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS060B – MARCH 1998 – REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 2 $\times V_{CC}$ GND



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV16292

LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS055C – MARCH 1998 – REVISED NOVEMBER 1998

- 4- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Make-Before-Break Feature
- Internal 500- Ω Pulldown Resistors to Ground
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

The SN74CBTLV16292 is a 12-bit 1-of-2 high-speed FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

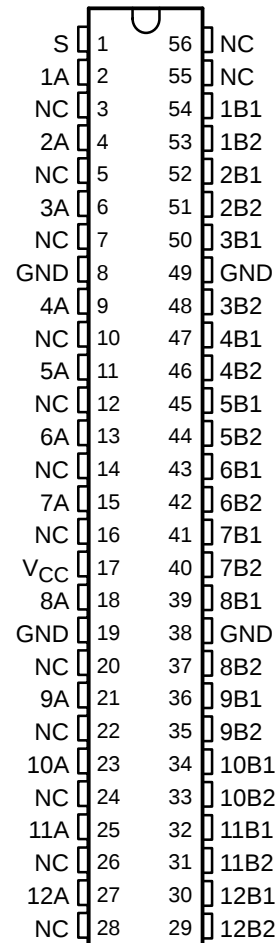
When the select (S) input is low, port A is connected to port B1 and R_{INT} is connected to port B2. When S is high, port A is connected to port B2 and R_{INT} is connected to port B1.

The SN74CBTLV16292 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT S	FUNCTION
L	A port = B1 port R_{INT} = B2 port
H	A port = B2 port R_{INT} = B1 port

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



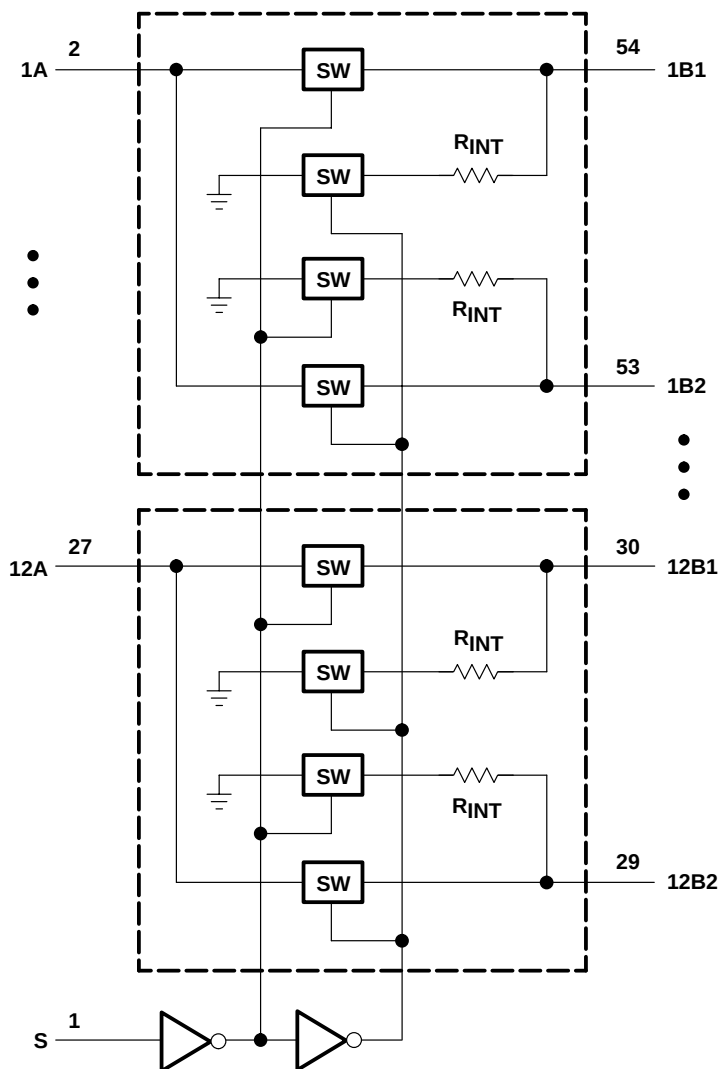
NC – No internal connection

PRODUCT PREVIEW

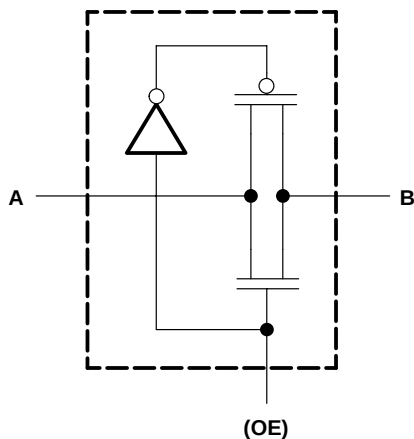
SN74CBTLV16292 LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS055C – MARCH 1998 – REVISED NOVEMBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



SN74CBTLV16292

LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS055C – MARCH 1998 – REVISED NOVEMBER 1998

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger}$	A or B	B or A					ns
t_{en}	S	A or B					ns
t_{dis}	S	A or B					ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

switching characteristics, $T_A = 0^{\circ}\text{C}$ to 70°C (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger}$	A or B	B or A					ns
t_{en}	S	A or B					ns
t_{dis}	S	A or B					ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

switching characteristics, $T_A = 0^{\circ}\text{C}$ to 70°C (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	DESCRIPTION	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
		MIN	MAX	MIN	MAX	
$t_{mbb}^{\ddagger}$	Make-before-break time					ns

[‡] The make-before-break time is the time interval between make and break, during the transition from one selected port to the other.

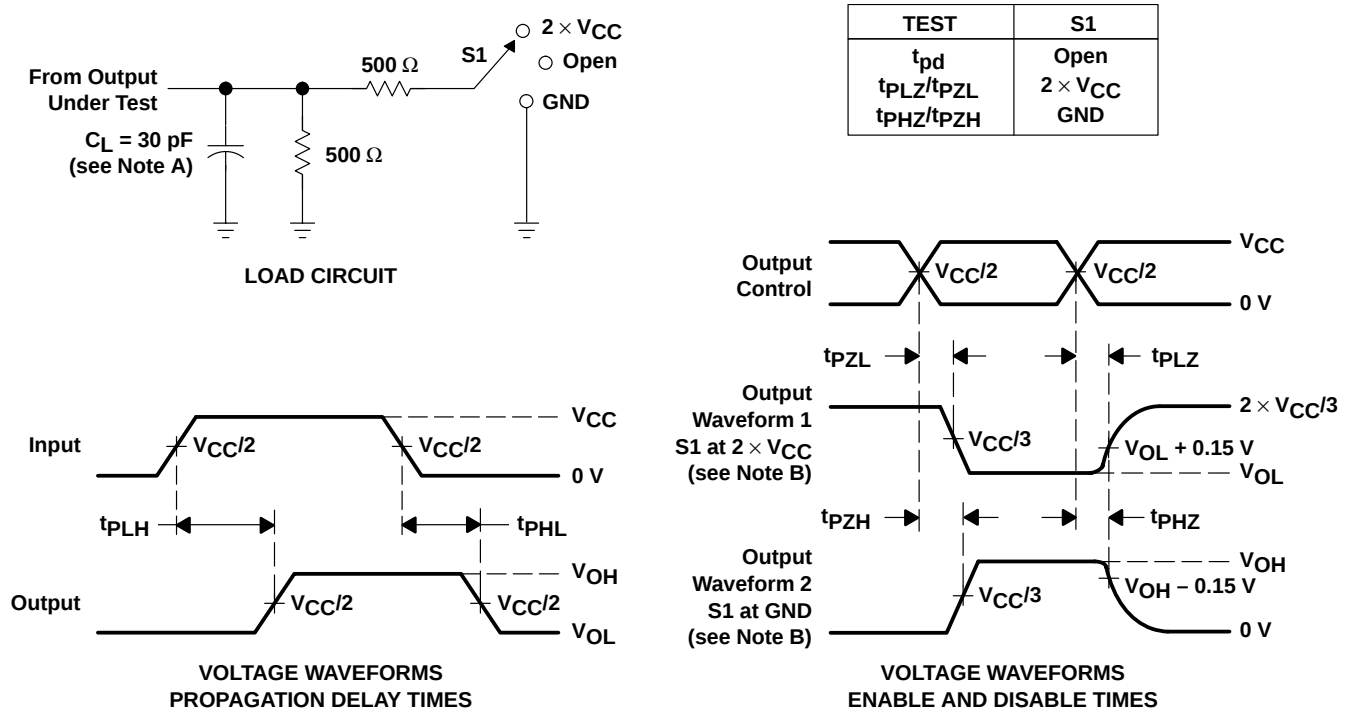
SN74CBTLV16292

LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS055C – MARCH 1998 – REVISED NOVEMBER 1998

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

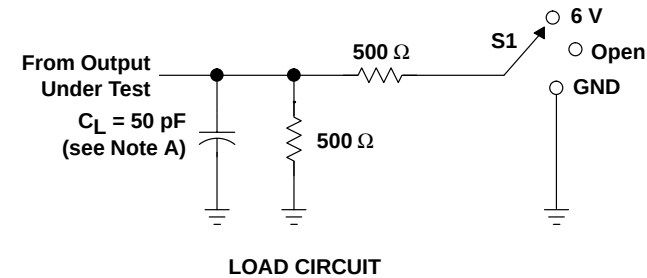
Figure 1. Load Circuit and Voltage Waveforms

PRODUCT PREVIEW

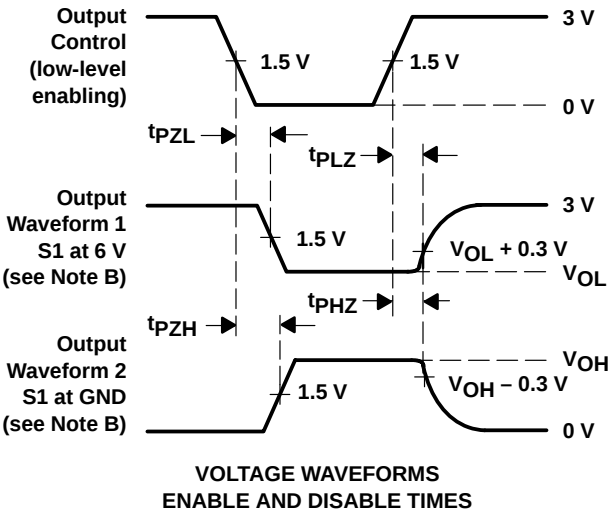
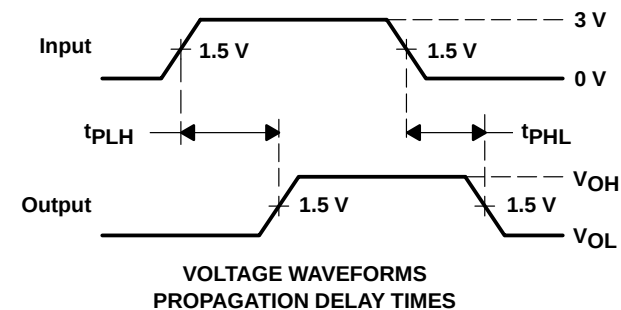
SN74CBTLV16292
LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER
WITH INTERNAL PULLDOWN RESISTORS

SCDS055C – MARCH 1998 – REVISED NOVEMBER 1998

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV162292

LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS056C – MARCH 1998 – REVISED NOVEMBER 1998

- 4- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- Make-Before-Break Feature
- Internal 500- Ω Pulldown Resistors to Ground
- A-Port Inputs/Outputs Have Equivalent 25- Ω Series Resistors, So No External Resistors Are Required
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

NOTE: For order entry:

The DGG package is abbreviated to G, and
the DGV package is abbreviated to V.

description

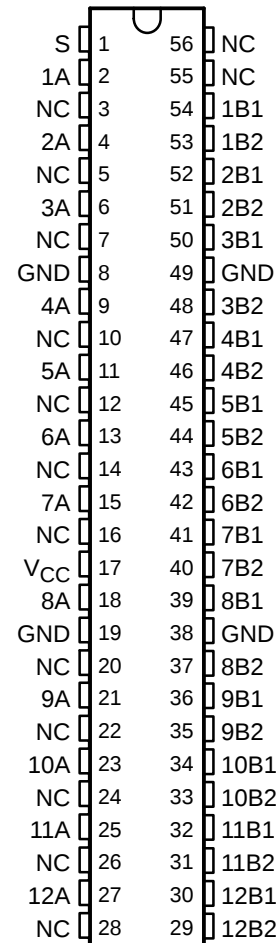
The SN74CBTLV162292 is a 12-bit 1-of-2 high-speed FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

When the select (S) input is low, port A is connected to port B1 and R_{INT} is connected to port B2. When S is high, port A is connected to port B2 and R_{INT} is connected to port B1.

The A-port inputs/outputs include equivalent 25- Ω series resistors to reduce overshoot and undershoot.

The SN74CBTLV162292 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

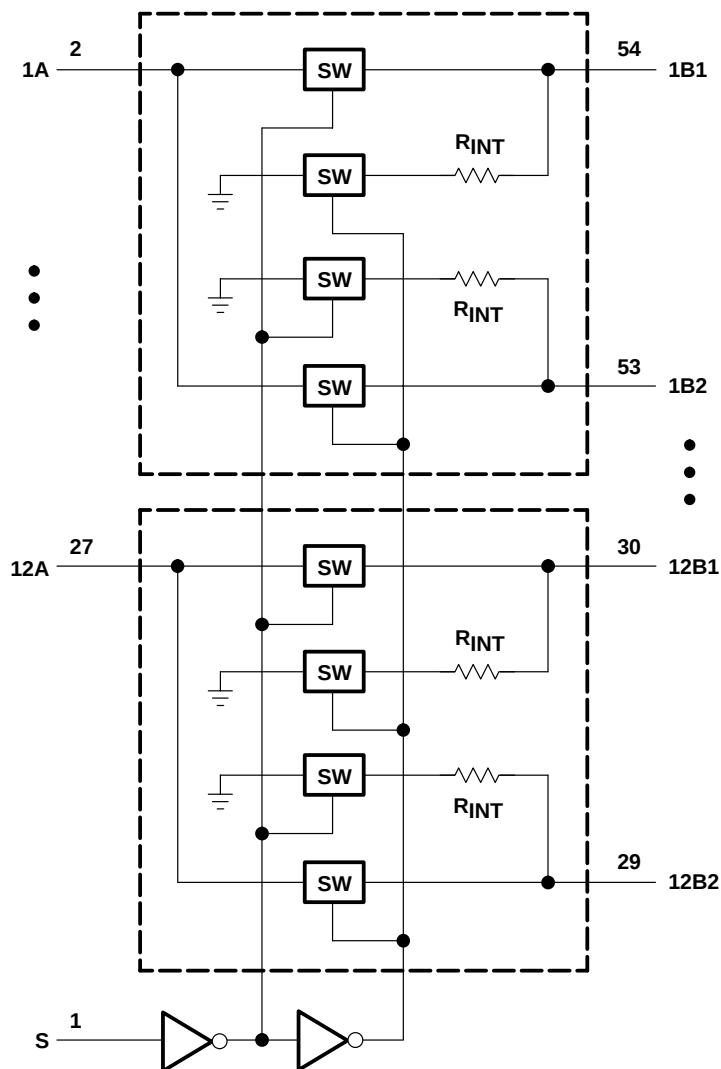
INPUT S	FUNCTION
L	A port = B1 port R_{INT} = B2 port
H	A port = B2 port R_{INT} = B1 port

SN74CBTLV162292

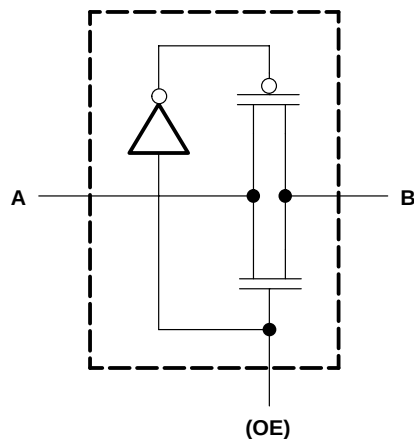
LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS056C – MARCH 1998 – REVISED NOVEMBER 1998

logic diagram (positive logic)



simplified schematic, each FET switch



SN74CBTLV162292

LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS056C – MARCH 1998 – REVISED NOVEMBER 1998

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger}$	A or B	B or A					ns
t_{en}	S	A or B					ns
t_{dis}	S	A or B					ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

switching characteristics, $T_A = 0^{\circ}\text{C}$ to 70°C (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger}$	A or B	B or A					ns
t_{en}	S	A or B					ns
t_{dis}	S	A or B					ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

switching characteristics, $T_A = 0^{\circ}\text{C}$ to 70°C (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	DESCRIPTION	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
		MIN	MAX	MIN	MAX	
$t_{mbb}^{\ddagger}$	Make-before-break time					ns

[‡] The make-before-break time is the time interval between make and break, during the transition from one selected port to the other.

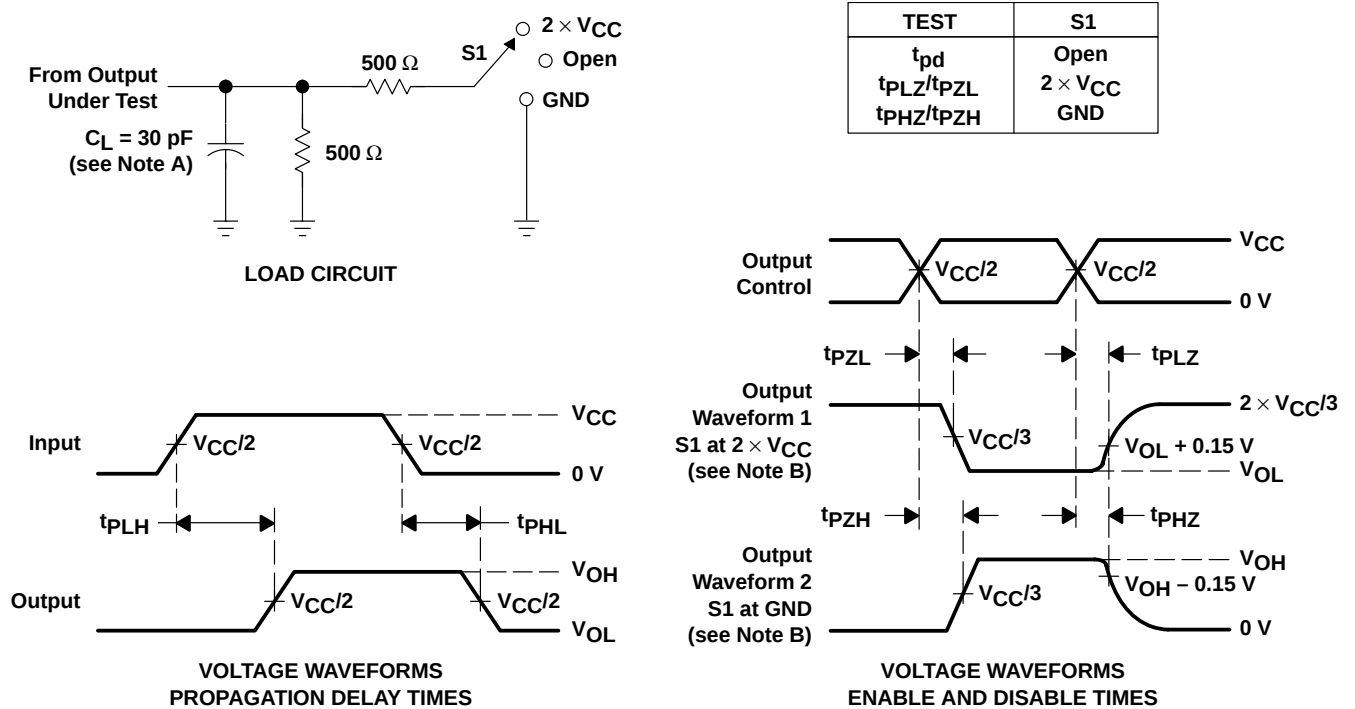
SN74CBTLV162292

LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER WITH INTERNAL PULLDOWN RESISTORS

SCDS056C – MARCH 1998 – REVISED NOVEMBER 1998

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

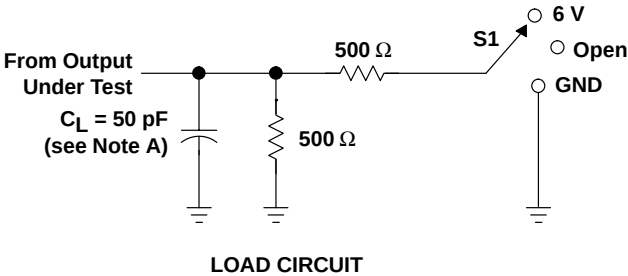
Figure 1. Load Circuit and Voltage Waveforms

PRODUCT PREVIEW

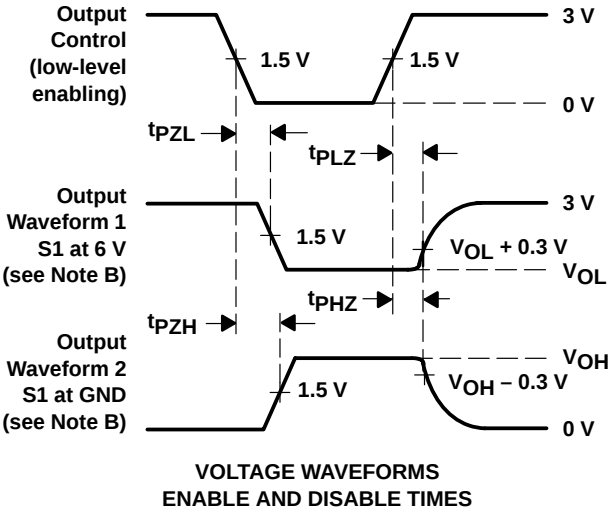
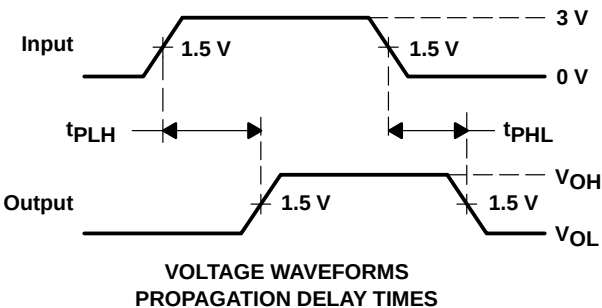
SN74CBTLV162292
 LOW-VOLTAGE 12-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER
 WITH INTERNAL PULLDOWN RESISTORS

SCDS056C – MARCH 1998 – REVISED NOVEMBER 1998

PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

SN74CBTLV16800

LOW-VOLTAGE 20-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS

SCDS045E – DECEMBER 1997 – REVISED NOVEMBER 1998

- 5- Ω Switch Connection Between Two Ports
- Isolation Under Power-Off Conditions
- B-Port Outputs Are Precharged by Bias Voltage to Minimize Signal Distortion During Live Insertion
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

description

The SN74CBTLV16800 provides 20 bits of high-speed bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. The device also precharges the B port to a user-selectable bias voltage (BIASV) to minimize live-insertion noise.

The device is organized as dual 10-bit bus switches with separate output-enable ($\overline{OE}$) inputs. It can be used as two 10-bit bus switches or one 20-bit bus switch. When $\overline{OE}$ is low, the associated 10-bit bus switch is on and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, a high-impedance state exists between the two ports, and port B is precharged to BIASV through the equivalent of a 10-k Ω resistor.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTLV16800 is characterized for operation from -40°C to 85°C .

DGG, DGV, OR DL PACKAGE
(TOP VIEW)

BIASV	1	48	$1\overline{OE}$
1A1	2	47	$2\overline{OE}$
1A2	3	46	1B1
1A3	4	45	1B2
1A4	5	44	1B3
1A5	6	43	1B4
1A6	7	42	1B5
GND	8	41	GND
1A7	9	40	1B6
1A8	10	39	1B7
1A9	11	38	1B8
1A10	12	37	1B9
2A1	13	36	1B10
2A2	14	35	2B1
V_{CC}	15	34	2B2
2A3	16	33	2B3
GND	17	32	GND
2A4	18	31	2B4
2A5	19	30	2B5
2A6	20	29	2B6
2A7	21	28	2B7
2A8	22	27	2B8
2A9	23	26	2B9
2A10	24	25	2B10

FUNCTION TABLE
(each 10-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	A port = Z B port = BIASV

PRODUCT PREVIEW

SCDS045E – DECEMBER 1997 – REVISED NOVEMBER 1998

The diagram illustrates a 16-channel multiplexer circuit. It features two sets of 8 inputs each, labeled 1A1 through 1A10 and 2A1 through 2A10. The outputs are labeled 1B1 through 1B10 and 2B1 through 2B10. The circuit is controlled by a 3-bit address (10E, 12, 2) and a 3-bit enable (2OE, 24, 13). The inputs are connected to 16-channel multiplexers (SW) which are controlled by the address and enable signals. The outputs are connected to a 3-bit decoder (10E, 2OE) and a 3-bit enable logic (24, 13). The circuit uses 16-channel multiplexers (SW), 3-bit decoders (10E, 2OE), and 3-bit enable logic (24, 13).

SN74CBTLV16800

LOW-VOLTAGE 20-BIT FET BUS SWITCH

WITH PRECHARGED OUTPUTS

SCDS045E – DECEMBER 1997 – REVISED NOVEMBER 1998

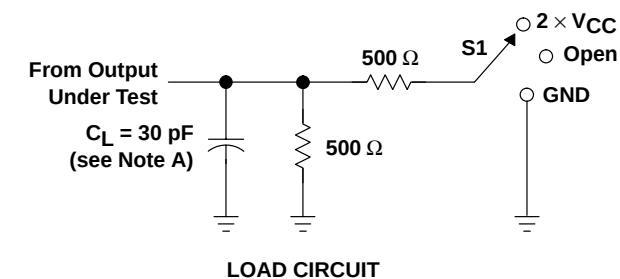
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	TEST CONDITIONS	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		UNIT
				MIN	MAX	MIN	MAX	
$t_{pd}^{\dagger}$		A or B	B or A					ns
t_{pZH}	BIASV = GND	$\overline{OE}$	A or B					ns
t_{pZL}	BIASV = 3 V							
t_{pHZ}	BIASV = GND	$\overline{OE}$	A or B					ns
t_{pLZ}	BIASV = 3 V							

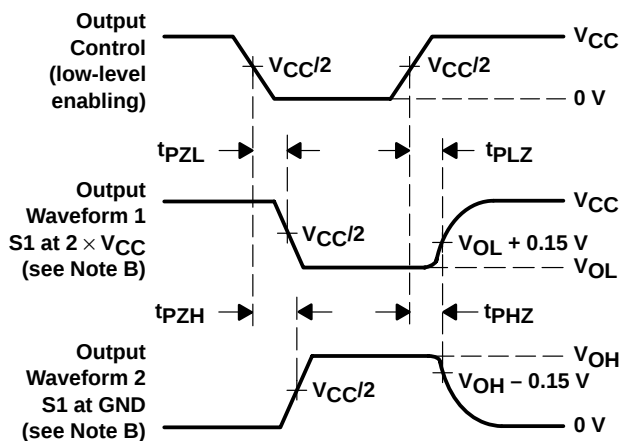
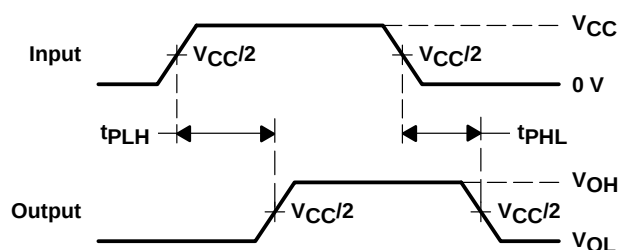
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



TEST	S1
t_{pd}	Open
t_{pLZ}/t_{pZL}	$2 \times V_{CC}$
t_{pHZ}/t_{pZH}	GND

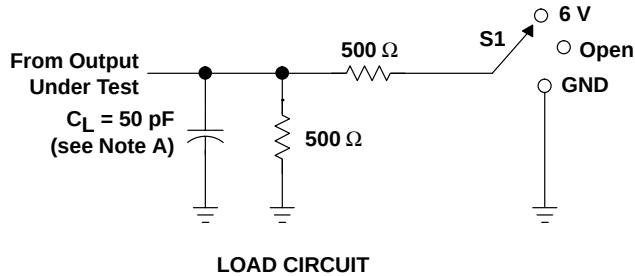


- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLH} and t_{PHL} are the same as t_{pd} .

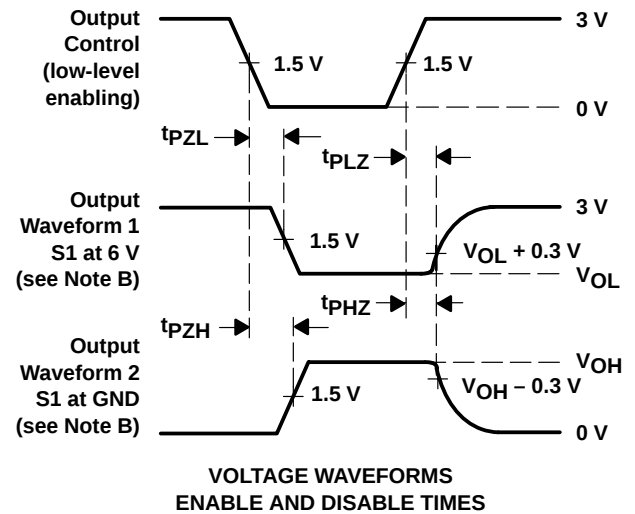
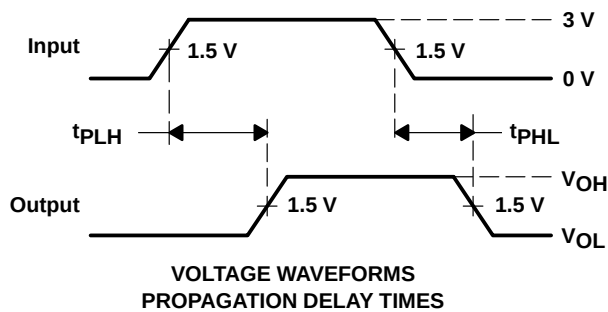
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$$



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

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Texas Instruments Crossbar Switches

SCDA001A
July 1995



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What Are Texas Instruments Crossbar Switches?

Crossbar switches are high-speed bus-connect devices. Each switch consists of an n-channel MOS transistor driven by a CMOS gate. When enabled, the n-channel transistor gate is pulled to V_{CC} and the switch is on. These devices have an on-state resistance of approximately $5\ \Omega$ and a propagation delay of 250 ps. They are capable of conducting a current of 64 mA each. The transistor clamps the output at $\approx 1\text{ V}$ less than the gate potential, regardless of the level at the input pin. This is one of the n-channel transistor characteristics (see Figures 1 and 2). Note the $\approx 1\text{-V}$ difference between the gate (V_{CC}) and the source (V_O) at any point on the graph.

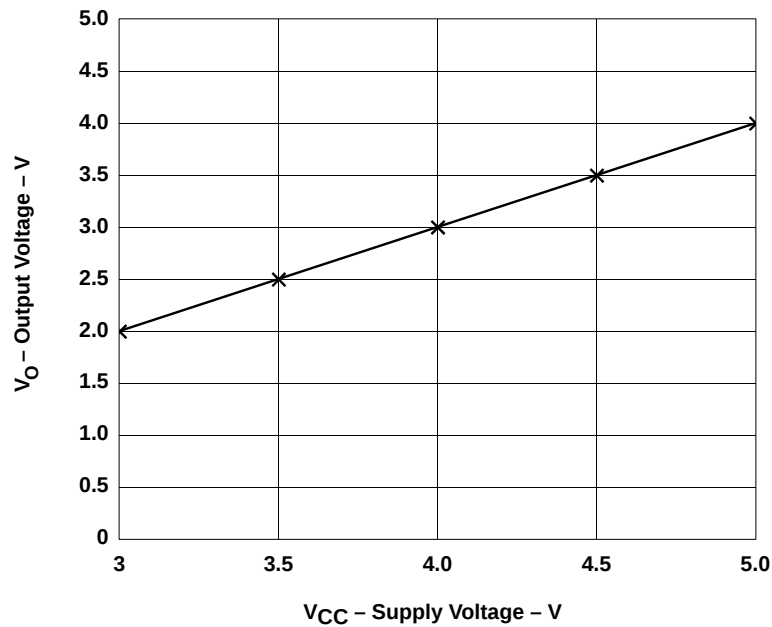


Figure 1. Output Voltage Versus Supply Voltage

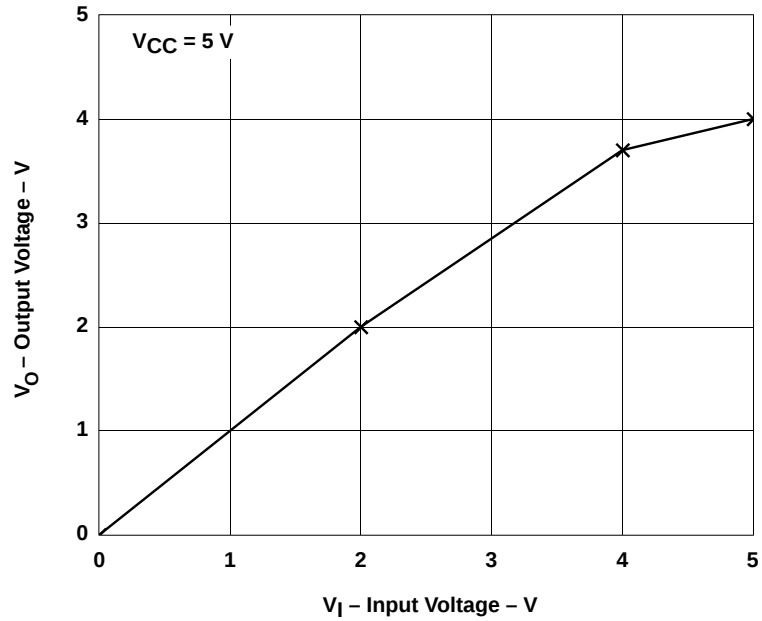


Figure 2. Output Voltage Versus Input Voltage

The on-state resistance (r_{on}) increases gradually with V_I until V_I approaches $V_{CC} - 1$ V, where r_{on} rapidly increases, clamping V_O at $V_{CC} - 1$ V (see Figure 3). Also, by the nature of the n-channel transistor design, the input and output terminals are fully isolated when the transistor is off. Leakage and capacitance are to ground and not between input and output, which minimizes feedthrough when the transistor is off.

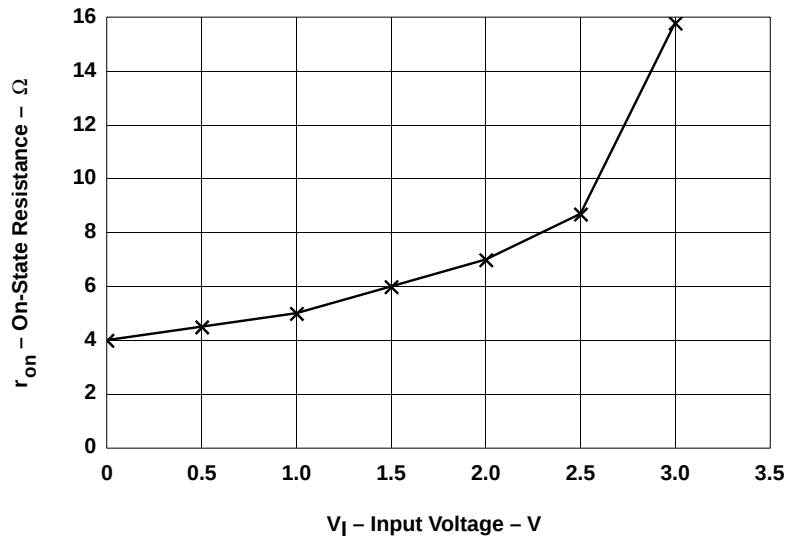


Figure 3. On-State Resistance Versus Input Voltage

Bus Switches Provide 5-V to 3-V Translation When 3-V Supply Line Is Not Provided

These devices also can provide bidirectional 5-V to 3-V translation with minimal propagation delay or direction control, using only a 5-V supply line and a diode. Figure 4 illustrates this application. A 4.3-V V_{CC} can be created by placing a diode between V_{CC} and the switch. This causes gate voltage of 4.3 V due to the diode drop of approximately 0.7 V. This drop, coupled with the gate-to-source drop of 1 V, brings V_O to a maximum 3.3-V level that can be used to drive a signal in a 3-V environment.

These devices consume very little current ($I_{CC} = 3 \mu A$). This current is not satisfactory for the diode to operate. Using a resistor from the cathode of the diode to GND allows more current from the supply voltage, causing the diode to operate and to clamp at the specified 4.3 V (see Figure 4). The recommended value of the resistor is 1 k Ω or less.

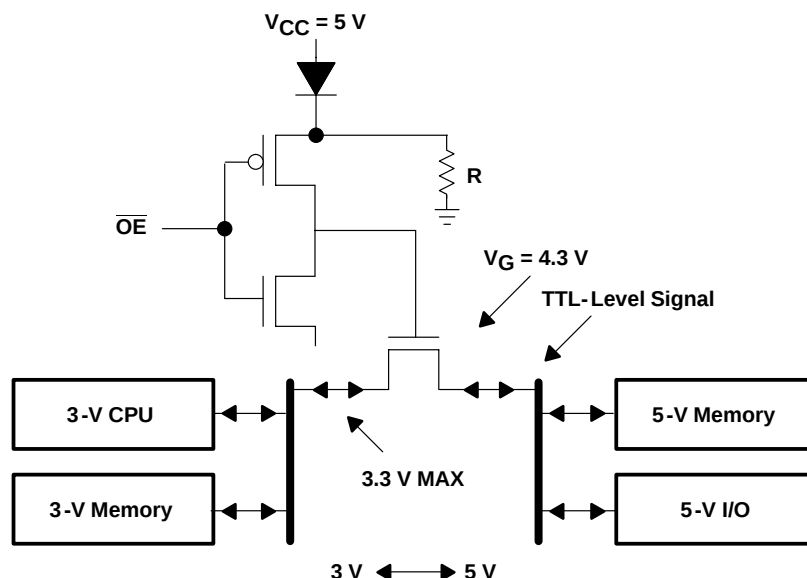


Figure 4. 5-V TTL to 3-V TTL Translator System

Bus Switches Can Be Used to Replace Drivers and Transceivers in Bus Applications

Bus switches introduce near-zero propagation delay. They can replace drivers and transceivers in systems in which signal buffering is not required. They can be used in a multiprocessor system as a fast bus connect, or they can be used as a bus-exchange switch for crossbar systems, ping-pong memory connect, or bus-byte swap. These devices also can replace relays that are used in automated test equipment (ATE) to connect or disconnect load resistors in negligible time with the same low on-state resistance and without relay-reliability problems.

Bus Switches Convert TTL Logic to Hot Card-Insertion Capability

This application is used mostly in systems that require hot card insertion or removal of cards without disturbing or loading down the bus. These systems are designed to run continuously and cannot be shut down for any reason, such as telephone switches, manufacturing controls, real-time transaction systems, and airline-reservation networks. These systems/cards use some logic families like ACL, HCMOS, etc., which do not provide isolation from the bus when power is partially removed, causing system error. Also, connectors are designed so that the ground pins are connected first, followed by the signal pins, then V_{CC} last. In this condition, the existing logic must ensure that the I/O signals do not disturb or load down the bus. This assurance cannot be achieved using CMOS logic since it contains p-channel transistors that provide an inherent diode between the I/O pins and V_{CC} . The diode is forward biased when driven above V_{CC} (see Figure 5). In a situation where V_{CC} is disconnected, these diodes are capable of pulling the system bus to approximately one diode drop above ground, leaving the bus disturbed.

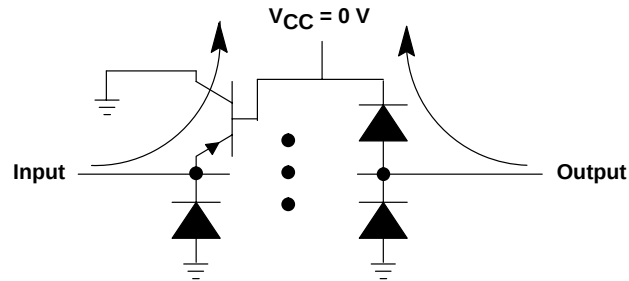


Figure 5. ACL Direction of Current Flow When $V_{CC} = 0$ V

Another issue to consider is that, when V_{CC} is ramping, but still below the device-operating voltage, the logic should ensure that the outputs are in the high-impedance state and that the bus is totally isolated until the card is ready for operation. Finally, the capacitance of the card must be seen by the system bus as low as possible so that when the card is inserted and the capacitance is charged up, disturbance or bus error does not occur.

There are two solutions to this problem; one is to use Texas Instruments BiCMOS technology (BCT) or advanced BiCMOS technology (ABT) families, since both ensure the input and output to be off when V_{CC} is removed due to the absence of the clamping diodes to V_{CC} (see Figure 6). They also provide an active circuit that ensures the output to be in the high-impedance state during part of the V_{CC} power up or power down.

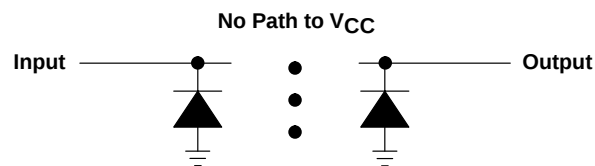


Figure 6. No ABT Current Flow When $V_{CC} = 0$ V

The second solution is to use the Texas Instruments CBT family. This can be done by placing the switch between the card logic and the connector to serve as an isolator when power is removed. The switch uses an n channel that prevents the current from flowing into the switch when powered down (see Figure 7). One device in particular, the SN74CBT6800, is designed specifically for hot card insertion. It has a built-in channel pullup tied to a bias voltage (BIASV) that is provided to ensure power up with the buses not connected. Other devices can be used in the same manner, however, to ensure the high-impedance state during power up or power down. The enable pins of the switch should be tied to V_{CC} through a pullup resistor. The minimum value of the resistor is determined by the current-sinking capability of the driver (see Figure 8).

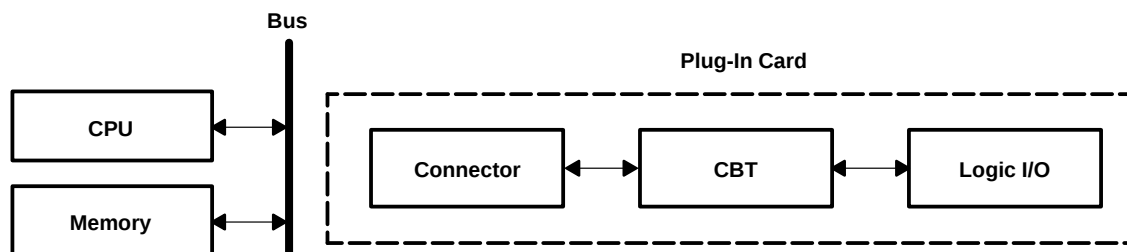


Figure 7. Hot Card-Insertion Application

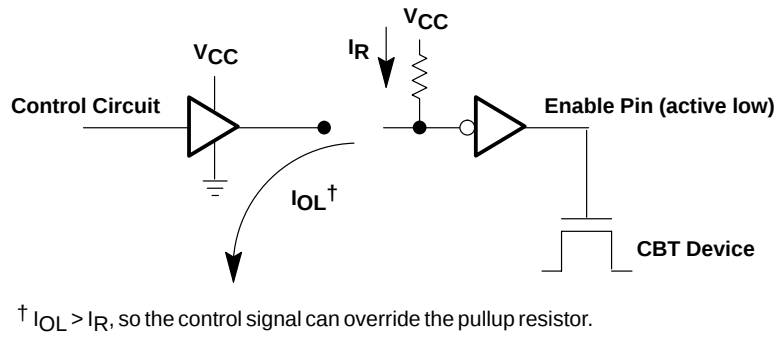


Figure 8. Power-Up High-Impedance State With CBT

Conclusion

Texas Instruments crossbar switches can be used in several applications. Although they are simple n-channel transistors, they are capable of providing several important bus functions, such as hot card insertion, near-zero-delay communication, 5-V to 3-V translation, and memory management in multiprocessor environments.

Acknowledgment

The author of this document is Ramzi Ammar.

SN74CBTS3384 Bus Switches Provide Fast Connection and Ensure Isolation

SCDA002A
August 1996



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Introduction

Buses are the pathways for communication between the CPU, memory, and I/O ports in electronic systems. Today's standards demand both fast connection as well as isolation of these buses. Bus switches are usually used to address these demands because the use of a single MOSFET provides negligible propagation delay, low power dissipation and bidirectional switching; however, the use of a single transistor also can allow large negative undershoots below -1 V to cause unwanted switching and possible disruption of the bus. To prevent this problem from occurring, the SN74CBTS3384 bus switches are developed with Schottky diodes at the inputs that clamp any undershoot to approximately -300 mV (see Figure 1).

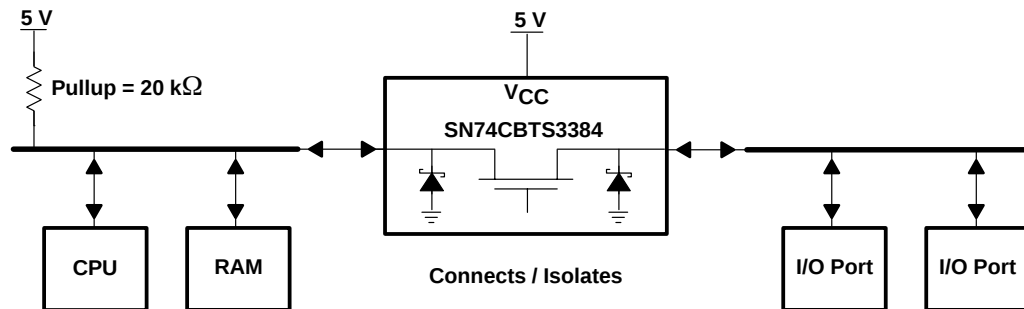
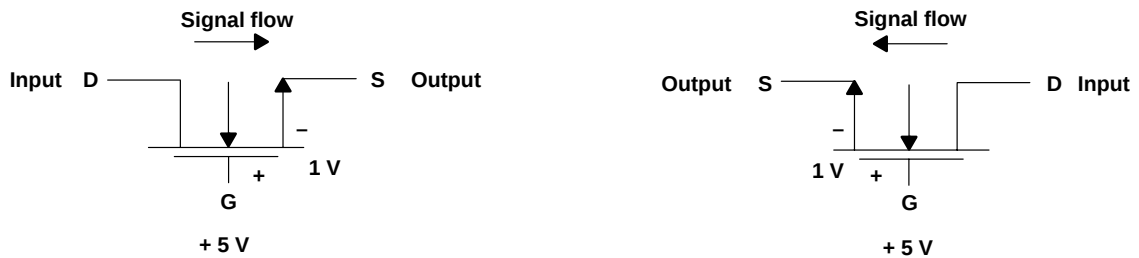


Figure 1. The SN74CBTS3384 With Schottky Diodes Attached at Both Ports

The Mechanics of the MOSFET Switch Leading to False Switching

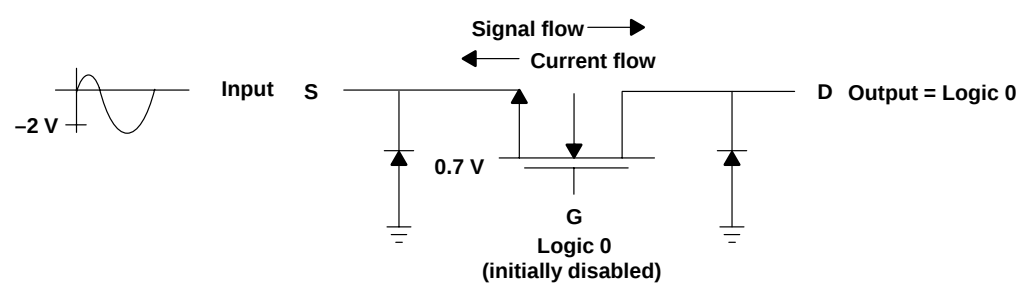
The MOSFET is used for bus switches because of its enabling and disabling speed, its low on-state resistance, and its high off-state resistance. The substrate of the N-channel MOSFET is grounded and the two n-type doped regions are interchangeable. As shown in Figure 2, when a logic high is applied to the gate, the region with a voltage of 1 V or more below the gate becomes the source and the other region the drain. At this point, the switch turns fully on and a signal flows from the input side. While this physical structure of the MOSFET provides bidirectional capability in a switch, it also allows large negative undershoots on either port to turn on a disabled switch.



The interchangeability of the source and drain provides bidirectional signal flow.

Figure 2. Switching Mechanics of the NMOS Switch

As Figure 3 shows, even though the switch is initially disabled and there is a logic low at the gate, large negative undershoots at the input cause the existing clamping diode to clamp to approximately -650 mV. Since this voltage is parallel to the gate-to-source voltage of the transistor and lasts for a few nanoseconds, the transistor starts conducting a certain amount of current. This causes a logic low to appear on the bus and disrupts any signals on it.

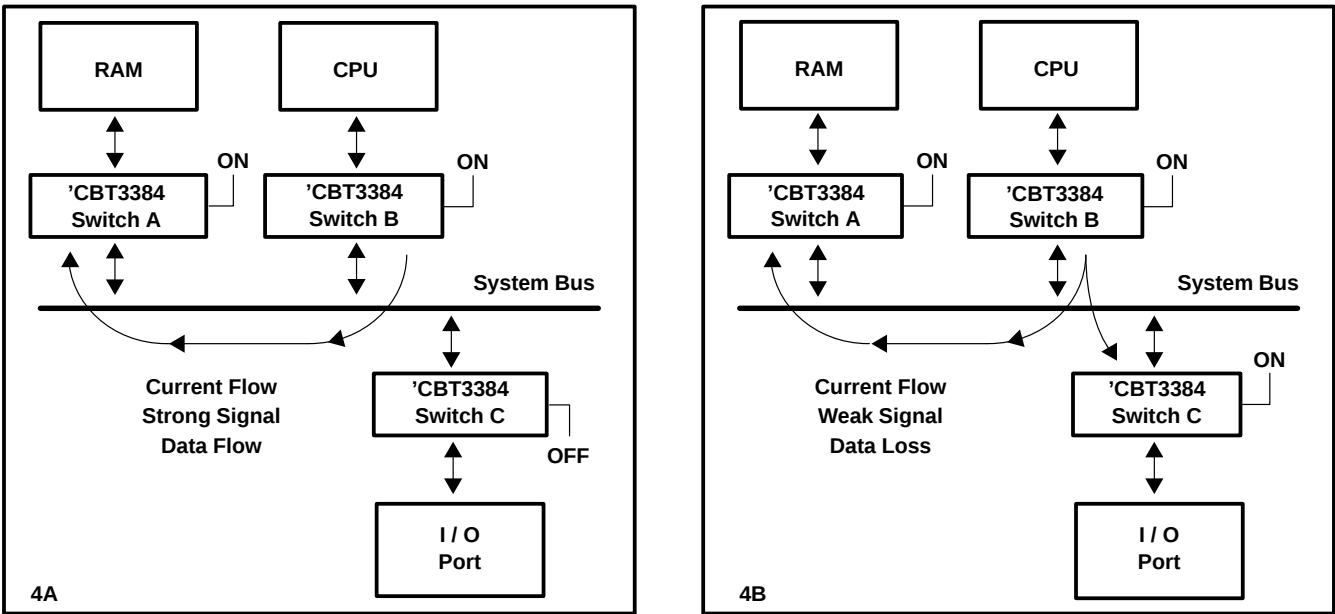


Output enable ($\overline{OE}$) is high, but large negative undershoot causes NMOS switch to turn on.

Figure 3. Mechanics Behind False Switching

Disruption of the Bus

False switching can disrupt the bus in many ways. Bus switches connect two buses or several components on a bus when on, and isolates them when off. Because each component has a certain amount of capacitance, an unexpected connection loads the bus with additional capacitance. Under normal circumstances, a signal is given enough drive to charge the expected capacitance on the bus and then switch voltage levels at the receiver. A signal propagating on the disrupted line may not have enough drive to overcome the additional load capacitance. In fact, the logic low introduced to the bus by the false connection can absorb some of the drive current from the signal. In any case, the end result is signal weakening, loss of speed, and failure to switch voltage levels at the receiver. Figure 4A shows a transaction between a CPU and a RAM chip connected by switches A and B. When switch C is off, the data flow is uninterrupted. As shown in Figure 4B, switch C can turn on unexpectedly and connect the I/O port to the bus. This results in signal degradation and data loss.



Uninterrupted data flow from CPU to RAM

Resulting bus interruption and data loss

Figure 4. The Effect of Bus Interruption on Data Flow and Signal Integrity

False switching also can cause bus contention, a case occurring when two or more transmitters on a bus are active at the same time. If the logic levels of these outputs are different, a high current flows on the line, possibly damaging the line or the components connected to it. These problems can cause serious setbacks to the high performance and reliability demands of today's systems. The use of the SN74CBTS3384 bus switch helps prevent false switching and addresses many of these problems.

The SN74CBTS3384 Solution

The SN74CBTS3384 utilizes Schottky diode at the inputs to clamp undershoot to about 300 mV below ground (see Figure 5). With the gate grounded in the disabled state, the Schottky diode prevents the gate-to-source voltage from exceeding the threshold voltage of the NMOS transistor, thus preventing weak enabling. In addition, a disabled SN74CBTS3384 switch offers a very low capacitance of about 6 pF and very low leakage current. Figure 5 shows total leakage current of only 2 μ A. As a result, the disabled SN74CBTS3384 bus switch succeeds in isolating its output from any unwanted undershoots at the input. The buses are left uninterrupted and the signals on the buses are not disturbed.

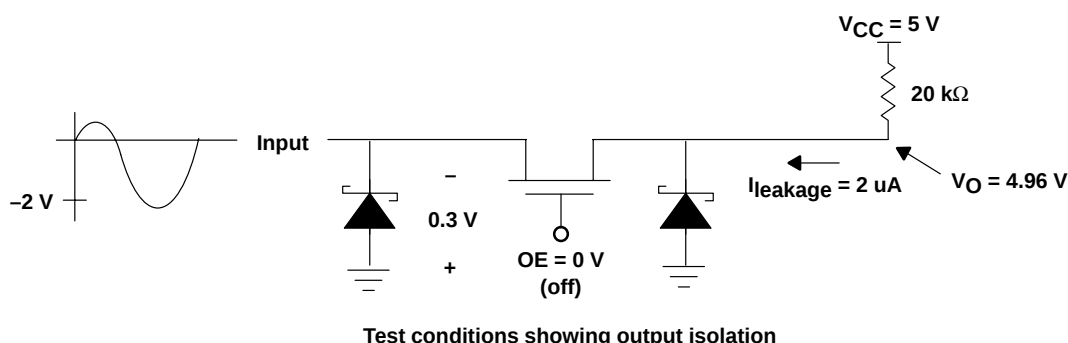


Figure 5. Test Conditions of the SN74CBTS3384 With Switch Disabled

Figure 6 shows the output of a disabled SN74CBT3384A (without Schottky diodes) as it turns on and follows the input to a negative level. This level is low enough to possibly disrupt the bus. Figure 6 also shows the SN74CBTS3384 where the Schottky diode prevents any switching throughout the wide input sweep and keeps the output at a steady level. Figure 7 shows the input current of the SN74CBTS3384 as the Schottky diode turns on, conducting about 10 mA from ground.

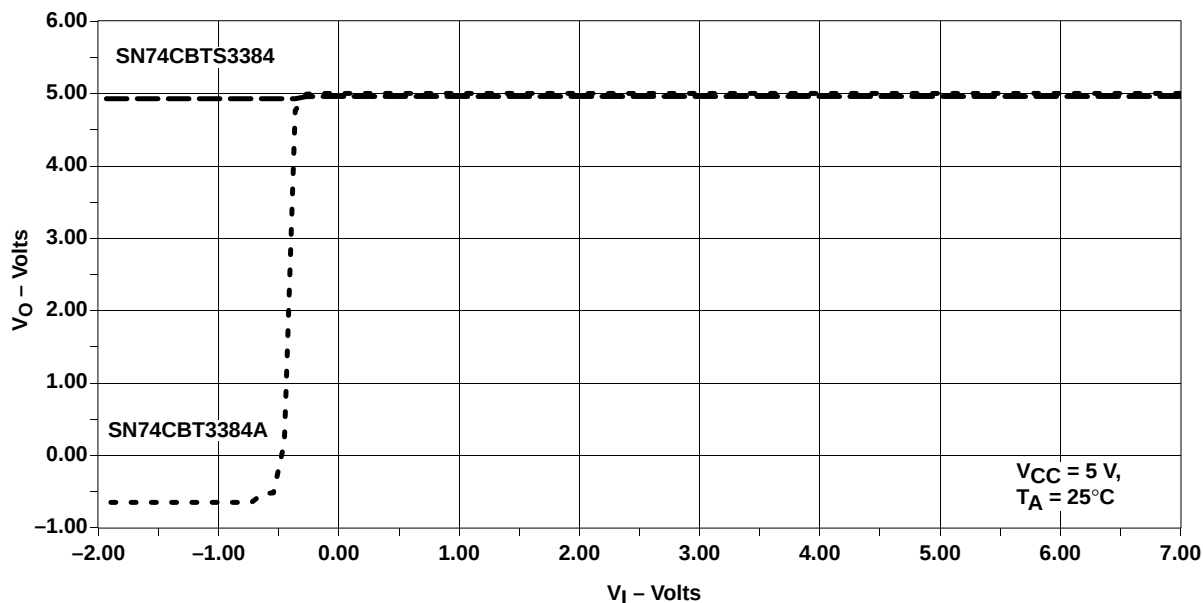


Figure 6. V_O vs V_I of the SN74CBTS3384 and a SN74CBT3384A in the Disabled State

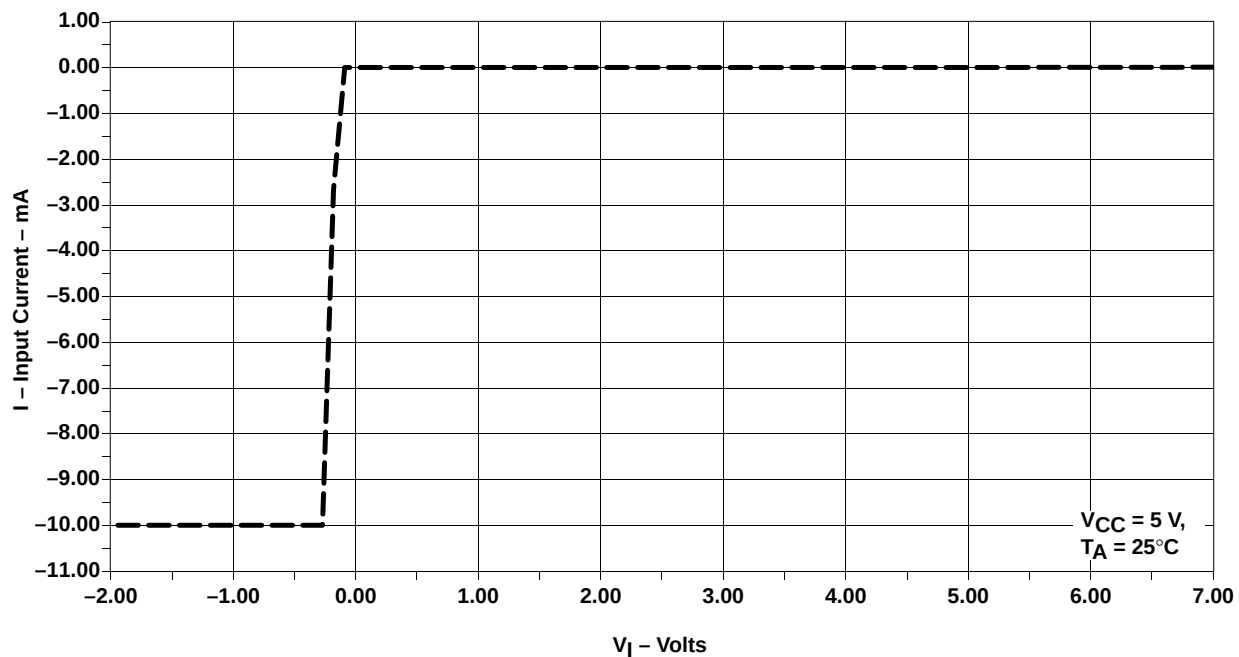


Figure 7. Input Current vs V_I of SN74CBTS3384 in the Disabled State

Conclusion

The SN74CBTS3384 bus switch provides a high-speed, low-power solution to bus connection, while providing a reliable solution to bus isolation. As a result, buses function properly without any problematic interruptions and the high-performance demands of today's systems are easily reached.

Acknowledgment

The author of this report is Nalin Yogasundram.

5-V to 3.3-V Translation With the SN74CBTD3384

SCDA003B
March 1997



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Introduction

The emergence of low-voltage technology has required existing 5-V systems to interact with 3.3-V systems. Issues concerning compatibility of the two systems in mixed-mode operation have created the need for 5-V to 3.3-V translation. Buffers and transceivers serve as effective translators. While providing additional drive, these devices also add propagation delay and require directional control. In cases where additional drive is not required, the solution that provides 5-V to 3.3-V translation, in addition to negligible propagation delay, lower power dissipation, and bidirectional bus switching, is the SN74CBTD3384 bus switch. The SN74CBTD3384 uses the inherent voltage drop of its MOSFET switch, coupled with an internal diode from V_{CC} to provide the necessary 5-V to 3.3-V translation (see Figure 1).

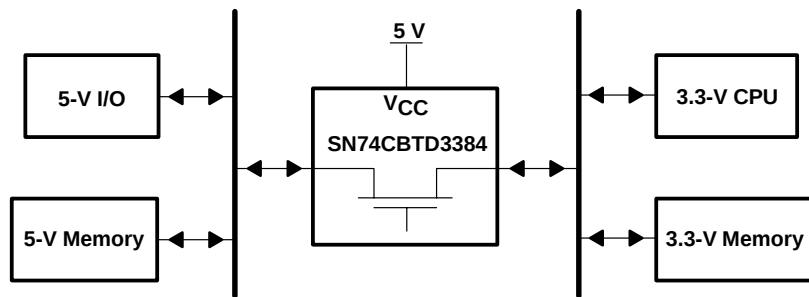
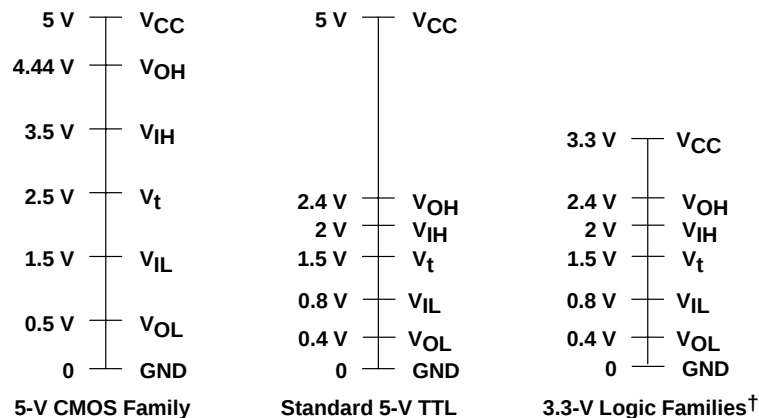


Figure 1. The SN74CBTD3384 Bus Switch Provides 5-V to 3.3-V Translation and Bidirectional Switching

The Need for 5-V to 3.3-V Translation

To realize the need for 5-V to 3.3-V translation, the I/O specifications for mixed-mode operation must be understood. Devices operating in this mode must have TTL-compatible output levels and be able to accept up to 5.5 V at the input. Figure 2 shows various interface levels for 5-V and 3.3-V families. While many 5-V and 3.3-V logic families have been designed with TTL-compatible interface levels and 5-V input tolerance, some CMOS families lack these features. Some 5-V CMOS outputs drive to 5 V; however, certain 3.3-V CMOS inputs do not tolerate 5 V. It is the incompatibility of the described input and output structures that creates the need for 5-V to 3.3-V translation.



† In accordance with JEDEC Standard 8-A for LV interface levels

Figure 2. Comparison of 5-V and 3.3-V Interface levels

The Mechanics of 5-V to 3.3-V Translation

The CBT bus switches consist of an N-channel MOSFET with its drain and source connected from input to output. The nominal value of the threshold of the MOSFET is 1 V. The MOSFET (Pass transistor) is on when the gate-to-source voltage (V_g) exceeds 1 V. A V_{CC} of 5 V connected to the gate, and a gate-to-source voltage drop of 1 V results in a maximum source voltage of about 4 V. This source voltage limitation, coupled with the transistor's typical on-state resistance of 5 Ω , gives the switch both 5-V to 4-V translation and low propagation delay. If the gate voltage is reduced lower than V_{CC} , the source will be limited to a voltage lower than 4 V. As shown in Figure 3, the SN74CBTD3384 has a diode from V_{CC} to the rest of the circuit. This diode voltage drop is 0.7 V from V_{CC} , which leads to 4.3 V at the gate of the Pass transistor. With the additional 1-V drop from gate to source, the typical output of the SN74CBTD3384 is 3.3 V. Additional diodes can be added to limit the output to even lower voltages. It is important to note that in some cases, the quiescent current (I_{CC}) flowing through the diode may not be enough to turn on the diode. A resistor (R) is added to ground to ensure enough bias current through the diode. The bidirectional nature of the switch is not sacrificed in this translation. A logic high from a 3.3-V device is relayed to the output untranslated. A 5-V receiver with TTL-compatible interface levels reads this signal as a valid high.

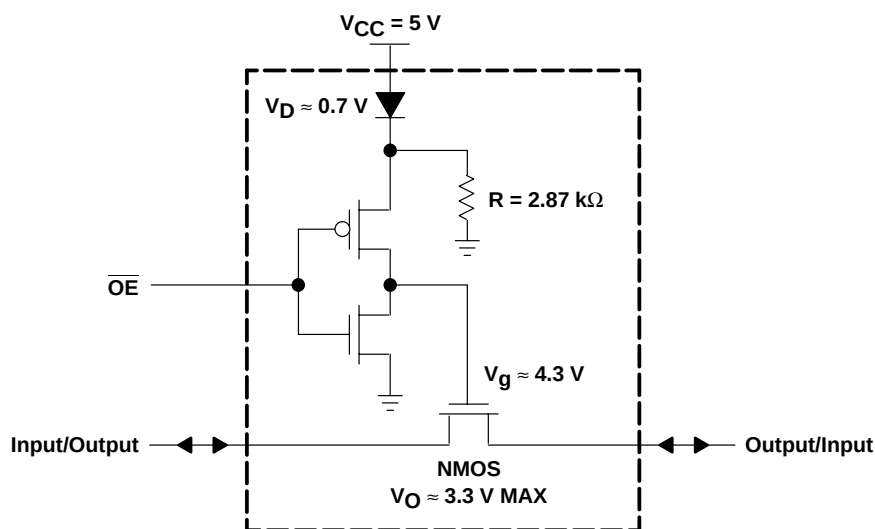


Figure 3. NMOS Switch of SN74CBTD3384 With Maximum V_O of 3.5 V

SN74CBTD3384 Improves Upon Existing Methods for 5-V to 3.3-V Translation

An existing practice for 5-V to 3.3-V translation using a bus switch involves the diode external to the chip. For most purposes, this method provides a quick, effective solution for voltage reduction. But, with increased use of low-voltage technology, the use of smaller, more reliable parts becomes an important issue. The SN74CBTD3384 addresses this issue by integrating the diode and resistor internally into the chip. As a result, board space is reduced and the cost of external components is eliminated. The integration of the components into one chip also eliminates extra solder connections and makes testing easier. Noise sensitivity is decreased, as well as the chance of false switching. The modified control input threshold of the SN74CBTD3384 compensates for the diode drop from V_{CC} and retains the normal 5-V TTL input threshold. This further reduces the noise problem. As demonstrated by the preceding factors, the SN74CBTD3384 offers increased reliability.

Figure 4 shows a comparison between the SN74CBT3384A, SN74CBT3384A with a 1N916 external diode for voltage translation, and the SN74CBTD3384. The SN74CBTD3384 output follows the input closely, but reaches a maximum of approximately 3.45 V at a V_{CC} of 5.5 V. Even at an extreme input level of 7 V, the SN74CBTD3384 limits the output to 3.5 V. Figure 5 emphasizes the role of V_{CC} in limiting the output. As V_{CC} changes from 4.5 V to 5.5 V, so does the limit of the output.

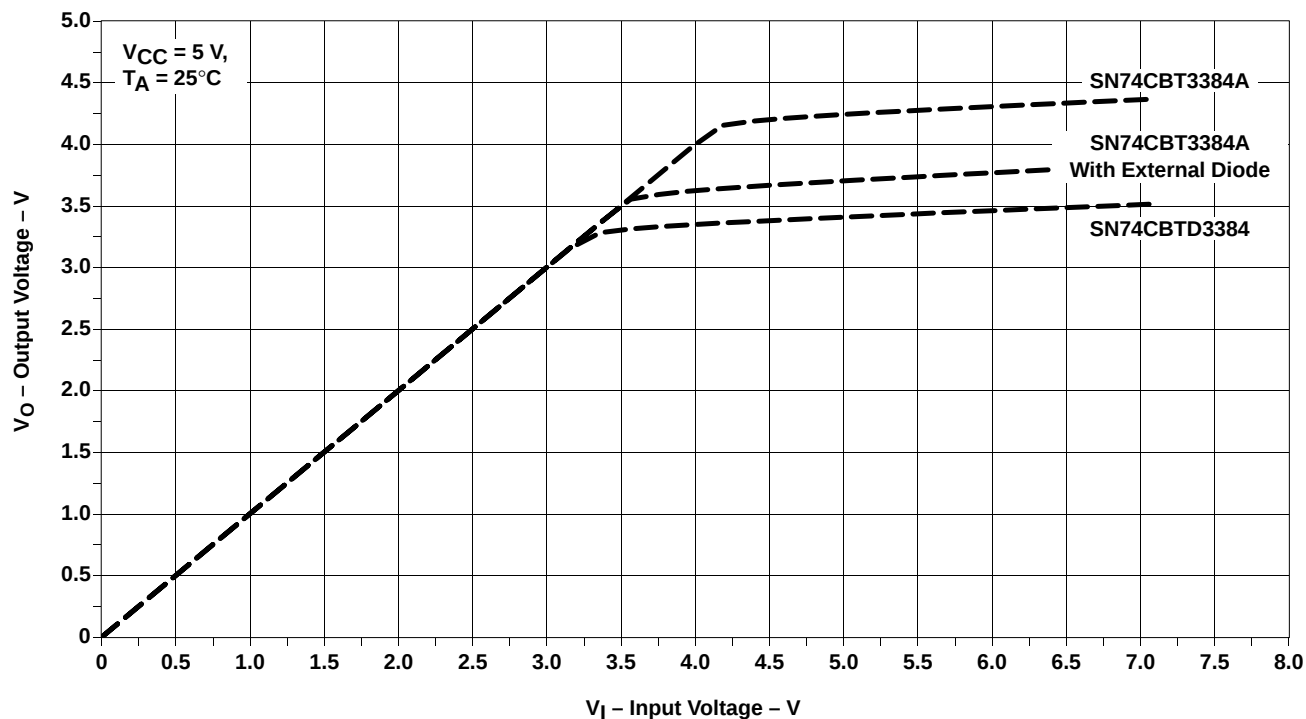


Figure 4. V_O Versus V_I of SN74CBT3384A, SN74CBT3384A With 1N916 External Diode, and SN74CBTD3384

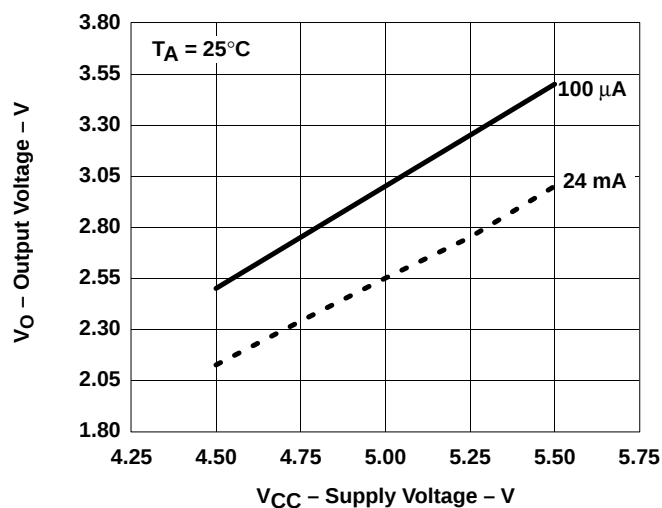


Figure 5. V_O Versus V_{CC} of the SN74CBTD3384

Conclusion

Lack of compatibility between certain 5-V and 3.3-V devices has driven the need for 5-V to 3.3-V translation. The standard method of using a bus switch to address this need has, historically, required an external diode. The SN74CBTD3384 bus switch is an improvement to this method because it provides reliable 5-V to 3.3-V translation and maintains its bidirectional capability, negligible propagation delay, and low power dissipation.

Acknowledgment

The author of this report is Nalin Yogasundram.

Implications of Slow or Floating CMOS Inputs

SCBA004C
February 1998



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Introduction

In recent years, CMOS (AC/ACT, AHC/AHCT, ALVC, CBT, CBTLV, HC/HCT, LVC, LV/LV-A) and BiCMOS (ABT, ALVT, BCT, FB, GTL, and LVT) logic families have further strengthened their position in the semiconductor market. New designs have adopted both technologies in almost every system that exists, whether it is a PC, a workstation, or a digital switch. The reason is obvious: power consumption is becoming a major issue in today's market. However, when designing systems using CMOS and BiCMOS devices, one must understand the characteristics of these families and the way inputs and outputs behave in systems. It is very important for the designer to follow all rules and restrictions that the manufacturer requires, as well as to design within the data-sheet specifications. Because data sheets do not cover the input behavior of a device in detail, this application report explains the input characteristics of CMOS and BiCMOS families in general. It also explains ways to deal with issues when designing with families in which floating inputs are a concern. Understanding the behavior of these inputs results in more robust designs and better reliability.

Characteristics of Slow or Floating CMOS Inputs

Both CMOS and BiCMOS families have a CMOS input structure. This structure is an inverter consisting of a p-channel to V_{CC} and an n-channel to GND as shown in Figure 1. With low-level input, the p-channel transistor is on and the n-channel is off, causing current to flow from V_{CC} and pulling the node to a high state. With high-level input, the n-channel transistor is on, the p-channel is off, and the current flows to GND, pulling the node low. In both cases, no current flows from V_{CC} to GND. However, when switching from one state to another, the input crosses the threshold region, causing the n-channel and the p-channel to turn on simultaneously, generating a current path between V_{CC} and GND. This current surge can be damaging, depending on the length of time that the input is in the threshold region (0.8 to 2 V). The supply current (I_{CC}) can rise to several milliamperes per input, peaking at approximately $1.5 \cdot V_I$ (see Figure 2). This is not a problem when switching states within the data-sheet-specified input transition time limit specified in the recommended operating conditions table for the specific devices. Examples are shown in Figure 3.

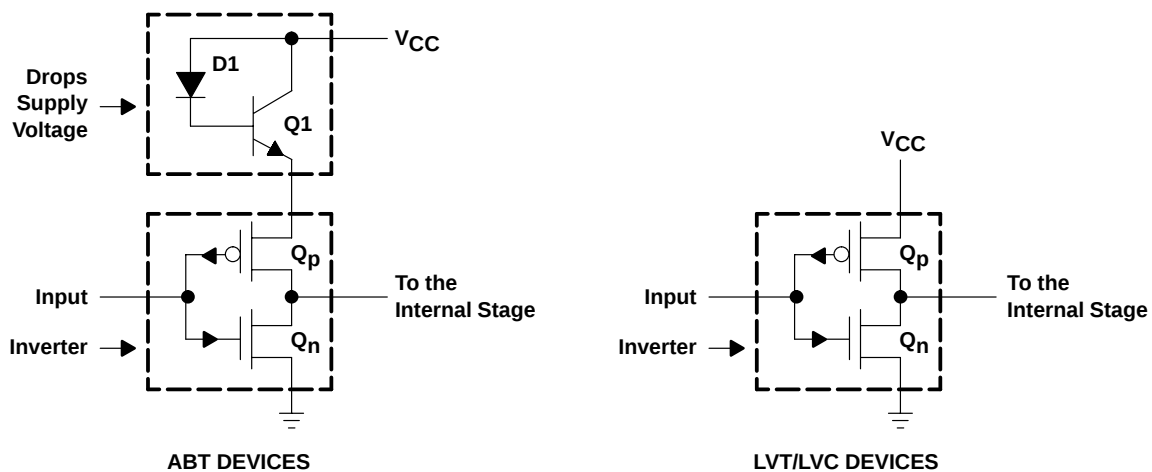


Figure 1. Input Structures of ABT and LVT/LVC Devices

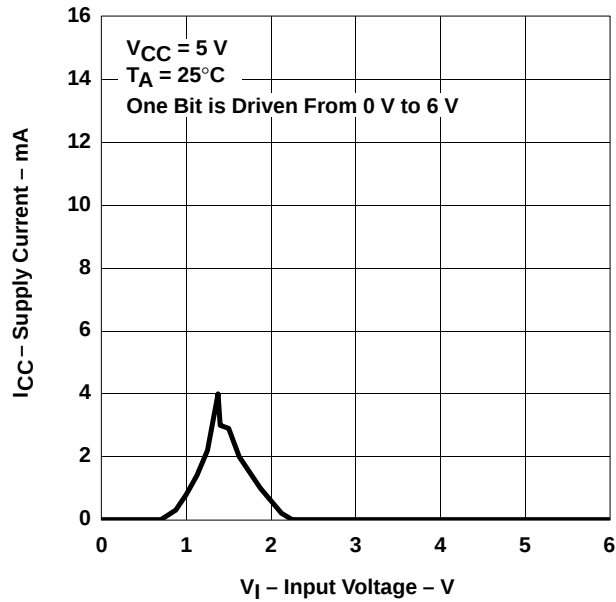


Figure 2. Supply Current Versus Input Voltage (One Input)

recommended operating conditions[†]

			MIN	MAX	UNIT
$\Delta t/\Delta v$	Input transition rise or fall rate	ABT octals		5	ns/V
		ABT Widebus™ and Widebus+™		10	
		AHC, AHCT		20	
		FB		10	
		LVT, LVC, ALVC, ALVT		10	
		LV		100	
	LV-A	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		200	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$		100	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		20	
t_t	Input transition (rise and fall) time	HC, HCT	$V_{CC} = 2\text{ V}$	1000	ns
			$V_{CC} = 4.5\text{ V}$	500	
			$V_{CC} = 6\text{ V}$	400	

[†] Refer to the latest TI data sheets for device specifications.

Figure 3. Input Transition Rise or Fall Rate as Specified in Data Sheets

Slow Input Edge Rate

With increased speed, logic devices have become more sensitive to slow input edge rates. A slow input edge rate, coupled with the noise generated on the power rails when the output switches, can cause excessive output errors or oscillations. Similar situations can occur if an unused input is left floating or is not actively held at a valid logic level.

These functional problems are due to voltage transients induced on the device's power system as the output load current (I_O) flows through the parasitic lead inductances during switching (see Figure 4). Because the device's internal power-supply nodes are used as voltage references throughout the integrated circuit, inductive voltage spikes, V_{GND} , affect the way signals appear to the internal gate structures. For example, as the voltage at the device's ground node rises, the input signal, V_I' , appears to decrease in magnitude. This undesirable phenomenon can then erroneously change the output if a threshold violation occurs.

In the case of a slowly rising input edge, if the change in voltage at GND is large enough, the apparent signal, V_I' , at the device appears to be driven back through the threshold and the output starts to switch in the opposite direction. If worst-case conditions prevail (simultaneously switching all of the outputs with large transient load currents), the slow input edge is repeatedly driven back through the threshold, causing the output to oscillate. Therefore, the maximum input transition time of the device should not be violated, so no damage to the circuit or the package occurs.

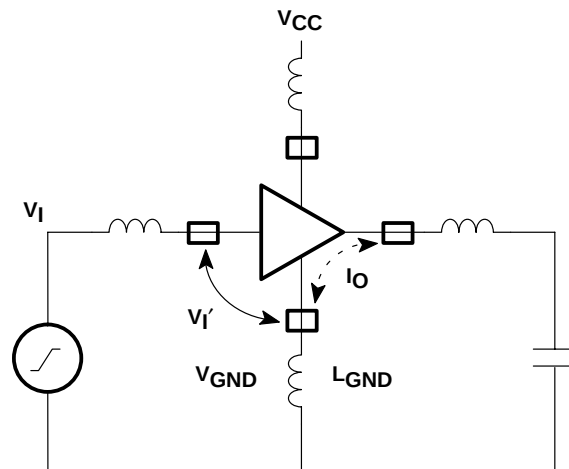


Figure 4. Input/Output Model

Floating Inputs

If a voltage between 0.8 V and 2 V is applied to the input for a prolonged period of time, this situation becomes critical and should not be ignored, especially with higher bit count and more dense packages (SSOP, TSSOP). For example, if an 18-bit transceiver has 36 I/O pins floating at the threshold, the current from V_{CC} can be as high as 150 mA to 200 mA. This is approximately 1 W of power consumed by the device, which leads to a serious overheating problem. This continuous overheating of the device affects its reliability. Also, because the inputs are in the threshold region, the outputs tend to oscillate, resulting in damage to the internal circuit over a long period of time. The data sheet shows the increase in supply current (ΔI_{CC}) when the input is at a TTL level [for ABT $V_I = 3.4$ V, $\Delta I_{CC} = 1.5$ mA (see Figure 5)]. This becomes more critical when the input is in the threshold region as shown in Figure 6.

These characteristics are typical for all CMOS input circuits, including microprocessors and memories.

For CBT or CBTLV devices, this applies to the control inputs. For FB and GTL devices, this applies to the control inputs and the TTL ports only.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)[†]

PARAMETER		TEST CONDITIONS			MIN	MAX	UNIT
$\Delta I_{CC}^{\ddagger}$	ABT, AHCT	$V_{CC} = 5.5\text{ V}$,	One input at 3.4 V,	Other inputs at V_{CC} or GND		1.5	mA
	CBT Control inputs	$V_{CC} = 5.5\text{ V}$,	One input at 3.4 V,	Other inputs at V_{CC} or GND		2.5	
$\Delta I_{CC}^{\ddagger}$	CBTLV Control inputs	$V_{CC} = 3.6\text{ V}$,	One input at 3 V,	Other inputs at V_{CC} or GND		750	μA
$\Delta I_{CC}^{\ddagger}$	LVT	$V_{CC} = 3\text{ V to }3.6\text{ V}$,	One input at $V_{CC} - 0.6\text{ V}$,	Other inputs at V_{CC} or GND		0.2	mA
	LVC, ALVC, LV					0.5	

[†] Refer to the latest TI data sheets for device specifications.
[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

Figure 5. Examples of Supply-Current Change of the Input at TTL Level as Specified in Data Sheets

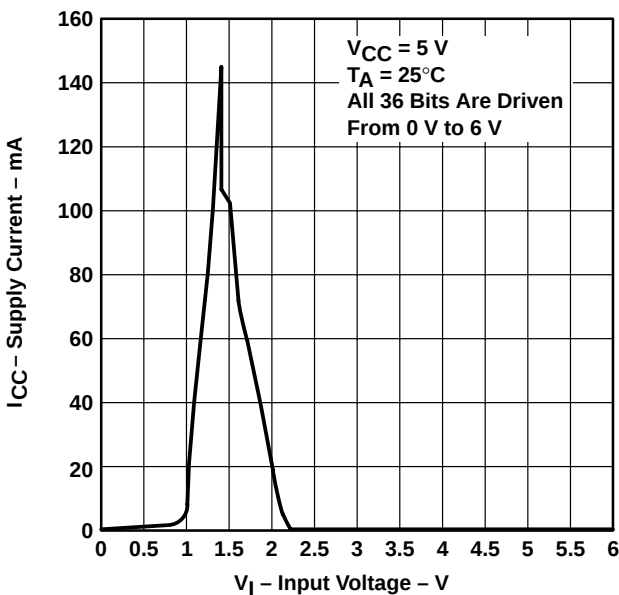


Figure 6. Supply Current Versus Input Voltage (36 Inputs)

As long as the driver is active in a transmission path or bus, the receiver’s input is always in a valid state. No input specification is violated as long as the rise and fall times are within the data-sheet limits. However, when the driver is in a high-impedance state, the receiver input is no longer at a defined level and tends to float. This situation can worsen when several transceivers share the same bus. Figure 7 is an example of a typical bus system. When all transceivers are inactive, the bus-line levels are undefined. When a voltage that is determined by the leakage currents of each component on the bus is reached, the condition is known as a *floating state*. The result is a considerable increase in power consumption and a risk of damaging all components on the bus. Holding the inputs or I/O pins at a valid logic level when they are not being used or when the part driving them is in the high-impedance state is recommended.

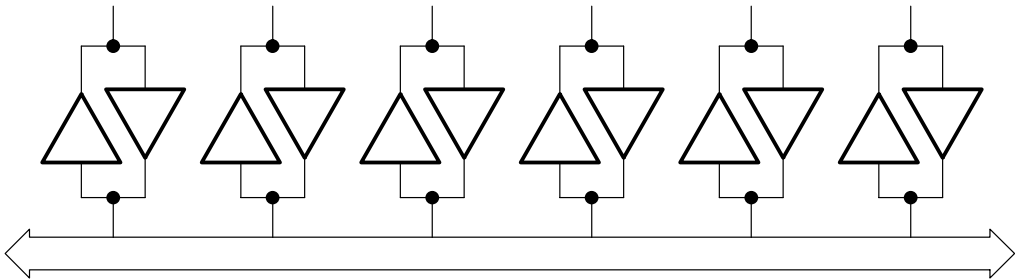


Figure 7. Typical Bidirectional Bus

Recommendations for Designing More-Reliable Systems

Bus Control

The simplest way to avoid floating inputs in a bus system is to ensure that the bus always is either active or inactive for a limited time when the voltage buildup does not exceed the maximum V_{IL} specification (0.8 V for TTL-compatible input). At this voltage, the corresponding I_{CC} value is too low and the device operates without any problem or concern (see Figures 2 and 4).

To avoid damaging components, the designer must know the maximum time the bus can float. First, assuming that the maximum leakage current is $I_{OZ} = 50 \mu A$ and the total capacitance (I/O and line capacitance) is $C = 20 \text{ pF}$, the change in voltage with respect to time on an inactive line that exceeds the 0.8-V level can be calculated as shown in equation 1.

$$\Delta V / \Delta t = \frac{I_{OZ}}{C} = \frac{50 \mu A}{20 \text{ pF}} = 2.5 \text{ V} / \mu s \quad (1)$$

The permissible floating time for the bus in this example should be reduced to 320 ns maximum, which ensures that the bus does not exceed the 0.8-V level specified. The time constant does not change when multiple components are involved because their leakage currents and capacitances are summed.

The advantage of this method is that it requires no additional cost for adding special components. Unfortunately, this method does not always apply because buses are not always active.

Pullup or Pulldown Resistors

When buses are disabled for more than the maximum allowable time, other ways should be used to prevent components from being damaged or overheated. A pullup or a pulldown resistor to V_{CC} or GND, respectively, should be used to keep the bus in a defined state. The size of the resistor plays an important role and, if its resistance is not chosen properly, a problem may occur. Usually, a 1-k Ω to 10-k Ω resistor is recommended. The maximum input transition time must not be violated when selecting pullup or pulldown resistors (see Figure 3). Otherwise, components may oscillate, or device reliability may be affected.

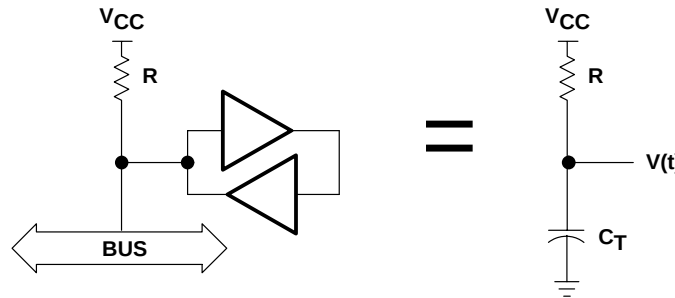


Figure 8. Inactive-Bus Model With a Defined Level

Assume that an active-low bus goes to the high-impedance state as modeled in Figure 8. C_T represents the device plus the bus-line capacitance and R is a pullup resistor to V_{CC} . The value of the required resistor can be calculated as shown in equation 2.

$$V(t) = V_{CC} - [e^{-t/RC_T} (V_{CC} - V_i)] \quad (2)$$

Where:

- $V(t)$ = 2 V, minimum voltage at time t
- V_i = 0.5 V, initial voltage
- V_{CC} = 5 V
- C_T = total capacitance
- R = pullup resistor
- t = maximum input rise time as specified in the data sheets (see Figure 3).

Solving for R, the equation becomes:

$$R = \frac{t}{0.4 \times C_T} \quad (3)$$

For multiple transceivers on a bus:

$$R = \frac{t}{0.4 \times C \times N} \quad (4)$$

Where:

C = individual component and trace capacitance

N = number of components connected to the bus

Assuming that there are two components connected to the bus, each with a capacitance C = 15 pF, requiring a maximum rise time of 10 ns/V and t = 15-ns total rise time for the input (2 V), the maximum resistor size can be calculated:

$$R = \frac{15 \text{ ns}}{0.4 \times 15 \text{ pF} \times 2} = 1.25 \text{ k}\Omega \quad (5)$$

This pullup resistor method is recommended for ac-powered systems; however, it is not recommended for battery-operated equipment because power consumption is critical. Instead, use the bus-hold feature that is discussed in the next section. The overall advantage of using pullup resistors is that they ensure defined levels when the bus is floating and help eliminate some of the line reflections, because resistors also can act as bus terminations.

Bus-Hold Circuits

The most effective method to provide defined levels for a floating bus is to use Texas Instruments (TI™) built-in bus-hold feature on selected families or as an external component like the SN74ACT1071 and SN74ACT1073 (refer to Table 1).

Table 1. Devices With Bus Hold

DEVICE TYPE	BUS HOLD INCORPORATED
SN74ACT1071	10-bit bus hold with clamping diodes
SN74ACT1073	16-bit bus hold with clamping diodes
ABT Widebus+ (32 and 36 bit)	All devices
ABT Octals and Widebus	Selected devices only
AHC/AHCT Widebus	TBA (Selected devices only)
Low Voltage (LVT and ALVC)	All devices
LVC Widebus	All devices

Bus-hold circuits are used in selected TI families to help solve the floating-input problem and eliminate the need for pullup and pulldown resistors. Bus-hold circuits consist of two back-to-back inverters with the output fed back to the input through a resistor (see Figure 9). To understand how the bus-hold circuit operates, assume that an active driver has switched the line to a high level. This results in no current flowing through the feedback circuit. Now, the driver goes to the high-impedance state and the bus-hold circuit holds the high level through the feedback resistor. The current requirement of the bus-hold circuit is determined only by the leakage current of the circuit. The same condition applies when the bus is in the low state and then goes inactive.

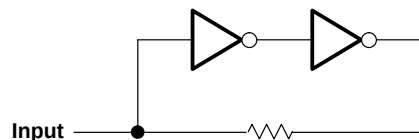


Figure 9. Typical Bus-Hold Circuit

As mentioned previously in this section, TI offers the bus-hold capability as stand-alone 10-bit and 16-bit devices (SN74ACT1071 and SN74ACT1073) with clamping diodes to V_{CC} and GND for added protection against line reflections caused by impedance mismatch on the bus. Because purely ohmic resistors cannot be implemented easily in CMOS circuits, a configuration known as a transmission gate is used as the feedback element (see Figure 10). An n-channel and a p-channel are arranged in parallel between the input and the output of the buffer stage. The gate of the n-channel transistor is connected to V_{CC} and the gate of the p-channel is connected to GND. When the output of the buffer is high, the p-channel is on, and when the output is low, the n-channel is on. Both channels have a relatively small surface area — the on-state resistance from drain to source, $R_{ds(on)}$, is about 5 k Ω .

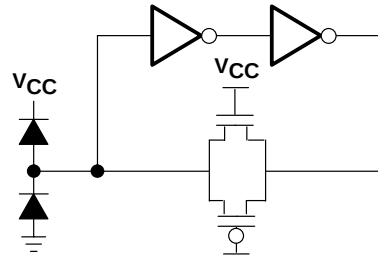


Figure 10. Stand-Alone Bus-Hold Circuit (SN74ACT107x)

Assume that in a practical application the leakage current of a driver on a bus is $I_{OZ} = 10 \mu\text{A}$ and the voltage drop across the 5-k Ω resistance is $V_D = 0.8 \text{ V}$ (this value is assumed to ensure a defined logic level). Then, the maximum number of components that a bus-hold circuit can handle is calculated as follows:

$$N = \frac{V_D}{I_{OZ} \times R} = \frac{0.8 \text{ V}}{10 \mu\text{A} \times 5 \text{ k}\Omega} = 16 \text{ components} \quad (6)$$

The 74ACT1071 and 74ACT1073 also provide clamping diodes as an added feature to the bus-hold circuit. These diodes are useful for clamping any overshoot or undershoot generated by line reflections. Figure 11 shows the characteristics of the diodes when the input voltage is above V_{CC} or below GND. At $V_I = -1 \text{ V}$, the diode can source about 50 mA, which can help eliminate undershoots. This can be very useful when noisy buses are a concern.

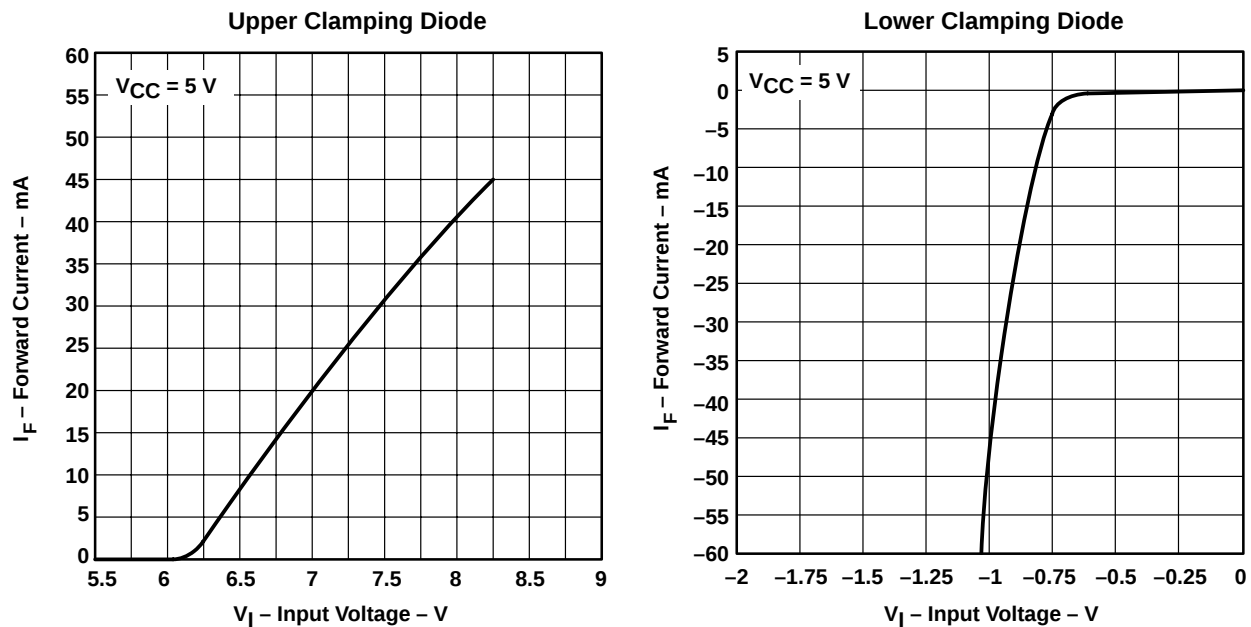


Figure 11. Diode Characteristics (SN74ACT107x)

TI also offers the bus-hold circuit as a feature added to some of the advanced-family drivers and receivers. This circuit is similar to the stand-alone circuit, with a diode added to the drain of the second inverter (ABT and LVT only, see Figure 12). The diode blocks the overshoot current when the input voltage is higher than V_{CC} ($V_I > V_{CC}$), so only the leakage current is present. This circuit uses the device's input stage as its first inverter; a second inverter creates the feedback feature. The calculation of the maximum number of components that the bus-hold circuit can handle is similar to the previous example. However, the advantage of this circuit over the stand-alone bus-hold circuit is that it eliminates the need for external components or resistors that occupy more area on the board. This becomes critical for some designs, especially when wide buses are used. Also, because cost and board-dimension restrictions are a major concern, designers prefer the easy fix: drop-in replaceable parts. TI offers this feature in most of the commonly used functions in several families (refer to Table 1 for more details).

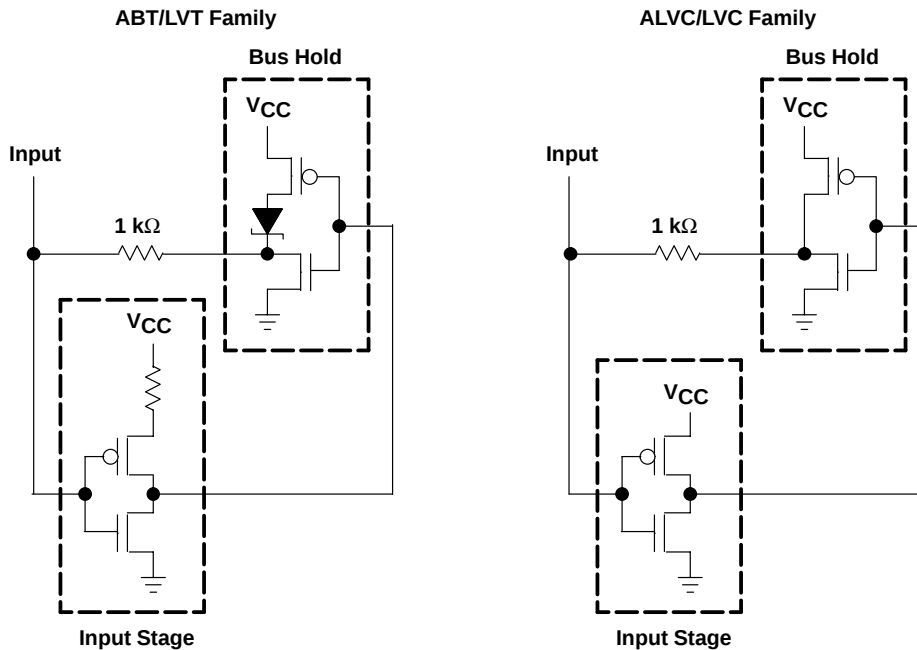


Figure 12. Input Structure of ABT/LVT and ALVC/LVC Families With Bus-Hold Circuit

Figure 13 shows the input characteristics of the bus-hold circuit at 3.3-V and 5-V operations, as the input voltage is swept from 0 to 5 V. These characteristics are similar in behavior to a weak driver. This driver sinks current into the part when the input is low and sources current out of the part when the input is high. When the voltage is near the threshold, the circuit tries to switch to the other state, always keeping the input at a valid level. This is the result of the internal feedback circuit. The plot also shows that the current is at its maximum when the input is near the threshold. $I_{I(\text{hold})}$ maximum is approximately 25 μA for 3.3-V input and 400 μA for 5-V input.

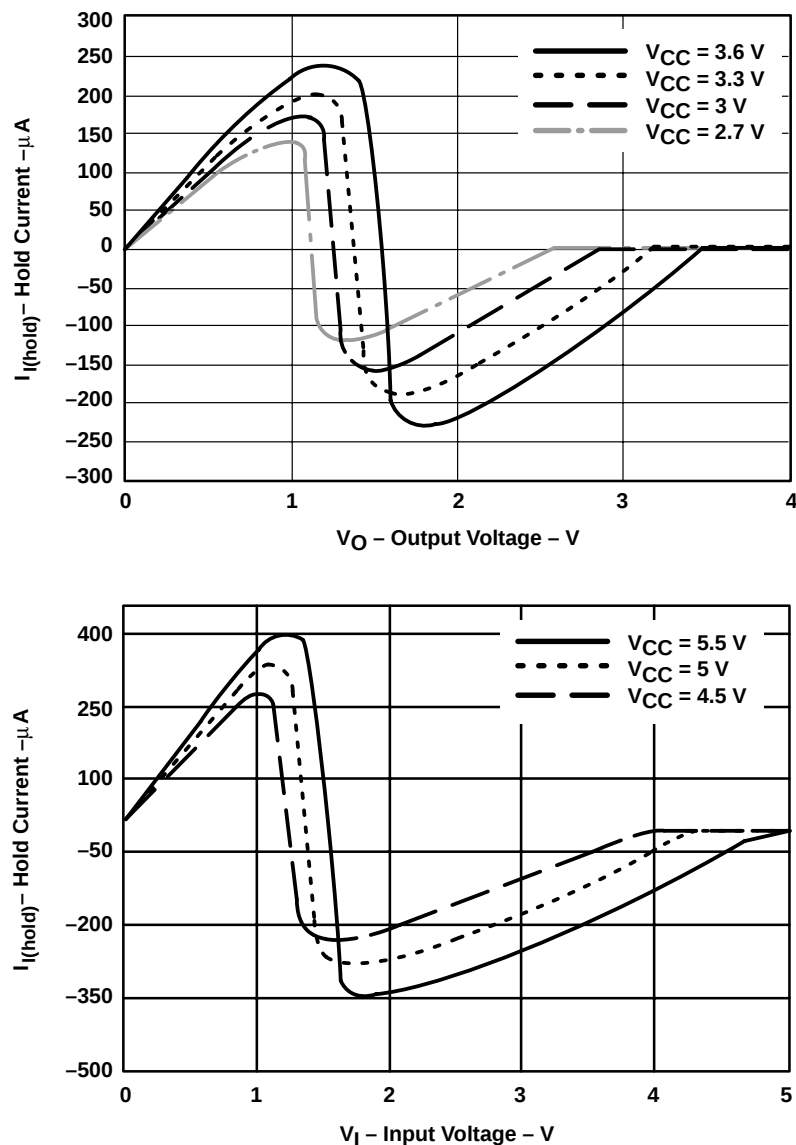


Figure 13. Bus-Hold Input Characteristics

When multiple devices with bus-hold circuits are driven by a single driver, there may be some concern about the ac switching capability of the driver becoming weaker. As small drivers, bus-hold circuits require an ac current to switch them. This current is not significant when using TI CMOS and BiCMOS families. Figure 14 shows a 4-mA buffer driving six LVTH16244 devices. The trace is a 75- Ω transmission line. The receivers are separated by 1cm, with the driver located in the center of the trace. Figure 15 shows the bus-hold loading effect on the driver when connected to six receivers switching low or high. It also shows the same system with the bus-hold circuit disconnected from the receivers. Both plots show the effect of bus hold on the driver's rise and fall times. Initially, the bus-hold circuit tries to counteract the driver, causing the rise or fall time to increase. Then, the bus-hold circuit changes states (note the crossover point), which helps the driver switch faster, decreasing the rise or fall time.

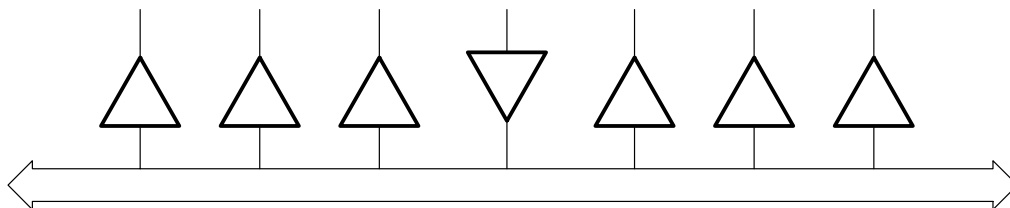


Figure 14. Driver and Receiver System

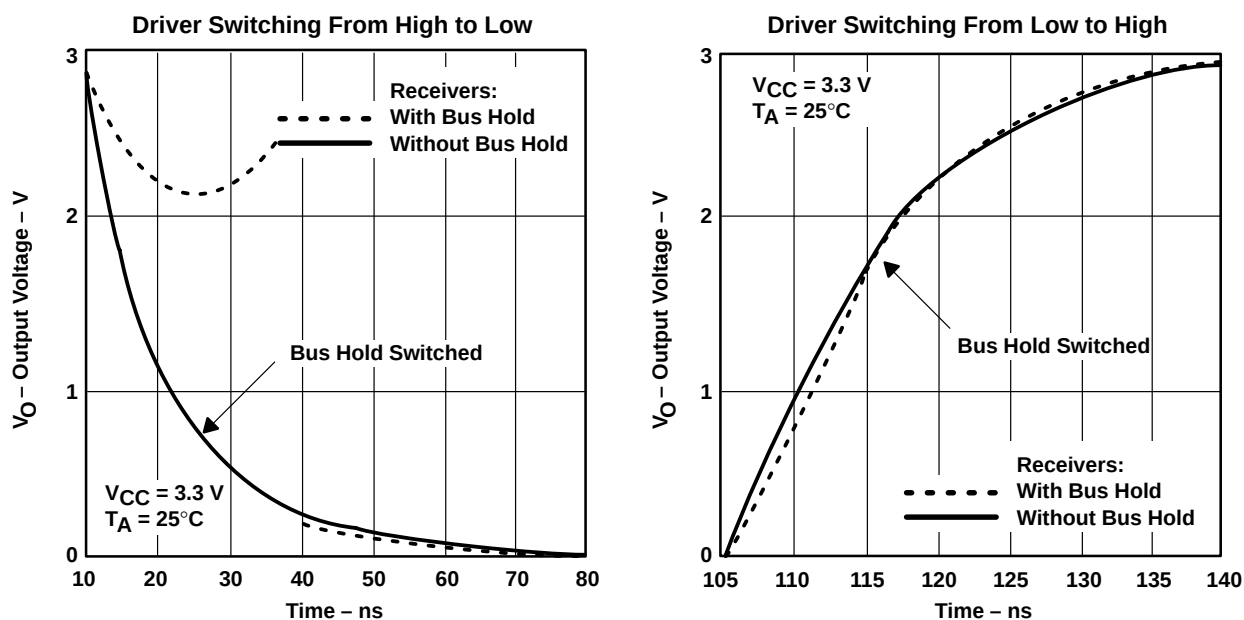


Figure 15. Output Waveforms of Driver With and Without Receiver Bus-Hold Circuit

Figure 16 shows the supply current (I_{CC}) of the bus-hold circuit as the input is swept from 0 to 5 V. The spike at about 1.5-V V_I is due to both the n-channel and the p-channel conducting simultaneously. This is one of the CMOS transistor characteristics.

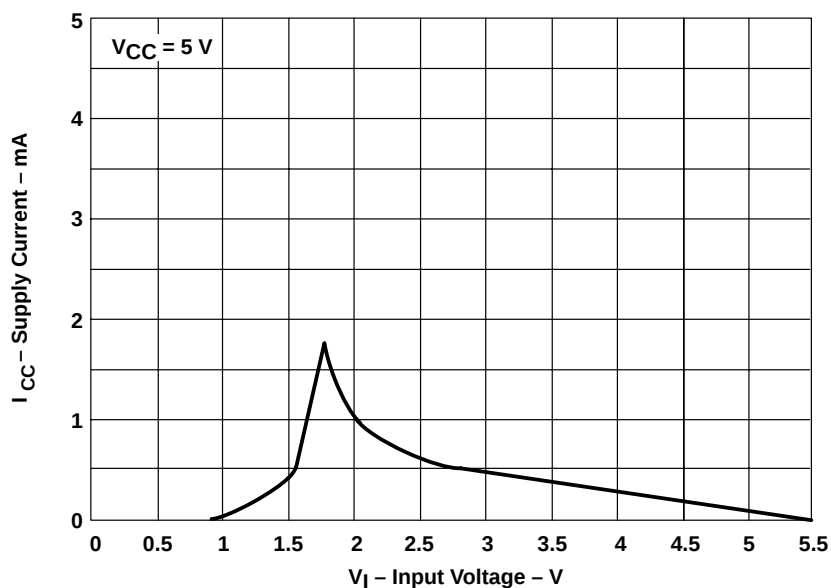


Figure 16. Bus-Hold Circuit Supply Current Versus Input Voltage

The power consumption of the bus-hold circuit is minimal when switching the input at higher frequencies. Figure 17 shows the power consumed by the input at different frequencies, with or without bus hold. The increase in power consumption of the bus-hold circuit at higher frequencies is not significant enough to be considered in power calculations.

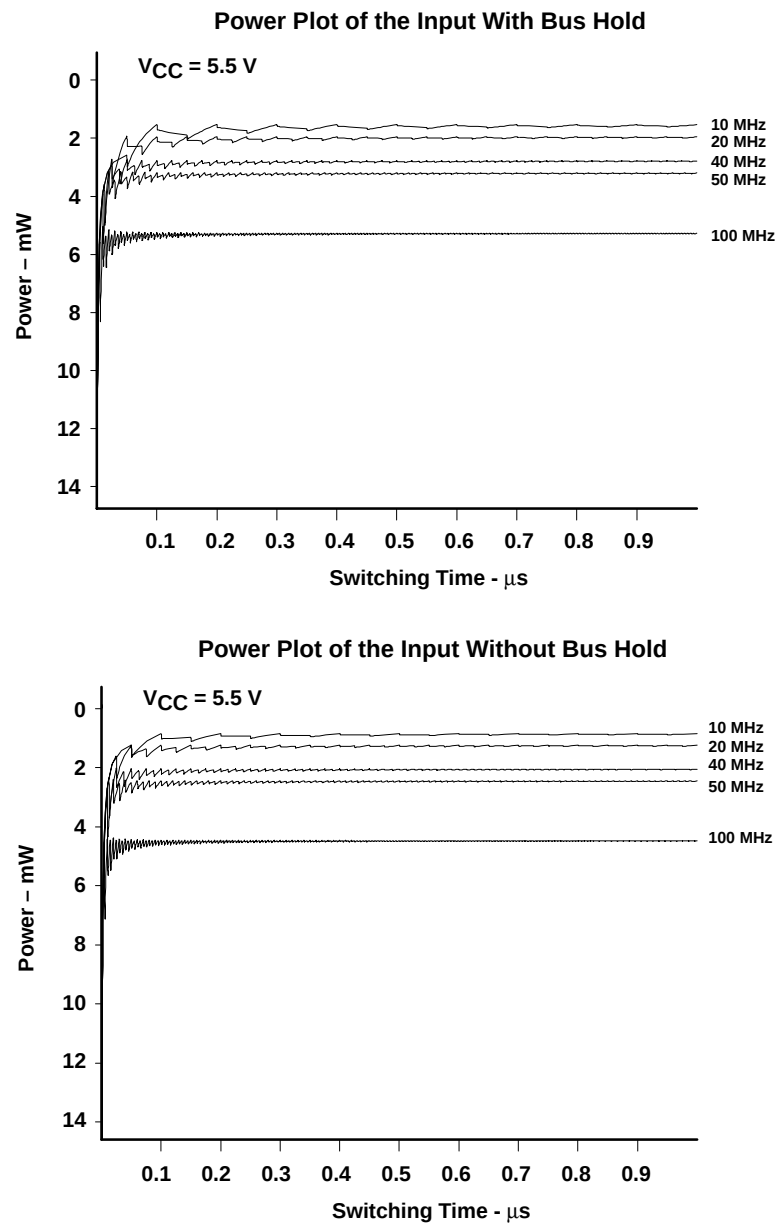


Figure 17. Input Power With and Without Bus Hold at Different Frequencies

Figure 18 shows the data-sheet dc specifications for bus hold. The first test condition is the minimum current required to hold the bus at 0.8 V or 2 V. These voltages meet the specified low and high levels for TTL inputs. The second test condition is the maximum current that the bus-hold circuit sources or sinks at any input voltage between 0 V and 3.6 V (for low-voltage families) or between 0 V and 5.5 V (for ABT). The bus-hold current becomes minimal as the input voltage approaches the rail voltage. The output leakage currents, I_{OZH} and I_{OZL} , are insignificant for transceivers with bus hold because a true leakage test cannot be performed due to the existence of the bus-hold circuit. Because the bus-hold circuit behaves as a small driver, it tends to source or sink a current that is opposite in direction to the leakage current. This situation is true for transceivers with the bus-hold feature only and does not apply to buffers. All LVT, ABT Widebus+, and selected ABT octal and Widebus devices have the bus-hold feature (refer to Table 1 or contact the local TI sales office for more information).

electrical characteristics over recommended operating free-air temperature range (for families with bus-hold feature)[†]

PARAMETER			TEST CONDITIONS		MIN	MAX	UNIT
$I_{I(hold)}$	Data inputs or I/Os	LVT, LVC, ALVC	$V_{CC} = 3\text{ V}$	$V_I = 0.8\text{ V}$	75	μA	
		$V_I = 2\text{ V}$		-75			
		LVC, ALVC	$V_{CC} = 3.6\text{ V},$	$V_I = 0\text{ to }3.6\text{ V}$	± 500		
		ABT Widebus+ and selected ABT	$V_{CC} = 4.5\text{ V}$	$V_I = 0.8\text{ V}$	100		
				$V_I = 2\text{ V}$	-100		
I_{OZH}/I_{OZL}	Transceivers with bus hold	ABT	This test is not a true I_{OZ} test because bus hold always is active on an I/O pin. Bus hold tends to supply a current that is opposite in direction to the output leakage current.		± 1	μA	
		LVT, LVC, ALVC					
	Buffers with bus hold	ABT	This test is a true I_{OZ} test since bus hold does not exist on an output pin.		± 10		
		LVT, LVC, ALVC			± 5		

[†] Refer to the latest TI data sheets for device specifications.

Figure 18. Example of Data-Sheet Minimum Specification for Bus Hold

Summary

Floating inputs and slow rise and fall times are important issues to consider when designing with CMOS and advanced BiCMOS families. It is important to understand the complications associated with floating inputs. Terminating the bus properly plays a major role in achieving reliable systems. The three methods recommended in this application report should be considered. If it is not possible to control the bus directly, and adding pullup or pulldown resistors is impractical due to power-consumption and board-space limitations, bus hold is the best choice. TI designed bus hold to reduce the need for resistors used in bus designs, thus reducing the number of components on the board and improving the overall reliability of the system.

3.3-V to 2.5-V Translation With Texas Instruments Crossbar Technology

SCDA004A
April 1998



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Introduction

The Texas Instruments (TI™) crossbar-technology (CBT) family is known for its multipurpose use in the design arena. It is used in almost every personal computer, server, workstation, and telecom application in the industry. CBT is an easy and low-cost solution for systems that require:

- Bus isolation
- Bus swapping in a multiprocessor/memory environment
- Live insertion
- 5-V to 3.3-V translation
- 3.3-V to 2.5-V translation

Translation from 3.3 V to 2.5 V is accomplished easily; however, reliable translation from 2.5 V to 3.3 V cannot be achieved with the existing CBT family because there is no noise margin for the high-state switching.

2.5-V and 3.3-V Switching Standards

Figure 1 shows the 3.3-V and 2.5-V switching thresholds.

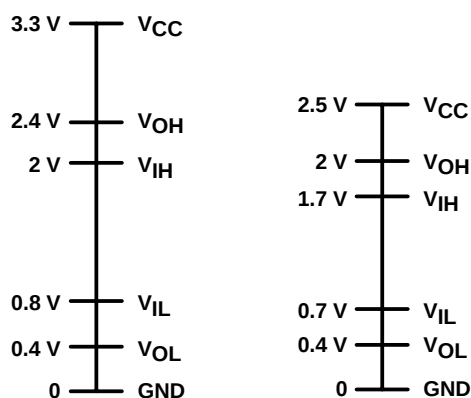


Figure 1. 3.3-V and 2.5-V V_{CC} Thresholds

3.3-V to 2.5-V Translation

Figure 1 shows there is enough noise margin (300 mV for low state and 700 mV for high state) to establish reliable translation from 3.3-V logic to 2.5-V logic. This is always valid, but one must ensure that the input clamping diode of the 2.5-V device is not forward biased. V_{IH} should not exceed V_{CC} (2.5-V logic) + 0.3 V.

2.5-V to 3.3-V Translation

Figure 1 shows a 400-mV noise margin for the low-state translation, but zero noise margin for the high state, and therefore, translation from 2.5-V to 3.3-V devices cannot be achieved without additional consideration.

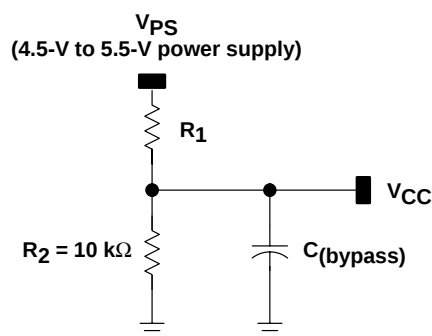
Translating With CBT

A CBT switch is a simple NMOS transistor that acts like a resistor when it is on. Its impedance varies with the amount of current flowing from its drain to its source. A single 3.3-V power supply connected to V_{CC} is not enough to provide sufficient translation since V_{OH} can vary, depending on the input current (I_I) through the switch. The higher I_I is, the lower the output logic level V_{OH} is. A higher 2.5-V device V_{CC} is required to maintain the minimum V_{OH} . The following tables show the required 2.5-V device V_{CC} to maintain a 2-V and 2.4-V V_{OH} .

$V_{IN} = 3.3 \text{ V}, V_{OH(MIN)} = 2 \text{ V}$	
I_I THROUGH THE SWITCH	REQUIRED V_{CC}
1 μA	2.75 V
100 μA	3 V
1 mA	3.1 V
15 mA	3.5 V
30 mA	3.7 V

$V_{IN} = 3.3 \text{ V}, V_{OH(MIN)} = 2.4 \text{ V}$	
I_I THROUGH THE SWITCH	REQUIRED V_{CC}
1 μA	3.1 V
100 μA	3.4 V
1 mA	3.6 V
15 mA	4 V
30 mA	4.2 V

To achieve a good supply voltage to the V_{CC} pin and still be able to modify it based on the input current requirement, a voltage divider should be used to derive the required voltage, as shown in Figure 2. The recommended value of R_2 is 10 $k\Omega$. $C_{(bypass)}$ is the bypass capacitor (recommended value ranges from 0.1 to 0.01 μF and should be as close as possible to the V_{CC} pin of the CBT device). The value of R_1 is determined from the power-supply voltage, the input current, and the V_{OH} requirement.



Note: $C_{(bypass)} = 0.1$ to $0.01 \mu\text{F}$

Figure 2. Divider Network

Choosing the correct resistor size (R_1) depends on three factors:

- Power-supply voltage level (V_{PS})
- Chip power-supply voltage needed (V_{CC})
- V_{OH} level of the switch

R_1 can be calculated using the generalized formula:

$$R_1 = V_{R1}/I_{R1} \quad (1)$$

Where:

$$V_{R1} = V_{PS} - V_{CC}$$

$$I_{R1} = I_{R2} + I_{CC}$$

$$I_{R2} = V_{CC}/R_2$$

$$I_{CC} = 100 \mu A$$

$$R_2 = 10 k\Omega$$

The generalized formula for R_1 can be expanded, by substitution, to:

$$R_1 = (V_{PS} - V_{CC})/[(V_{CC}/10 k\Omega) + 100 \mu A] \quad (2)$$

The following tables show the range of R_1 based on a 5-V supply voltage (V_{PS}), 3.3-V input signal (V_{IH}), 2-V and 2.4-V V_{OH} level with up to 30-mA $I_{(I)}$ through the switch. These tables allow the designer to choose the correct resistor for the design, based on design requirements.

$V_{IN} = 3.3 V, V_{OH(MIN)} = 2 V, I_{CC} = 100 \mu A$				
I_I THROUGH THE SWITCH	REQUIRED V_{CC} (V)	R_1 AT $V_{PS} = 4.5 V$ (k Ω)	R_1 AT $V_{PS} = 5 V$ (k Ω)	R_1 AT $V_{PS} = 5.5 V$ (k Ω)
1 μA	2.75	4.64	6.04	7.32
100 μA	3	3.74	4.99	6.19
1 mA	3.1	3.4	4.64	5.9
15 mA	3.5	2.21	3.32	4.42
30 mA	3.7	1.69	2.74	3.83

$V_{IN} = 3.3 V, V_{OH(MIN)} = 2.4 V, I_{CC} = 100 \mu A$				
I_I THROUGH THE SWITCH	REQUIRED V_{CC} (V)	R_1 AT $V_{PS} = 4.5 V$ (k Ω)	R_1 AT $V_{PS} = 5 V$ (k Ω)	R_1 AT $V_{PS} = 5.5 V$ (k Ω)
1 μA	3.1	3.4	4.64	5.9
100 μA	3.4	2.49	3.65	4.75
1 mA	3.6	1.96	3.01	4.12
15 mA	4	1	2	3.01
30 mA	4.2	0.576	1.54	2.49

Conclusion

TI's CBT family is versatile, not only in the 5-V or the 3.3-V environment, but also in the 2.5-V arena, using a single 5-V power supply to generate required voltage for its V_{CC} pin. This family functions reliably as long as the above conditions are met.

Acknowledgment

This application report was written by Ramzi Ammar, SLL Applications, Texas Instruments.

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Electrical characteristics presented in this data book, unless otherwise noted, apply for the circuit type(s) listed in the page heading, regardless of package. The availability of a circuit function in a particular package is denoted by an alphabetical reference above the pin-connection diagram(s). These alphabetical references refer to mechanical outline drawings shown in this section.

Factory orders for circuits described in this data book should include a three-part type number as explained in the following example.

EXAMPLE: SN 74CBT3245A PW R

Prefix

SN = Standard prefix
SNJ = Compliant to MIL-PRF-38535 (QML)

Unique Circuit Description

MUST CONTAIN SIX TO THIRTEEN CHARACTERS

Examples: 74CBT3125
74CBT16233
74CBTLV162292

Package

MUST CONTAIN ONE TO THREE LETTERS

D, DW = plastic small-outline package (SOIC)
DB, DBQ, DL (or L) = plastic shrink small-outline package (SSOP)[†]
DBV = plastic small-outline transistor (SOT)
DGG (or G), PW = plastic thin shrink small-outline package (TSSOP)[†]
DGV (or V) = plastic thin very small-outline package (TVSOP)[†]
FK = leadless ceramic chip carrier (LCCC)
JT = ceramic dual-in-line package (CDIP)
W, WD = ceramic flat package (CFP)
(from pin-connection diagram on individual data sheet)

Tape-and-Reel Packaging

Valid for surface-mount packages only. All orders for tape and reel must be for whole reels.

R = Standard tape and reel [required for DGG (or G) and DGV (or V); optional for D, DL (or L), and DW packages][‡]

The purpose of tape-and-reel packing is to position components so they can be placed automatically. Components such as, but not limited to, diodes, capacitors, resistors, transistors, inductors, and integrated circuits can be packed in this manner.

The packing materials include a carrier tape, cover tape, and a reel. The normal dimensions for these items are listed in Table 1.

[†] TI is changing the nomenclature for select logic devices. For details, see page 1–6.

[‡] All reeled material previously designated LE will continue to be reeled left embossed, but an R designator will be used.

Table 1. Normal Dimensions of Packing Materials

CARRIER-TAPE WIDTH (mm)	COVER-TAPE WIDTH (mm)	REEL WIDTH (mm)	REEL DIAMETER (mm)
8	5.4	9.0	178
12	9.2	12.4	330
16	13.3	16.4	330
24	21.0	24.4	330
32	25.5	32.4	330
44	37.5	44.4	330
56	49.5	56.4	330

All material meets or exceeds industry guidelines for ESD protection.

Dimensions are selected based on package size and design configurations. All dimensions are established to be within the recommendations of the Electronics Industry Association Standard EIA-481-1,2,3.

Common dimensions of particular interest to the end user are carrier-tape width, pocket pitch, and quantity per reel (see Figure 1 and Table 2).

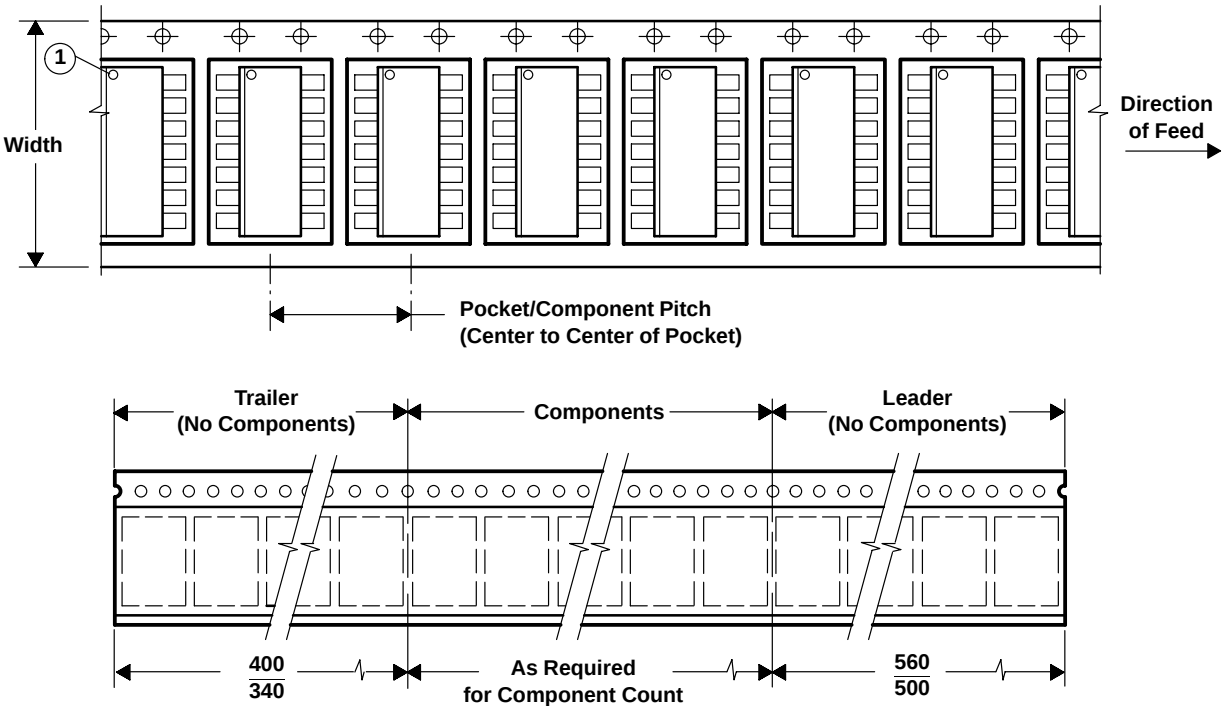


Figure 1. Typical Carrier-Tape Design

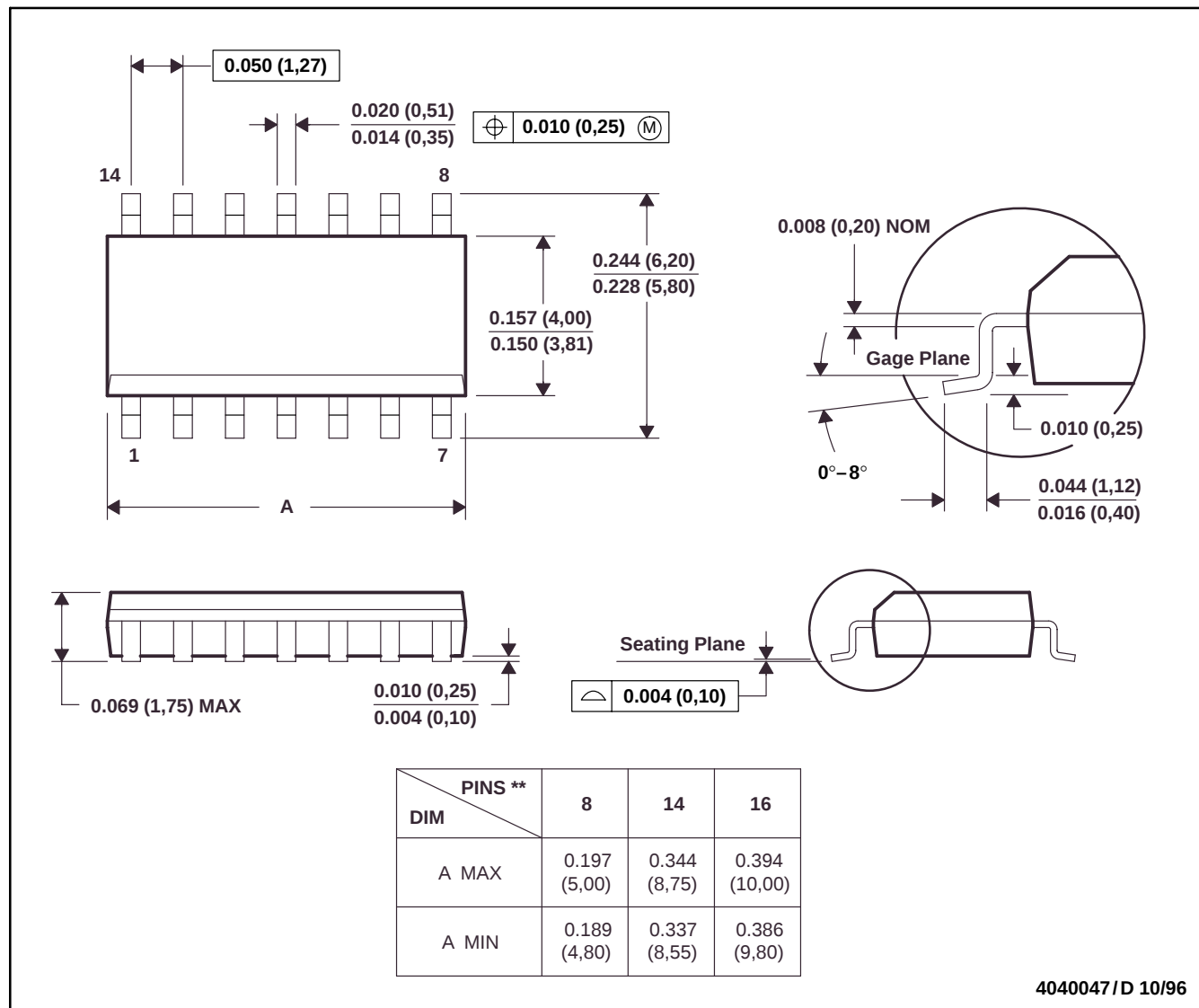
Table 2. Selected Tape-and-Reel Specifications

PACKAGE		NO. OF PINS	CARRIER-TAPE WIDTH (mm)	POCKET PITCH (mm)	QTY/REEL
SOIC	D	14	16.00	8.00	2500
		16	16.00	8.00	2500
	DW	16	16.00	8.00/12.00	1000
		20	24.00	12.00	1000
SOT	DBV	5	8.00	4.00	3000
	DCK	5	8.00	4.00	3000
SSOP	DB	14/16	16.00	12.00	2000
		20	16.00	12.00	2000
	DL	48	32.00	16.00	1000
TSSOP	DGG	48	24.00	12.00	2000
	PW	8	16.00	8.00	2000
		14/16	16.00	8.00	2000
		20	16.00	8.00	2000
TVSOP	DGV	14	16.00	8.00	2000
		16	16.00	8.00	2000
		20	16.00	8.00	2000
		48	16.00	8.00	2000

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



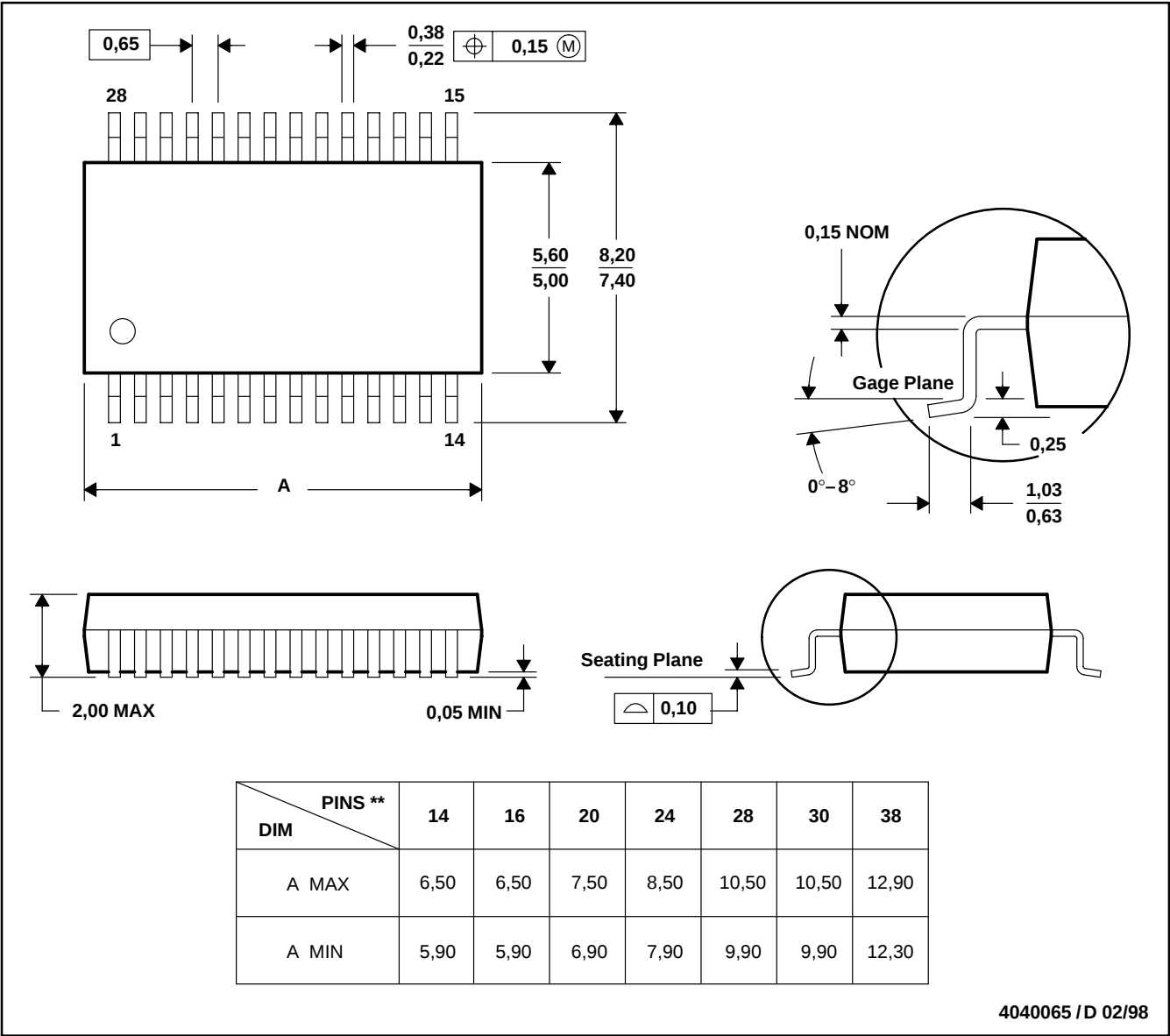
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012

MECHANICAL DATA

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

28 PIN SHOWN

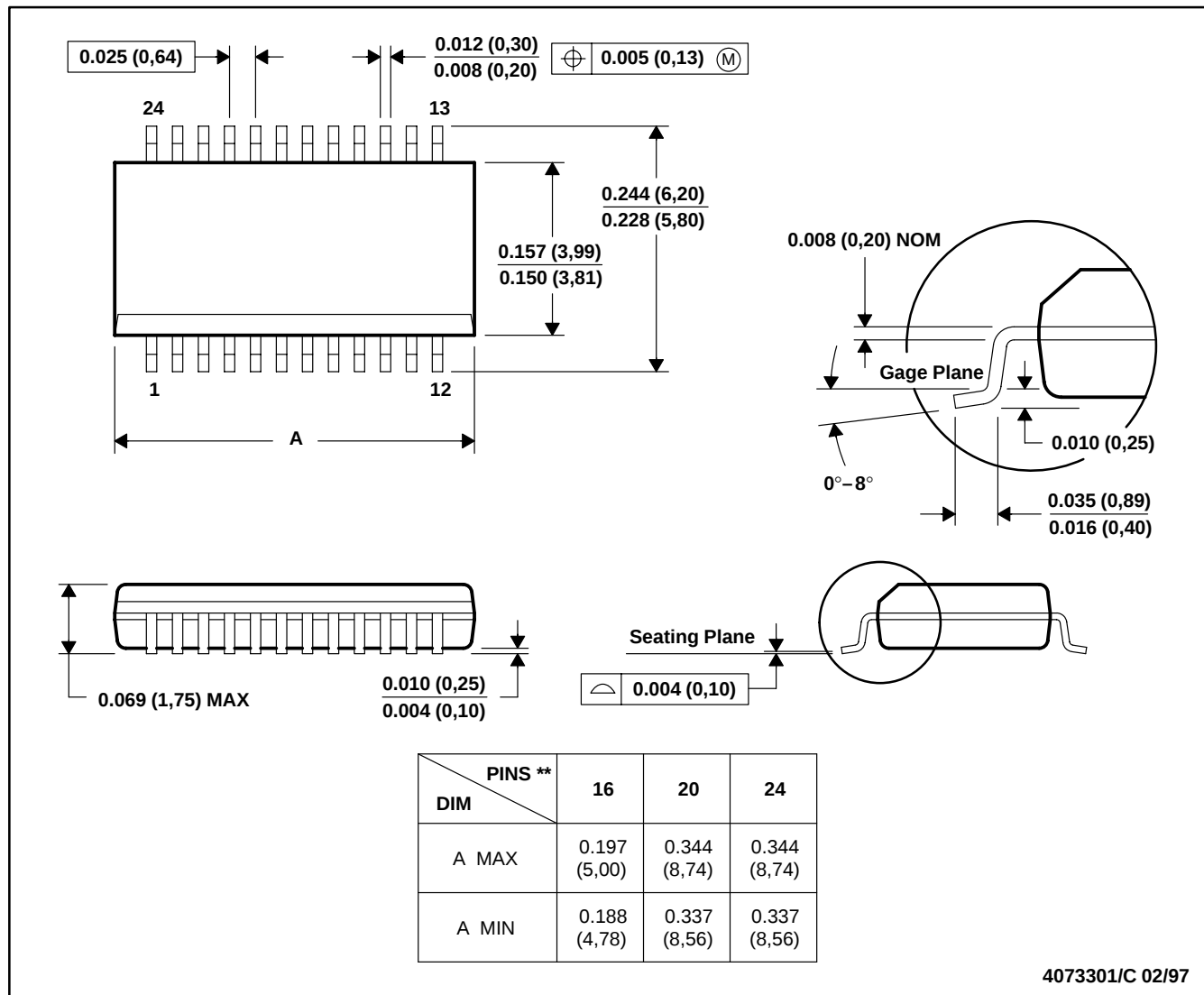


- NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

DBQ (R-PDSO-G**)

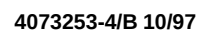
PLASTIC SMALL-OUTLINE PACKAGE

24-PIN SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-137

PLASTIC SMALL-OUTLINE PACKAGE

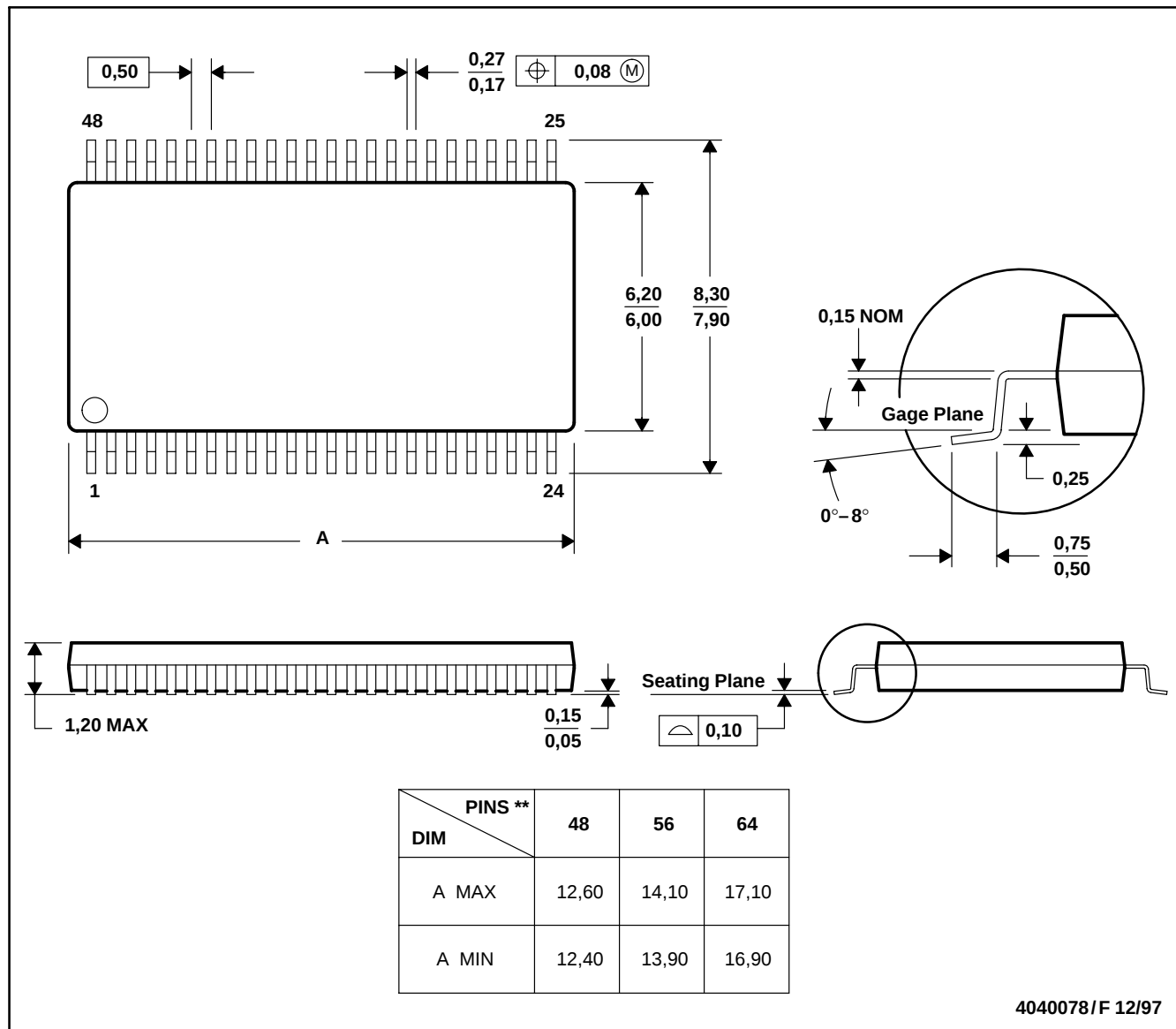


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DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PIN SHOWN

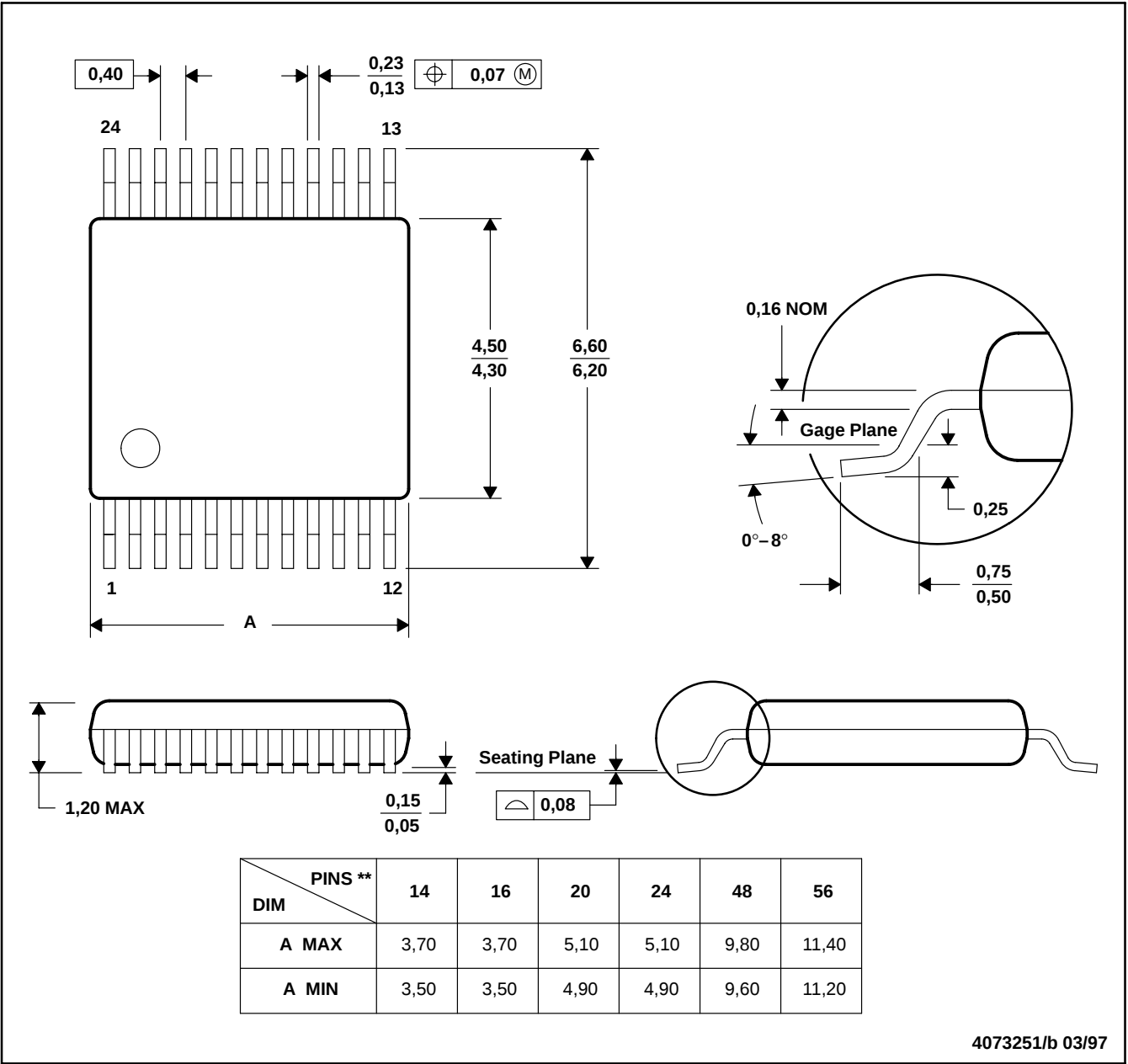


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

24 PIN SHOWN

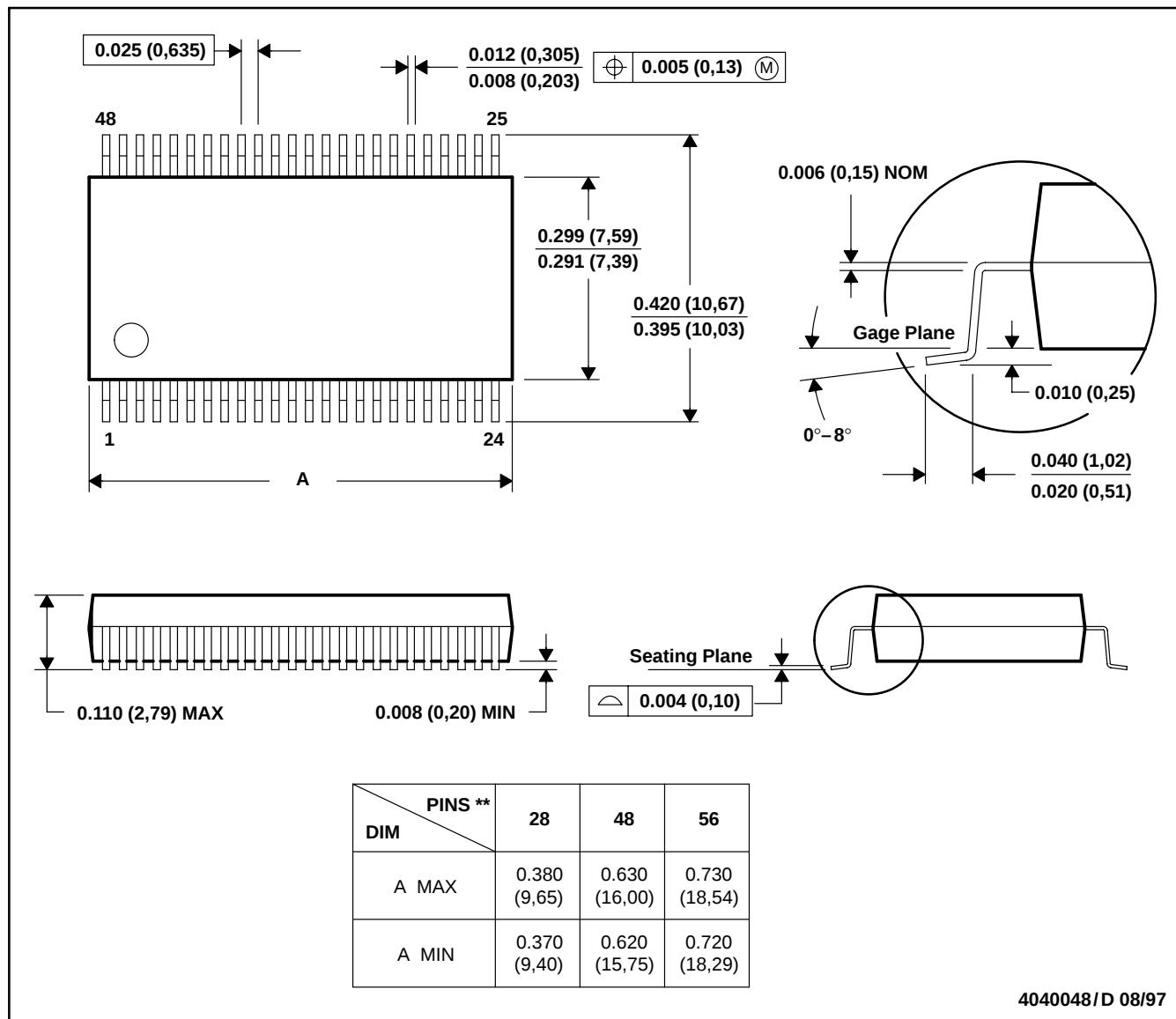


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 - D. The 24 and 48 pins falls within JEDEC MO-153 and the 14, 16, 20, and 56 pins falls within JEDEC MO-194.

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48-PIN SHOWN

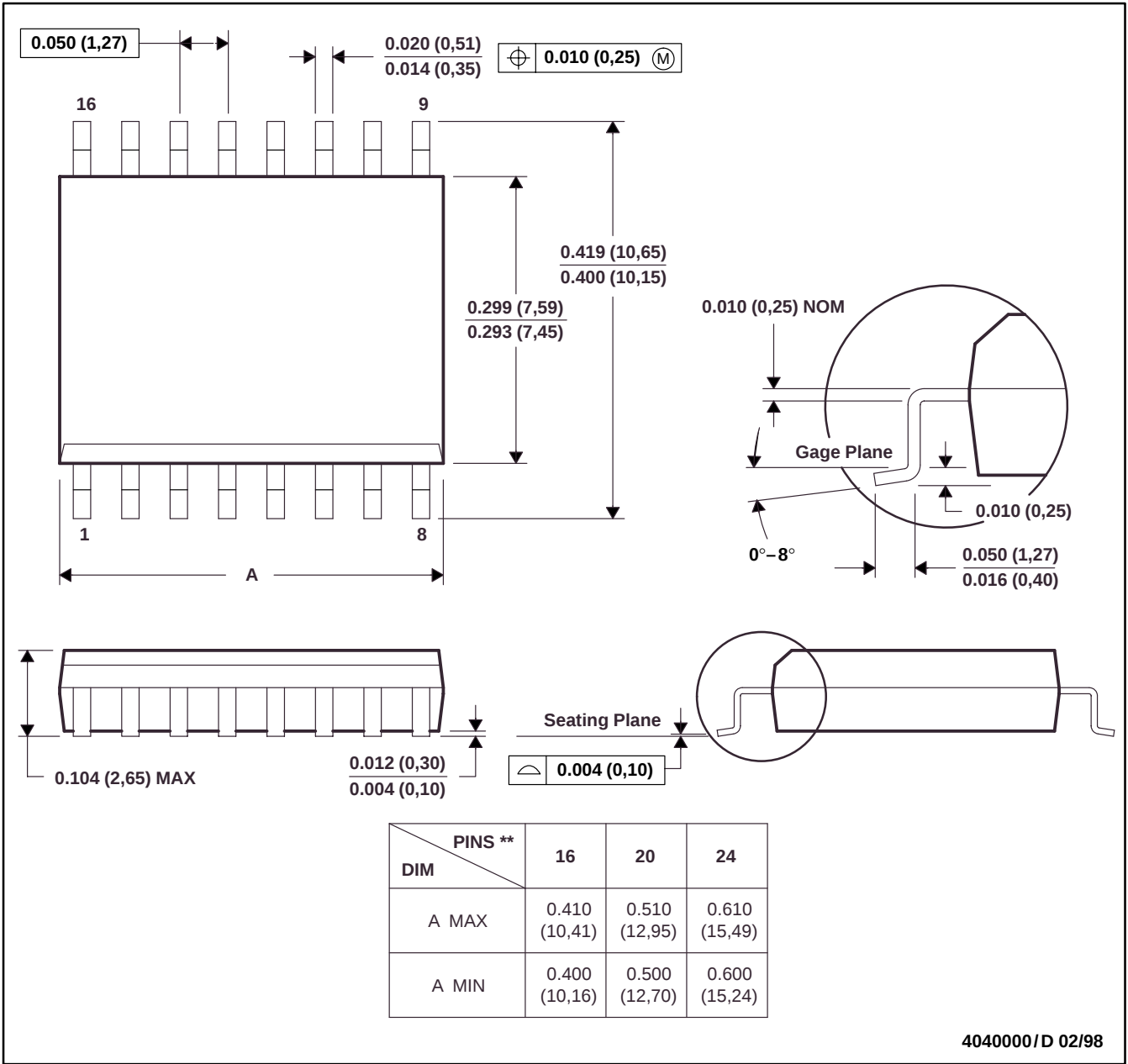


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PIN SHOWN

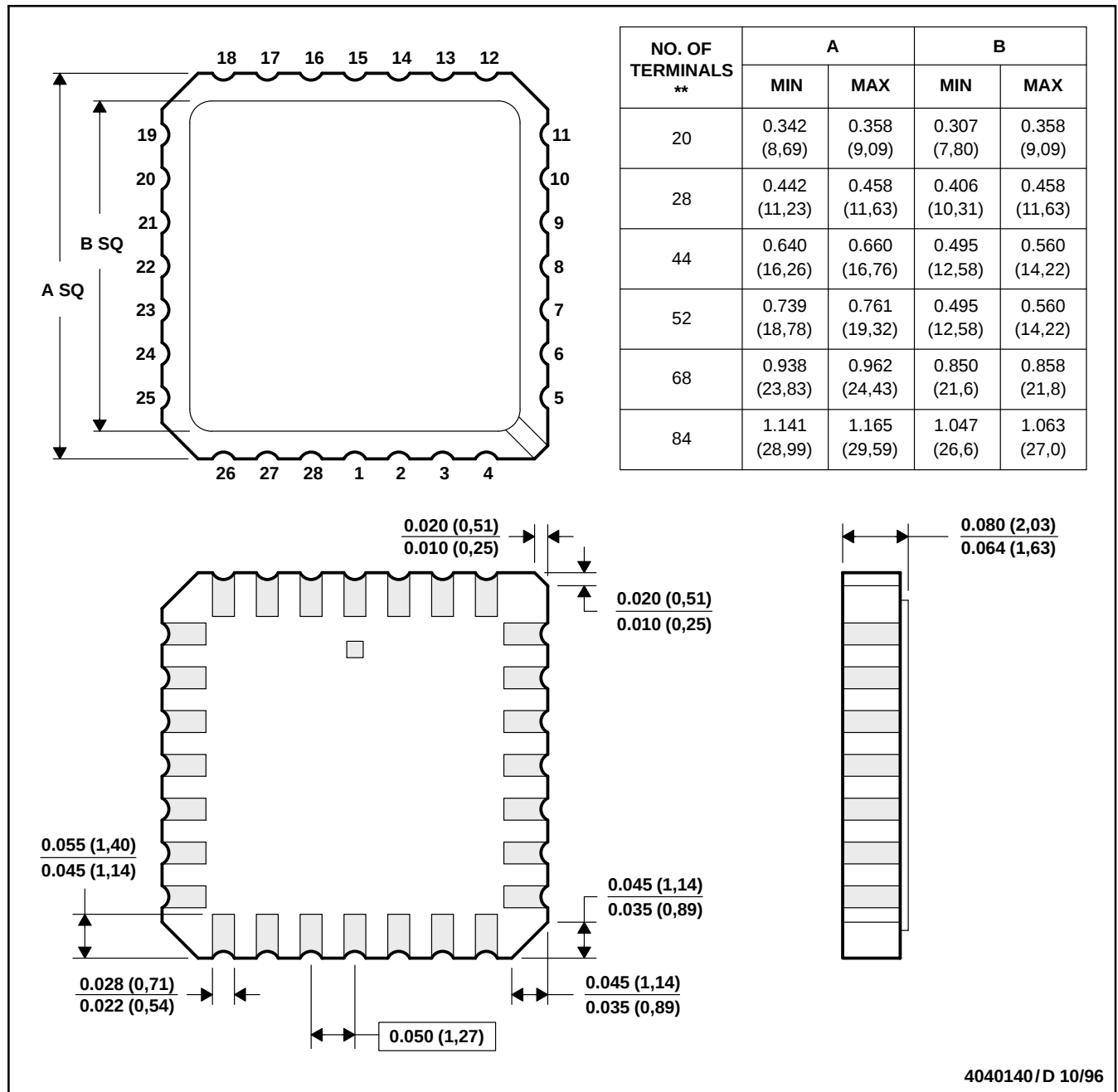


- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

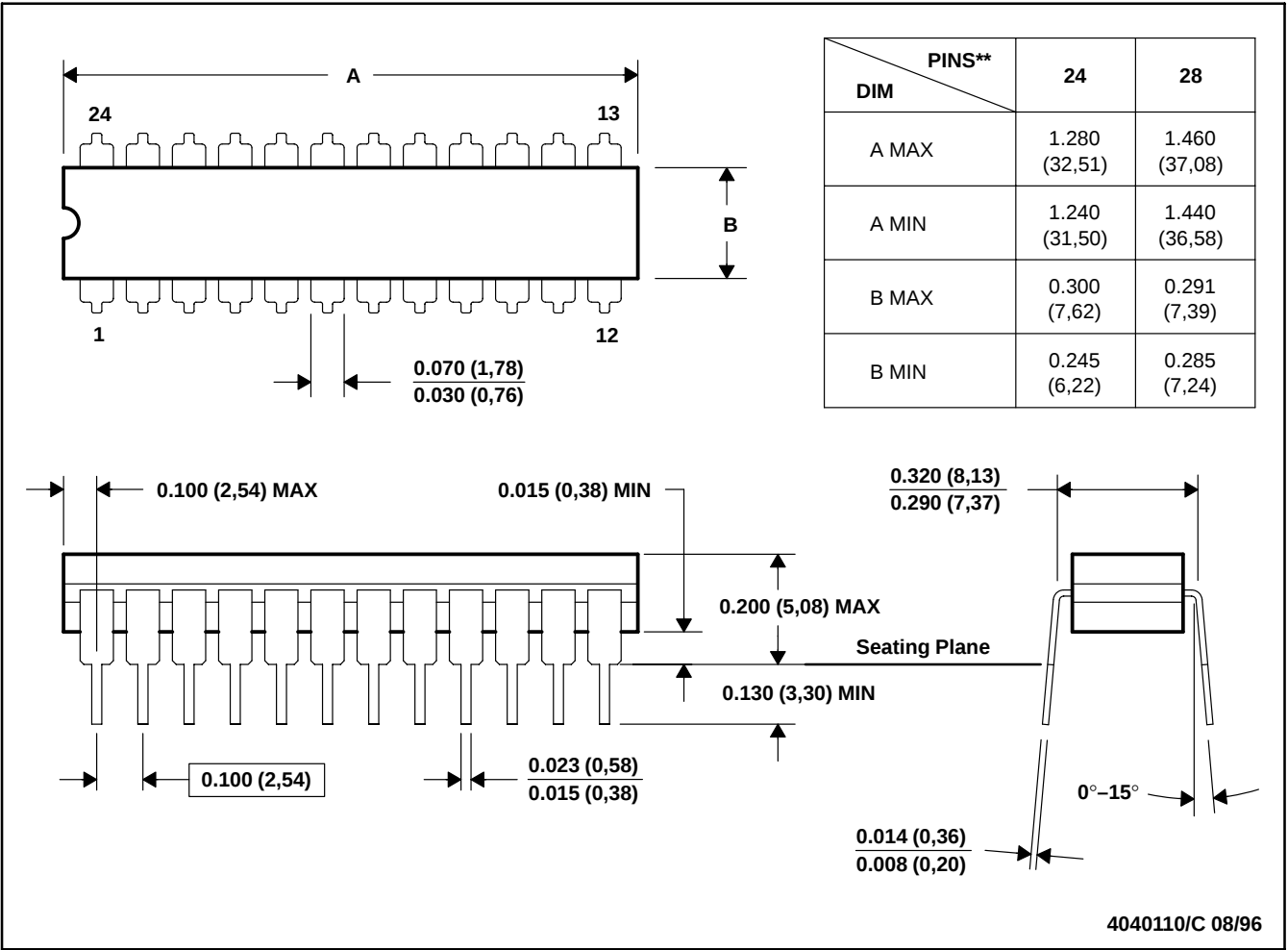


- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

MECHANICAL DATA

JT (R-GDIP-T**)
24 PIN SHOWN

CERAMIC DUAL-IN-LINE PACKAGE

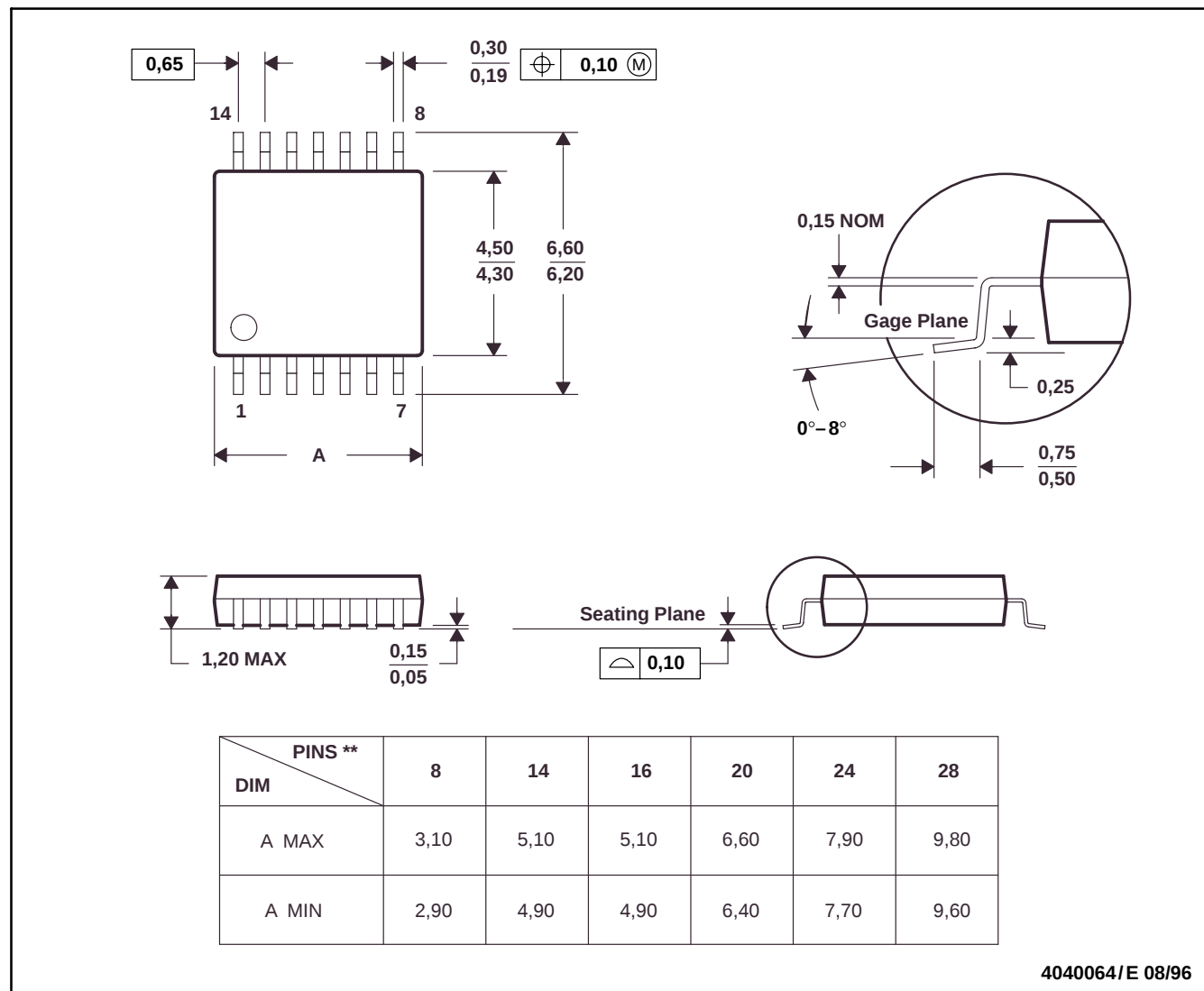


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP-T24, GDIP-T28 and JEDEC MO-058 AA, MO-058 AB.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

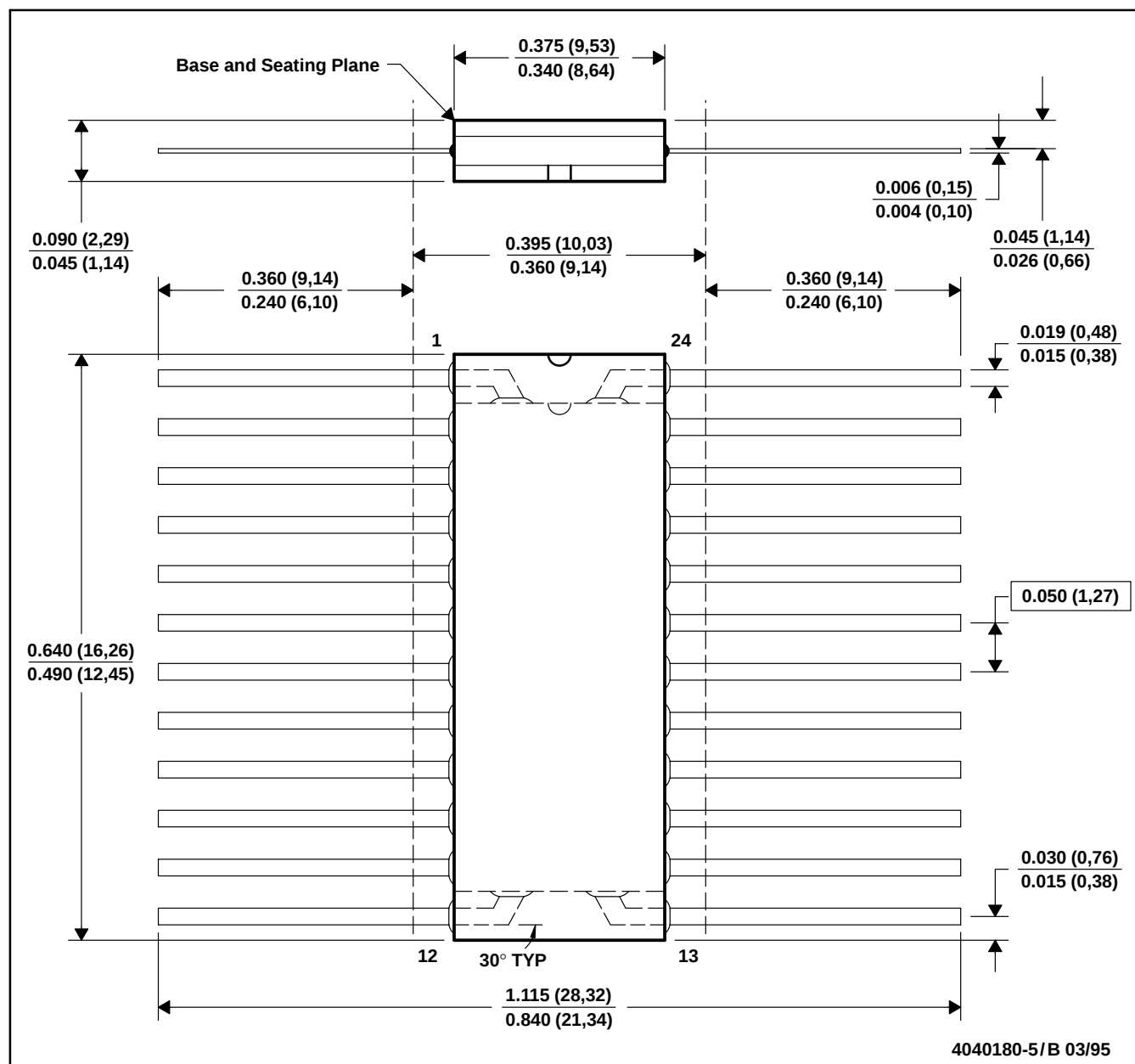
14 PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

W (R-GDFP-F24)

CERAMIC DUAL FLATPACK

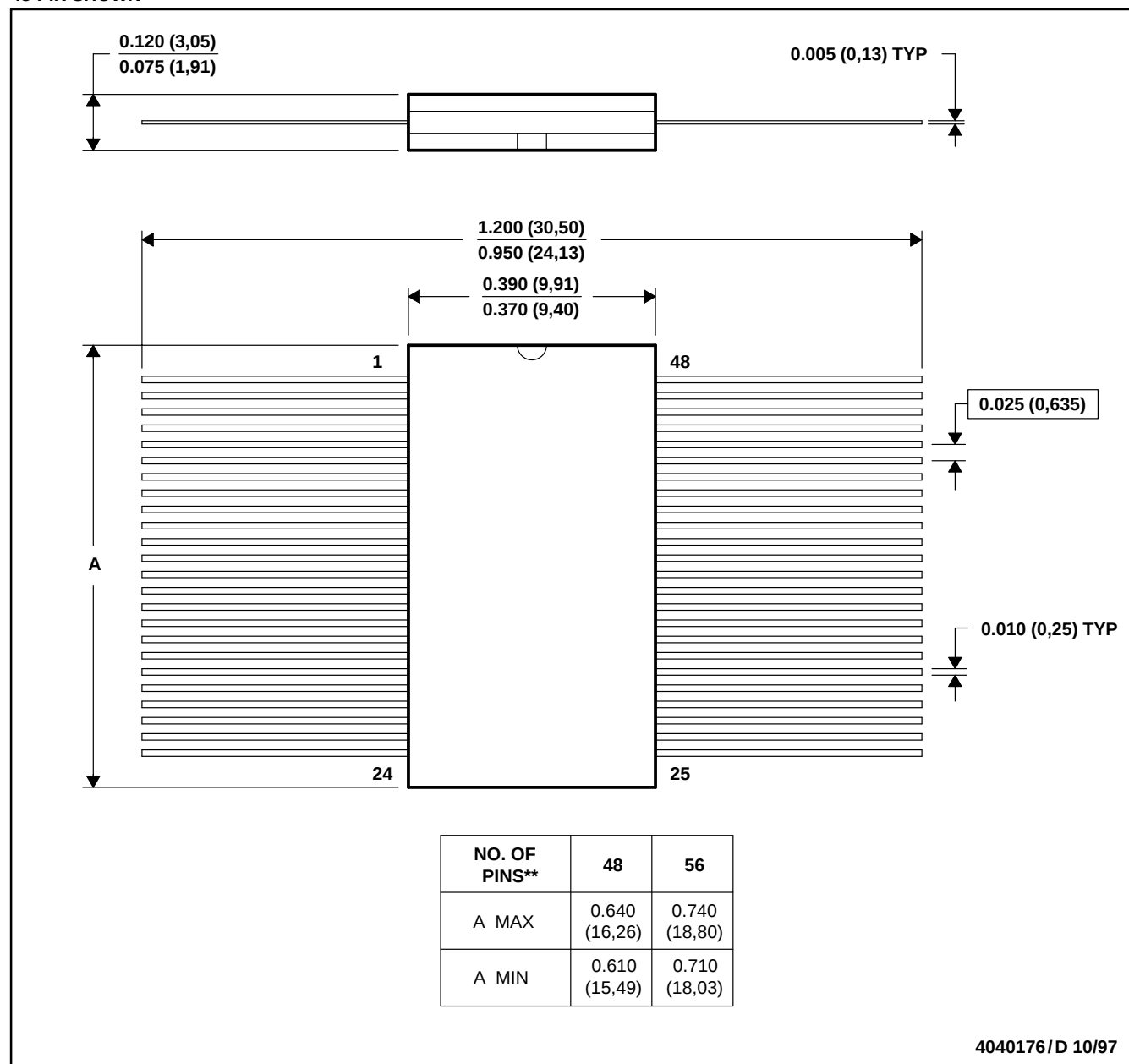


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
 E. Index point is provided on cap for terminal identification only.

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48-PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for pin identification only
 E. Falls within MIL-STD-1835: GDFP1-F48 and JEDEC MO-146AA
 GDFP1-F56 and JEDEC MO-146AB